Clean Track LITHIUS PRO-V

INTEL Finger Print Document



PRO-V Immersion System TD & PRO-V System TD

All Tools except Dry tools
Software version: 100.0.58.226
Sub Operation Panel version: 5.01.40

Dry Tools
Software version: 100.0.58.218
Sub Operation Panel version: 5.01.39

TBL Only

Software version: 100.0.58.228 Sub Operation Panel version: 5.01.40

Teaching Version: 1.28 Temperature Version: 1.30

Revision 7.03

For the P1274 Tool Created by TEA I-Pro 6/1/2021

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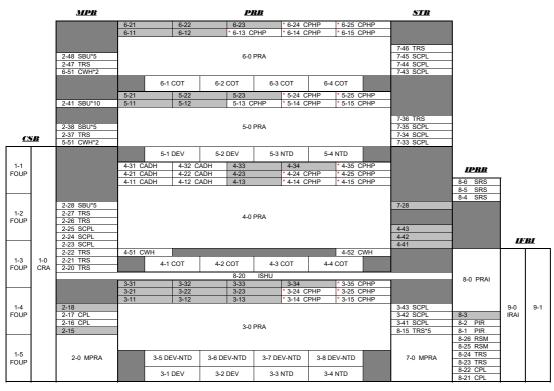
LITHIUS ProV Hardware Fingerprint

1. Overview (Configuration)

1.1 [NTD 6x6] Immersion Configuration (Resist Tracks)

			0.04	0.00.0	555	0.00.05		0040	000	0.05.6	2000				
			6-21 6-11 CPRP	6-22 C		6-23 CF 6-13 CF		6-24 C		6-25 C					
			0-11 CPRP	0-12 C	FRF	0-13 CF	KP	0-14 C	FRF	0-15	PERF	-			
												7-46 TRS	-		
		2-48 SBU*5				6-0 F	RA					7-45 SCPL	1		
		2-47 TRS										7-44 SCPL	1		
		6-51 CWH*2	i									7-43 SCPL	1		
				6-1 COT	6-2	СОТ	6-3	СОТ	6-4	СОТ					
			5-21	5-22		5-23 CF	PRP	5-24 C	PRP	5-25 0	PRP	-			
		2-41 SBU*10	5-11	5-12		5-13 CF		5-14 C		5-15 C					
		2-36 TRS		•											
		2-35 SCPL													
		2-34 SCPL				5-0 F	PRA					7-38 TRS			
cs	R	2-33 SCPL										7-37 TRS			
												5-51			
				5-1 DEV	5-2	DEV	5-3	NTD	5-4	NTD			<u>IPRB</u>		
1-1			4-31 CADH	4-32 C	ADH	4-33 CA	νDH	4-34 C	PRP	4-35 C	PRP		8-10 PIR		
FOUP			4-21 CADH	4-22 C		4-23 CA	ЮH	4-24 C	PRP	4-25 C			8-9 PIR		
			4-11 CADH	4-12 C	ADH	4-13 CA	DH	4-14 C	PRP	4-15 C	PRP		8-8 SRS		
													8-7 SRS		
		0.00										7.00 CDU#5	8-6 SRS		
1-2		2-28 2-27 TRS										7-28 SBU*5			
FOUP		2-27 TRS	ł			4-0 F	PRA								
1001		2-25 SCPL										4-43			
		2-24 SCPL										4-42			
		2-23 SCPL										4-41	1	<u>IF</u>	<u>BI</u>
		2-22 TRS	4-51 CWH							4-52	CWH				
1-3	1-0	2-21 TRS		4-1 COT	4.2	СОТ	4.2	сот	4.4	СОТ					
FOUP	CRA	2-20 TRS		4-1 001	4-2			COI	4-4	COI					
						8-20							8-0 PRAI		
			3-31	3-32 CF		3-33 CF		3-34 C		3-35 (
			3-21	3-22 CF		3-23 CF		3-24 C		3-25 0					
		0.40	3-11	3-12 CF	PRP	3-13 CF	RP	3-14 C	PRP	3-15 0	PRP	0.40.000	0.4 DID		
1-4 FOUP		2-18										3-43 SCPL	8-4 PIR 8-3 PIR	9-0	9-1
FOUP		2-17 TRS 2-16 TRS										3-42 SCPL 3-41 SCPL	8-2 SRS	IRAI	9-1
		2-16 1R3				3-0 F	PRA					8-15 TRS*5	8-1 SRS		
_		2=13										0=13 11(3 3	8-26 RSM		
													8-25 RSM		
1-5													8-24 TRS		
FOUP		2-0 MPRA		3-5 DEV	3-6	DEV	3-7	NTD	3-8	NTD		7-0 MPRA	8-23 TRS		
				2.1 DEV	2.0	DEV	2.0	NITO	2.4	NITO			8-22 CPL		
				3-1 DEV	3-2	DEV	3-3	NTD	3-4	NTD			8-21 CPL		

1.2 [NTD 4x4] Immersion Configuration (Resist Tracks)



CIM Control Number: 09TEA-CT-00192-1.00

CONFIDENTIAL INFORMATION

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1.3 BARC Configuration TBC/TBE

		<u>MPB</u>					P	RB				<u>STB</u>
			6-21 C		-22 C		6-23 C		6-24 C	3CH	6-25	
			6-11 C	GCH 6	-12 C	GCH	6-13 C	GCH	6-14		6-15	
												7-46 TRS
		2-48 SBU*5					6-0	PRA				7-45 TKS 7-45 SCPL
		2-47 TRS										7-44 SCPL
		6-51 CWH*2										7-43 SCPL
				6-1 BC	Γ	6-2	вст	6-3	вст	6-4	BCT	
			5-21 C		-22 C		5-23 C		5-24 C	GCH	5-25	
		2-41	5-11 C	GCH 5	-12 C	GCH	5-13 C	GCH	5-14		5-15	
												7-36 TRS
		2-38 SBU*5					5-0	PRA				7-35 TKS
		2-37 TRS										7-34 SCPL
		5-51 CWH*2										7-33 SCPL
				5-1 BC	Γ	5-2	вст	5-3	вст	5-4	ВСТ	
			4-31 C		-32 C		4-33 C		4-34 C		4-35	
			4-21 C		-22 C		4-23 C		4-24 C		4-25 4-15	
CS	SB		4-11 C	ADH 4	-12 C	ADH	4-13 C	ADH	4-14 C	ADH	4-15	
		2-28										7-28 SBU*5
1-1		2-27 TRS					4-0	PRA				7 20 000 0
FOUP		2-26 TRS 2-25										4-43
		2-23	-									4-43 4-42 TRS
	i	2-23										4-41
		2-22 TRS	4-51								4-52	
1-2 FOUP		2-21 TRS 2-20 TRS		4-1		4	-2	4	-3	4	-4	
							7-	20				
	1-0		3-31		-32	,	3-33		3-34		3-35	7 13
	CRA		3-21		-22		3-23		3-24		3-25	7-12 7-11
1-3		2-18	3-11	3	-12		3-13		3-14		3-15	3-43
FOUP		2-17										3-42
		2-16					2	-0				3-41
		2-15					3	-0				8-15
1-4 FOUP		2-0 MPRA		3-5		3	-6	3	-7	3	-8	7-0 MPRA
				3-1		3	-2	3	-3	3	-4	

1.4 BARC Configuration TBEna

		<u>MPB</u>					PI	RB				<u>STB</u>
			6-21 CG		6-22 C		6-23 C		6-24 CC	3CH	6-25	
			6-11 CG	CH	6-12 C	GCH	6-13 C	GCH	6-14		6-15	
												7-46 TRS
		2-48 SBU*5	-				6-0	PRA				7-45 TKS 7-45 SCPL
		2-47 TRS					0.0					7-44 SCPL
		6-51 CWH*2										7-43 SCPL
				6-1 B0	СТ	6-2	вст	6-3	вст	6-4 E	вст	
			5-21 CG		5-22 C		5-23 C		5-24 C	GCH	5-25	
		2-41	5-11 CG	CH	5-12 C	GCH	5-13 C	GCH	5-14		5-15	
												7-36 TRS
		2-38 SBU*5	•				5-0	PRA				7-36 TRS 7-35 SCPL
		2-37 TRS	1				5-0	1100				7-34 SCPL
		5-51 CWH*2	1									7-33 SCPL
				5-1 B0	СТ	5-2	вст	5-3	вст	5-4 E	ВСТ	
			4-31		4-32		4-33		4-34		4-35	
			4-21		4-22		4-23		4-24		4-25	
CS	B		4-11		4-12		4-13		4-14		4-15	
		2-28										7-28 SBU*5
1-1 FOUP		2-27 TRS 2-26 TRS					4-	-0				
		2-25										4-43
		2-24 2-23										4-42 TRS 4-41
		2-23 2-22 TRS	4-51								4-52	4-41
1-2		2-21 TRS		4-1			-2		-3	4-		
FOUP		2-20 TRS		4-1		4-			-3	4-	4	
	4.0		0.04		0.00			20	0.04		0.05	 7.40
-	1-0 CRA		3-31 3-21		3-32		3-33 3-23		3-34 3-24		3-35 3-25	7 13 7-12
	OIVA		3-11		3-12		3-23		3-14		3-15	7-12
1-3		2-18										3-43
FOUP		2-17										3-42
		2-16					3-	-0				3-41
		2-15										8-15
1-4 FOUP		2-0 MPRA		3-5	i	3-	-6	3-	-7	3-	8	7-0 MPRA
				3-1		3-	-2	3-	-3	3-	4	

1.5 CE TNE Configuration

		<u>MPB</u>				PI	RB					STB		
			6-21	6-22 C		6-23 C		6-24 CF		6-25 (1	
			6-11 CPRP	6-12 C	PRP	6-13 C	PRP	6-14 CF	PRP	6-15 (PRP	7 47 + TDC		
												7-47 * TRS 7-46 TRS (* SCPL		
		2-48 SBU*5				6-0	PRA					7-45 SCPL		
		2-47 TRS										7-44 SCPL		
		6-51 CWH*2										7-43 SCPL		
				6-1 COT	6-2	COT	6-3	COT	6-4	COT				
			5-21	5-22		5-23		5-24		5-25				
		2-41 SBU*10	5-11	5-12		5-13		5-14		5-15		-		
												7-36		
		2-38				5-	-0					7-35		
CS	B	2-37 5-51	-									7-34 7-33		
		5-51			_		_			. ,		1-33		
				5-1	-	-2		i-3		5-4				
1-1 FOUP			4-31 CADH	4-32 C		4-33 C		4-34 CF		4-35 (_		
FOUP			4-21 CADH 4-11 CADH	4-22 C		4-23 C		4-24 CF		4-25 (4-15 (_		
								1						
		0.00 001145										7.00		
1-2		2-28 SBU*5 2-27 TRS										7-28		
FOUP		2-26 TRS	1			4-0	PRA							
		2-25 SCPL										4-43		
		2-24 SCPL 2-23 SCPL										4-42 4-41	<u>IFBI</u>	
		2-23 3CFL 2-22 TRS	4-51 CWH							4-52 (CWH	4-41		
1-3	1-0	2-21 TRS		4-1 COT	4-2	СОТ	4-3	СОТ	1-1	COT				
FOUP	CRA	2-20 TRS		+-1 001	7-2			001		001				
			3-31	3-32		7-20 3-33 C	ISHU PRP	3-34 CF	PRP	3-35 (PRP	7-13 RSM		
			3-21	3-22		3-23 C		3-24 CF		3-25 (7-12 CPL		
			3-11	3-12		3-13 C	PRP	3-14 CF	PRP	3-15 (PRP	7-11 CPL		
1-4 FOUP		2-18 2-17 TRS										3-43 SCPL 3-42 SCPL	8-0	8-1
1001		2-16 TRS										3-42 SCPL	IRAS	0=1
		2-15 * SCPL				3-0	PRA					8-15 TRS*5		
1-5														
FOUP		2-0 MPRA		3-5 DEV	3-6	DEV	3-7	DEV	3-8	DEV		7-0 MPRA		
				3-1 DEV	3-2	DEV	3-3	DEV	3-4	DEV				
		l .	* Only page											

^{*} Only present after the High Throughput upgrade.

1.6 Non-CE TNE Configuration

		g												
		<u>MPB</u>				P	RB					<u>STB</u>		
			6-21		***CPRP		*CPRP	6-24 **		6-25 C				
			6-11 ***0	CPRP 6-1	***CPRP	6-13 **	*CPRP	6-14 C	PRP	6-15 C	PRP	7-47 **TRS		
												7-47 TRS 7-46 TRS (**SCPL)		
		2-48 SBU*5				6-0	PRA					7-45 SCPL		
		2-47 TRS										7-44 SCPL		
		6-51 CWH*2					1					7-43 SCPL		
				6-1 COT	6-2	COT	6-3	СОТ	6-4	СОТ				
		0.44 CDUI+40	5-21	5-		5-23		5-24		5-25		1		
		2-41 SBU*10	5-11	5-	12	5-13		5-14		5-15		-		
												7-36 TRS		
		2-38 SBU*5				5	-0					7-35 ***SCPL		
<u>cs</u>	B	2-37 TRS 5-51 CWH*2										7-34 ***SCPL 7-33 ***SCPL		
		3-31 CWI12		* 5-1 COT	+5		+50		+5.4	COT		7-00 SCFE		
						2 COT		COT		COT		_		
1-1 FOUP			4-31 CAI 4-21 CAI		CADH CADH		*CADH	4-34 C 4-24 C		4-35 C				
FOUP			4-21 CAL		CADH CADH		*CADH	4-24 C		4-25 C		-		
		2-28 SBU*5										7-28		
1-2		2-20 3B0 3										7-20		
FOUP		2-26 TRS				4-0	PRA							
		2-25 SCPL 2-24 SCPL										4-43	*****	
		2-24 SCPL 2-23 SCPL										4-42 4-41	<u>IFBI</u>	
		2-22 TRS	4-51 CW	'H						4-52 C	WH			
1-3 FOUP	1-0	2-21 TRS		4-1 COT	4-2	COT	4-3	СОТ	4-4	СОТ				
FOUP	CRA	2-20 TRS				7-20	ISHU							
			3-31	3-3			*CPRP	3-34 C	PRP	3-35 C	PRP	7-13 RSM		
			3-21	3-2			*CPRP	3-24 C		3-25 C		7-12 CPL		
1-4		2-18	3-11	3-1	2	3-13 **	*CPRP	3-14 C	PRP	3-15 C	PRP	7-11 CPL 3-43 SCPL		
FOUP		2-17 CPL										3-42 SCPL	8-0 IRAS	8-1
		2-16 CPL				3-0	PRA					3-41 SCPL	IRAS	
		2-15 **SCPL										8-15 TRS*5		
1-5		2-0 MPRA		3-5 DEV	3-6	DEV	3-7	DEV	3-8	DEV		7-0 MPRA		
FOUP		,										I		
				3-1 DEV	3-2	DEV	3-3	DEV	3-4	DEV				

^{*}Reserved module (D5 - COT)

** Only present after the High Throughput upgrade.

*** Not present on HVM conversion tool.

1.7 HVM TNE Configuration_D5 Reserved

6-21			<u>MPB</u>				P	RB					<u>STB</u>		
### 1-248 SBU'5 6-0 PRA				6-21	6-22		6-23	**CPHP	6-24 **	CPHP	6-25 (PHP		1	
248 SBU'5 247 TRS 6-51 CWH'2 6-61 COT 6-2 COT 6-3 COT 6-4 COT 241 SBU'10 5-21 5-22 5-23 5-24 "CPHP 5-25 "CPHP 243 SBU'5 2-38 SBU'5 2-38 SBU'5 5-51 CWH'2 1-1 FOUP 1-1 FOUP 1-1 FOUP 1-1 FOUP 1-2 FOUP 1-3 FOUP 1-3 FOUP 1-3 FOUP 1-3 FOUP 1-4 FOUP 1-3 FOUP 1-4 FOUP 1-5 FOUP 1-5 FOUP 1-5 FOUP 1-5 FOUP 1-5 FOUP 1-5 FOUP 1-6 FOUP 1-7 FOUP 1				6-11	6-12		6-13	**CPHP	6-14 C	PHP	6-15 (PHP			
## SECPL T-48 SE															
## 1-3 1-0 FOUP Four F			2-48 SRI I*5				6-0	PRΔ						1	
6-51 CWH'2 6-1 COT							0-0	1101							
## CSP 5-21 5-22 5-23 S-24 "CPHP 5-25 * CPHP															
## CSB 2.41 SBU*10 5-11					6-1 COT	6-2	COT	6-3	СОТ	6-4	COT				
## CSB 2-38 SBU*5 2-37 TRS 5-10 7-36 TRS 7-36 SCPL 7-34 SCPL 7-34 SCPL 7-34 SCPL 7-34 SCPL 7-34 SCPL 7-33 SCPL 7-34 SCPL 7-33 SCPL 7-28 SCPL 7-29 SCPL 7-2				5-21	5-22		5-23		5-24 **	CPHP	5-25 *	CPHP			
2-38 SBU*5 2-37 TRS 5-10 5-1 COT 5-3 COT 7-33 SCPL 7-34 SCPL 7-34 SCPL 7-33 SCPL 7-28			2-41 SBU*10	5-11	5-12		5-13 **	CPHP	5-14 **	CPHP	5-15 *	CPHP			
2-38 SBU*5 2-37 TRS 5-10 5-1 COT 5-3 COT 7-33 SCPL 7-34 SCPL 7-34 SCPL 7-33 SCPL 7-28															
1-1 FOUP 1-2 FOUP 1-3 CADH			2.20 CDI I*E				5	0							
1-1 FOUP				-			3	-0							
1-1 FOUP 1-1 FOUP 1-1 FOUP 1-2 FOUP 1-2 FOUP 1-3 1-0 FOUP 1-4 FOUP 1-5 FOUP 1-5 FOUP 1-1 FOUP 1-1 FOUP 1-1 FOUP 1-2 FOUP 1-2 FOUP 1-3 1-0 FOUP 1-4 FOUP 1-5 FOUP 1-5 FOUP 1-5 FOUP 1-6 FOUP 1-7 FOUP 1-7 FOUP 1-8 FOUP 1-9 FOUP 1-1 FOUP 1-1 FOUP 1-1 FOUP 1-1 FOUP 1-2 FOUP 1-3 1-0 FOUP 1-4 FOUP 1-5 FOUP 1-5 FOUP 1-6 FOUP 1-7 FOUP 1-7 FOUP 1-8 FOUP 1-8 FOUP 1-9 FOUP 1-1 FOUP 1-1 FOUP 1-1 FOUP 1-1 FOUP 1-1 FOUP 1-2 FOUP 1-3 FOUP 1-4 FOUP 1-5 FOUP 1-5 FOUP 1-6 FOUP 1-7 FOUP 1-7 FOUP 1-8 FOUP 1-8 FOUP 1-9 FOUP 1-9 FOUP 1-1 FOUP 1-2 FOUP 1-2 FOUP 1-3 FOUP 1-4 FOUP 1-5 FOUP 1-5 FOUP 1-6 FOUP 1-7	<u>cs</u>	SB .													
FOUP 4-21 CADH					* 5-1 COT	* 5-2	COT	* 5-3	COT	* 5-4	1 COT				
FOUP 4-21 CADH	1-1			4-31 CADI	4-32 C	ADH	4-33		4-34 C	PHP	4-35 (PHP	-		
1-2 FOUP FOUP 1-3 FOUP 1-3 FOUP 1-3 FOUP 1-3 FOUP 1-3 FOUP 1-4 FOUP 1-5 FOUP 1-5 FOUP 1-5 FOUP 1-5 FOUP 1-7 FOU															
1-2 FOUP				4-11 CADI	4-12 C	ADH	4-13		4-14 C	PHP	4-15 (PHP			
1-2 FOUP					·										
1-2 FOUP			2.20 CDU16										7.00		
FOUP 2-26 TRS 2-25 SCPL 2-24 SCPL 2-24 SCPL 2-22 SCPL 2-22 TRS 4-51 CWH 4-41 4-4 4-4 4-4 4-4 4-4 4-4 4-4 4-4 4-4 4-4 4-4 4-4 4-4 4-4 4-4 4-4	1-2												1-20		
1-3 1-0 1-3 1-0 1-3 1-0 1-3 1-0 1-3 1-3 1-0 1-3							4-0	PRA							
1-3													4-43		
1-3 1-0 FOUP FOUP 1-10														<u>IFBI</u>	
1-3				4.54.004									4-41		
FOUP CRA	1.0	1.0		4-51 CWH							4-52 (WH	_		
7-20 ISHU 7-20 ISHU 3-31 3-32 3-33 3-34 CPHP 3-35 CPHP 7-13 RSM 3-21 3-22 3-23 3-24 CPHP 3-25 CPHP 7-12 CPL 3-11 3-12 3-13 3-14 CPHP 3-15 CPHP 7-11 CPL 3-43 SCPL 3-42 SCPL 3-42 SCPL 3-42 SCPL 3-42 SCPL 3-43 SCPL 3-42 SCPL 3-45 SCPL 3-45 SCPL 3-45 SCPL 3-45 SCPL 3-45 SCPL 3-45 SCPL 3-46 SCPL 3-45 SCPL 3-47 SCPL 8-15 TRS'5 1-5 FOUP 2-0 MPRA 3-5 DEV 3-6 DEV 3-7 DEV 3-8 DEV 7-0 MPRA				-	4-1 COT	4-2	COT	4-3	COT	4-4	COT				
3-21 3-22 3-23 3-24 CPHP 3-25 CPHP 7-12 CPL 3-11 3-12 3-13 3-14 CPHP 3-15 CPHP 7-11 CPL 3-18 2-17 CPL 2-16 CPL 2-16 CPL 2-15 "SCPL 3-0 PRA 3-0 PRA 3-15 TRS"5 1-5 FOUP 2-0 MPRA 3-5 DEV 3-6 DEV 3-7 DEV 3-8 DEV 7-0 MPRA 3-10 MPRA 3-5 DEV 3-6 DEV 3-7 DEV 3-8 DEV 7-0 MPRA		0.01					7-20	ISHU						1	
1-4 FOUP 1-5 FOUP 2-10 MPRA 3-11 3-12 3-13 3-14 CPHP 3-15 CPHP 7-11 CPL 3-43 SCPL 3-42 SCPL 3-42 SCPL 3-41 SCPL 3-41 SCPL 3-41 SCPL 8-15 TRS'5 8-1															
1-4 FOUP 2-16 CPL 2-16 CPL 3-42 SCPL 3-42 SCPL 3-42 SCPL 3-42 SCPL 3-42 SCPL 3-45 SCPL 3-45 SCPL 3-45 SCPL 8-15 TRS*5 1-5 FOUP 2-0 MPRA 3-5 DEV 3-6 DEV 3-7 DEV 3-8 DEV 7-0 MPRA 8-1															
FOUP 2-17 CPL 2-16 CPL 2-16 CPL 3-0 PRA 3-1 SCPL			0.40	3-11	3-12		3-13		3-14 C	PHP	3-15 (PHP			
2-16 CPL 3-0 PRA 3-1 SCPL 8-15 TRS*5 1-5 FOUP 2-0 MPRA 3-5 DEV 3-6 DEV 3-7 DEV 3-8 DEV 7-0 MPRA															0.1
2-15 **SCPL 8-15 TRS*5 1-5 FOUP 2-0 MPRA 3-5 DEV 3-6 DEV 3-7 DEV 3-8 DEV 7-0 MPRA	FOUP													IRAS	0-1
FOUP 2-0 MPRA 3-5 DEV 3-6 DEV 3-7 DEV 3-8 DEV 7-0 MPRA							3-0	PRA							
FOUP 2-0 MPRA 3-5 DEV 3-6 DEV 3-7 DEV 3-8 DEV 7-0 MPRA														1	
FOUP 2-0 MPRA 3-5 DEV 3-6 DEV 3-7 DEV 3-8 DEV 7-0 MPRA	1														
			2-0 MPRA		3-5 DEV	3-6	DEV	3-7	DEV	3-8	DEV		7-0 MPRA		
	FOUP														
3-1 DEV 3-2 DEV 3-3 DEV 3-4 DEV					3-1 DEV	3-2	DEV	3-3	DEV	3-4	DEV				

1.9 HVM TNE Configuration_D5 Blanked

Second S			<u>MPB</u>				PI	RB					<u>STB</u>		
## 1-4 TRS SCPL				6-21										1	
2.48 SBU'S 2.47 TRS 6-51 CWH'2 6-1 COT 6-2 COT 6-3 COT 6-4 COT 2.41 SBU'10 5-21 5-22 5-23 5-24 5-25 2.38 2.38 2.38 2.38 3.35 5-0 7.36 7.36 7.36 7.36 7.36 7.37 7.34 7.33 1-1 FOUP 1.2 FOUP 1.3 FOUP 1.3 FOUP 1.4 FOUP 1.5 FOUP 1.4 FOUP 1.5 FOUP 1.5 FOUP 1.5 FOUP 1.6 FOUP 1.7 FOUP 1.7 FOUP 1.8 FOUP 1.9 FOUP 1.1 FOUP 1.2 FOUP 1.3 FOUP 1.4 FOUP 1.5				6-11	6-12		6-13	*CPHP	6-14 CI	PHP	6-15 C	PHP			
2.48 SBU°S 2.47 TRS 6-51 CWH°2 6-1 COT 6-2 COT 6-3 COT 6-3 COT 7-43 SCPL 7-35 7-34 7-36 7-36 7-36 7-36 7-36 7-36 7-36 7-36															
## CSB CSB			2.49 SDII*E				6.0	DDA							
## 1-3 1-0 CRA COT E-1 COT E-2 COT E-3 COT E-4 COT E-2 E-2							0-0	FIVA							
## CSUR 1-1 FOUP Foun															
## CSB 1-1 5-11 5-12 5-13 5-14 5-15					6-1 COT	6-2	СОТ	6-3	СОТ	6-4	СОТ				
## CSR 2-38 5-0 7-36 7-35 7-35 7-34 7-35 7-34 7-35 7-34 7-35 7-34 7-33 7-35 7-34 7-33 7-28 7				5-21	5-22		5-23		5-24		5-25				
2.38 2.37 5.51 5.0 5.0 7.34 7.34 7.33 1.1 FOUP 1.2 FOUP 1.2 FOUP 1.3 FOUP 1.4 1.5 FOUP 1.5 1.6 2.28 SBU'5 2.26 TRS 2.26 TRS 2.26 TRS 2.27 TRS 2.26 TRS 2.27 TRS 2.27 TRS 2.27 TRS 2.27 TRS 2.28 SCPL 2.24 SCPL 2.23 SCPL 2.24 SCPL 2.25 TSCPL 3.31 3.32 3.31 3.32 3.33 3.34 CPHP 3.35 CPHP 3.36 7.34 7.33 7.33 7.33 1.4 FOUP 1.5 FOUP 1.6 1.7 1.7 1.7 1.7 1.7 1.7 1.7 1.7 1.7 1.7			2-41 SBU*10	5-11	5-12		5-13		5-14		5-15				
2.38 2.37 5.51 5.0 5.0 7.34 7.34 7.33 1.1 FOUP 1.2 FOUP 1.2 FOUP 1.3 FOUP 1.4 1.5 FOUP 1.5 1.6 2.28 SBU'5 2.26 TRS 2.26 TRS 2.26 TRS 2.27 TRS 2.26 TRS 2.27 TRS 2.27 TRS 2.27 TRS 2.27 TRS 2.28 SCPL 2.24 SCPL 2.23 SCPL 2.24 SCPL 2.25 TSCPL 3.31 3.32 3.31 3.32 3.33 3.34 CPHP 3.35 CPHP 3.36 7.34 7.33 7.33 7.33 1.4 FOUP 1.5 FOUP 1.6 1.7 1.7 1.7 1.7 1.7 1.7 1.7 1.7 1.7 1.7															
1-1 FOUP			0.00				-	^							
1-1 FOUP				-			5.	-0							
1-1 FOUP	CS	B													
FOUP 1-2 FOUP 1-2 FOUP 1-2 FOUP 1-3 FOUP 1-3 FOUP 1-4 FOUP 1-5 FOUP 1-5 FOUP 1-5 FOUP 1-7 FOUP					5-1	5	i-2	5	i-3	5	5-4				
1-2 FOUP	1-1			4-31 CA	DH 4-32 C	CADH	4-33		4-34 **	CPHP	4-35 C	PHP	7		
1-2 FOUP FOUP FOUP 1-2 FOUP 1-3 FOUP 1-3 FOUP 1-3 FOUP 1-3 FOUP 1-3 FOUP 1-4 FOUP 1-5 FOUP 1-5 FOUP 1-7 FOUP 1-	FOUP														
1-2 FOUP 1-2 2-7 TRS 2-26 TRS 2-25 SCPL 2-24 SCPL 2-24 SCPL 2-22 TRS 4-3 4-42 4-41 2-22 TRS 4-51 CWH 4-41 1-3 1-0 FOUP 1-3 1-0 CRA 2-20 TRS 4-1 COT 4-2 COT 4-3 COT 4-4 COT 4-4 COT 4-4 COT 4-5 CWH 4-41 4-42 4-41 4-42 4-41 4-42 4-41 4-42 4-41 4-42 4-41 4-5 CWH 4-5 CWH 4-6 CWH 4-7 COT 4-8				4-11 CA	DH 4-12 C	CADH	4-13		4-14 C	PHP	4-15 C	PHP			
1-2 FOUP 1-2 2-7 TRS 2-26 TRS 2-25 SCPL 2-24 SCPL 2-24 SCPL 2-22 TRS 4-3 4-42 4-41 2-22 TRS 4-51 CWH 4-41 1-3 1-0 FOUP 1-3 1-0 CRA 2-20 TRS 4-1 COT 4-2 COT 4-3 COT 4-4 COT 4-4 COT 4-4 COT 4-5 CWH 4-41 4-42 4-41 4-42 4-41 4-42 4-41 4-42 4-41 4-42 4-41 4-5 CWH 4-5 CWH 4-6 CWH 4-7 COT 4-8															
FOUP 1-3													7-28		
1-3 1-0 CRA 2-21 TRS 4-51 CWH 4-52 CWH 4-41 4-42 4-444 4-44 4-44 4-44 4-44 4-44 4-44 4-44 4-44 4-444 4-444 4-444 4-444 4-444 4-444 4-444 4-444 4-4							4-0	PRA							
1-3 1-0 2-22 TRS	FOUP												4.42		
1-3 1-0 2-22 TRS 4-51 CWH 4-52 CWH 4-452 CWH 4-52 CWH														IFRI	
1-3 1-0														<u></u>	
FOUP CRA 2-20 TRS 4-1 COI 4-2 COI 4-3 COI 4-4 COI 4-4 COI 4-3 COI 4-4				4-51 CV	VH						4-52 C	WH			
7-20 ISHU 3-31 3-32 3-33 3-34 CPHP 3-35 CPHP 7-13 RSM 3-21 3-22 3-23 3-24 CPHP 3-25 CPHP 7-12 CPL 3-11 3-12 3-13 3-14 CPHP 3-15 CPHP 7-11 CPL 3-15 CPL 3-16 CPL 3-16 CPL 3-17 CPL 2-16 CPL 3-19 CPL 3-19 CPL 3-19 CPL 2-15 SCPL 3-19 CPL 3-19					4-1 COT	4-2	COT	4-3	СОТ	4-4	СОТ				
3-21 3-22 3-23 3-24 CPHP 3-25 CPHP 7-12 CPL 3-11 3-12 3-13 3-14 CPHP 3-15 CPHP 7-11 CPL 3-16 CPL 3-15 CPL 3-15 CPL 3-15 CPL 3-15 CPL 3-15 CPL 3-16 CPL 3-17 CPL 3-18		0.01	2 20 1110			1	7-20	ISHU							
1-4 FOUP]	
1-4 FOUP 2-18 3-43 SCPL 3-42 SCPL 3-42 SCPL 3-42 SCPL 3-42 SCPL 3-42 SCPL 3-41 SCPL 3-41 SCPL 3-41 SCPL 3-41 SCPL 8-15 TRS*5 1-5 FOUP 2-0 MPRA 3-5 DEV 3-6 DEV 3-7 DEV 3-8 DEV 7-0 MPRA															
FOUP 2-17 CPL 3-42 SCPL 3-40 PRA 3-5 DEV 3-6 DEV 3-7 DEV 3-8 DEV 7-0 MPRA 8-15 TRS*5				3-11	3-12		3-13		3-14 C	PHP	3-15 C	PHP			
2-16 CPL 3-0 PRA 3-1 SCPL 8-15 TRS*5 1-5 FOUP 2-0 MPRA 3-5 DEV 3-6 DEV 3-7 DEV 3-8 DEV 7-0 MPRA														8-0	0.1
2-15 *SCPL 8-15 TRS*5 1-5 FOUP 2-0 MPRA 3-5 DEV 3-6 DEV 3-7 DEV 3-8 DEV 7-0 MPRA	FOUF													IRAS	0-1
1-5 FOUP 2-0 MPRA 3-5 DEV 3-6 DEV 3-7 DEV 3-8 DEV 7-0 MPRA							3-0	PRA							
FOUP 2-0 MPRA 3-5 DEV 3-6 DEV 3-7 DEV 3-8 DEV 7-0 MPRA				1									2.1200		
3-1 DEV 3-2 DEV 3-3 DEV 3-4 DEV			2-0 MPRA		3-5 DEV	3-6	DEV	3-7	DEV	3-8	DEV		7-0 MPRA		
					3-1 DEV	3-2	DEV	3-3	DEV	3-4	DEV				

^{*} Only present after the High Throughput upgrade. ** 4-33 CPRP relocate to 6-24

^{*} Reserved module (D5 - COT and CPHP)

** Only present after the High Throughput upgrade. (5-13/14/24 CPHP relocate to 6/13/23/24 CPHP)

1.10 HVM TNE Configuration_D5/D6 Blanked

		<u>MPB</u>				P	RB					<u>STB</u>		
			6-21	6-22			*CPHP	6-24 *C		6-25 *			1	
			6-11	6-12		6-13	**CPHP	6-14 *C	PHP	6-15 *	CPHP			
												7-47 *TRS		
		2-48 *SBU*5				6.0	PRA					7-46 *SCPL 7-45 *SCPL	-	
		2-47 *TRS				0-0	1101					7-44 *SCPL	1	
		6-51 *CWH*2										7-43 *SCPL		
				*6-1 COT	*6-2	СОТ	*6-3	COT	*6-4	COT				
			5-21	5-22		5-23		5-24		5-25				
		2-41 SBU*10	5-11	5-12		5-13		5-14		5-15				
				<u> </u>						•				
												7-36		
		2-38				5	-0					7-35		
CS	B	2-37 5-51										7-34 7-33	-	
		5-51			_			_				1-00		
				5-1	5-	-2	5	-3		5-4				
1-1			4-31 CAE			4-33		4-34 **		4-35 (
FOUP			4-21 CAE			4-23		4-24 CI		4-25 (
			4-11 CAE	OH 4-12 C	ADH	4-13		4-14 CI	HP	4-15 (SPHP	-		
		2-28 SBU*5										7-28	1	
1-2		2-27 TRS				4-0	PRA						I	
FOUP		2-26 TRS												
		2-25 SCPL 2-24 SCPL										4-43 4-42	IFBI	
		2-24 SCPL 2-23 SCPL										4-41	<u>IFBI</u>	
		2-22 TRS	4-51 CW	Н						4-52 (CWH			1
1-3	1-0	2-21 TRS		4-1 COT	42	СОТ	4.3	СОТ	4.4	СОТ		1		
FOUP	CRA	2-20 TRS		4-1 001	4=2			COI	4-4	COI				
			0.04	0.00		7-20	ISHU	2 24 0	DLID.	0.05 /	DUD	7.40 DOM	-	
			3-31 3-21	3-32 3-22		3-33		3-34 CI 3-24 CI		3-35 (7-13 RSM 7-12 CPL	-	
			3-11	3-12		3-13		3-14 CI		3-15 (7-11 CPL		
1-4		2-18										3-43 SCPL	8-0	
FOUP		2-17 TRS(*CPL)										3-42 SCPL	IRAS	8-1
		2-16 TRS(*CPL)				3-0	PRA					3-41 SCPL	11010	
		2-15 *SCPL										8-15 TRS*5	-	
														1
1-5		2-0 MPRA		3-5 DEV	3-6	DEV	2.7	DEV	20	DEV		7-0 MPRA		
FOUP		2-U IVIFICA		3-3 DEV	3-6	DEV	3-7	DEV	J-8	DEV		7-U IVIPRA		
				3-1 DEV	3-2	DEV	3-3	DEV	3-4	DEV				
		ļ		sent after the H	<u> </u>								1	1

^{*} Only present after the High Throughput upgrade.

** 4-33 CPRP relocate to 6-13 after the High Thoughput upgrade.

1.11 TNG Configuration

		<u>MPB</u>				PR	R IB					<u>STB</u>		
			6-21	6-22 C		6-23 CF		6-24 C		6-25 (
			6-11 CPRP	6-12 C	PRP	6-13 CF	PRP	6-14 C	PRP	6-15 (PRP	7.47.4700		
												7-47 * TRS 7-46 TRS (* SCPL		
		2-48 SBU*5	1			6-0 F	PRA					7-45 TKS (SCFE	4	
		2-47 TRS										7-44 SCPL		
		6-51 CWH*2										7-43 SCPL		
			6	3-1 COT	6-2 C	COT	6-3	COT	6-4	COT				
			5-21	5-22		5-23		5-24		5-25				
		2-41 SBU*10	5-11	5-12		5-13		5-14		5-15				
												7-36		
		2-38				5-	0					7-35		
cs	a R	2-37										7-34		
<u> </u>	115	5-51										7-33		
				5-1	5-2	2	5	5-3	5	5-4				
1-1			4-31 CADH	4-32 C	ADH	4-33 C/	ADH	4-34 C	PRP	4-35 (PRP			
FOUP			4-21 CADH	4-22 C		4-23 C/		4-24 C		4-25 (
			4-11 CADH	4-12 C	ADH	4-13 C/	ADH	4-14 C	PRP	4-15 (PRP	_		
		2-28 SBU*5	-									7-28		
1-2		2-27 TRS				4-0 I	DDA							
FOUP		2-26 TRS				4-0 1	FIVA							
		2-25 SCPL 2-24 SCPL										4-43 4-42	IFBI	
		2-24 SCPL 2-23 SCPL	-									4-42	II:BI	
		2-22 TRS	4-51 CWH							4-52 (WH			
1-3	1-0	2-21 TRS		1-1 COT	4-2 C	COT	4-3	СОТ	4-4	СОТ				
FOUP	CRA	2-20 TRS				7-20								
			3-31	3-32		3-33 CF	ISHU	3-34 C	PRP	3-35 (PRP	7-13 RSM	1	
			3-21	3-22		3-23 CF		3-24 C		3-25 (7-12 CPL	1	
			3-11	3-12		3-13 CF		3-14 C	PRP	3-15 (7-11 CPL]	
1-4		2-18										3-43 SCPL	8-0	
FOUP		2-17 TRS 2-16 TRS	-									3-42 SCPL 3-41 SCPL	IRAS	8-1
		2-15 * SCPL	-			3-0 F	PRA					8-15 TRS*5	1	
		2.0 301E	1									0.000	1	
1-5 FOUP		2-0 MPRA	3	3-5 DEV	3-6 E	DEV	3-7	DEV	3-8	DEV		7-0 MPRA		
			3	3-1 DEV	3-2 0	DEV	3-3	DEV	3-4	DEV				
$oldsymbol{oldsymbol{\sqcup}}$		<u> </u>	* Only presen	4 -64 4b - T	E-b Thu-								L	



1.12 TBL Configuration

		<u>MPB</u>				PI	RB					<u>STB</u>		
			6-21	6-22		6-23		6-24 C	PRP	6-25 C	PRP		1	
			6-11	6-12		6-13		6-14 C	PRP	6-15 C	PRP			
												7.40.700		
		2-48 SBU*5				6-0	PRA					7-46 TRS 7-45 SCPL		
		2-47				0-0	1103					7-43 SCPL 7-44 SCPL		
		6-51 CWH*2	1									7-43 SCPL		
				6-1 COT	6-2 (СОТ	6-3 C	OT	6-4	COT				
			5-21	5-22		5-23		5-24 C	PRP	5-25 C	PRP			
		2-41 SBU*10	5-11	5-12		5-13		5-14 CI	PRP	5-15 C	PRP			
		0.00 001#5				E 0	PRA					7-36 TRS 7-35 SCPL		
		2-38 SBU*5 2-37				5-0	FRA					7-35 SCPL 7-34 SCPL		
<u>CS</u>	B	5-51 CWH*2										7-33 SCPL		
				5-1 COT	E 2.	COT	5-3 C	OT	E 4	COT				
							3-3 C							
1-1			4-31 CADH			4-33		4-34 CI		4-35 C				
FOUP			4-21 CADH 4-11 CADH			4-23	ADII	4-24 CI		4-25 C				
			4-11 CADE	4-12 C	ADH	4-13 C	ADH	4-14 CI	PRP	4-15 C	PRP	-		
		2-28	i									7-28 SBU*5		
1-2		2-27 TRS				4-0	PRA							
FOUP		2-26 TRS				4-0	1103							
		2-25 2-24 TRS										4-43 4-42	TENT.	
		2-24 TRS	ł									4-42	<u>IFBI</u>	
		2-22 TRS	4-51							4-52		4-41		
1-3	1-0	2-21 TRS		4-1		-2	4-3	,		-4				
FOUP	CRA	2-20 TRS		4-1	4-	-2	4-3	3	4	-4				
			0.04	1 0 05		7-20	ISHU	004 -	200	0.05 -	000	7 10 0011		
			3-31	3-32 3-22		3-33 C		3-34 CI		3-35 C		7-13 RSM 7-12 CPL		
			3-21 3-11	3-22 3-12 C	PRP	3-23 C		3-24 CI		3-25 C		7-12 CPL 7-11 CPL		
1-4		2-18	0-11	0-12-0	110	0-10-0	110	0-14-01	131	0-10-0	110	3-43 SCPL		
FOUP		2-17 TRS	i									3-42 SCPL	8-0 IRAS	8-1
		2-16 TRS				3-0	PRA					3-41 SCPL	IRAS	
		2-15 SCPL				5-0	1100					8-15 TRS*5		
1-5		2-0 MPRA		3-5 DEV	261	DEV	3-7 D	E\/	2.0	DEV		7-0 MPRA		
FOUP		2-U IVIFICA		3-3 DEV	3-61	DEV	3-7 L	'L V	3-8	DEV		7-U IVIPRA		
				3-1 DEV	3-2 [DEV	3-3 D	EV	3-4	DEV				

1.13 TBM Configuration

S-21			<u>STB</u>					RB	P					<u>MPB</u>		
2.48 SBU'5 2.48 SBU'5 2.47 TRS 6-51 CWH'2 6-1 COT 6-2 COT 6-2 COT 6-3 COT 6-4 COT 5-21 5-22 5-23 5-24 5-24 5-25 7-36 7-35 7-35 7-35 7-34 7-33 CSB 1-1 FOUP 1-2 FOUP 1-3 FOUP 1-3 FOUP 1-3 FOUP 1-3 FOUP 1-3 FOUP 1-4 FOUP 1-4 FOUP 1-5 FOUP 1-7				PRP	6-25 C	PRP	6-24 C	PRP	6-23 C	PRP	6-22 C		6-21			
## Company of the com				PRP	6-15 C	PRP	6-14 C	PRP	6-13 C	PRP	6-12 C	PRP	6-11 C			
## 1-2																
## 1-1 CADH		_						DD.4								
## CSB 6-1 COT 6-2 COT 6-3 COT 6-4 COT 6-4 COT 6-3 COT 6-4 COT 6-4 COT 6-2 COT 6-3 COT 6-4 COT 6-4 COT 6-3 COT 6-4 COT 6-3 COT 6-4 COT 6-4 COT 6-3 COT 6-4 COT 6-3 COT 6-4 COT 6-3 COT 6-4 COT 6-4 COT 6-3 COT 6-4 COT 6-4 COT 6-4 COT 6-3 COT 6-4 COT		-						PRA	6-0				4			
## 1-0 FOUP		-	7-44 SCPL 7-43 SCPI													
## CSB 241 SBU*10 5-11 5-12 5-13 5-14 5-15 2-38 2-37 5-51 5-2 5-3 5-4 1-1			1-40 GOI E		COT	6-4	COT	6-3	COT	6-2	COT	6-1		7-01 OWIT 2		
## CSB 2-38			1		5-25		5-24		5-23		5-22		5-21			
1-1 FOUP F					5-15		5-14		5-13		5-12		5-11	2-41 SBU*10		
1-1 FOUP F																
1-1 FOUP FOUP FOUP FOUP									_							
FOUP FOUP CRA 5-51 5-52 5-3 5-4 4-31 CADH 4-32 CADH 4-33 CADH 4-34 CPRP 4-35 CPRP 4-21 CADH 4-22 CADH 4-23 CADH 4-24 CPRP 4-25 CPRP 4-11 CADH 4-12 CADH 4-13 CADH 4-14 CPRP 4-15 CPRP 2-28 SBU'5 2-27 TRS 2-26 TRS 2-26 TRS 2-25 SCPL 2-24 SCPL 2-23 SCPL 2-22 TRS 4-0 PRA 4-43 4-43 4-42 4-41 4-42 COT 4-3 COT 4-3 COT 4-4								-0	5							
1-1 FOUP													-		B	C
FOUP 4-21 CADH 4-22 CADH 4-23 CADH 4-24 CPRP 4-25 CPRP 4-25 CPRP 4-15 CPRP			7 00		5-4	5	5-3		-2	5	5-1			, , ,		
FOUP 4-21 CADH 4-22 CADH 4-23 CADH 4-24 CPRP 4-25 CPRP 4-11 CADH 4-12 CADH 4-13 CADH 4-14 CPRP 4-15 CPRP 1-2			-	DDD.	1 25 0	DDD	1 24 C	VDH	4 22 C	ADU	1 4 32 C	VDH.	4 31 C			1.1
1-2 FOUP FOUP CRA 1-3 1-0 FOUP CRA 1-4 1-1 CADH 4-12 CADH 4-13 CADH 4-14 CPRP 4-15 CPRP 2-28 SBU*5 2-26 TRS 2-26 TRS 2-26 TRS 2-25 SCPL 2-24 SCPL 2-22 SCPL 2-22 TRS 4-40 PRA 4-43 4-42 4-41 4-41 4-41 4-42 IFRI 4-52 CWH 2-22 TRS 2-20 TRS 3-31 3-32 3-33 CPRP 3-34 CPRP 3-35 CPRP 7-13 RSM 3-21 3-22 3-23 CPRP 3-24 CPRP 3-25 CPRP 7-12 CPL 3-13 TRS 2-16 TRS 2-17 TRS 2-16 TRS 2-16 TRS 2-16 TRS 3-10 SPA 3-11 S-12 3-13 CPRP 3-14 CPRP 3-15 CPRP 7-11 CPL 3-42 SCPL 3-43 SCPL 3-45 S																
1-2 FOUP FOUP FOUP 1-3 FOUP 1-3 FOUP 1-4 FOUP 1-4 FOUP 1-7 FOUP 1-7 FOUP 1-8 FOUP 1-8 FOUP 1-9 FOUP 1-																1001
1-2 FOUP					1											
1-2 FOUP 1-2 FOUP 1-3 1-0 FOUP 1-3 1-0 CRA 1-3 1-0 CRA 1-4 1-0 CRA 1-4 1-0 CRA 1-5 1-0 CRA 1-7 1-0 CRA 1-8 1-9 1-9 1-9 1-9 1-9 1-9 1-9 1-9 1-9 1-9			7.20											20 0011*5		
FOUP			7-20													1-2
1-3 1-0								PRA	4-0				1			
1-3 1-0 CRA 2-22 TRS 4-51 CWH 4-2 COT 4-2 COT 4-3 COT 4-4 COT 4-4 COT 4-52 CWH 4-52			4-43													
1-3 FOUP CRA FOUR CRA	BI	- i	4-42										1	2-24 SCPL		
1-3			4-41											2-23 SCPL		
FOUP CRA 2-20 TRS 4-1 COT 4-2 COT 4-3 COT 4-3 COT 4-4				WH	4-52 C							WH	4-51 C	2-22 TRS		
7-20 ISHU 3-31 3-32 3-33 CPRP 3-34 CPRP 3-35 CPRP 7-13 RSM 3-21 3-22 3-23 CPRP 3-24 CPRP 3-25 CPRP 7-12 CPL 3-11 3-12 3-13 CPRP 3-14 CPRP 3-15 CPRP 7-11 CPL 3-43 SCPL 3-42 SCPL 3-42 SCPL 3-42 SCPL 3-42 SCPL 3-43 SCPL 3-45 SCPL 3-45 SCPL 3-47 TRS 2-16 TRS 3-10 DPA 3-10 DPA 3-11 SCPL 3-12 SCPL 3-13 SCPL 3-14 SCPL 3-15 CPRP 3-15 CPRP 3-15 CPRP 3-16 CPRP 3-16 CPRP 3-17 TRS 3-18 SCPL 3-18 SCPL 3-19 SCPL 3-1					COT	4-4	COT	4-3	COT	4-2	COT	4-1				
3-31 3-32 3-33 CPRP 3-34 CPRP 3-35 CPRP 7-13 RSM 3-21 3-22 3-23 CPRP 3-24 CPRP 3-25 CPRP 7-12 CPL 3-11 3-12 3-13 CPRP 3-14 CPRP 3-15 CPRP 7-11 CPL 3-43 SCPL 3-42 SCPL 3					001		, 001							2-20 TRS	CRA	FOUP
3-21 3-22 3-23 CPRP 3-24 CPRP 3-25 CPRP 7-12 CPL 3-11 3-12 3-13 CPRP 3-14 CPRP 3-15 CPRP 7-11 CPL 3-43 SCPL 3-42 SCPL 3-45 SCP		_	7.12 DCM	DDD	0.05.0	000	1 2 24 2				0.00		0.04			
1-4 FOUP 2-16 TRS 3-11 3-12 3-13 CPRP 3-14 CPRP 3-15 CPRP 7-11 CPL 3-43 SCPL 8-0 IRAS 3-42 SCPL 1-4 SCPL 3-45 SCPL 3		-														
1-4		-														
FOUP 2-17 TRS 3-42 SCPL IRAS 3.0 DPA 3.41 SCPL IRAS	9.0	_			,		1							2-18		1-4
2-16 TRS 3.0 DPA 3-41 SCPL 3-41 SCPL																FOUP
	110.00							PRA	3-0							
2-15 SCPL 8-15 TRS*5		_	8-15 TRS*5											2-15 SCPL		
		- 1														
1-5 FOUP 2-0 MPRA 3-5 DEV 3-6 DEV 3-7 DEV 3-8 DEV 7-0 MPRA			7-0 MPRA		DEV	3-8	DEV	3-7	DEV	3-6	5 DEV	3-5		2-0 MPRA		
3-1 DEV 3-2 DEV 3-3 DEV 3-4 DEV					DEV	3-4	B DEV	3-3	DEV	3-2	1 DEV	3-1				1 00P

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CSB

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
CSB	SYSTEM	Positive Pressure	0.4	Pa	0.3 - 0.4	PRB≧CSB	Gauge is below 5-1 Layer flow valves
CSB	SYSTEM	CSB Wind Velocity	0.3	m/sec	0.3 ~ 0.4	0.3 (+0.1/-0)	Measure 100mm below punching plate
CSB	SYSTEM	CSB Installation Height	150	mm		150	
CSB	SYSTEM	STAGE Installation Height	913	mm	910 ~ 916	900	From floor to top on Foup pin
CSB	SYSTEM	Clearance between CSB to MPB	5	mm	4.5 ~ 5.5	5	
CSB	CRA	CRA Level	0	degree	-0.2 ~ 0.2	±0.2	
CSB	SYSTEM	FFU Fan Volume	Tool Specific			Tool Specific	Set after Mini Evn. Test
CSB	SYSTEM	DC Fan Setting	Tool Specific	m/sec		Tool Specific	Used for adjusting positive pressure
CSB	SYSTEM	FIMS Door Open Flag Setting Closed	4.5	mm		4.5	Light is ON> Flag not yet breaks the sensor position
CSB	SYSTEM	FIMS Door Open Flag Setting Closed	4.0	mm		4.0	Light is OFF> Flag breaks the sensor position
CSB	SYSTEM	Load Port Air Supply Setting	0.45	Mpa	0.42 ~ 0.48	0.45±0.03	ONLY if Split LP CT-PCP-13-0007 Rev.2 is complete
CSB	SYSTEM	Load Port Door OPEN/CLOSED Speed	2.8	sec	2.5 ~ 3.1	2.8±0.3	
CSB	SYSTEM	Load Port Door OPEN/CLOSED Speed	2.3	sec	2.0 ~ 2.6	2.3±0.3	ONLY if Split LP CT-PCP-13-0007 Rev.2 is complete
CSB	SYSTEM	Door Protrusion Check	1.7	mm	1.5 ~1.9	1.7+/-0.2	Standard setting
CSB	SYSTEM	STAGE VAC.	-55.0	kPa	-53 to -57	-55.0	Static Setting
CSB	Loader	Loader Level	0	degree	-0.2 to 0.2	±0.2	
CSB	LOADER	Foup Vac	-55.0	kPa	-52 to -58	-55.0	Static Setting
CSB	LOADER	Foup Vac. Upper Limit Foup Vac. Lower Limit	-46.6 -98.6	kPa		-46.6 -98.6	
CSB	LOADER	CLAMP UNCLAMP	0.8 0.8	sec	0.5 to 1.1	0.8 0.8	Set by Sub-Op display
CSB	LOADER	DOCK UNDOCK	1.8 1.8	sec	1.5 ~ 2.1	1.8 1.8	Set by Sub-Op display
CSB	LOADER	LATCH UNLATCH	0.8 0.8	sec	0.5 ~ 1.1	0.8 0.8	Set by Sub-Op display
CSB	LOADER	UP DOWN	5.7 4.8	sec	5.4 ~ 6.0 4.5 ~ 5.1	5.7 4.8	Set by Sub-Op display

MPB

MII D							
Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
MPB	SYSTEM	MPB Wind Pressure	200	Pa	150 to 250	Tool Specific	See Wind Pressure Sheet when setting values
MPB	SYSTEM	MPB Installation Height	250	mm		250	
MPB	MPRA	2-0 Level	0	degree	-0.2 to 0.2	0	
MPB	SYSTEM	Chemical Exhaust - L (E6)	100	Pa	25 to 300	100	Set by 42.4 cfm
MPB	SYSTEM	Chemical Exhaust - L (U/L Setting) (E6)	0	Pa		0	
WIFD	SISIEM	Chemical Exhaust - L (L/L Setting) (E6)	10	Pa		10	
MPB	SYSTEM	Clearance between MPB to PRB	5	mm	4.5 to 5.5	5	
MPB	SCPL	Plate Temperature	22.2	degree	22.0 to 22.4	22.2+/-0.15	All SCPL's in MPB ONLY
MPB	CPL	Plate Temperature	22.2	degree	22.0 to 22.4	22.2+/-0.15	

PRB

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	SYSTEM	PRB Positive Pressure	0.5	Pa	0.4 to 0.6	0.5 (+/-0.1)	Includes MPB and STB block. PRB≥CSB
PRB	SYSTEM	PRA Wind Pressure-L	500	Pa	400 to 700	Tool Specific	See Wind Pressure Sheet when setting values
PRB	SYSTEM	PRA Wind Pressure-R	500	Pa	400 to 700	Tool Specific	See Wind Pressure Sheet when setting values
PRB	SYSTEM	PRB Installation Height	250	mm		250	
PRB	SYSTEM	Spinner Wind Pressure-L	200	Pa	125 to 275	150	See Wind Pressure Sheet when setting values
PRB	SYSTEM	Spinner Wind Pressure-R	200	Pa	125 to 275	150	See Wind Pressure Sheet when setting values
PRB	SYSTEM	Spinner Wind Pressure-L *	300	Pa	250 to 350	TBD	
PRB	SYSTEM	Spinner Wind Pressure-R *	300	Pa	250 to 350	TBD	
PRB	SYSTEM	Amine concentration (SPIN 3-5,6,7,8)	<1.0	ppb		<1.0	Measurement port Located next to Cup Source gauge
PRB	SYSTEM	Amine concentration (HP Area 1/2)	<1.0	ppb		<1.0	Measurement port Located next to Cup Source gauge
PRB	PRA	PRA Level	0 +/-0.2	degree	-0.2 to 0.2	0 +/-0.2	
PRB	SYSTEM	Clearance between PRB to MPB/STB	5	mm	4.5 to 5.5	5	
PRB	COT	Supply Exhaust COT (E3,E4,E5)	420	Pa	400 to 440	340	EPC damper must be held Open and use EXH BKMTarget CFM 320
PRB	COT	Low Setting EXH COT (E3,E4,E5)	20	Pa		20	Sensor located in above 4-0 Layer

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PRB

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Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	СОТ	Supply Exhaust COT (E4,E5) *	610	Pa	590 ~ 630	610+/-20	Use with Facilities setting [Facilities will pre open to set position]and Blower Fan Dampers.[will be used to achieve the final setting]
PRB	СОТ	Supply Exhaust COT (E34,E35) *	610	Pa	590 ~ 630	610+/-20	Use with Facilities setting [Facilities will pre open to set position]and Blower Fan Dampers.[will be used to achieve the final setting]
PRB	COT/BCT	RRC (Dispense Rate)	70	ml/min	63 ~ 77	75	Dynamic Setting - Calibration factor by mass with 2.0 sec dispense assuming density = 1 mg/mL
PRB	COT/BCT	EBR (Dispense Rate)	20	ml/min	18 ~ 22	20	Dynamic Setting - Calibration factor by mass with 0.7 sec dispense assuming density = 1 mg/mL
PRB	COT/BCT	Back Rinse (Dispense Rate)	100	ml/min	90 ~ 110	100	With Bevel Ver.2
PRB	COT/BCT	EXH. Duct Clean (Dispense Rate)	200	ml/min	180 ~ 220	200	Dynamic Setting
PRB	COT/BCT	Drain Case Cleaning (Dispense Rate)	250	ml/min	225 ~ 275	250	Dynamic Setting
PRB	COT/BCT	Nozzle / Bath CLN (Dispense Rate)	600	ml/min	540 ~ 660	600	Dynamic Setting
PRB	COT/BCT	Nozzle SC (Dispense Rate)	900	ml/min	810 ~ 990	900	Dynamic Setting
PRB	COT/BCT	Bevel Rinse (Dispense Rate)	50	ml/min	45 ~ 55	60	Dynamic Setting - (With Bevel Ver.2)
PRB	COT/BCT	Bevel Rinse Dispense Speed Controller**	15	Turns			15 turns from the fully close position.
PRB	COT/BCT	Resist Temperature	22.2	°C	22.0 ~ 22.4	22.2 +/-0.1	Measured at the nozzle block on Layer 4. On the INLET side of the block. (LEFT Tube)
PRB	COT/BCT	Cup Temperature	22.2	°C	22.0 ~ 22.4	22.2 +/-0.1	
PRB	COT/BCT	Cup Humidity	40.7	%	40.2 ~ 41.2	40.7 +/-0.5%	
PRB	COT/BCT	Motor Flange Temperature	22.2	°C	22.2 ~ 22.4	22.2 +/-0.1	Same as Resist Temp measurement
PRB	COT/BCT	Wind Velocity	0.2	m/sec	0.14 ~ 0.26		Measurement is taken above each cup and avg. is input to the Setting Value. Measure at 40mm above each cup
PRB	COT/BCT	Positive Pressure	0.7	Pa	0.5 ~ 0.9	0.6 to 0.8	COT value must be >than PRA value
PRB	COT/BCT	AMC N2 Purge (Sunx-DP-100)	11	kPa	9 ~ 13	10 (+/-2)	Static Setting
PRB	COT/BCT	AMC N2 Purge U/L (Sunx-DP-100) AMC N2 Purge L/L (Sunx-DP-100)	15 5	kPa		15 5	
PRB	COT/BCT	Pump Cycle Time (CRD)	11	sec	10 ~ 12	Tool Specific	CRD Cycle time
PRB	COT/BCT	Pump Cycle Time (ACRD)	Pump Specific	sec	Pump Specific	Tool Specific	Cycle time is dependant on several pump recipusettings. Please set based on INTEL Specific Setting
PRB	DEV	DEV LD (Dispense Rate)	1800	ml/min	1620 ~ 1980	1800	Dynamic Setting
PRB	DEV	Bypass (Dispense Rate)	250	ml/min	225 ~ 275	250	Dynamic Setting
PRB	DEV	Nozzle RINSE (Dispense Rate)	2500	ml/min	2200 ~ 2800	2500	Dynamic Setting
PRB	DEV	MGP (Dispense Rate)	300	ml/min	270 ~ 330	300	Dynamic Setting
PRB	DEV	GP (Dispense Rate)	600	ml/min	540 ~ 660	600	Dynamic Setting
PRB	DEV	MGP Sub DEV (Dispense Rate)	250	ml/min	225 ~ 275	250	Dynamic Setting
PRB	DEV	MGP Sub DIW (Dispense Rate)	250	ml/min	225 ~ 275	400	Dynamic Setting
PRB	DEV	RINSE (Dispense Rate)	1000	ml/min	900 ~ 1100	1000	Dynamic Setting
PRB	DEV	ADR (Dispense Rate)	350	ml/min	315 ~ 385	350	Dynamic Setting
PRB	DEV	XDR (Dispense Rate)	430	ml/min	387 ~ 473	430	Dynamic Setting
PRB	DEV	BACK RINSE (Dispense Rate)	200	ml/min	180 ~ 220	200	Dynamic Setting
PRB	NTD	NTD (Dispense Rate)	300	ml/min	270 - 330	300	Dynamic Setting
PRB	NTD	Rinse with NTD (Dispense Rate)	120	ml/min	108 ~ 132	120	Dynamic Setting
PRB	NTD	Back Rinse with NTD (Dispense Rate)	200	ml/min	180 ~ 220	200	Dynamic Setting
PRB	NTD	Bevel Rinse with NTD (Dispense Rate)	50	ml/min	45 ~ 55	50	Dynamic Setting Static Setting I control to the right of Cup 4
PRB	DEV	MGP Bath Exhaust Flow	10	L/min	7.5 ~ 12.5	10+/-2.5	Static Setting - Located to the right of Cup 4 for all PTD layers
PRB	DEV	Water Seal (Dispense Rate)	100	ml/min	>100	100+100/-0	Dynamic Setting Not Used for NTD CUP
PRB	DEV	LD Nozzle Blow	0	ml/min	25	25	Not use at INTEL Set to 0 with correct flow meter gauge

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^{** =} Speed controller not present on Dry tools

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PRB

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
	DEV						1
PRB		XDR N2 Source Pressure	0.35	MPa	0.32 to 0.35	0.35+0/-0.03	Static Setting
PRB	DEV	XDR N2 Flow Setting	20	L/min	20 ~ 20.5	20+0.5-0	Measure mass flow meter JIG
PRB	DEV	XDR N2 Pressure Setting XDR N2 Pressure Sensor U/L	265 Module Specific	kPa	150 ~ 300	Module Specific	Based on 20L/min setting U/L is based on flow setting of 21L/min
PRB	DEV	XDR N2 Pressure Sensor L/L	Module Specific	kPa		Module Specific	L/L is based on flow setting of 16L/mir
PRB	DEV	ADR N2 Source Pressure	50	kPa	40 to 60	50 (+/-10)	Dynamic Setting
PRB	DEV	ADR N2 Flow Setting	5	L/min	4.5 ~ 5.5	5	
PRB	DEV	ADR N2 Pressure Setting	15	kPa	5 to 25		Based on 5L/min setting
PRB	DEV	ADR N2 Pressure Sensor U/L ADR N2 Pressure Sensor L/L	Module Specific Module Specific	kPa		Module Specific Module Specific	U/L is based on flow setting of 6L/min L/L is based on flow setting of 3L/mir
PRB	NTD	NTD N2 Pressure Setting	4	kPa	2 to 6		Based on 5L/min setting
PRB	NTD	NTD N2 Pressure Sensor U/L NTD N2 Pressure Sensor L/L	Module Specific Module Specific	kPa		Module Specific Module Specific	U/L is based on flow setting of 6L/min L/L is based on flow setting of 3L/mir
PRB	DEV/NTD	Developer Solution Temperature	23	°C	22.8 to 23.2	23+/-0.15	Checked in the chemical box below 3-1 layer (under tool)
PRB	DEV/NTD	Cup Temperature	22.2	°C	22.0 to 22.4	22.2 (+/-0.1)	
PRB	DEV/NTD	SPIN Cup Humidity	40.7	%	40.2 ~ 41.2	40.7 (+/-0.5%)	
PRB	DEV/NTD	Motor Flange Temperature	23	°C	22.8 to 23.2	23 (+/-0.15)	Same temp as Developer Solution check point
PRB	DEV/NTD	Wind Velocity	0.2	m/sec	0.14 ~ 0.26		and avg. is input to the Setting Value. Measure at 40mm above each cup
PRB	DEV/NTD	Positive Pressure	0.6	Pa	0.5 ~ 0.6	$0.6 \sim 0.8$	DEV value must be HIGHER than PRA value $(0.6 \pm 0.0 / -0.1)$
PRB	DEV/NTD	DEV/NTD Positive Pressure Bias	0.0 to 0.1	Pa	-	-	Bias = DEV/NTD positive pressure – PRB positive pressure
PRB	DEV	Supply Exhaust DEV (E1,E2) (8x0 Config)	320	Pa	300 ~ 340	320 ~ 400	Value is checked with outer cup up and following the EXH BKM.
PRB	DEV	Supply Exhaust DEV (E1) (4x4 Config)	320	Pa	300 ~ 340	320 ~ 400	Value is checked with outer cup up and following the EXH BKM.
PRB	NTD	Supply Exhaust NTD (E2) (4x4 Config)	400	Pa	250 to 550		Following the EXH BKM.
PRB	DEV/NTD	Supply Exhaust NTD (E1,E2) (6x6 Config)	400	Pa	300 to 600	400 to 500	Following the EXH BKM.
PRB	DEV/NTD	Supply Exhaust NTD (E23) (6x6 Config)	500	Pa	400 to 600	400 to 500	Following the EXH BKM.
PRB	CADH	Ring Purging Pressure	0.18	MPa	0.17 ~ 0.19	0.18 (+/-0.01)	Static Pressure [Chamber Down]
PRB	CADH	Vaporize CADH	0.1	MPa	0.1 ~ 0.12	0.08	Static Pressure
PRB	CADH	Chamber Purge CADH	0.04	MPa	0.04 ~ 0.05	0.04	Static Pressure
PRB	CADH	Chemical Area Exhaust (E8)	150	Pa	75 ~ 325	>100	Set by CFM
PRB	CADH	Chemical Area Exhaust U/L Setting (E8)	0	Pa		0	15.9 +/- 10%
TKB	CADII	Chemical Area Exhaust L/L Setting (E8)	70	Pa		20	Applies to all track configurations
PRB	CADH	Chemical Area Exhaust (E24)	180	Pa	160 ~ 200	100	
PRB	CADH	Chemical Area Exhaust U/L Setting (E24)	0	Pa		0	Target is min of 100Pa 12 CADH System Tool Spec
FKB	CADII	Chemical Area Exhaust L/L Setting (E24)	100	Pa		20	, ,
PRB	CADH	Ejector Chamber Exhaust Source	0.32	MPa	0.31 ~ 0.33	0.32 +/-0.01	Chamber should be down
PRB	CADH	Ejector Chamber Exhaust Setting	0.47	KPa	0.45 to 0.49	0.47	Chamber should be down
PRB	CADH	EXH Upper Limit EXH Lower Limit	0.76 0.38	KPa		0.76 0.38	
PRB	CPRP	CPRP Chamber N2 Purge Source Pressure	0.15	MPa	0.10 to 0.20	0.15	TBL Deck 4 specific

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STB

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
STB	SYSTEM	STB Wind Pressure	200	Pa	150 to 250	Tool Specific	See Wind Pressure Sheet when setting values
STB	SYSTEM	SCPL Plate VAC (STB ONLY) (V1)	-75	kPa	-75 to -80	-75 (+/-0.4)	Static Pressure Setting
STB	SYSTEM	SCPL Plate (MPB only) (V1)	-75	kPa	-75 to -80	-75 (+/-0.4)	Static Pressure Setting
STB	SYSTEM	Module Drive (A1)	0.35	MPa	0.32 to 0.38	0.35 (+/-0.03)	Static Pressure Setting
STB	SYSTEM	Air Pressure Switch (A1) Digital Gauge	0.35	MPa	0.32 to 0.38	0.35 (+/-0.03)	Static Pressure Setting
STB	SYSTEM	Air Pressure Switch (A1) Digital GaugeUL	0.38	MPa		0.38	
STB	SYSTEM	Air Pressure Switch (A1) Digital GaugeLL	0.32	MPa		0.32	
STB	SYSTEM	HP Cooling (A3,A4,A5,A6,A7,A8)	≥0.50	MPa		≧0.45	Static Pressure Setting
STB	MPRA	7-0 Level	0	degree	-0.2 to 0.2	0+0.2/-0.2	
STB	SYSTEM	CRD Resist Pump Purge	11	kPa	9.0 to 13.0	10 (+/-2)	Static Pressure Setting
STB	SYSTEM	CRD Resist Pump Purge U/L Setting CRD Resist Pump Purge L/L Setting	15 5	kPa		15 5	
STB	SYSTEM	ACRD Resist Pump Purge	15	kPa	14 to 16	15(+/-1)	Static Pressure Setting
STB	SYSTEM	ACRD Resist Pump Purge U/L Setting ACRD Resist Pump Purge L/L Setting	20 5	kPa		15 5	
STB	SYSTEM	Resist Bottle Pressure	30	kPa	25.0 to 35.0	50	Dynamic Pressure Setting
STB	SYSTEM	Resist Pump Vac	-50	kPa	-45 to -55	-50	Static Pressure Setting
STB	SYSTEM	CRD Resist Pump Pressure	20	kPa	15 to 25	20	Static Pressure Setting
STB	SYSTEM	Chemical Exhaust - R (E7)	150	Pa	25 to 250	100	Set by 35.3 cfm
STB	SYSTEM	Chemical Exhaust - R (U/L Setting) (E7)	0	Pa		0	
818	SYSTEM	Chemical Exhaust - R (L/L Setting) (E7)	10	Pa		10	
STB	SYSTEM	Clearance between STB to PRB	5	mm	4.5 to 5.5	5	
STB	SCPL	Plate Temperature	23	degree	22.8 to 23.2	22.2+/-0.15	ONLY 3-41,42,43 All others at 22.2

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IPRB**

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
IPRB	SYSTEM	Positive Pressure	0.4	Pa	0.3 to 0.5	STP≧IFB ≦PRB/iPRB	INTEL Setting: SRS/PIR at 0.3 < PRAI 0.4
IPRB	SYSTEM	Positive Pressure (PIR/SRS)	0.3	Pa	0.2 to 0.4	PIR/SRS>/=PRAi	INTEL Setting: SRS/PIR at 0.3 < PRAI 0.4
IPRB	SYSTEM	Module Drive	0.35	MPa	0.32 to 0.38	0.35 (+/-0.03)	Static Pressure Setting
IPRB	SYSTEM	Spin Chuck Vac	-75	kPa	-75 to -80	-75 (+/-0.4)	Static Pressure Setting
IPRB	SYSTEM	IFB Seal	0.07	MPa	0.06 to 0.08	0.07 (+/-0.01)	Static Pressure Setting
IPRB	SYSTEM	Wind Pressure PRAi	100	Pa	50 to 150	Tool Specific	See Wind Pressure Sheet when setting values
IPRB	SYSTEM	Wind Pressure PIR (4X4)	25	Pa	15 to 35	Tool Specific	See Wind Pressure Sheet when setting values
IPRB	SYSTEM	Wind Pressure SRS (4X4)	25	Pa	15 to 35	Tool Specific	See Wind Pressure Sheet when setting values
IPRB	SYSTEM	Wind Pressure PIR (6X6)	45	Pa	35 to 55	Tool Specific	See Wind Pressure Sheet when setting values
IPRB	SYSTEM	Wind Pressure SRS (6X6)	45	Pa	35 to 55	Tool Specific	See Wind Pressure Sheet when setting values
IPRB	SYSTEM	Air Pressure Switch (A1) Digital Gauge	0.35	MPa	0.32 to 0.38	0.35 (+/-0.03)	Static Pressure Setting
IPRB	SYSTEM	Air Pressure Switch (A1) Digital GaugeUL	0.38	MPa		0.38	
IPRB	SYSTEM	Air Pressure Switch (A1) Digital GaugeLL	0.32	MPa		0.32	
IPRB	SYSTEM	Amine concentration (PIR/SRS)	<1.0	ppb		<1.0	Measurement port in lower right chemical area of IPB
IPRB	SYSTEM	iPRB Installation Height	150	mm	145 ~ 155	150 (+/-5)	
IPRB	PRAI	Level of PRAi base	0	degree	0+/-0.2	0 (+/-0.2)	
IPRB	PIR/SRS	BACK RINSE (Dispense Rate)	200	ml/min	180 ~ 220	200	Dynamic Setting
IPRB	PIR/SRS	IDR (Dispense Rate)	150	ml/min	135 ~ 165	200	Dynamic Setting
IPRB	SRS	IE Nozzle (Dispense Rate)	200	ml/min	180 ~ 220	200	Dynamic Setting
IPRB	PIR/SRS	PDR N2 Drive Pressure	50	kPa	40 ~ 60	50	Dynamic Setting
IPRB	PIR/SRS	PDR N2 Flowrate	5	L/min	4.5 ~ 5.5	5	
IPRB	PIR/SRS	PDR N2 Pressure Setting	11	kPa	6 to 16		Based on 5L/min setting
IPRB	PIR/SRS	PDR N2 Pressure Upper Sensor U/L PDR N2 Pressure Upper Sensor L/L	Module Specific Module Specific	kPa		Module Specific Module Specific	U/L is based on flow setting of 10L/min L/L is based on flow setting of 3L/mir
IPRB	CPL	Plate Temperature	22.2	Degree	22.0 to 22.4	22.2+/-0.18	
IPRB	PIR	Exhaust Source Setting (E13)	N/A	Pa	35 ~ 45	40	SET BY PRESSURE (Use Start-up BKM] [Manual Damper should be fully CLOSED in Blank/RSV modules]
IPRB	SRS	Exhaust Source Setting (E14)	N/A	Pa	55 ~ 65	60	SET BY PRESSURE (Use Start-up BKM] [Manual Damper should be fully CLOSED in Blank/RSV modules]

^{**=}for immersion tool only

IFBI/IFB

11 D1/11 1	,						
Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
IFBI/IFB	SYSTEM	Positive Pressure	0.3	Pa	0.2 ~ 0.4	STP≧IFB	
пыпы	BIBILM	1 ositive 1 lessure	0.5	1 4	0.2 0.4	≦IPB	
IFBI/IFB	SYSTEM	Amine concentration (IFB/IFBi)	<1.0	ppb		<1.0	Measurement port
11 22 11 2	BIBIL!!	Timme concentration (II B/II BI)	\\ 1.0	PPO		7110	Located next to Cup Source gauge
IFBI/IFB	SYSTEM	IFBi/IFB Installation Height	68.5	mm	78.5 ~ 68.5	68.5 (+10/0)	
		-					
IFBI/IFB	IRAI/IRA	Level of IRA base	0	degree	0.2 ~ -0.2	0.2 ~ -0.2	
IFB	SYSTEM	IFB Seal	0.07	MPa	0.06 to 0.08	0.07 (+/-0.01)	Static Pressure Setting
IFBI	SYSTEM	Clearance between iPRB and IFBi	5	mm	4.5 ~ 5.5	5	
IFBI/IFB	SYSTEM	Clearance between IFBI/IFB and EXP	30	mm	20 ~ 40	30 (+/-10)	Both for ASML and Nikon

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AC Power Box

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	AC Power Box	AC Power Box Installation Height	100	mm	95 ~ 105	100 ±5	
External	AC Power Box	Primary Supply Power Voltage	3Phases AC200 to 220	V	+/-10%	+/-10%	

COT Cabinet

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	COT Cabinet	COT CAB Installation Height (V5)	90	mm	85 ~ 95	90 ±5	Taller Version of Cabinet
External	COT Cabinet	COT CAB Installation Height (V4)	100	mm	95 ~ 105	100 ±5	
External	COT Cabinet	Module Drive (A2)	0.35	MPa	$0.30 \sim 0.40$	0.35 (+0.05/-0)	Static Pressure Setting
External	COT Cabinet	XDR N2 Pressure Source	0.45	MPa	$0.45 \sim 0.50$	0.45 (+0.05/-0)	
External	COT Cabinet	N2 (1)	0.4	MPa	$0.35 \sim 0.45$	0.4 (+/-0.05)	
External	COT Cabinet	Solvent PCS (1,2) Drive	0.25	MPa	$0.20 \sim 0.30$	$0.10 \sim 0.30$	
External	COT Cabinet	Solvent PCS (1,2) Ejector Drive 1,2,3	$0.1 \sim 0.35$	MPa		$0.1 \sim 0.35$	
External	COT Cabinet	Solvent PCS (1,2) Fill Pressure	0.1	MPa	0.1 ~ 0.12	0.1 (+0.02/-0)	
External	COT Cabinet	PCS (1,2,3) VAC Setting Sol. (1,2)	-45.0	kPa	-40.0 to -50.0	-35.0 (+0/-5)	
External	COT Cabinet	PCS (1,2,3) VAC U/L Setting Sol. (1,2) PCS (1,2,3) VAC L/L Setting Sol. (1,2)	-29.0 -99.9	kPa		-29.0 -99.0	
External	COT Cabinet	HMDS Tank Pressure	0.11	MPa	$0.10 \sim 0.12$	0.11	
External	COT Cabinet	HMDS Empty Weight	Variable	kg			Zero with empty weight scale
External	COT Cabinet	HMDS Vent Valve Setting	2T			Full Open	2T= Full open then closed by 2 Turns. This allows for some adjustment if needed
External	COT Cabinet	FILTER VENT	60	ml/min	54 to 66		IFFS ENABLED TOOL CONFIGURATIONS
External	COT Cabinet	FILTER PURGE	75	ml/min	68 to 82		IFFS ENABLED TOOL CONFIGURATIONS
External	COT Cabinet	IFFS SOL. PCS (1,2,3) VAC Setting Sol. (1,2)	-80.0	kPa	-77.0 to -83.0	-80.0 (+/-3)	IFFS ENABLED TOOL CONFIGURATIONS
External	COT Cabinet	IFFS SOL.PCS (1,2,3) VAC U/L Setting Sol. (1,2) IFFS SOL.PCS (1,2,3) VAC L/L Setting Sol. (1,2)	-75.0 -85.0	kPa		-75.0 -85.0	IFFS ENABLED TOOL CONFIGURATIONS
External	COT Cabinet	IFFS Control box P_1 setting	0.1	MPa	0.08 ~ 0.12	Tool Specific	IFFS ENABLED TOOL CONFIGURATIONS Pressure necessary to achieve 100 ml/min with filter vent valve full open and filter blank installed
External	COT Cabinet	IFFS Control box P_2 setting	0.14	MPa	0.12 ~ 0.16	Tool Specific	IFFS ENABLED TOOL CONFIGURATIONS P 2 setting is 0.03 higher than P 1
External	COT Cabinet	IFFS Control box P_3 setting	0.19	MPa	0.17 ~ 0.21	Tool Specific	CRF ENABLED TOOL CONFIGURATIONS P_3 is 0.05 less than PCS drive pressure, (POS only) P_3 for both decks must be matched.
External	COT Cabinet	CRF Return Line	60.0	ml/min	54 to 66	60.0	CRF ENABLED TOOL CONFIGURATIONS
External	COT Cabinet	CRF Drain Line	60.0	ml/min	54 to 66	60.0	CRF ENABLED TOOL CONFIGURATIONS

DEV Cabinet

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	DEV Cabinet	DEV CAB Installation Height (V5)	90	mm	85 ~ 95	90 ±5	Taller Version of Cabinet
External	DEV Cabinet	DEV CAB Installation Height (V4)	100	mm	95 ~ 105	100 ±5	
External	DEV Cabinet	Module Drive (A2)	0.35	MPa	$0.32 \sim 0.38$	0.35 (+0.05/-0)	Static Pressure Setting
External	DEV Cabinet	DEV Solution (1,2) PCS (1,2) Drive	0.25	MPa	$0.20 \sim 0.30$	$0.10 \sim 0.30$	Static Pressure Setting
External		DEV Solution (1,2) PCS (1,2) Ejector Drive 1,2,3	0.1 ~ 0.35	MPa		0.1 ~ 0.35	Static Pressure Setting
External	DEV Cabinet	DEV Solution PCS (1,2) Fill Pressure	0.15	MPa	0.15 to 0.17	0.1 (+0.02/-0)	Due to Pre-PCS filter add from INTEL
External	DEV Cabinet	PCS (1,2,3) VAC Setting Dev Sol. (1,2)	-65.0	kPa	-60.0 to 65.0	-55 (+0/-5)	Static Pressure Setting
External		PCS (1,2,3) VAC U/L Setting DEV (1,2) PCS (1,2,3) VAC L/L Setting DEV (1,2)	-49.0 -99.9	kPa		-49.0 -99.0	Static Pressure Setting

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TNE DEV Cabinet

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	DEV Cabinet	DIW 4 Sub Setting (MGP)	0.15	MPa	$0.15 \sim 0.17$	0.15 (+0.02/-0)	
External	DEV Cabinet	DEV Rinse Nozzle	0.20	MPa	$0.20 \sim 0.22$	0.15 (+0.02/-0)	
External	DEV Cabinet	DEV Back Rinse	0.15	MPa	$0.15 \sim 0.17$	0.15 (+0.02/-0)	
External	DEV Cabinet	Nozzle Bath (2)	0.20	MPa	0.20 ~ 0.22	0.20 (+0.02/-0)	

TNE w/ HTP upgrade DEV Cabinet

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	DEV Cabinet	DIW 4 Sub Setting (MGP)	0.15	MPa	$0.15 \sim 0.17$	0.15 (+0.02/-0)	
External	DEV Cabinet	DEV Rinse Nozzle	0.20	MPa	$0.20 \sim 0.22$	0.15 (+0.02/-0)	
External	DEV Cabinet	DEV Back Rinse	0.15	MPa	0.15 ~ 0.17	0.15 (+0.02/-0)	

TNG/TBL DEV Cabinet

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	DEV Cabinet	C.P.V for D.I. Water (1)	0.20	MPa	0.19 ~ 0.21	0.2	For DEV RINSE
External	DEV Cabinet	DEV Rinse Nozzle	0.25	MPa	$0.25 \sim 0.27$	0.20 (+0.02/-0)	Supply Regulator
External	DEV Cabinet	DIW 4 Sub Setting (MGP)	0.15	MPa	$0.15 \sim 0.17$	0.15 (+0.02/-0)	
External	DEV Cabinet	DEV Back Rinse	0.15	MPa	$0.15 \sim 0.17$	0.15 (+0.02/-0)	
External	DEV Cabinet	Nozzle Bath (2)	0.20	MPa	0.20 ~ 0.22	0.20 (+0.02/-0)	

TNG w/ HTP upgrade and TBM DEV Cabinet

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	DEV Cabinet	C.P.V for D.I. Water (1)	0.20	MPa	0.19 ~ 0.21	0.2	For DEV RINSE
External	DEV Cabinet	DEV Rinse Nozzle	0.25	MPa	$0.25 \sim 0.27$	0.20 (+0.02/-0)	Supply Regulator
External	DEV Cabinet	DIW 4 Sub Setting (MGP)	0.15	MPa	$0.15 \sim 0.17$	0.15 (+0.02/-0)	
External	DEV Cabinet	DEV Back Rinse	0.15	MPa	$0.15 \sim 0.17$	0.15 (+0.02/-0)	

TAR/TNR DEV Cabinet

	DL Cubi						
Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	DEV Cabinet	DIW 4 Sub Setting (MGP)	0.15	MPa	$0.15 \sim 0.17$	0.15 (+0.02/-0)	
External	DEV Cabinet	DEV Rinse Nozzle	0.20	MPa	$0.20 \sim 0.22$	0.15 (+0.02/-0)	
External	DEV Cabinet	DEV Back Rinse	0.15	MPa	$0.15 \sim 0.17$	0.15 (+0.02/-0)	
External	DEV Cabinet	Nozzle Bath (2)	0.20	MPa	$0.20 \sim 0.22$	0.20 (+0.02/-0)	
External	DEV Cabinet	PIR/SRS Rinse	0.15	MPa	$0.15 \sim 0.17$	0.15 (+0.02/-0)	
External	DEV Cabinet	PIR/SRS Back Rinse	0.15	MPa	0.15 ~ 0.17	0.15 (+0.02/-0)	

Immersion DEV Cabinet

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	DEV Cabinet	DEV Rinse Nozzle	0.25	MPa	$0.25 \sim 0.27$	0.20 (+0.02/-0)	Supply Regulator
External	DEV Cabinet	DEV Back Rinse Nozzle	0.15	MPa	$0.15 \sim 0.17$	0.15 (+0.02/-0)	Supply Regulator / Same as non-CPV-tool
External	DEV Cabinet	C.P.V for D.I. Water (1)	0.20	MPa	$0.19 \sim 0.21$	0.2	For DEV RINSE and BACK RINSE
External	DEV Cabinet	MGP1 SUB DIW	0.20	MPa	$0.20 \sim 0.22$	0.15 (+0.02/-0)	Supply Regulator
External	DEV Cabinet	C.P.V for MGP Sub D.I. Water	0.15	MPa	$0.14\sim0.16$	0.15	
External	DEV Cabinet	SRS Rinse / Back Rinse	0.20	MPa	0.20 ~ 0.22	0.15 (+0.02/-0)	Supply Regulator / For 8-1 / 8-2 / 8-6 / 8-7 / 8-8
External	DEV Cabinet	C.P.V for SRS	0.15	MPa	$0.14 \sim 0.16$	0.15	
External	DEV Cabinet	PIR Rinse / Back Rinse	0.20	MPa	$0.20 \sim 0.22$	0.15 (+0.02/-0)	Supply Regulator / For 8-3 / 8-4 / 8-9/ 8-10
External	DEV Cabinet	C.P.V for PIR	0.15	MPa	$0.14 \sim 0.16$	0.15	

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NTD Cabinet - [For TAR/TAS/TAU/TNK/TNR/TNS/TNU location is COT Cab] [For TAQ/TNQ location is DEV Cab]

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	COT Cabinet	Solvent 2 PCS (1,2) Drive	0.25	MPa	0.20 ~ 0.30	0.10 ~ 0.30	
External	COT Cabinet	Solvent 2 PCS (1,2) Ejector Drive	$0.1 \sim 0.35$	MPa		0.1 ~ 0.35	
External	COT Cabinet	Solvent 2 PCS (1,2) Fill Pressure	0.1	MPa	$0.1 \sim 0.12$	0.1 (+0.02/-0)	
External	COT Cabinet	Solvent 2 PCS (1,2) VAC Setting	-65.0	kPa	-60.0 ~ -70.0		Reduces bubble generation at the nozzle
External	COT Cabinet	Solvent 2 PCS (1,2) VAC U/L Solvent 2 PCS (1,2 VAC L/L	-49.0 -99.9	kPa		-29.0 -99.0	Reduces bubble generation at the nozzle
External	COT Cabinet	DEV Sol 2 PCS (1,2,3) Drive	0.25	MPa	0.20 ~ 0.30	0.10 ~ 0.30	Static Pressure Setting
External	COT Cabinet	DEV Sol 2 PCS (1,2,3) Ejector Drive	0.1 ~ 0.35	MPa		0.1 ~ 0.35	Static Pressure Setting
External	COT Cabinet	DEV Sol 2 PCS (1,2,3) Fill Pressure	0.1	MPa	$0.1 \sim 0.12$	0.1 (+0.02/-0)	Dynamic Setting
External	COT Cabinet	PCS (1,2,3) VAC Setting Dev Sol. (1,2,3)	-45.0	kPa	-40.0 ~ -50.0	-55 (+0/-5)	Static Pressure Setting
External	COT Cabinet	PCS (1,2,3) VAC U/L Setting DEV (1,2,3) PCS (1,2,3) VAC L/L Setting DEV (1,2,3)	-29.0 -99.9	kPa		-49.0 -99.0	Static Pressure Setting
External	COT Cabinet	FILTER VENT	60	ml/mir	54 to 66		IFFS ENABLED TOOL CONFIGURATIONS
External	COT Cabinet	FILTER PURGE	75	ml/mir	68 to 82		IFFS ENABLED TOOL CONFIGURATIONS
External	COT Cabinet	IFFS SOL. PCS (1,2,3) VAC Setting Sol. (1,2)	-80.0	kPa	-77.0 to -83.0	-80.0 (+/-3)	IFFS ENABLED TOOL CONFIGURATIONS
External	COT Cabinet	IFFS SOL.PCS (1,2,3) VAC U/L Setting Sol. (1,2) IFFS SOL.PCS (1,2,3) VAC L/L Setting Sol. (1,2)	-75.0 -85.0	kPa		-75.0 -85.0	IFFS ENABLED TOOL CONFIGURATIONS
External	COT Cabinet	FILTER VENT	60	ml/min	54 to 66		IFFS ENABLED TOOL CONFIGURATIONS
External	COT Cabinet	FILTER PURGE	75	ml/min	68 to 82		IFFS ENABLED TOOL CONFIGURATIONS
External	COT Cabinet	IFFS DEV.2 PCS (1,2,3) VAC Setting Sol. (1,2)	-80.0	kPa	-77.0 to -83.0	-80.0 (+/-3)	IFFS ENABLED TOOL CONFIGURATIONS
External	COT Cabinet	IFFS DEV.2PCS (1,2,3) VAC U/L Setting Sol. (1,2) IFFS DEV.2PCS (1,2,3) VAC L/L Setting Sol. (1,2)	-75.0 -85.0	kPa		-75.0 -85.0	IFFS ENABLED TOOL CONFIGURATIONS
External	COT Cabinet	IFFS Control box P_1 setting	0.1	MPa	0.08 ~ 0.12	Tool Specific	IFFS ENABLED TOOL CONFIGURATIONS Pressure necessary to achieve 100 ml/min with filter vent valve full open and filter blank installe
External	COT Cabinet	IFFS Control box P_2 setting	0.14	MPa	0.12 ~ 0.16	Tool Specific	IFFS ENABLED TOOL CONFIGURATIONS P_2 setting is 0.03 higher than P_1
External	COT Cabinet	IFFS Control box P_3 setting	0.19	MPa	0.17 ~ 0.21	Tool Specific	CRF ENABLED TOOL CONFIGURATIONS P_3 is 0.05 less than PCS drive pressure, (POS only) P_3 for both decks must be matched.
External	COT Cabinet	CRF Return Line	60.0	ml/mir	54 to 66		CRF ENABLED TOOL CONFIGURATIONS
External	COT Cabinet	CRF Drain Line	60.0	ml/min	54 to 66		CRF ENABLED TOOL CONFIGURATIONS

Ultrasonic flov	Ultrasonic flowmeter setting for "Liquid Kind"								
CHEMICAL NAME Flow meter Chemical TYPE									
Solvent (POS, PGMEA, EL)	Solvent/Cyclohexane								
DI Water	DIW								
Developer Solution	Developer Solution/Developer Solution								
LNR	Solvent/Other								
LND	Solvent/Other								



Chemical Cabinet Exhaust Setting for all Configurations

Tool Config	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
	COT Cabinet	Exhaust Solvent (EA1)	100	Pa	15 to 325	100	TARGET CFM
	COT Cabinet	Exhaust Solvent (EA1) U/L Setting (EA1)	350	Pa		0	70.6
•	COT Cabinet	Exhaust Solvent (EA1) L/L Setting (EA1)	10	Pa		70	
	COT Cabinet	Exhaust Solvent (EA2)	100	Pa	15 to 325	100	TARGET CFM
	COT Cabinet	Exhaust Solvent (EA2) U/L Setting (EA2)	350	Pa		0	70.6
	COT Cabinet	Exhaust Solvent (EA2) L/L Setting (EA2)	10	Pa		70	70.0
TAQ/TNQ	COT Cabinet	Exhaust HMDS (EA5)	200	Pa	15 to 325	200	TARGET CFM
	COT Cabinet	Exhaust HMDS U/L Setting (EA5)	350	Pa		0	14.1
	COT Cabinet	Exhaust HMDS L/L Setting (EA5)	10	Pa		50	17.1
	DEV Cabinet	DEV CAB Exhaust (EC1)	25	Pa	15 to 325	30	TARGET CFM
	DEV Cabinet	DEV CAB Exhaust U/L Setting (EC1)	350	Pa		0	35.3
		DEV CAB Exhaust L/L Setting (EC1)	10	Pa		5	
	DEV Cabinet	DEV CAB Exhaust (EC2)	25	Pa	15 to 325	30	TARGET CFM
	DEV Cabinet	DEV CAB Exhaust U/L Setting (EC2)	350	Pa		0	17.7
	COTCL	DEV CAB Exhaust L/L Setting (EC2)	10	Pa		5	
	COT Cabinet	Exhaust Solvent (EA1)	125	Pa	15 to 325	100	TARGET CFM
	COT Cabinet	Exhaust Solvent (EA1) U/L Setting (EA1)	350	Pa		0	70.6
	COT Cabinet	Exhaust Solvent (EA1) L/L Setting (EA1)	10	Pa	15 (225	70	
NE [NON-CE]	COT Cabinet	Exhaust HMDS (EA5)	150	Pa	15 to 325	200	TARGET CFM
		Exhaust HMDS U/L Setting (EA5)	350	Pa		0	14.1
TNE [CE]	COT Cabinet	Exhaust HMDS L/L Setting (EA5)	10	Pa		50	
	DEV Cabinet	DEV CAB Exhaust (EC1)	25	Pa	15 to 325	30	TARGET CFM
TNE [HVM]	DEV Cabinet	DEV CAB Exhaust U/L Setting (EC1)	350	Pa		0	35.3
	DELL C 1	DEV CAB Exhaust L/L Setting (EC1)	10	Pa		5	
	DEV Cabinet	DEV CAB Exhaust (EC2)	20	Pa	15 to 325	30	TARGET CFM
	DEV Cabinet	DEV CAB Exhaust U/L Setting (EC2)	350	Pa		0	17.7
	00m 0 1	DEV CAB Exhaust L/L Setting (EC2)	10	Pa		5	
	COT Cabinet	Exhaust Solvent (EA1)	50	Pa	15 to 325	100	TARGET CFM 14.1
	COT Cabinet	Exhaust Solvent (EA1) U/L Setting (EA1)	350	Pa		0	
	COT Cabinet	Exhaust Solvent (EA1) L/L Setting (EA1)	10	Pa		70	
TNG / TBL /	COT Cabinet	Exhaust HMDS (EA5)	15	Pa	5 to 100	200	TARGET CFM
TBM	COT Cabinet	Exhaust HMDS U/L Setting (EA5)	100	Pa		0	14.1
		Exhaust HMDS L/L Setting (EA5)	5	Pa	15 : 225	50	
	DEV Cabinet	DEV CAB Exhaust (EC1)	50	Pa	15 to 325	30	TARGET CFM
	DEV Cabinet	DEV CAB Exhaust U/L Setting (EC1)	350	Pa		0	17.7
	COT Cabinet	DEV CAB Exhaust L/L Setting (EC1) Exhaust Solvent (EA1)	10	Pa Pa	15 (225	5 100	
-			50		15 to 325	0	TARGET CFM
-		Exhaust Solvent (EA1) U/L Setting (EA1)	350	Pa		70	21.2
-	COT Cabinet	Exhaust Solvent (EA1) L/L Setting (EA1) Exhaust HMDS (EA5)	10 15	Pa Pa	5 to 100	200	
AS/TAU/TNU/			100				TARGET CFM
TNK	COT Cabinet	Exhaust HMDS U/L Setting (EA5) Exhaust HMDS L/L Setting (EA5)	5	Pa Pa		50	14.1
-	DEV Cabinet	DEV CAB Exhaust (EC1)	50	Pa Pa	15 to 325	30	
-				Pa Pa	15 to 325	0	TARGET CFM
	DEV Cabinet	DEV CAB Exhaust U/L Setting (EC1) DEV CAB Exhaust L/L Setting (EC1)	350 10	Pa Pa		5	21.2
	COT Cabinet	Exhaust Solvent (EA1)	100	Pa Pa	15 to 325	100	
-	COT Cabinet	Exhaust Solvent (EA1) Exhaust Solvent (EA1) U/L Setting (EA1)	350	Pa Pa	15 to 325	0	TARGET CFM
}		Exhaust Solvent (EA1) U/L Setting (EA1) Exhaust Solvent (EA1) L/L Setting (EA1)	10	Pa Pa		70	35.3
TBC	COT Cabinet	Exhaust HMDS (EA5)	150	Pa	15 to 325	200	
}	COT Cabinet	Exhaust HMDS (EA5) Exhaust HMDS U/L Setting (EA5)	350	Pa	13 10 323	0	TARGET CFM
ŀ	COT Cabinet	Exhaust HMDS U/L Setting (EAS) Exhaust HMDS L/L Setting (EAS)	350	Pa Pa		50	14.1
	COT Cabinet	Exhaust HMDS L/L Setting (EA3) Exhaust Solvent (EA1)	15	Pa Pa	5 to 100	100	
-		Exhaust Solvent (EA1) Exhaust Solvent (EA1) U/L Setting (EA1)	100	Pa Pa		0	TARGET CFM
-						70	14.1
TBE	COT Cabinet	Exhaust Solvent (EA1) L/L Setting (EA1) Exhaust HMDS (EA5)	5 15	Pa Pa	5 to 100	200	
	COI Cabinet	EXHAUST FINIDS (EAS)	15	Pa	2 to 100	200	TARGET CFM
}	COT Cabinet	Exhaust HMDS U/L Setting (EA5)	100	Pa		0	TARGET CEW

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STHC1

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	STHC	STHC&CHILLER Installation Height	110	mm	105 ~ 115	110 ±5	
External	STHC	Primary Supply Power Voltage	3Phases AC200 to 220	V	+/-10%	+/-10%	
External	THC	Blower Inverter Setting Range	Tool Specific	Hz	30 ~ 60	30 ~ 60	
External	THC	Condensation Pressure (REF 1)	1.5	MPa	1.45 to 1.55	1.5 ±0.02	
External	THC	Evaporating Pressure (REF 1)	0.45	MPa	0.4 to 0.6	0.42 to 0.58	
External	THC	Condensation Pressure (REF 2)	1.5	MPa	1.45 to 1.55	1.5 ±0.02	
External	THC	Evaporating Pressure (REF 2)	0.45	MPa	0.4 to 0.6	0.42 to 0.50	
External	THC	Air volume warning value	Adjustment value ±10%	m3/min		Adjustment value ±10%	
External	THC	Cup Temperature Offset Value	22.2	degree	22.1 to 22.3	22.2±0.1C	
External	THC	Cup Humidity Offset Value	40.7	%	40.2 to 41.2	40.7±5%	
External	THC	Cup Temperature across all Cups	0.2	degree	-	0.2	
External	THC	Cup Humidity across all Cups	1.0	%		1.0	
External	THC	Utility Supply (DIW)	0.1	Mpa	0.08 to .12	$0.08 \sim 0.12$	Set this with Valve Closed
External	THC	Utility Supply (PCW)	0.35	Mpa	0.3 to 0.4	$0.3 \sim 0.4$	Not present on all tracks
External	THC	AIR Digital Pressure Gauge	0.35	MPa	0.3 to 0.4	$0.35 \sim 0.50$	Set at Dev Cabinet
External	THC	AIR Digital Pressure Gauge U/L Setting	0.4	MPa		0.4	
External	THC	AIR Digital Pressure Gauge L/L Setting	0.25	MPa		0.25	
External	CHILLER	HMDS Buffer Tank Flow Rate	2.0	L/min	1.5 to 2.5	>1.0LPM	
External	CHILLER	HMDS Buffer Tank Temperature	22.0	degree	21.5 to 22.5	21.5 to 22.5	
External	CHILLER	Pump Inverter Setting Range	Tool Specific	Hz	30 to 60	30 ~ 60	
External	CHILLER	Condensation Pressure	1.5	MPa	1.45 to 1.55	1.5 ±0.02	
External	CHILLER	Evaporating Pressure	0.46	MPa	0.43 to 0.49	0.43 to 0.49	

T/H 2 TNU ONLY

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	STHC	STHC&CHILLER Installation Height	110	mm	105 ~ 115	110 ±5	
External	STHC	Primary Supply Power Voltage	3Phases AC200 to 220	V	+/-10%	+/-10%	
External	THC	Blower Inverter Setting Range	Tool Specific	Hz	30 ~ 60	30 ~ 60	
External	THC	Condensation Pressure	1.5	MPa	1.4 to 1.6	1.5 ±0.10	
External	THC	Evaporating Pressure	0.45	MPa	0.4 to 0.6	0.40 to 0.60	
External	THC2	Utility Supply (DIW)	0.1	Mpa	0.08 to .12	$0.08 \sim 0.12$	
External	THC2	Utility Supply (PCW)	0.35	Mpa	0.3 to 0.4	0.3 ~ 0.4	
External	THC2	AIR Digital Pressure Gauge	0.35	MPa	0.3 to 0.4	$0.35 \sim 0.50$	

STHC CHILLER FLOW RATE SETTING CHART

TAQ/TNQ

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	CHILLER	remperature Control water Flow Kate	2.0	L/min	1.9 to 2.1	2+/-0.1	4-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH1) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	5-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH2) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	6-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH3) CPL-i	4.0	L/min	3.9 to 4.1	4+/-0.1	8-21 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-1) SRS	2.0	L/min	1.9 to 2.1	2+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH4-2) PIR	2.0	L/min	1.9 to 2.1	2+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH4-3) Cool Arm	5.2	L/min	5.1 to 5.3	5.2+/-0.1	2-16 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-4) S-CPL	18.0	L/min	17.5 to 18.5	18+/-0.5	
External	CHILLER	Temperature Control Water Flow Rate (CH4-6) M-CPL	15.0	L/min	14.5 to 15.5	15+/-0.5	
External	CHILLER	Temperature Control Water Flow Rate (CH5-1) CPL-D	9.0	L/min	8.9 to 9.1	9+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-2) DEV M/F *	4.0	L/min	3.9 to 4.1	4+/-0.1	3-41 CPLModule = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-1) DEV (Nozzle Lower)	2.0	L/min	1.9 to 2.1	2+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-3) DEV (Nozzle Upper)	2.0	L/min	1.9 to 2.1	2+/-0.1]
External	CHILLER	Utility Supply (PCW)	0.35	MPa	0.3 to 0.4	0.3 ~ 0.4	

^{*=472} ONLY Developer for NTD Chemical

STHC CHILLER FLOW RATE SETTING CHART

NON-CE TNE

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	CHILLER	Temperature Control Water Flow Rate (CH0) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	4-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH1) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	5-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH2) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	6-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH3) CPL	4.0	L/min	3.9 to 4.1	4+/-0.1	7-11 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-1) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-2) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-3) Cool Arm	6.6*	L/min	6.5 to 6.7	6.6+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH4-4) S-CPL	18.0*	L/min	17.5 to 18.5	18+/-0.5	2-16 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-6) CPL-M	15.0	L/min	14.5 to 15.5	15+/-0.5	
External	CHILLER	Temperature Control Water Flow Rate (CH5-1) CPL-D	9.0	L/min	8.9 to 9.1	9+/-0.1	3-41 CPI Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH5-2) DEV	8.0	L/min	7.9 to 8.1	8+/-0.1	75-41 Cr Liviodule – Ose Politi Colitioi
External	CHILLER	Utility Supply (PCW)	0.35	MPa	0.3 to 0.4	0.3 ~ 0.4	

*For HVM conversion tools Channel 4-3 = 4.2L/min Channel 4-4 = 9.0L/min

NON-CE TNE with High Throughput Upgrade

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	CHILLER	Temperature Control Water Flow Rate (CH0) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	4-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH1) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	5-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH2) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	6-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH3) CPL-i	4.0	L/min	3.9 to 4.1	4+/-0.1	7-11 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-1) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-2) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-3) Cool Arm	6.6	L/min	6.5 to 6.7	6.6+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH4-4) S-CPL	21.0	L/min	20.5 to 21.5	21+/-0.5	7-33 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-6) CPL-M	15.0	L/min	14.5 to 15.5	15+/-0.5	
External	CHILLER	Temperature Control Water Flow Rate (CH5-1) DEV	8.0	L/min	7.9 to 8.1	8+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-1) CPL-M 2-15	3.0	L/min	2.9 to 3.1	3+/-0.1	2-15 SCPL = Use Posint Control
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-2) CPL-D	9.0	L/min	8.9 to 9.1	9+/-0.1	
External	CHILLER	Utility Supply (PCW)	0.35	MPa	0.3 to 0.4	0.3 ~ 0.4	

STHC CHILLER FLOW RATE SETTING CHART

CE TNE

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	CHILLER	Temperature Control Water Flow Rate (CH0) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	4-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH1) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH2) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	6-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH3) CPL	4.0	L/min	3.9 to 4.1	4+/-0.1	7-11 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-1) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-2) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-3) Cool Arm	6.6	L/min	6.5 to 6.7	6.6+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH4-4) S-CPL	9.0	L/min	8.5 to 9.5	9+/-0.5	2-23 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-6) M-CPL	9.0	L/min	8.5 to 9.5	9+/-0.5	
External	CHILLER	Temperature Control Water Flow Rate (CH5-1) CPL-D	9.0	L/min	8.9 to 9.1	9+/-0.1	2.41 CDI M. July B. int Control
External	CHILLER	Temperature Control Water Flow Rate (CH5-2) DEV	8.0	L/min	7.9 to 8.1	8+/-0.1	3-41 CPLModule = Use Point Control
External	CHILLER	Utility Supply (PCW)	0.35	MPa	0.3 to 0.4	0.3 ~ 0.4	

CE TNE with High Throughput Upgrade

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	CHILLER	Temperature Control Water Flow Rate (CH0) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	4-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH1) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH2) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	6-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH3) CPL -i	4.0	L/min	3.9 to 4.1	4+/-0.1	7-11 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-1) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-2) Bypass	13.0	L/min	12.5 to 13.5	13+/-0.5	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-3) Cool Arm	6.6	L/min	6.5 to 6.7	6.6+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH4-4) S-CPL	12.0	L/min	11.5 to 12.5	12+/-0.5	7-43 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-6) M-CPL	9.0	L/min	8.5 to 9.5	9+/-0.5	
External	CHILLER	Temperature Control Water Flow Rate (CH5-1) DEV	8.0	L/min	7.9 to 8.1	8+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-1) CPL-M 2-15	3.0	L/min	2.9 to 3.1	3+/-0.1	2-15 SCPL = Use Posint Control
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-2) CPL - D	9.0	L/min	8.9 to 9.1	9+/-0.1	
External	CHILLER	Utility Supply (PCW)	0.35	MPa	0.3 to 0.4	0.3 ~ 0.4	

STHC CHILLER FLOW RATE SETTING CHART

D5 Reserved HVM TNE

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	CHILLER	Temperature Control Water Flow Rate (CH0) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	4-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH1) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	5-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH2) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	6-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH3) CPL	4.0	L/min	3.9 to 4.1	4+/-0.1	7-11 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-1) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-2) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-3) Cool Arm	5.2	L/min	5.1 to 5.3	5.2+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH4-4) S-CPL	18.0	L/min	17.5 to 18.5	18+/-0.5	2-16 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-6) M-CPL	15.0	L/min	14.5 to 15.5	15+/-0.5	
External	CHILLER	Temperature Control Water Flow Rate (CH5-1) CPL-D	9.0	L/min	8.9 to 9.1	9+/-0.1	3-41 CPLModule = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH5-2) DEV	8.0	L/min	7.9 to 8.1	8+/-0.1	73-41 Cr Liviodule – Use Point Control
External	CHILLER	Utility Supply (PCW)	0.35	MPa	0.3 to 0.4	0.3 ~ 0.4	

D5 Reserved HVM TNE with High Throughput Upgrade

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	CHILLER	Temperature Control Water Flow Rate (CH0) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	4-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH1) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	5-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH2) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	6-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH3) CPL	4.0	L/min	3.9 to 4.1	4+/-0.1	7-11 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-1) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-2) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-3) Cool Arm	5.2	L/min	5.1 to 5.3	5.2+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH4-4) S-CPL	21.0	L/min	20.5 to 21.5	21+/-0.5	7-33 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-6) M-CPL	15.0	L/min	14.5 to 15.5	15+/-0.5	
External	CHILLER	Temperature Control Water Flow Rate (CH5-1) DEV	8.0	L/min	7.9 to 8.1	8+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-1) CPL-M 2-15	3.0	L/min	2.9 to 3.1	3+/-0.1	2-15 CPLModule = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-2) CPL - D	9.0	L/min	8.9 to 9.1	9+/-0.1	
External	CHILLER	Utility Supply (PCW)	0.35	MPa	0.3 to 0.4	0.3 ~ 0.4	

STHC CHILLER FLOW RATE SETTING CHART

D5 Blanked HVM TNE

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	CHILLER	Temperature Control Water Flow Rate (CH0) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	4-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH1) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH2) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	6-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH3) CPL	4.0	L/min	3.9 to 4.1	4+/-0.1	7-11 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-1) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-2) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-3) Cool Arm	4.6	L/min	4.5 to 4.7	4.6+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH4-4) S-CPL	12.0	L/min	11.5 to 12.5	12+/-0.5	2-16 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-6) M-CPL	15.0	L/min	14.5 to 15.5	15+/-0.5	
External	CHILLER	Temperature Control Water Flow Rate (CH5-1) CPL-D	9.0	L/min	8.9 to 9.1	9+/-0.1	3-41 CPLModule = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH5-2) DEV	8.0	L/min	7.9 to 8.1	8+/-0.1	3-41 Cr Liviodule – Ose Politi Control
External	CHILLER	Utility Supply (PCW)	0.35	MPa	0.3 to 0.4	0.3 ~ 0.4	

D5 Blanked HVM TNE with High Throughput Upgrade

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	CHILLER	Temperature Control Water Flow Rate (CH0) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	4-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH1) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH2) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	6-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH3) CPL	4.0	L/min	3.9 to 4.1	4+/-0.1	7-11 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-1) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-2) Bypass	9.0	L/min	8.5 to 9.5	9+/-0.5	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-3) Cool Arm	4.6	L/min	4.5 to 4.7	4.6+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH4-4) S-CPL	12.0	L/min	11.5 to 12.5	12+/-0.5	7-43 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-6) M-CPL	15.0	L/min	14.5 to 15.5	15+/-0.5	
External	CHILLER	Temperature Control Water Flow Rate (CH5-1) DEV	8.0	L/min	7.9 to 8.1	8+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-1) CPL-M 2-15	3.0	L/min	2.9 to 3.1	3+/-0.1	2-15 CPLModule = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-2) CPL - D	9.0	L/min	8.9 to 9.1	9+/-0.1	
External	CHILLER	Utility Supply (PCW)	0.35	MPa	0.3 to 0.4	0.3 ~ 0.4	

STHC CHILLER FLOW RATE SETTING CHART

D5/D6 Blanked HVM TNE

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	CHILLER	Temperature Control Water Flow Rate (CH0) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	4-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH1) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH2) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH3) CPL	4.0	L/min	3.9 to 4.1	4+/-0.1	7-11 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-1) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-2) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-3) Cool Arm	3.6	L/min	3.5 to 3.7	3.6+/-0.1	2-23 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-4) S-CPL	9.0	L/min	8.5 to 9.5	9+/-0.5	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-6) M-CPL	9.0	L/min	8.5 to 9.5	9+/-0.5	2-23 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH5-1) CPL-D	9.0	L/min	8.9 to 9.1	9+/-0.1	3-41 CPLModule = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH5-2) DEV	8.0	L/min	7.9 to 8.1	8+/-0.1	15-41 CPLIVIOQUIE = Use Point Control
External	CHILLER	Utility Supply (PCW)	0.35	MPa	0.3 to 0.4	0.3 ~ 0.4	

D5/D6 Blanked HVM TNE with High Throughput Upgrade

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	CHILLER	Temperature Control Water Flow Rate (CH0) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	4-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH1) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH2) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	6-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH3) CPL	4.0	L/min	3.9 to 4.1	4+/-0.1	7-11 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-1) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-2) Bypass	9.0	L/min	8.5 to 9.5	9+/-0.5	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-3) Cool Arm	4.6	L/min	4.5 to 4.7	4.6+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH4-4) S-CPL	12.0	L/min	11.5 to 12.5	12+/-0.5	7-43 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-6) M-CPL	15.0	L/min	14.5 to 15.5	15+/-0.5	
External	CHILLER	Temperature Control Water Flow Rate (CH5-1) DEV	8.0	L/min	7.9 to 8.1	8+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-1) CPL-M 2-15	3.0	L/min	2.9 to 3.1	3+/-0.1	2-15 CPLModule = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-2) CPL - D	9.0	L/min	8.9 to 9.1	9+/-0.1	
External	CHILLER	Utility Supply (PCW)	0.35	MPa	0.3 to 0.4	0.3 ~ 0.4	

STHC CHILLER FLOW RATE SETTING CHART

TNG

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	CHILLER	Temperature Control Water Flow Rate (CH0) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	4-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH1) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH2) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	6-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH3) CPL-i	4.0	L/min	3.9 to 4.1	4+/-0.1	7-11 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-1)	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-2)	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-3) Cool Arm	6.6	L/min	6.5 to 6.7	6.6+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH4-4) S-CPL	9.0	L/min	8.5 to 9.5	9+/-0.5	2-23 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-6) M-CPL	9.0	L/min	8.5 to 9.5	9+/-0.5	
External	CHILLER	Temperature Control Water Flow Rate (CH5-1) CPL-D	9.0	L/min	8.9 to 9.1	9+/-0.1	3-41 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH5-2) DEV	8.0	L/min	7.9 to 8.1	8+/-0.1	73-41 Cr Liviodule – Ose Politi Collifol
External	CHILLER	Utility Supply (PCW)	0.35	MPa	0.3 to 0.4	0.3 ~ 0.4	

TNG with High Throughput Upgrade and TBM

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	CHILLER	Temperature Control Water Flow Rate (CH0) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	4-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH1) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH2) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	6-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH3) CPL -i	4.0	L/min	3.9 to 4.1	4+/-0.1	7-11 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-1) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-2) Bypass	13.0	L/min	12.5 to 13.5	13+/-0.5	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-3) Cool Arm	6.6	L/min	6.5 to 6.7	6.6+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH4-4) S-CPL	12.0	L/min	11.5 to 12.5	12+/-0.5	7-43 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-6) M-CPL	9.0	L/min	8.5 to 9.5	9+/-0.5	
External	CHILLER	Temperature Control Water Flow Rate (CH5-1) DEV	8.0	L/min	7.9 to 8.1	8+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-1) CPL-M 2-15	3.0	L/min	2.9 to 3.1	3+/-0.1	2-15 SCPL = Use Posint Control
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-2) CPL - D	9.0	L/min	8.9 to 9.1	9+/-0.1	
External	CHILLER	Utility Supply (PCW)	0.35	MPa	0.3 to 0.4	0.3 ~ 0.4	

STHC CHILLER FLOW RATE SETTING CHART

TBC/TBE

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	CHILLER	Temperature Control Water Flow Rate (CH0) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH1) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	5-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH2) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	6-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH3)	4.0	L/min	3.9 to 4.1	4+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-1)	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-2)	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-3) Cool Arm	5.2	L/min	5.1 to 5.3	5.2+/-0.1	7-33 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-4) S-CPL	18.0	L/min	17.5 to 18.5	18+/-0.5	7-33 CFL Wodule – Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-6) M-CPL	15.0	L/min	14.5 to 15.5	15+/-0.5	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH5-1)	9.0	L/min	8.9 to 9.1	9+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-1)	4.0	L/min	3.9 to 4.1	4+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-2)	4.0	L/min	3.9 to 4.1	4+/-0.1	BYPASS
External	CHILLER	Utility Supply (PCW)	0.35	MPa	0.3 to 0.4	0.3 ~ 0.4	

TBE na

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	CHILLER	Temperature Control Water Flow Rate (CH0) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH1) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	5-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH2) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	6-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH3)	4.0	L/min	3.9 to 4.1	4+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-1)	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-2)	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-3) Cool Arm	2.8	L/min	2.7 to 2.9	2.8+/-0.1	7-33 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-4) S-CPL	18.0	L/min	17.5 to 18.5	18+/-0.5	7-33 CFL Wodule – Use Folin Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-6) M-CPL	15.0	L/min	14.5 to 15.5	15+/-0.5	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH5-1)	9.0	L/min	8.9 to 9.1	9+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-1)	4.0	L/min	3.9 to 4.1	4+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-2)	4.0	L/min	3.9 to 4.1	4+/-0.1	BYPASS
External	CHILLER	Utility Supply (PCW)	0.35	MPa	0.3 to 0.4	0.3 ~ 0.4	

STHC CHILLER FLOW RATE SETTING CHART

TAS/TAU/TNU/TNK

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	CHILLER	Temperature Control Water Flow Rate (CH0) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	4-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH1) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH2) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	6-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH3) CPL-i	4.0	L/min	3.9 to 4.1	4+/-0.1	8-21 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-1) SRS	2.0	L/min	1.9 to 2.1	2+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH4-2) PIR	2.0	L/min	1.9 to 2.1	2+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH4-3) Cool Arm	8.4	L/min	8.3. to 8.5	8.4+/-0.1	2-23 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-4) S-CPL	9.0	L/min	8.5 to 9.5	9+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH4-6) M-CPL	9.0	L/min	8.5 to 9.5	9+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH5-1) CPL-D	9.0	L/min	8.9 to 9.1	9+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-1) DEV	6.0	L/min	5.9 to 6.1	6+/-0.2	3-41 CPLModule = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-2) DEV	6.0	L/min	5.9 to 6.2	6+/-0.2	
External	CHILLER	Utility Supply (PCW)	0.35	MPa	0.3 to 0.4	0.3 ~ 0.4	

TBL

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	CHILLER	Temperature Control Water Flow Rate (CH0) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH1) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	5-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH2) COT	2.0	L/min	1.9 to 2.1	2+/-0.1	6-0 COT Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH3) CPL-i	4.0	L/min	3.9 to 4.1	4+/-0.1	7-11 CPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-1) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-2) Bypass	2.0	L/min	1.9 to 2.1	2+/-0.1	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH4-3) Cool Arm	6.2	L/min	6.1 to 6.3	6.2+/-0.1	7-33 SCPL Module = Use Point Control
External	CHILLER	Temperature Control Water Flow Rate (CH4-4) S-CPL	18.0	L/min	17.5 to 18.5	18+/-0.5	7-33 SCFE Woddie – Ose Folia Condo
External	CHILLER	Temperature Control Water Flow Rate (CH4-6) Bypass	14.0	L/min	13.5 to 14.5	14+/-0.5	BYPASS
External	CHILLER	Temperature Control Water Flow Rate (CH5-1) DEV	8.0	L/min	7.9 to 8.1	8+/-0.1	
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-1) CPL-M 2-15	3.0	L/min	2.9 to 3.1	3+/-0.1	2-15 SCPL = Use Posint Control
External	CHILLER	Temperature Control Water Flow Rate (CH5-2-2) CPL-D	9.0	L/min	8.9 to 9.1	9+/-0.1	
External	CHILLER	Utility Supply (PCW)	0.35	MPa	0.3 to 0.4	0.3 ~ 0.4	

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Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	DEV/NTD	Chuck Vac	-75	kPa	-71.0 ~ -79.0	-75.0 +/-0.4	Static - Keep 71kPa or higher after 1 minute, with the original pressure set at 75kPa. Fluctuation at Wafer spin start should be within 0.4kPa.
PRB	DEV/NTD	Chuck Vac U/L (Sunx-DP-100) Chuck Vac L/L (Sunx-DP-100)	-45.0 -99.9	kPa		-45.0 -99.9	
PRB	DEV/NTD	3-PIN Level	0	degree	0.06 ~ -0.06	0.06 ~ -0.06	
PRB	DEV/NTD	Chuck Level	0	degree	0.06 ~ -0.06	0.06 ~ -0.06	
PRB	DEV/NTD	3-PIN Height - Up	45	mm		45	From the chuck to the top surface of the 3-Pii
PRB	DEV/NTD	3-PIN Height - Down	-10	mm		-10	From the chuck to the top surface of the 3-Pii
PRB PRB	DEV/NTD DEV/NTD	3-PIN Up	N/A* N/A*	sec		1.5 1.5	*Controlled by motor. Nominal timing is 1.5s
		3-PIN Down SHUTTER OPEN	0.9	sec		0.9	*Controlled by motor. Nominal timing is 1.5s
PRB	DEV/NTD	SHUTTER CLOSED	0.9	sec	0.8 ~ 1.0	0.9	Set by Sub-Op display
PRB	DEVAITD	Auto Damper OPEN	0.4		02.05	0.4	Set her Set On displan
PKB	DEV/NTD	Auto Damper CLOSED	0.4	sec	0.3 - 0.5	0.4	Set by Sub-Op display
PRB	DEV/NTD	RINSE MODULE-Arm UP RINSE MODULE-Arm DOWN	0.9 0.9	sec	$0.8 \sim 1.0$	0.9 0.9	Set by Sub-Op display [Adjust @ dispense position]
			8	Pa	7~9	8 (+/-1)	Layer is checked with all modules Cup up and then execute auto
PRB	DEV/NTD	Cup Exhaust Open				, , ,	damper
		Cup Exhaust Closed Cup EXH U/L Setting (Nagano Keiki)	45 85	Pa Pa	40 ~ 50 	45 (+/-5) 85	
PRB	DEV/NTD	Cup EXH L/L Setting (Nagano Keiki)	1	Pa		1	
PRB	DEV	Knife Edge Height	-1.0	mm	-0.8 to -1.2	-1+/-0.2	Use Digital cup height JIG 3 points of measurement, gauge doesn't move during Cup UP/DOWN
PRB	NTD	Middle Cup Height	2.8	mm	2.6 to 3.0	2.8+/-0.5	Torque 75cn*m Check current Torque Doc Use Digital cup height JIG NTD with IC cup Torque 75cn*m Check current Torque Doc
PRB	DEV/NTD	Cup Height Range Value	0.2	mm	-		Applies to the 3 adjustments pts. on the base cup.
PRB	DEV/NTD	Cup Height Range Value	0.5	mm	+		Applies to the 6 measurements pts.
PRB	DEV	SUS Ring Up	28	mm	26 to 30	28+/-2	Measured from the bottom of the SUS Ring to the top of the White middle ring.
PRB	DEV	SUS Ring Down	3	mm	1 to 5	3+/-2	Measured from the bottom of the SUS Ring to the top of the White middle ring.
PRB	DEV	Upper Cup and Nozzle Arm Gap	>1	mm	>1	>1	To be measured at the bottom of the nozzle and top of the upper cup Arm is positioned at chuck center
PRB	DEV	SUS Ring and Under Cup Gap Spacer	0.5	mm	0.5	0.5	Checked around the entire area of the Cup.
PRB	DEV	GP/MGP Nozzle Height	12.6	mm	12.1 to 13.1	12.6+/-0.5	Set by using PRO-V set up tool
PRB	DEV	MGP sub DEV	20.0	mm	19.5 ~ 20.5	20.0+/-0.5	The setting is information only
	52.	inor suo B2.	2010		17.5 20.5	20.0 17 0.3	The height set up by MGP nozzle heigh The setting is information only
PRB	DEV	MGP sub DIW	20.0	mm	19.5 ~ 20.5	20.0+/-0.5	The height set up by MGP nozzle heigh
PRB	NTD	NTD Nozzle Height	16	mm	14.5 to 16.5	+0.5/-1.5	Measure from Tip of nozzle to wafer surface
PRB	NTD	NTD Rinse Nozzle Height	16	mm	14.5 to 16.5	+0.5/-1.5	NTD Rinse Nozzle height as "informational only" since the arm is calibrated with the NTD Nozzle
PRB	DEV	LD Nozzle Height	2	mm	1.8 ~ 2.2	1.0+/-0.2	Measured at 5 Points using spacer
PRB	DEV	ADR N2 Nozzle Height	25	mm	23.5 ~ 25.5	25+0.5/-1.5	The setting is information only
PRB	DEV	ADR-Rinse Nozzle Height	12	mm	10.5 ~ 12.5	12+0.5/-1.5	The height set up by ADR Rinse nozzle heigh The setting is informal only on XDR-equipped tools ADR Rinse enabled tool set ADR rinse nozzle by using PRO-V set up tool
PRB	DEV	XDR N2 Nozzle Height	3	mm	2.8 ~ 3.2	3+0.2	XDR enabled tool set XDR N2 nozzle height by using PRO-V set up tool
PRB	DEV	XDR-Rinse Nozzle Height	12	mm	11.5 ~ 12.5	12+/-0.5	The setting is information only The height set up by XDR N2 nozzle heigh
PRB	DEV	Back Rinse Nozzle Position	80	mm	78 to 82	φ160+/-5	Dispense stream hits glass wafer 80 mm from center of the chuck.
		Outer Cup UP	0.9			0.9	i i
PRB	DEV	Outer Cup Down	0.9	sec	0.8 ~ 1.0	0.9	Set by Sub-Op display
PRB	DEV	MGP Nozzle Center Position	Center = Chuck Center	mm		Center = Chuck Center	Set by using PRO-V set up tool
PRB	DEV	DEV SUB	Center = Chuck Center	mm		Center = Chuck Center	Set by using PRO-V set up tool
PRB	DEV	DIW SUB	Center = Chuck Center	mm		Center = Chuck Center	Set by using PRO-V set up tool
PRB	DEV	LD Nozzle Center Position	Center = Chuck Center	mm		Center = Chuck Center	
PRB	DEV	Rinse Nozzle Center Position	LD Center =	mm		LD Center =	Set by using PRO-V set up tool
PRB	DEV	ADR N2 Nozzle Center Position	Chuck Center ADR Center = -15	mm		Chuck Center ADR Center =	
			Center =			-15 Center =	Set by using PRO-V set up tool
PRB	DEV	ADR Nozzle Center Position	Chuck Center	mm		Chuck Center	[Set value is based on ADR dispense]

5. COT / BCT

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PRB COT/BCT Chuck Vac -75 kPa -71.0 ~ -79.0 -75.0 +/-0.4 original pressure set at 75 be within 0.4kPa. PRB COT/BCT Chuck Vac U/L (Sunx-DP-100) 45.0 kPa 45.0 be within 0.4kPa. PRB COT/BCT 3-PIN Level 0 degree 0.06 ~ -0.06 0.06 ~ -0.06 0.06 ~ -0.06 PRB COT/BCT 3-PIN Level 0 degree 0.06 ~ -0.06 0.06 ~ -0.06 0.06 ~ -0.06 PRB COT/BCT 3-PIN Height - Up 45 mm 45 From the chuck to the top PRB COT/BCT 3-PIN Height - Down -10 mm 1.15 *Controlled by motor. No PRB COT/BCT 3-PIN Down N/A* sec 1.5 *Controlled by motor. No PRB COT/BCT 3-PIN Down N/A* sec 1.5 *Controlled by motor. No PRB COT/BCT Middle Cup Height Resist = 3.1 mm Resist = 2.6 ~ 3.6 2.8 +/-0.5	a or higher after 1 minute, with the Pa. Fluctuation at Wafer spin start should
PRB COT/BCT Chuck Vac L/L (Sunx-DP-100) -99.9 KPa	
PRB	
PRB	
PRB	
PRB	surface of the 3-Pi
PRB	
PRB	
PRB COT Middle Cup Height Resist = 3.1 mm Resist = 2.6 ~ 3.6 2.8 ± 4.0.5 Average of 6 measuremer COT Spinner uses PV Cup [Torque 75cn*m] Check chartual reading will be 2.3 the top of the middle cup. PRB COT Knife Edge Height Range Value 0.2 mm	
PRB COT Middle Cup Height Resist = 3.1 mm Resist = 2.6 ~ 3.6	isoi
PRB COT Knife Edge Height Resist = -1.5 mm Resist = -1.0 ~ -2.0 -1.6 +/-0.5 uses PV Cup [Torque 75c The setting is reference on the setting is	
PRB BCT BARC Knife Edge Height -2.5 mm -2.3 to -2.7 -2.5+/-0.5 BCT Spinner for BARC to cup. [Torque 75cn*m] Check of Measured from the botton Applies to the 3 adjustment of the superior of	s with digital cup height jigCOT Spinner *m] Check current Torque Doc ly, cup is set up by Middle Cup height.
PRB COT/BCT Cup Height Range Value 0.2 mm Applies to the 6 measuren	ols uses TCT Cup withsmooth upper
	ents pts.on the base cup.
PRB COT/BCT ARRC Nozzle X Centering Value 0.0 mm -0.08 to 0.08 0+/-0.08 ARRC ONLY	
	a Cup 1 to Cup 4 use 0 +/-0.05
	er surface on chuci
PRB COT/BCT Distance from Resist Nozzle to RRC -9 mm -9 PRB COT/BCT EBR Height Positior 1 mm 0.8 ~ 1.2 1+/-0.2 Set by using PRO-V set u	tool
PRB COT/BCT Resist Nozzle Height Home Positior 6.5 mm $6.0 \sim 7.0$ $4.5 \pm 1.0 \times 10^{-3}$ Set by using PRC-5 set up to the property of the prop	1001
PRB	
	wafer 80 mm from center of the
PRB COT/BCT Shutter OPEN 0.9 sec 0.8 ~1.0 0.9 Set by Sub-Op display	, ,
PRB COT/BCT COT E.B.R. MODULE-Arm UP 0.9 sec 0.8~1.0 0.9 Set by Sub-Op display	
PRB COT/BCT Auto Damper OPEN 0.4 sec 0.3 - 0.5 0.4 Set by Sub- Op display	
PRB COT/BCT Additional Auto Damper OPEN 0.4 sec 0.3 - 0.5 0.4 Set by Sub-Op display	
PRB COT/BCT Cup Change UP 3.0 sec 2.0 ~ 4.0 3.0+/-0.2 Set by Stop Watch	
PRB COT/BCT Resist Center Position Center = mm Center +/0.2 Center = Set by wafer flow dispens	
PRB COT/BCT RRC Center Position Center = mm Center +/-0.3 Center =	check
PRB COT/BCT EBR Cut Width Cut Value mm Cut Value +/-0.1 Cut Value +/-0.1	check
PRB COT/BCT EBR Nozzle Angle 30 degree 30 Set by HW (NO ADJ)	check

5. COT / BCT 29 / 147

5. COT / BCT

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Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	COT TBL/TNF/TNG/	Cup Exhaust Open	20	Pa	15~ 25	30	Checked in idle state when the Add. Auto damper is "OPEN" and each cup damper is set to "MODULE"
FKB	TBM	Cup Exhaust Closed	95	Pa	90 ~ 100	95	Check by setting Add. Auto damper to "CLOSED" and auto dampe for each module to "CUP"
	COT	Cup EXH U/L Setting (Nagano Keiki)	140	Pa		140	
PRB	TBL/TNE/TNG/ TBM	Cup EXH L/L Setting (Nagano Keiki)	13	Pa		23	
PRB	COT/BCT	Cup Exhaust Open	40	Pa	35~ 45	30	Checked in idle state when the Add. Auto damper is "OPEN" and each cup damper is set to "MODULE"
FKB	СОТ/ВСТ	Cup Exhaust Closed	95	Pa	90 ~ 100	95	Check by setting Add. Auto damper to "CLOSED" and auto dampe for each module to "CUP"
PRB	COT/BCT	Cup EXH U/L Setting (Nagano Keiki)	140	Pa		140	
		Cup EXH L/L Setting (Nagano Keiki	33	Pa		23	
PRB	COT/BCT	PSB- Process Suckback Position	2	mm	2 ~ 3	2~3	
PRB	COT/BCT	DDS Amplifier Reading Value	800		600 to 1000		Value is taken with a "CLEAN BARE" wafer on the chuck and the laser ON.
PRB	COT/BCT	DDS Light Intensity	30	%	30		Dip Switch setting done on the DDS IF BRD Black squares are the active Dip Switch position 4 3 2 1 ON DSW1
PRB	COT/BCT	DDS Alarm Threshold	40	%	40		Dip Switch setting done on the DDS IF BRD Black squares are the active Dip Switch position 4 3 2 1 OFF ON DSW2
PRB	COT/BCT	Changing DDS Alarms from STOP to WARNING					See 1.07 BKM for jumper WRN/ALM options Section 2.4

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6. PIR** / SRS**

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Block	Module		Tool Setting	Unit	Tolerance	TEL Std.	Remarks
							Static Setting - Keep 71kPa or higher after 1 minute, with the
IPRB	PIR/SRS	Chuck Vac	-75	kPa	-71.0 ~ -79.0	-75.0 +/-0.4	original pressure set at 75kPa. Fluctuation at Wafer spin start should be within 0.4kPa
IPRB	PIR/SRS	Chuck Vac U/L (Sunx-DP-100) Chuck Vac L/L (Sunx-DP-100)	-45.0 -99.9	kPa		-45.0 -99.9	
IPRB	PIR/SRS	3-PIN Level	0	degree	0.10 ~ -0.10	0.10 ~ -0.10	Use digital Level
IPRB	PIR/SRS	Chuck Level	0	degree	0.10 ~ -0.10	0.10 ~ -0.10	Use digital Level
IPRB	PIR/SRS	3-Pin Height - Up	45	mm		45	From the chuck to the top surface of the 3-Pin
IPRB	PIR/SRS	3-Pin Height - Down	-10	mm		-10	From the chuck to the top surface of the 3-Pin
PRB	PIR/SRS	3-PIN Up	N/A*	sec		1.5	*Controlled by motor. Nominal timing is 1.5s
PRB	PIR/SRS	3-PIN Down	N/A*	sec		1.5	*Controlled by motor. Nominal timing is 1.5s
IPRB	PIR/SRS	Knife Edge Height	-2.5	mm	-2.3 ~ -2.7	-2.5 +/-0.5	Use Digital cup height JIG Measured @ 3 points Set by using PRO-V tool [Torque 75cn*m] Check current Torque Doc Measured from the bottom of the wafer to the top of the INNER cup
IPRB	PIR/SRS	Cup Height Range Value	0.2	mm		-	Applies to the 3 adjustments pts. on the base cup.
IPRB	PIR/SRS	Cup Height Range Value	0.5	mm		-	Applies to the 6 measurements pts.on the base cup.
IPRB	PIR/SRS	IDR Nozzle Height	4	mm	3.5 ~ 4.5	4	
IPRB	PIR/SRS	MODULE-Arm UP	0.9	sec	0.8 ~ 1.0	0.9	Set by Sup-Op display
II KD	11103103	MODULE-Arm DOWN	0.9	SCC	0.0 1.0	0.9	ber of bup-op display
IPRB	PIR/SRS	IDR Center Position	Center = Dispense at Chuck Center	mm		Center = Dispense at Chuck Center	Dispense on glass wafer and check if liquid covers center of wafer
IPRB	PIR/SRS	Back Rinse Position	80	mm	78 to 82	φ160+/-5	Dispense stream hits glass wafer 80 mm from center of the chuck.
IPRB	cnc	Cup EXH U/L Setting (Nagano Keiki)	35	Pa		30	(E14) = SRS
IPRB	SRS	Cup EXH L/L Setting (Nagano Keiki)	12	Pa		7	(E14) = SRS
IPRB	SRS	Cup Exhaust	20	Pa	15 to 25	15	(E14) = SRS
IDDD	DVD	Cup EXH U/L Setting (Nagano Keiki)	30	Pa		30	(E13) = PIR
IPRB	PIR	Cup EXH L/L Setting (Nagano Keiki)	7	Pa		7	(E13) = PIR
IPRB	PIR	Cup Exhaust	15	Pa	10 to 20	15	(E13) = PIR
IPRB	SRS	IE Nozzle Dispense Position	4.5	mm		4.5	From edge of wafer

^{**=} for Immersion tool ONLY

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CPHP/CPRP/CGCH/CHCH

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	CPHP/CPRP/CGCH	Module Exhaust Setting (E12)	300	Pa	285 to 315	300+/-5	
	CPHP/CPRP/CGCH	Module EXH U/L Setting (Nagano Keiki) (E12)	330	Pa		330	SET BY PRESSURE
PRB	CPHP/CPRP/CGCH	Module EXH L/L Setting (Nagano Keiki) (E12)	270	Pa		270	
PRB	CPHP/CPRP	Chamber L Exhaust Setting (E10)	190	Pa	180 to 205		
		Chamber L EXH U/L Setting (Nagano Keiki) (E10)	210	Pa			
PRB	CPHP/CPRP	Chamber L EXH L/L Setting (Nagano Keiki) (E10)	170	Pa			
PRB	CPHP/CPRP	Chamber R Exhaust Setting (E17)	90	Pa	80 to 100		
110	erm/erm	Chamber R EXH U/L Setting (Nagano Keiki) (E17)	105	Pa			
PRB	CPHP/CPRP			 			
		Chamber R EXH L/L Setting (Nagano Keiki) (E17)	75	Pa			
PRB	CGCH/CHCH	Module Exhaust Setting (E9)	550	Pa	520 - 580	265+/- 10	Set by pressure and setting for Individual Chamber
DDD	CCCHCHOH	Module EXH U/L Setting (Nagano Keiki) (E9)	610	Pa		305	exhausts. DO NOT EXCEED TARGET CHAMBER EXH
PRB	CGCH/CHCH	Module EXH L/L Setting (Nagano Keiki) (E9)	490	Pa		225	SETTING
PRB	CGCH/CHCH	Module Exhaust Setting (E16)	500	Pa	470 - 530	210 +/-2	Set by pressure and setting for Individual Chamber
		Module EXH U/L Setting (Nagano Keiki) (E16)	550	Pa		250	exhausts.
PRB	CGCH/CHCH			1			DO NOT EXCEED TARGET CHAMBER EXH
		Module EXH L/L Setting (Nagano Keiki) (E16)	450	Pa		170	SETTING
PRB	CPHP/CPRP	Individual Chamber Exhaust Setting	9.4	Pa	7.4 - 11.3	4.0L/min +/-0.5	Target Value is with in Upper and Lower settings
PRB	erin/eria	Individual Chamber Exhaust U/L Setting	11.3	Pa		11.3	DO NOT EXCEED TARGET CHAMBER EXH
PRB	CPHP/CPRP	Individual Chamber Exhaust L/L Setting	7.4	Pa		7.4	SETTING
PRB	CGCH/CHCH	Individual Chamber Exhaust Setting	19.0	Pa	16.0 - 22.0	4.0L/min +/-0.5	T (771 : 21: 11 11 12
PRB	CGCH/CHCH	Individual Chamber Exhaust U/L Setting	22.0	Pa			Target Value is with in Upper and Lower settings DO NOT EXCEED TARGET CHAMBER EXH
PRB	CGCH/CHCH	Individual Chamber Exhaust L/L Setting		Pa			SETTING
		5	16.0		15 . 25	20.7.2	CET L., CEM
PRB	CPHP/CPRP	ODOR Exhaust Setting (E21/E22)	20	Pa	15 to 25	20+/-2	SET by CFM
PRB PRB	CPHP/CPRP CPHP/CPRP	ODOR Exhaust U/L Setting (Nagano Keiki) (E21/E22) ODOR Exhaust L/L Setting (Nagano Keiki) (E21/E22)	30 10	Pa Pa		30 10	For TAQ/TNQ/HVM TNE [E22 Only] For TNE/TNG/TBM/TBL[E21/E22]
PRB	CPHP/CPRP	ODOR Exhaust L/L Setting (Nagano Keiki) (E21/E22) ODOR Exhaust Setting (E21/E22 - Layer 3)	20	Pa	15 to 25	20+/-2	FOR TINE/TING/TBIVI/TBL[E21/E22]
PRB	CPHP/CPRP	ODOR Exhaust Setting (E21/E22 - Layer 3) ODOR Exhaust U/L Setting (Nagano Keiki) (E21/E22)	30	Pa	13 to 23	30	
PRB	CPHP/CPRP	ODOR Exhaust L/L Setting (Nagano Keiki) (E21/E22)	10	Pa		10	SET by CFM
PRB	CPHP/CPRP	ODOR Exhaust Setting (E21/E22 - Layer5,6)	40	Pa	35 to 45	40 +/- 2	[E21/E22]
PRB	CPHP/CPRP	ODOR Exhaust U/L Setting (Nagano Keiki) (E21/E22)	50	Pa		50	For 6x6 Tools
PRB	CPHP/CPRP	ODOR Exhaust L/L Setting (Nagano Keiki) (E21/E22)	30	Pa		30	
PRB	CPHP/CPRP/CGCH	HP Level	0	degree	-0.1 ~ 0.1	0+/-0.1	
PRB	CPHP/CPRP/CGCH	3-Pin Level	0	degree	-0.2 ~ 0.2	0+/-0.2	Against HP Level
PRB	CPHP/CPRP/CGCH	Cool Arm in Position	3	mm	3 ~ 4.5	3+1.5/-0	Height of Cool Arm to HP wafer guides
PRB	CPHP/CPRP/CGCH	3-Pin Up Height [Above the HP]	15	mm	15 ~ 16	15 +1/-0	
PRB	CPHP/CPRP/CGCH	3-Pin Down Height [below the HP]	1	mm	1 ~ 0.5	0.5 =</td <td>3-Pin does not protrude above the HP</td>	3-Pin does not protrude above the HP
PRB	CPHP/CPRP/CGCH	Cool Arm to 3-Pin Up Height [Above the Cool Arm]	>1.5	mm	$1.5\sim4.0$	>1.5	Measure from the cool arm Guide pin to the top of the 3 pin
PRB	CPHP/CPRP	Cool Arm Upper Surface to Base Height	78	mm	78.2 ~ 77.6	78+.2 /-0.4	
PRB	CGCH	Cool Arm Upper Surface to Base Height	77.4	mm	77.04 to 77.76	77.4+/-0.36	
PRB	CPHP/CPRP	Chamber Up Support Ring Height	15	mm	15 ~ 13.5	15+0/-1.5	
PRB	CPHP/CPRP	Chamber Down Support Ring Height	0.5	mm	0.3 ~ 0.7	0.5+/-0.2	
PRB	CGCH	HP PLATE Surface to CHAMBER Top plate Under surface	21.0	mm	20 to 22	21 +/-1	
PRB	CPHP/CGCH	HP Gap Pin	0.1	mm	$0.092 \sim 0.108$	0.1+/-0.008	
PRB	CPRP	HP Gap Pin - Outer Circle	0.103	mm	0.100 ~ 0.106	0.1+/-0.008	Onsite adjustment target
PRB	CPRP	HP Gap Pin - Middle Circle	0.100	mm	0.097 ~ 0.103	0.1+/-0.008	Onsite adjustment target
PRB	CPRP	HP Gap Pin - Inner Circle	0.097	mm	0.094 ~ 0.100		Onsite adjustment target
PRB PRB	CPHP/CPRP CGCH	Cool Arm Gap Pin Cool Arm Gap Pin	0.19	mm	$0.205 \sim 0.175$ $0.335 \sim 0.365$	+/-0.015 +/-0.015	
PRB	CGCH CPHP/CPRP	Cool Arm Gap Pin Chamber (L/R) Purge flowrate	0.35 4	mm L/min	0.335 ~ 0.365 3.8 ~ 4.2	+/-0.015 4.0+/-0.2	
		Chamber (L/R) Purge flowrate Chamber (L/R) Purge flowrate U/L Setting	4.5			4.0+/-0.2	For Air and N2
PRB	CPHP/CPRP	Chamber (L/R) Purge flowrate L/L Setting	3.5	L/min		3.5	N2 = TBL D4 CPRP
PRB	CPHP/CPRP	Chamber-R/L OPEN / CLOSED	0.7	sec	0.6 ~ 0.8	0.7	L/R must match
PRB	CPRP	Cool Arm IN/OUT	1.8	sec		0.7	Set by SW
PRB	CPHP/CPRP/CGCH	3-Pin UP / DOWN	0.7	sec	$0.6 \sim 0.8$	0.7	Set by Sup-Op display
PRB	CGCH	RING SHUTTER(L/R) UP/DOWN	0.7	sec	$0.6 \sim 0.8$	0.7	Set by Sup-Op display

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CADH

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	CADH	Chamber Open L/R	0.7	sec	0.6 ~ 0.8	0.7	L/R must match
		Chamber Closed L/R	0.7	300	0.6 ~ 0.8	0.7	
PRB	CADH	3-Pin Up / Down	0.7	sec	0.6 ~ 0.8	0.7	Set by Sub-Op display
PRB	CADH	HMDS Vapor Flow Rate	2500	ml/min	2300 ~ 2700	2500	Dynamic Setting ['Chamber Down]
PRB	CADH	N2 Purge Flow Rate	5000	ml/min	4800 ~ 5200	5000	Dynamic Setting ['Chamber Down]
PRB	CADH	HP Level	0	degree	-0.1 ~ 0.1	0+/-0.1	
PRB	CADH	3-Pin Level	0	degree	-0.2 ~ 0.2	0+/-0.2	Against HP Level
PRB	CADH	Cool Arm in Position	3	mm	3 ~ 4.5	3+1.5/-0	Height of Cool Arm to wafer guides
PRB	CADH	3-Pin Up Height	15	mm	15 ~ 16	15 +1/-0	
PRB	CADH	3-Pin Down Height [below the HP]	1	mm	1 ~ 0.5	0.5 =</td <td>3-Pin does not protrude above the HP</td>	3-Pin does not protrude above the HP
PRB	CADH	Cool Arm to 3-Pin Up Height	>1.5	mm	1.5 ~ 4.0	>1.5	Measure from the cool arm Guide pin to the top of the 3 pin
PRB	CADH	Cool Arm Upper Surface to Base Height	78	mm	78.2 ~ 77.6	78+.2 /-0.4	
PRB	CADH	Chamber Up Support Ring Height	15	mm	15 ~ 13.5	15+0/-1.5	
PRB	CADH	Chamber Down Support Ring Height	0.5	mm	0.3 ~ 0.7	0.5+/-0.2	
PRB	CADH	HP Gap Pin	0.1	mm	$0.075 \sim 0.105$	0.1+0.005/ -0.025	
PRB	CADH	Cool Arm Gap Pin	0.19	mm	$0.175 \sim 0.205$	0.19+/-0.015	
PRB	CADH	Local Exhaust (E11)	300	Pa	290 to 310	300+/-10	
PRB	CADH	EXH Upper Limit (E11)	330	Pa		330	When E11 = 4 or Less CADH units
FKB	CADII	EXH Lower Limit (E11)	270	Pa		270	
PRB	CADH	Local Exhaust (E11)	370	Pa	360 to 380	370+/-10	
PRB	CADH	EXH Upper Limit (E11)	410	Pa		390	When $E11 = 5$ or 6 CADH units
rkb	CADH	EXH Lower Limit (E11)	330	Pa		350	
PRB	CADH	Local Exhaust (E11)	450	Pa	430 to 470	450+/-50	
PRB	CADH	EXH Upper Limit (E11)	500	Pa		500	When E11 = 7 CADH units
PKB	CADH	EXH Lower Limit (E11)	400	Pa		400	
PRB	CADH	Local Exhaust (E11)	0.500	kPa	0.480 to 0.520	0.500+/-0.050	
PRB	CADH	EXH Upper Limit (E11)	0.550	kPa		0.550	When E11 = 9 CADH units
rkB	CADH	EXH Lower Limit (E11)	0.450	kPa		0.450	1
PRB	CADH	Local Exhaust (E23)	250	Pa	240 to 260	250+/-10	When E23 = 4 or Less CADH units
PRB	CADH	EXH Upper Limit (E23)	270	Pa		270	when E23 = 4 or Less CADH units
TKD	CADII	EXH Lower Limit (E23)	230	Pa		230	

CPL

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
MPB/IPB		CPL 3-Pin Up CPL 3-Pin Down	0.9 0.9	sec	0.8 ~ 1.0	0.9 0.9	Set by Sub-Op display
MPB/IPB	CPL	3-Pin Height	21	mm	20.5 ~ 21.5	21+/-0.5	Top of 3-Pin to Plate surface
MPB/IPB	CPL	Plate Level	0	Degree	0.1 ~ -0.1	0+/-0.1	
MPB/IPB	CPL	3-Pin Level	0	Degree	0.1 ~ -0.1	0+/-0.1	

SCPL

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	SCPL	VAC setting	1	kPa	0.95 ~ 1.05	1	Setting is positive Value represents differential pressure on the plate. Set by using 3 touch wafers at the same time.
PRB		VAC setting U/L VAC setting L/L	1.8 0.3	kPa	1.8 0.3		Place a wafer on all 3 grouped SCPL's then set the VAC setting
PRB	SCPL	Plate Level	0	degree	0.1 ~ -0.1	0+/-0.1	

ISHU

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	ICHII	CPL 3-Pin Up CPL 3-Pin Down	0.9 0.9	sec	0.8 ~ 1.0	0.9 0.9	Set by Sub-Op display
PRB	ISHU	ISHU 3-Pin Height	28.5	mm	28 ~ 29	28.5+/-0.5	
PRB	ISHU	3-Pin Level	0	degree	$0.1 \sim 0.1$	0+/-0.1	

TRS/SBU/RSM

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
MPB/STB/ IPRB	TRS [RSM]	3-Pin Level	0	degree	0.1 ~ -0.1	0+/-0.1	
MPB/STB/ IPRB	TRS[RSM]	3-Pin Height	18	mm	17.8 ~ 18.2	18+/-0.2	
MPB/STB	TRS/SBU	Gap Pin Level	0	degree	0.3 ~ -0.3	0+/-0.3	

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CRA

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
CSB	CRA	Z-Height - ISHU	4	mm		4	
CSB	CRA	Z-Height - TRS	4	mm		4	
CSB	CRA	Z-Height - CPL	4	mm		4	
CSB	CRA	Z-Height - Foup [TAQ/TNQ]	2	mm	1	2.0	Standard Forks uses these front guides
CSB	CRA	Z-Height - Foup [All Others]	2.5	mm		2.5	High Speed Forks uses these front guides 5010-525176-12
CSB	CRA	Fork Diameter	300.4	mm		300.4	

MPRA

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
MPB	MPRA	Fork Diameter - 2-0	300.4	mm		300.4	when checking fork for tightness, use the 300.3mm disc.
MPB	MPRA	Z-Height CPL/RCPL	5.5	mm		5.5	
MPB	MPRA	Z-Height SCPL	6	mm		6	
MPB	MPRA	Z-HeightSBU	5.5	mm		5.5	
MPB	MPRA	Z-Height SBU 10 stage	5.5	mm		5.5	
MPB	MPRA	Z-Height TRS	5.5	mm		5.5	
MPB	MPRA	Z-Height - ISHU	5.5	mm		5.5	
MPB	MPRA	Fork Diameter - 7-0	300.4	mm		300.4	when checking fork for tightness, use the 300.3mm disc.
MPB	MPRA	Z-Height TRS	5.5	mm		5.5	
MPB	MPRA	Z-Height SCPL	6	mm		6	

PRA

1 11/1							
Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	PRA	Fork Diameter (3-0, 4-0,5-0,6-0) Fork 1	300.4	mm	+/- 0.020	300.4	Tolerance updated when using micrometer when checking fork for tightness, use the 300.3mm disc.
PRB	PRA	Fork Diameter (3-0, 4-0,5-0,6-0) Fork 2	300.4	mm	+/- 0.020	300.4	Tolerance updated when using micrometer when checking fork for tightness, use the 300.3mm disc.
PRB	PRA	Z-Height - BCT	5.5	mm		5.5	
PRB	PRA	Z-Height - COT	5.5	mm		5.5	
PRB	PRA	Z-Height - DEV	5.5	mm		5.5	
PRB	PRA	Z-Height - OVEN	7	mm		7	
PRB	PRA	Z-Height - SCPL	6	mm		6	
PRB	PRA	Z-Height - SBU	5.5	mm		5.5	
PRB	PRA	Z-Height - TRS	5.5	mm		5.5	
PRB	PRA	Z-Height - Cup Wash	5.5	mm		5.5	Check height of 5.5mm at center of Cup Wash module

PRAI *

1 11/11							
Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
IPRB	PRAI	Fork Diameter 8-0-Fork 1-Wet	300.4	mm		300.4	when checking fork for tightness, use the 300.3mm disc.
IPRB	PRAI	Fork Diameter 8-0-Fork 2-Dry	300.4	mm		300.4	when checking fork for tightness, use the 300.3mm disc.
IPRB	PRAI	Z-Height - CPL/SCPL	5.5	mm		5.5	
IPRB	PRAI	Z-Height - ISHU	5.5	mm		5.5	
IPRB	PRAI	Z-Height - TRS	5.5	mm		5.5	
IPRB	PRAI	Z-Height - RSM	5.5	mm		5.5	

IRAI

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
IFBI	IRAI	Z-Height - TRS	4	mm		4	
IFBI	IRAI	Z-Height - RSM	4	mm		4	
IFBI	IRAI	Z-Height - CPL	4	mm		4	
IFBI	IRAI	Fork Diameter 9-0-Fork 1-Wet	300.4	mm		300.4	
IFBI	IRAI	Fork Diameter 9-0-Fork 2-Dry	300.4	mm		300.4	

ISHU

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	ISHU	Diameter	300.4	mm		300.4	

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9. Sensor Setting

DP100 Sensor

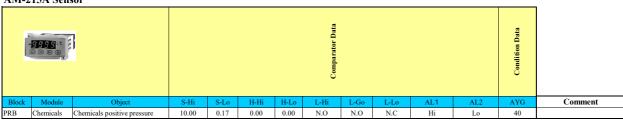
D1 10	o Sensor												
	-935 - 935 - 935 - 935					Menu Setting Mode					M WIN	Note that	
Block	Module	Object	Out1	Out2	I/O	N.oN.c	SPED	CLOR	Unit	Zero Adj.	Lo-1	Hi-1	Key Lock
PRB	SYSTEM	Module Drive (Source)	W.CMP	OFF	A.out	N.o	2.5	R-ON	MPa	Required	LL	UL	Required
CSB**	SYSTEM	Stage Vac	W.CMP	OFF	-	N.o	2.5	R-ON	kPa	Required	LL	UL	Required
PRB	COT	COT Chuck VAC	W.CMP	OFF	A.out	N.o	2.5	R-ON	kPa	Required	LL	UL	Required
PRB	BCT	BCT Chuck VAC	W.CMP	OFF	A.out	N.o	2.5	R-ON	kPa	Required	LL	UL	Required
IPRB	SRS	SRS Chuck VAC	W.CMP	OFF	A.out	N.o	2.5	R-ON	kPa	Required	LL	UL	Required
IPRB	PIR	PIR Chuck VAC	W.CMP	OFF	A.out	N.o	2.5	R-ON	kPa	Required	LL	UL	Required
IPRB	BST	BST Chuck VAC	W.CMP	OFF	A.out	N.o	2.5	R-ON	kPa	Required	LL	UL	Required
PRB	DEV	DEV Chuck VAC	W.CMP	OFF	A.out	N.o	2.5	R-ON	kPa	Required	LL	UL	Required
PRB	CRD	RESIST Pump Purge	W.CMP	OFF	A.out	N.o	5000	R-ON	kPa	Required	LL	UL	Required
PRB	DEV	SPIN N2	W.CMP	OFF	A.out	N.o	2.5	R-ON	kPa	Required	LL	UL	Required
PRB	CRD	AMC N2 Purge	W.CMP	OFF	A.out	N.o	5000	R-ON	kPa	Required	LL	UL	Required
PRB	DEV	ADR N2 REG	W.CMP	OFF	A.out	N.o	5	R-ON	kPa	Required	LL	UL	Required
IPRB	PIR	PDR N2 REG	W.CMP	OFF	A.out	N.o	2.5	R-ON	kPa	Required	LL	UL	Required
IPRB	SRS	PDR N2 REG	W.CMP	OFF	A.out	N.o	2.5	R-ON	kPa	Required	LL	UL	Required
External	CAB	PCS Pump VAC	W.CMP	OFF	A.out	N.o	2.5	R-ON	kPa	Required	LL	UL	Required
IPRB	BST+*	BST Back Side Air Nozzle	W.CMP	OFF	A.out	N.o	50	R-ON	MPa	Required	LL	UL	Required
IPRB	BST+*	BST Wafer Edge Air Nozzle	W.CMP	OFF	A.out	N.o	50	R-ON	kPa	Required	LL	UL	Required

^{**=} ProZ style loadports

DP4 Sensor

DIT	- V SCHSOI										_
			Zero Adj.	Default		Sunnlemental	•		Pressure	etting	
Block	Module	Object	Display		U-1	U-2	U-3	U-4	P-1	P-2	Comment
CSB	SYSTEM	Stage Vac	Required	PCd	no	256	512	-	UL	LL	

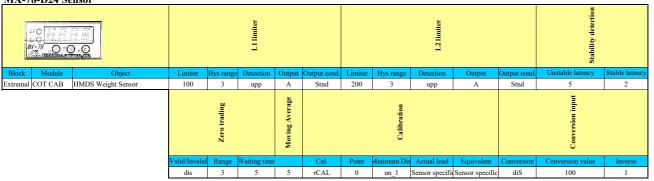
AM-215A Sensor



FS-V31 Sensor

rs-v.	or sensor										
				RUN Mode			Std Setting		Display Setting Mode		
Block	Module	Object		Pwr Adj	Key Lock	Pwr Set	SEt	Adj	rEu	CuSt	Comment
PRB	SYSTEM	RESIST LE SENSOR	D-ON	Required	Required	SuPr	SEtP	SCAL	oFF	no	

MX-78-D24 Sensor





9. Sensor Setting

E3X-MD36T-T Sensor

Block	Module	Object	Power tune	Key Lock	tEch	0-oP	1-Fn	2-tF	3-ot	4-md	PL	5-dP	6-ru
PRB	СОТ/ВСТ	RSV Tank(L,LL)	Required	Required	-	D-ON	Stnd	on-d	2out	PrUn	2000	Income Light Amount/Thre shold Value=1600	Unspecifie d
PRB	СОТ/ВСТ	RSV Tank(H)	Required	Required	-	L-ON	Stnd	oFFd	2out	PrUn	2000	Income Light Amount/Thre shold Value=1700	Unspecifie d

GC30	Sensor																
	- TOYOU																
Block	Module	Object	Zero Adj.	CnP	Uni	FiL	A-L	A-H	A-1	b-1	on1	off1	A-2	b-2	on2	off2	LoP
PRB	SYSTEM	SPIN CUP Source Exh (DEV)	Required	Hys	Pa	F-2	0	100	UL	-1	0	0	LL	0	0	0	*
PRB	SYSTEM	SPIN CUP Source Exh (COT)	Required	Hys	Pa	F-2	0	100	UL	-1	0	0	LL	0	0	0	*
PRB	SYSTEM	SPIN CUP Source Exh (BCT)	Required	Hys	Pa	F-2	0	100	UL	-1	0	0	LL	0	0	0	*
IPRB	SYSTEM	SPIN CUP Source Exh (PIR)	Required	Hys	Pa	F-3	0	100	UL	-1	0	0	LL	0	0	0	*
IPRB	SYSTEM	SPIN CUP Source Exh (SRS)	Required	Hys	Pa	F-3	0	100	UL	-1	0	0	LL	0	0	0	*
PRB	SYSTEM	CHEMICAL Source Exh (L)	Required	Hys	Pa	F-3	0	100	LL	0	0	0	0	0	0	0	*
PRB	SYSTEM	CHEMICAL Source Exh (R)	Required	Hys	Pa	F-3	0	100	LL	0	0	0	0	0	0	0	*
PRB	OVEN	Individual Chamber Exh.	Required	Win	Pa	F-5	0	100	LL	UL	0	0	0	0	0	0	*
PRB	SYSTEM	CADH CHEM Source Exh	Required	Hys	Pa	F-3	0	100	LL	0	0	0	0	0	0	0	*
PRB	SYSTEM	CADH Local Exh (Source)	Required	Win	Pa	F-3	0	100	LL	UL	0	0	0	0	0	0	*
PRB	SYSTEM	Chamber Source Exh	Required	Win	Pa	F-3	0	100	LL	UL	0	0	0	0	0	0	*
PRB	SYSTEM	Odor Mod Exhaust	Required	Win	Pa	F-3	0	100	LL	UL	0	0	0	0	0	0	*
PRB	SYSTEM	OVEN Module Source Exh	Required	Win	Pa	F-3	0	100	LL	UL	0	0	0	0	0	0	*
External	COT CAB	Exh (Supply Cabinet)	Required	Hys	Pa	F-3	0	100	LL	UL	0	0	0	0	0	0	*
External	DEV CAB	Exh (Supply Cabinet)	Required	Hys	Pa	F-3	0	100	LL	UL	0	0	0	0	0	0	*
PRB	CPL	SCPL Module	Required	Win	kPa	F-2	0	100	LL	UL	0	0	0	0	0	0	*
PRB	SYSTEM	CADH (Chamber Exh)	Required	Win	Pa	F-3	0	100	LL	UL	0	0	0	0	0	0	*
PRB	CPL	RCPL Module	Required	Win	kPa	F-2	0	100	LL	UL	0	0	0	0	0	0	*

* Tool specific

FSM2	2-NVF100	0-L063N (CKD)															
								Unloc	k by pressin	g and holding	down all 3 butt	ons					
									(H1	CH2	9,	ပ	b	ing	_	etting
Category	Utility	Block	Module	Object	Flow display	Key lock	CEI	CH2	High	Low	High - Low	Auto-Referenc	Response time setting	Display Spee Setting	Sub-Screen Setting	Display Color Setting	Hysteresis Setti
OVEN		PRB	OVEN	CHAM PURGE	L/min	on			4.5	3.5	-	out	SP-4	250	FLO	g rEn	I
OVEN		PRB	OVEN	HMDS VAPOR	L/min	on	74		4.0	4.0	-	out	SP-4	250	FLO	g rEn	Ι
OVEN		PRB	OVEN	HMDS PURGE	L/min	on	-		i	-	-	out	SP-4	250	FLO	g rEn	Ι

STHC TCW FLOW RATE SENSOR SETTINGS

STHE TEW TEOW RATE SENSOR SETTINGS										
Sensor with a internal sensor indicator										
	STO	OP ALM (CH1)	WARNING ALM (CH2)							
MODE	on:	off:	MODE	on:	off:					
_ = _	X -0.9	X-1.0	_ = _	X -0.4	X-0.5					
	,	V 4 4	1	, .	V					



Sensor with an external flow sensor indicator										
S	TOP ALM (OUT1	WARNING ALM (OUT2)								
Р	L	Н	P	L	Н	h				
0000	X -0.8	999.9	0000	X -0.3	999.9	0.2				



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					Tole	rance		
Location	Module	Description of Setting	F32	Unit	F	32 - MAX	TEL Std.	Remarks
PRB	CPHP/CPRP/CGCH	Module Exhaust Setting (E12)	290	Pa	275	305	300+/-5	
PRB	CPHP/CPRP/CGCH	Module EXH U/L Setting (Nagano Keiki) (E12)	319	Pa			330	SET BY PRESSURE
		Module EXH L/L Setting (Nagano Keiki) (E12)	261	Pa			270	
PRB	CPHP/CPRP	Chamber L Exhaust Setting (E10)	184	Pa	174	194		
PRB	CPHP/CPRP	Chamber L EXH U/L Setting (Nagano Keiki) (E10)	203	Pa				
PRB	CPHP/CPRP	Chamber L EXH L/L Setting (Nagano Keiki) (E10) Chamber R Exhaust Setting (E17)	164 87	Pa Pa	77	97		
		Chamber R EXH U/L Setting (Nagano Keiki) (E17)	101	Pa				
PRB	CPHP/CPRP	Chamber R EXH L/L Setting (Nagano Keiki) (E17)	72	Pa				
PRB	CGCH/CHCH	Module Exhaust Setting (E9)	531	Pa	501	561	265+/- 10	Set by pressure and setting for Individual
PRB	CGCH/CHCH	Module EXH U/L Setting (Nagano Keiki) (E9)	589	Pa			305	Chamber exhausts.
PRB		Module EXH L/L Setting (Nagano Keiki) (E9)	473	Pa			225	DO NOT EXCEED TARGET CHAMBER
PRB	CGCH/CHCH	Module Exhaust Setting (E16)	483	Pa	453	513	210 +/-2	Set by pressure and setting for Individual
PRB PRB	CGCH/CHCH	Module EXH U/L Setting (Nagano Keiki) (E16) Module EXH L/L Setting (Nagano Keiki) (E16)	531 435	Pa Pa			250 170	Chamber exhausts. DO NOT EXCEED TARGET CHAMBER
PRB	CPHP/CPRP	Individual Chamber Exhaust Setting	9.0	Pa	7.0		4.0L/min +/-0.5	Target Value is with in Upper and Lower settings
PRB		Individual Chamber Exhaust U/L Setting	10.9	Pa			11.3	DO NOT EXCEED TARGET CHAMBER
PRB	CPHP/CPRP	Individual Chamber Exhaust L/L Setting	7.1	Pa			7.4	EXH SETTING
PRB	CGCH/CHCH	Individual Chamber Exhaust Setting	18	Pa	15		4.0L/min +/-0.5	
PRB	CGCH/CHCH	Individual Chamber Exhaust U/L Setting	21	Pa				settings
PRB PRB	CGCH/CHCH CPHP/CPRP	Individual Chamber Exhaust L/L Setting ODOR Exhaust Setting (E21/E22)	15 19	Pa Pa	14	24	20+/-2	DO NOT EXCEED TARGET CHAMBER
PRB	CPHP/CPRP	ODOR Exhaust U/L Setting (Nagano Keiki) (E21/E22)	29	Pa			30	SET by CFM For TAQ/TNQ/HVM TNE [E22 Only]
PRB	CPHP/CPRP	ODOR Exhaust L/L Setting (Nagano Keiki) (E21/E22)	10	Pa			10	For TNE/TNG [E21/E22]
PRB	CPHP/CPRP	ODOR Exhaust Setting (E21/E22 - Layer 3)	19	Pa	14	24	20+/-2	
PRB	CPHP/CPRP	ODOR Exhaust U/L Setting (Nagano Keiki) (E21/E22)	29	Pa			30	SET by CFM
PRB PRB	CPHP/CPRP CPHP/CPRP	ODOR Exhaust L/L Setting (Nagano Keiki) (E21/E22) ODOR Exhaust Setting (E21/E22 - Layer5,6)	10 39	Pa Pa	34	44	10 40 +/- 2	[E21/E22]
PRB	CPHP/CPRP	ODOR Exhaust U/L Setting (Nagano Keiki) (E21/E22)	48	Pa			50	For 6x6 Tools
PRB	CPHP/CPRP	ODOR Exhaust C/L Setting (Nagano Keiki) (E21/E22) ODOR Exhaust L/L Setting (Nagano Keiki) (E21/E22)	29	Pa			30	
PRB	CADH	Local Exhaust (E11)	290	Pa	280	300	300+/-10	
PRB	CADH	EXH Upper Limit (E11)	319	Pa			330	When $E11 = 4$ or Less CADH units
PRB		EXH Lower Limit (E11)	261	Pa			270	
PRB PRB	CADH	Local Exhaust (E11) EXH Upper Limit (E11)	357 396	Pa Pa	347	367	370+/-10 390	When E11 = 5 or 6 CADH units
PRB	CADH	EXH Lower Limit (E11)	319	Pa Pa			350	when ETT – 3 of 6 CADH units
PRB	CADH	Local Exhaust (E11)	435	Pa	385	475	450+/-50	
PRB		EXH Upper Limit (E11)	483	Pa			500	When $E11 = 7$ CADH units
PRB	CADH	EXH Lower Limit (E11)	386	Pa			400	
PRB	CADH	Local Exhaust (E11)	0.483	kPa	0.433	0.533	0.500+/-0.050	
PRB	CADH	EXH Upper Limit (E11)	0.531	kPa			0.550	When E11 = 9 CADH units
		EXH Lower Limit (E11)	0.435	kPa			0.450	
PRB	CADH	Local Exhaust (E23) EXH Upper Limit (E23)	241 261	Pa Pa	231	251	250+/-10 270	When E23 = 4 or Less CADH units
PRB	CADH	EXH Lower Limit (E23)	222	Pa			230	When E23 – 4 or Less CADIT units
CSB	SYSTEM	CSB Wind Velocity	0.29	m/sec	0.29	0.39	0.3 (+0.1/-0)	Measure 100mm below punching plate
PRB	COT/BCT/DEV/NT D	Wind Velocity	0.19	m/sec	0.13	0.25		Measurement is taken above each cup and avg. is input to the Setting Value. Measure at 40mm above each cup
PRB	System	THC SPINNER(L) wind pressure	Tool Specific	kPa	See Pressure Data Sheet±0.005			See Wind Pressure Sheet when setting Values
PRB	System	THC SPINNER(R) wind pressure	Tool Specific	kPa		Sheet	ssure Data t±0.005	See Wind Pressure Sheet when setting Values
PRB	System	THC PRA(L) wind pressure	Tool Specific	kPa	See Pressure Data Sheett±0.005			See Wind Pressure Sheet when setting Values
PRB	System	THC PRA(R) wind pressure	Tool Specific	kPa	See Pressure Data Sheet±0.005			See Wind Pressure Sheet when setting Values
PRB	System	THC MP Tower wind pressure	Tool Specific	kPa	See Pressure Data Sheet±5		Data Sheet±5	See Wind Pressure Sheet when setting Values
PRB	System	THC SideTower wind pressure	Tool Specific	kPa	See Pressure Data Sheet±5			See Wind Pressure Sheet when setting Values
iPRB	System	THC PRAi wind pressure	Tool Specific	kPa	See l	Pressure	Data Sheet±5	See Wind Pressure Sheet when setting Values
iPRB	System	THC iPRB SPINNER(PIR/SRS) wind pressure	Tool Specific	kPa	See l	Pressure	Data Sheet±1	See Wind Pressure Sheet when setting Values

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Location	Module	Description of Setting	F32	Unit	Tolerance F32 MIN ~ MAX	TEL Std.	Remarks	
CSB	CSB	Positive Pressure	Tool Specific	Pa	Tool Specific		PRB≧CSB	
PRB	COT	Positive Pressure	Tool Specific	Pa	Tool	Specific	PRB SPIN≧PRA	
PRB	DEV	Positive Pressure	Tool Specific	Pa	Tool	Specific	PRB SPIN≧PRA	
PRB	PRA	Positive Pressure	Tool Specific	Pa	Tool	Specific	PRA≦PRB SPIN	
iPRB	PRAi	Positive Pressure	Tool Specific	Pa	Tool	Specific	PIR/SRS≦PRAi	
iPRB	PIR	Positive Pressure	Tool Specific	Pa	Tool	Specific	PRAI≧PIR	
iPRB	SRS	Positive Pressure	Tool Specific	Pa	Tool	Specific	PRAI≧SRS	
IFB	IFB	Positive Pressure	Tool Specific	Pa		Specific	Exposure machine ≧IFB≦iPRB	
MPB	SYSTEM	Chemical Exhaust - L (E6)	97	Pa	22 297	100	Set by 42.4 cfm	
MPB	SYSTEM	Chemical Exhaust - L (U/L Setting) (E6)	0	Pa		0		
		Chemical Exhaust - L (L/L Setting) (E6)	10	Pa		10		
STB	SYSTEM	Chemical Exhaust - R (E7)	145	Pa	70 245	100	Set by 35.3 cfm	
STB	SYSTEM	Chemical Exhaust - R (U/L Setting) (E7)	10	Pa		0 10		
PRB	CADH	Chemical Exhaust - R (L/L Setting) (E7)		Pa	125 165		Set by CFM	
		Chemical Area Exhaust (E8) Chemical Area Exhaust U/L Setting (E8)	145 0	Pa Pa	123 103	>100	15.9 +/- 10%	
PRB	CADH	Chemical Area Exhaust U/L Setting (E8) Chemical Area Exhaust L/L Setting (E8)	68	Pa Pa		20		
PRB	CADH	Chemical Area Exhaust L/L Setting (E8) Chemical Area Exhaust (E24)	174	Pa	99 204	100	Applies to all track configurations	
PRB		Chemical Area Exhaust (E24) Chemical Area Exhaust U/L Setting (E24)	0	Pa	99 204	0	Target is min of 100Pa	
PRB	CADH	Chemical Area Exhaust U/L Setting (E24) Chemical Area Exhaust L/L Setting (E24)	97	Pa		20	12 CADH System Tool Spec	
FKD	COT Cabinet	Exhaust Solvent (EA1)	97	Pa	12 322	100		
	COT Cabinet	Exhaust Solvent (EA1) U/L Setting (EA1)	338	Pa	12 322	0	TARGET CFM	
	COT Cabinet	Exhaust Solvent (EA1) L/L Setting (EA1)	10	Pa		70	70.6	
	COT Cabinet	Exhaust Solvent (EA2)	97	Pa	12 322	100		
	COT Cabinet	Exhaust Solvent (EA2) U/L Setting (EA2)	338	Pa		0	TARGET CFM	
	COT Cabinet	Exhaust Solvent (EA2) L/L Setting (EA2)	10	Pa		70	70.6	
	COT Cabinet	Exhaust HMDS (EA5)	193	Pa	8 318	200		
TAQ/TNQ	COT Cabinet	Exhaust HMDS U/L Setting (EA5)	338	Pa		0	TARGET CFM	
` `	COT Cabinet	Exhaust HMDS L/L Setting (EA5)	10	Pa		50	14.1	
•	DEV Cabinet	DEV CAB Exhaust (EC1)	24	Pa	14 324	30	TARGET OFM	
•	DEV.C.1.	DEV CAB Exhaust U/L Setting (EC1)	338	Pa		0	TARGET CFM	
	DEV Cabinet	DEV CAB Exhaust L/L Setting (EC1)	10	Pa		5	35.3	
	DEV Cabinet	DEV CAB Exhaust (EC2)	24	Pa	14 324	30	TARGET CFM	
	DEV Cabinet	DEV CAB Exhaust U/L Setting (EC2)	338	Pa		0	17.7	
	DE V Cabillet	DEV CAB Exhaust L/L Setting (EC2)	10	Pa		5	17.7	
	COT Cabinet	Exhaust Solvent (EA1)	121	Pa	11 321	100	TARGET CFM	
•	COT Cabinet	Exhaust Solvent (EA1) U/L Setting (EA1)	338	Pa		0	70.6	
TNE	COT Cabinet	Exhaust Solvent (EA1) L/L Setting (EA1)	10	Pa		70	70.0	
[NON-CE]	COT Cabinet	Exhaust HMDS (EA5)	145	Pa	10 320	200	TARGET CFM	
[1.OIT-CE]	COT Cabinet	Exhaust HMDS U/L Setting (EA5)	338	Pa		0	14.1	
TNE [CE]	COT Cabinet	Exhaust HMDS L/L Setting (EA5)	10	Pa		50	14.1	
THE [CE]	DEV Cabinet	DEV CAB Exhaust (EC1)	24	Pa	14 324	30	TARGET CFM	
TNE	DEV Cabinet	DEV CAB Exhaust U/L Setting (EC1)	338	Pa		0	35.3	
[HVM]		DEV CAB Exhaust L/L Setting (EC1)	10	Pa		5	33.3	
[11 4 [61]	DEV Cabinet	DEV CAB Exhaust (EC2)	19	Pa	14 324	30	TARGET CFM	
	DEV Cabinet	DEV CAB Exhaust U/L Setting (EC2)	338	Pa		0	17.7	
	DE v Caumet	DEV CAB Exhaust L/L Setting (EC2)	10	Pa		5	1/./	

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Location	Module	Description of Setting	F32	Unit	F MIN	erance 732 ~ MAX	TEL Std.	Remarks
	COT Cabinet	Exhaust Solvent (EA1)	48	Pa	13	323	100	TARGET CFM
	COT Cabinet	Exhaust Solvent (EA1) U/L Setting (EA1)	338	Pa			0	14.1
	COT Cabinet	Exhaust Solvent (EA1) L/L Setting (EA1)	10	Pa			70	
TNG /	COT Cabinet	Exhaust HMDS (EA5)	14	Pa	4	99	200	<u>_</u>
TBL /	COT Cabinet	Exhaust HMDS U/L Setting (EA5)	97	Pa			0	TARGET CFM 14.1
TBM	COT Cabinet	Exhaust HMDS L/L Setting (EA5)	5	Pa			50	
	DEV Cabinet	DEV CAB Exhaust (EC1)	48	Pa	13	323	30	
	DEV Cabinet	DEV CAB Exhaust U/L Setting (EC1)	338	Pa			0	TARGET CFM 17.7
		DEV CAB Exhaust L/L Setting (EC1)	10	Pa			5	
	COT Cabinet	Exhaust Solvent (EA1)	48	Pa	13	323	100	
	COT Cabinet	Exhaust Solvent (EA1) U/L Setting (EA1)	338	Pa			0	TARGET CFM 21.2
	COT Cabinet	Exhaust Solvent (EA1) L/L Setting (EA1)	10	Pa			70	
TAS/TAU/	COT Cabinet	Exhaust HMDS (EA5)	14	Pa	4	99	200	
TNU/	COT Cabinet	Exhaust HMDS U/L Setting (EA5)	97	Pa	-		0	TARGET CFM 14.1
TNK	COT Cabinet	Exhaust HMDS L/L Setting (EA5)	5	Pa	-		50	
	DEV Cabinet	DEV CAB Exhaust (EC1)	48	Pa	13	323	30	
	DEM C 1	DEV CAB Exhaust U/L Setting (EC1)	338	Pa	-		0	TARGET CFM 21.2
	DEV Cabinet	DEV CAB Exhaust L/L Setting (EC1)	10	Pa	-		5	
	COT Cabinet	Exhaust Solvent (EA1)	97	Pa	12	322	100	
	COT Cabinet	Exhaust Solvent (EA1) U/L Setting (EA1)	338	Pa	_		0	TARGET CFM35.3
	COT Cabinet	Exhaust Solvent (EA1) L/L Setting (EA1)	10	Pa	_		70	
TBC	COT Cabinet	Exhaust HMDS (EA5)	145	Pa	10	320	200	
	COT Cabinet	Exhaust HMDS U/L Setting (EA5)	338	Pa			0	TARGET CFM14.1
	COT Cabinet	Exhaust HMDS L/L Setting (EA5)	10	Pa			50	MRGET CIMIT-1
	COT Cabinet	Exhaust Solvent (EA1)	14	Pa	4	99	100	
	COT Cabinet	Exhaust Solvent (EA1) Exhaust Solvent (EA1) U/L Setting (EA1)	97	Pa	_		0	TARGET CFM14.1
	COT Cabinet	Exhaust Solvent (EA1) U/L Setting (EA1) Exhaust Solvent (EA1) L/L Setting (EA1)	5	Pa			70	TARGET CENTIAL
TBE			14	Pa	4	99	200	
	COT Cabinet	Exhaust HMDS (EA5)	97	Pa Pa				TARGET CFM14.1
	COT Cabinet	Exhaust HMDS U/L Setting (EA5)					50	IARGET CFM14.1
PRB	COT Cabinet COT	Exhaust HMDS L/L Setting (EA5) Supply Exhaust COT (E3,E4,E5)	5 406	Pa Pa	386	426	340	EPC damper must be held Open and use EXH BKMTarget CFM 320
PRB	COT	Low Setting EXH COT (E3,E4,E5)	19	Pa			20	Sensor located in above 4-0 Layer
PRB	COT TNU ONLY	Supply Exhaust COT (E4,E5)	589	Pa	569	609	610+/-20	Use with Facilities setting [Facilities will pre open to set position]and Blower Fan Dampers.[will be used to achieve the final setting]
PRB	COT TNU ONLY	Supply Exhaust COT (E34,E35)	589	Pa	569	609	610+/-20	Use with Facilities setting [Facilities will pre open to set position]and Blower Fan Dampers.[will be used to achieve the final setting]
PRB	COT TBL/TNE/TNG/TB	Cup Exhaust Open	19	Pa	14	24	30	Checked in idle state when the Add. Auto damper is "OPEN" and each cup damper is set to "MODULE"
TKD	M	Cup Exhaust Closed	92	Pa	87	97	95	Check by setting Add. Auto damper to "CLOSED" and auto damper for each module to "CUP".
PRB	COT	Cup EXH U/L Setting (Nagano Keiki)	135	Pa	-		140	
LVD	TBL/TNE/TNG/	Cup EXH L/L Setting (Nagano Keiki)	13	Pa			23	
PRB	COT/BCT	Cup Exhaust Open	39	Pa	34	44	30	Checked in idle state when the Add. Auto damper is "OPEN" and each cup damper is set to "MODULE"
		Cup Exhaust Closed	92	Pa	87	97	95	Check by setting Add. Auto damper to "CLOSED" and auto damper for each module to "CUP".
PRB	COT/BCT	Cup EXH U/L Setting (Nagano Keiki)	135	Pa	-		140	
PKB	COI/BCI	Cup EXH L/L Setting (Nagano Keiki)	32	Pa	_		23	

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Location	Module	Description of Setting	F32	Unit	Tolerance F32 MIN ~ MAX				TEL Std.	Remarks				
PRB	DEV	Supply Exhaust DEV (E1,E2) (8x0 Config)	309	Pa	289	329	320 ~ 400	Value is checked with outer cup up and following the EXH BKM.						
PRB	DEV	Supply Exhaust DEV (E1) (4x4 Config)	309	Pa	289	329	320 ~ 400	Value is checked with outer cup up and following the EXH BKM.						
PRB	NTD	Supply Exhaust NTD (E2) (4x4 Config)	386	Pa	236	536		Following the EXH BKM.						
PRB	DEV/NTD	Supply Exhaust NTD (E1,E2) (6x6 Config)	386	Pa	286	586	400 to 500	Following the EXH BKM.						
PRB	DEV/NTD	Supply Exhaust NTD (E23) (6x6 Config)	483	Pa	383	583	400 to 500	Following the EXH BKM.						
PRB	DEV/NTD	Cup Exhaust Open	8	Pa	7	9	8 (+/-1)	Layer is checked with all modules Cup up and then execute auto damper						
		Cup Exhaust Closed	43	Pa	38	48	45 (+/-5)							
PRB	DEV/NTD	Cup EXH U/L Setting (Nagano Keiki)	82	Pa									85	
FKB	DEV/NID	Cup EXH L/L Setting (Nagano Keiki)	1	Pa					1					
IPRB	PIR	Exhaust Source Setting (E13)	N/A	Pa	35	45	40	SET BY PRESSURE (Use Start-up BKM] [Manual Damper should be fully CLOSED in Blank/RSV modules]						
IPRB	SRS	Exhaust Source Setting (E14)	N/A	Pa	55	65	60	SET BY PRESSURE (Use Start-up BKM] [Manual Damper should be fully CLOSED in Blank/RSV modules]						
IPRB	SRS	Cup EXH U/L Setting (Nagano Keiki)	34	Pa	-		30	(E14) = SRS						
		Cup EXH L/L Setting (Nagano Keiki)	12	Pa	-		7	(E14) = SRS						
IPRB	SRS	Cup Exhaust	19	Pa	14	24	15	(E14) = SRS						
IPRB	PIR	Cup EXH U/L Setting (Nagano Keiki)	29	Pa	-		30	(E13) = PIR						
		Cup EXH L/L Setting (Nagano Keiki)	7	Pa	-		7	(E13) = PIR						
IPRB	PIR	Cup Exhaust	14	Pa	9	19	15	(E13) = PIR						

LITHIUS ProV Software Fingerprint

1. Overview

Parameter Layout

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Notes:

^{1.} System Configuration Parameter contains Dispense Parameter, Monitoring Parameter, Transfer Arm Parameter and Spinner Parameter.

^{2.} To avoid going over same parameter multiple times, only System configuration parameter is documented in this fingerprint.

^{3.} In this Fingerprint, System configuration parameter is divided into Arm, Spinner, and Oven.

^{4.} To audit values in Parameter Editor, log into User Service level with username CTADMIN4. User/level display in Parameter Editor will show: CTADMIN (Service).

^{5.} To audit values in the EC, use the "Temporary User Registration" function to log with username CTADMIN. User/level display in EC will show: CTADMIN with red background.

CIM Control Number: 09TEA-CT-00192-1.00

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2. Start Up Setting

Default Language Setting	English
HOST Computer Interface	Valid
LINKED LITHO Interface	Valid*

^{*=} Not present on BARC

System

Monitoring Parameter

Barometric Pressure

Valid, Invalid	Valid
Measured Data ID	Barometric Pressure
Recipe Setting Method	Local
Temperature Control Method	Tmp ctl ON
Recipe Verification Range Lower Limit	0.00
Recipe Verification Range Upper Limit	0.00

Controller Analogue Sensor

Controller ID	Analogue sensor
Set Value	FAB Specific*
Warning Range Lower Limit	100.00
Warning Range Upper Limit	100.00
Stop Range Lower Limit	100.00
Stop Range Upper Limit	100.00
Offset	Tool Specific
Calibration	0.00
Setting Band	100.00
Setting Determination Time	60.0
Setting Time-out Time	600.0

* Portland / Ireland : 1010.00hPa

* Phoenix: 970.00hPa * Albuquerque: 840.00hPa * Israel: 1000.00hPa

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Block 1 CS Block

1-0 CSB Arm

Reserved Flag	Invalid
Fork Simultaneous Swapping Level	Invalid
Wafer Store Count	1
Start Slot	0

Position Data

1 USITION Data		
Item	Set Value	Unit
X1-axis Access Reference Point	-75	pulse
X1-axis Wafer Check Position	-75	pulse
Y-axis Maintenance Position	0	pulse
Z-axis Maintenance Position	50000	pulse
Theta-axis Maintenance Position	0	pulse
X1-axis Pulse Rate	0.007325	mm/pulse
Y-axis Pulse Rate	0.004883	mm/pulse
Z-axis Pulse Rate	0.005771	mm/pulse
Theta-axis Pulse Rate	0.00165	deg/pulse

Transfer Arm Control Parameter

Transfer Arm Control rarameter							
Item / Axis	X1	Y	Z	Theta			
Movement between Modules Speed	100	100	100	100			
Wafer OUT Speed	100	100	N/A	100			
Wafer IN Speed	100	100	N/A	100			
Maintenance Speed	50	50	50	50			
Inching Speed	50	50	50	50			
Multiple Axes Synchronous Control of Movement between modules	Invalid	Valid	Valid	Valid			
IP Zone at Wafer OUT	N/A	N/A	0	N/A			
IP Zone at Wafer IN	N/A	N/A	0	N/A			

Fork1

TOTAL		
Item	FOUP	All Others
Z-axis Receive Stroke	1160	1600
Z-axis Receive Stroke Movement Speed	100%	100%
X-axis Receive Stroke Movement Speed	100%	100%
Z-axis Send Stroke	1160	1600
Z-axis Send Stroke Movement Speed	100%	100%
X-axis Send Stroke Movement Speed	100%	100%

X axis Position & Offset

Arm	Module	X Send Position	X Receive Position	Offset (X Receive - X Send)
1-0 CRA	FOUP	CCD Center - 205 pulse	CCD Center + 478 pulse	683 pulse
1-0 CKA	All Others	CCD Center - 27 pulse	CCD Center + 341 pulse	368 pulse

Y. Z and Theta axis Offset

1, Z and	1, Z and Theta axis Offset					
Arm	Module	Offset (Y Receive - Y Send)	Offset (Z Send - Z Receive)	Offset (Th Receive - Th Send)		
1-0 CRA	FOUP	0 pulse	1160 pulse	0 pulse		
	All Others	0 pulse	1600 pulse	0 pulse		

1-X FOUP UST

Reserved Flag	Invalid
Fork Simultaneous Swapping Level	Invalid
Wafer Store Count	25
Start Slot	1

Wafer Information

Water Information		
Wafer Thickness	800 um	
Thickness (+) Range	60%	
Thickness (-) Range	50%	

Mapping Data

Pitch between Slots	480
Mapping Type	Carrier
Mapping Start Position	-100
Mapping End Position	12100
Slot Recognition Position	Tool Specific
Standby Position	15400

CIM Control Number: 09TEA-CT-00192-1.00

4. System Configuration Parameter, Arm

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Block 2, 7 MP Block

2-0 / 7-0 MRB Arm

Reserved Flag	Invalid
Fork Simultaneous Swapping Level	Invalid
Wafer Store Count	1
Start Slot	0

Module Type

Immersion/DRY Value	VMPRA	
6x6 Value for 2-0	VMPRA (Z Long)	

Position Data

Item	Set Value	Unit
X1-axis Access Reference Point	1	pulse
X1-axis Wafer Check Position	Tool Specific (<1700)	pulse
Z-axis Maintenance Position	0	pulse
X1-axis Pulse Rate	0.007325	mm/pulse
Z-axis Pulse Rate	0.009766	mm/pulse

Transfer Arm Control Parameter

Transfer 71 in Control 1 arameter		
Item / Axis	X1	Z
Movement between Modules Speed	100	100
Wafer OUT Speed	100	N/A
Wafer IN Speed	100	N/A
Maintenance Speed	45	50
Inching Speed	50	40
Multiple Axes Synchronous Control of Movement between modules	Invalid	Valid
IP Zone at Wafer OUT	N/A	100
IP Zone at Wafer IN	N/A	100

Fork1

Item	SCPL	All Others
Z-axis Receive Stroke	2410	1840
Z-axis Receive Stroke Movement Speed	50%	50%
X-axis Receive Stroke Movement Speed	100%	100%
Z-axis Send Stroke	2410	1840
Z-axis Send Stroke Movement Speed	80%	80%
X-axis Send Stroke Movement Speed	100%	100%

X and Z axis Position & Offset

Arm	Module	X Send Position	X Receive Position	Offset (X Receive - X Send)	Offset (Z Send - Z Receive)
2-0 / 7-0	All Others	CCD Center - 27 pulse	CCD Center	37	1840 pulse
MRA	SCPL	CCD Center - 27 pulse	CCD Center	27 pulse	2410 pulse

^{*} In non existing or reserved modules, values are allowed to be 0.

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4. System Configuration Parameter, Arm

Block 3, 4, 5, 6 PR Block

3-0 / 4-0 / 5-0 / 6-0 PRB Arm

Reserved Flag	Invalid
Fork Simultaneous Swapping Level	1-2
Wafer Store Count	2
Start Slot	0

Module Type

V	alue	VPRA

Position Data

Item	Set Value	Unit
X1-axis Access Reference Point	1	pulse
X1-axis Wafer Check Position	Tool Specific (<1700)	pulse
X2-axis Access Reference Point	1	pulse
X2-axis Wafer Check Position	Tool Specific (<1700)	pulse
Y-axis Maintenance Position	213000	pulse
Z-axis Maintenance Position	2900	pulse
Theta-axis Maintenance Position	0	pulse
X1-axis Pulse Rate	0.007325	mm/pulse
X2-axis Pulse Rate	0.007325	mm/pulse
Y-axis Pulse Rate	0.007812	mm/pulse
Z-axis Pulse Rate	0.007053	mm/pulse
Theta-axis Pulse Rate	0.001663	deg/pulse

Transfer Arm Control Parameter

Transfer from Control Larameter					
Item / Axis	X1	X2	Y	Theta	Z
Movement between Modules Speed	100%	100%	100%	100%	100%
Wafer OUT Speed	80%	80%	100%	100%	N/A
Wafer IN Speed	80%	80%	100%	100%	N/A
Maintenance Speed	50%	50%	50%	50%	50%
Auto Temperature Adjustment Speed	50%	50%	70%	80%	50%
Inching Speed	50%	50%	50%	50%	50%
Multiple Axes Synchronous Control of Movement	Invalid	Invalid	Invalid	Valid	Valid
IP Zone at Wafer OUT	N/A	N/A	N/A	N/A	100
IP Zone at Wafer IN	N/A	N/A	N/A	N/A	100

Fork1 and 2

Item	CPL / TRS	DEV/COT/BCT/NTD	CPHP / CADH /CPRP / CGCH	SCPL	SBU	CWH
Z-axis Receive Stroke	2550	2550	3330	3330	2550	2550
Z-axis Receive Stroke Movement Speed	100%	100%	80%	40%	100%	100%
X-axis Receive Stroke Movement Speed	100%	100%	100%	100%	100%	100%
Z-axis Send Stroke	2550	2550	3330	3330	2550	2550
Z-axis Send Stroke Movement Speed	80%	80%	100%	100%	80%	80%
X-axis Send Stroke Movement Speed	100%	100%	100%	100%	100%	100%

Z-axis Multistep Movement

Item	CPL / TRS	DEV/COT/BCT/NTD	CPHP / CADH /CPRP / CGCH	SCPL	SBU	CWH
Valid, Invalid	Valid	Valid	Valid	Valid	Valid	Invalid
Slow Speed Start Position Offset	820	820	820	820	820	820
Slow Speed End Position Offset	960	960	960	960	960	960
Slow Speed	50%	50%	50%	50%	50%	50%
High Speed	80%	80%	80%	80%	80%	50%

Z-axis Multistep Movement (Receive) - Softlanding function installed tool only

	CPL / TRS	DEV/COT/BCT/NTD	CPHP / CADH /CPRP / CGCH	SCPL	SBU	CWH
Valid, Invalid	Valid	Valid	Valid	Valid	Valid	Invalid
Slow Speed Start Position Offset	1700	1700	2480	2130	1700	1700
Slow Speed End Position Offset	1840	1840	2620	2270	1840	1840
Slow Speed	50%	50%	50%	50%	50%	50%
High Speed	80%	80%	80%	80%	80%	50%

Z-axis Multistep Movement (Send) - Softlanding function installed tool only

	CPL / TRS	DEV/COT/BCT/NTD	CPHP / CADH /CPRP / CGCH	SCPL	SBU	CWH
Valid, Invalid	Valid	Valid	Valid	Valid	Valid	Invalid
Slow Speed Start Position Offset	820	820	820	820	820	820
Slow Speed End Position Offset	960	960	960	960	960	960
Slow Speed	50%	50%	50%	50%	50%	50%
High Speed	80%	80%	80%	80%	80%	50%

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Block 3, 4, 5, 6 PR Block

3-0 / 4-0 / 5-0 / 6-0 PRB Arm

X axis Position & Offset

Arm	Module	X Send Position	X Receive Position	Offset (X Receive - X Send)
3,4,5,6-0 PRA	All Modules	CCD Center - 27 pulse	CCD Center	27 pulse

^{*} In non existing or reserved modules, values are allowed to be 0.

Y, Z and Theta axis Offset

Arm	Module	Offset (Y Receive - Y Send)	Offset (Z Send - Z Receive)	Offset (Th Receive - Th Send)
	DEV / COT	0 pulse	2550 pulse	0 pulse
3,4,5,6-0	CPL / TRS / SBU / CWH	o puise	2550 paise	o puise
PRA	CGCH / CPRP / CPHP	0 pulse	3330 pulse	0 pulse
	CADH / SCPL	v puisc	5550 puise	v puisc

^{*} In non existing or reserved modules, values are allowed to be 0.

Block 8 IPB-Immersion Configuration ONLY

8-0 IPB Arn

0-U IFB AFM					
Reserved Flag	Invalid				
Fork Simultaneous Swapping Level	1-2				
Wafer Store Count	2				
Start Slot	0				

Module Type

module Type	
Value	VPRAI

Position Data

1 USILIUII Data		
Item	Set Value	Unit
X1-axis Access Reference Point	1	pulse
X1-axis Wafer Check Position	Tool Specific (<1700)	pulse
X2-axis Access Reference Point	1	pulse
X2-axis Wafer Check Position	Tool Specific (<1700)	pulse
Z-axis Maintenance Position	220000	pulse
Theta-axis Maintenance Position	0	pulse
X1-axis Pulse Rate	0.007325	mm/pulse
X2-axis Pulse Rate	0.007325	mm/pulse
Z-axis Pulse Rate	0.007053	mm/pulse
Theta-axis Pulse Rate	0.001663	deg/pulse

^{*} PRB ARM 5-0 is for TD Config. ONLY

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Block 8 IPB-Immersion Configuration ONLY

Transici Arin Control rarameter						
X1	X2	Theta	Z			
100	100	100	100			
80	80	100	N/A			
80	80	100	N/A			
50	50	50	50			
50	50	80	50			
50	50	50	50			
Invalid	Invalid	Valid	Valid			
N/A	N/A	N/A	100			
N/A	N/A	N/A	100			
	100 80 80 50 50 50 Invalid N/A	100 100 80 80 80 80 50 50 50 50 50 1nvalid Invalid N/A N/A	100 100 100 80 80 100 80 80 100 50 50 50 50 50 80 50 50 50 Invalid Invalid Valid N/A N/A N/A			

Fork1 and 2

Item	PIR	SRS	TRS	ISHU	CPL
Z-axis Receive Stroke	2550	2550	2550	2550	2550
Z-axis Receive Stroke Movement Speed	100%	100%	100%	100%	100%
X-axis Receive Stroke Movement Speed	100%	100%	100%	100%	100%
Z-axis Send Stroke	2550	2550	2550	2550	2550
Z-axis Send Stroke Movement Speed	80%	80%	80%	80%	80%
X-axis Send Stroke Movement Speed	100%	100%	100%	100%	100%

Z-axis Multistep Movement

E and many to rement						
Item	PIR	SRS	TRS	ISHU	CPL	
Valid, Invalid	Valid	Valid	Valid	Valid	Valid	
Slow Speed Start Position Offset	820	820	820	820	820	
Slow Speed End Position Offset	960	960	960	960	960	
Slow Speed	50%	50%	50%	50%	50%	
High Speed	80%	80%	80%	80%	80%	

Z-axis Multistep Movement (Receive) - Softlanding function installed tool only

	PIR	SRS	TRS	ISHU	CPL
Valid, Invalid	Valid	Valid	Valid	Valid	Valid
Slow Speed Start Position Offset	1700	1700	1700	1700	1700
Slow Speed End Position Offset	1840	1840	1840	1840	1840
Slow Speed	50%	50%	50%	50%	50%
High Speed	80%	80%	80%	80%	80%

Z-axis Multistep Movement (Send) - Softlanding function installed tool only

2 tais matistep movement (send) softanding function instance tool only						
	PIR	SRS	TRS	ISHU	CPL	
Valid, Invalid	Valid	Valid	Valid	Valid	Valid	
Slow Speed Start Position Offset	820	820	820	820	820	
Slow Speed End Position Offset	960	960	960	960	960	
Slow Speed	50%	50%	50%	50%	50%	
High Speed	80%	80%	80%	80%	80%	

X axis Position & Offset

Arm	Module	X Send Position	X Receive Position	Offset (X Receive - X Send)
8-0 PRAI	All Others	CCD Center - 27 pulse	CCD Center	27 pulse

^{*} In non existing or reserved modules, values are allowed to be 0.

Z and Theta axis Offset

Arm	Module	Offset (Z Send - Z Receive)	Offset (Th Receive - Th Send)
8-0 PRAI	All Module	2550 pulse	0 pulse

^{*} In non existing or reserved modules, values are allowed to be 0.

Block 9 IFB Sub (Immersion) and Block 8 IRA (DRY)

J-U II DSIAI III	
Reserved Flag	Invalid
Fork Simultaneous Swapping Level	Invalid
Wafer Store Count	*
Start Slot	0

* = 1 for Dry / 2 for Immersion Systems

Module Type

Value

* = VIRAi for Immersion / VIRAS for DRY

Position Data

Item	Set Value	Unit
X1-axis Access Reference Point	*	pulse
X1-axis Wafer Check Position	Tool Specific	pulse
X2-axis Access Reference PointImmersion	*	pulse
X2-axis Wafer Check PositionImmersion	Tool Specific	pulse
Y-axis Maintenance Position	0	pulse
Z-axis Maintenance Position	50000	pulse
Theta-axis Maintenance Position	0	pulse
X1-axis Pulse Rate	0.007325	mm/pulse
X2-axis Pulse Rate	0.007325	mm/pulse
Y-axis Pulse Rate	0.004883	mm/pulse
Z-axis Pulse Rate	0.005771	mm/pulse
Theta-axis Pulse Rate	0.001663	deg/pulse

^{*=} Dry tool IRA [-75] Wet tool IRAi [-340]

Transfer Arm Control Parameter

Item / Axis	X1	X2*	Y	Z	Theta
Movement between Modules Speed	100	100	100	100	100
Wafer OUT Speed	100	100	100	N/A	100
Wafer IN Speed	100	100	100	N/A	100
Maintenance Speed	50	50	50	50	50
Inching Speed	50	50	50	50	50
Multiple Axes Synchronous Control of Movement	Invalid	Invalid	Valid	Valid	Valid
IP Zone at Wafer OUT	N/A	N/A	N/A	0	N/A
IP Zone at Wafer IN	N/A	N/A	N/A	0	N/A

^{*=} Does not exist for DRY tools

Fork1 and 2*

TOTAL UNIO 2						
Item	CPL	TRS	RSM	EIF	ISHU	
Z-axis Receive Stroke	1600	1600	1600**	1250	1600	
Z-axis Receive Stroke Movement Speed	100%	100%	100%	100%	100%	
X-axis Receive Stroke Movement Speed	100%	100%	100%	100%	100%	
Z-axis Send Stroke	1600	1600	1600 **	1250	1600	
Z-axis Send Stroke Movement Speed	100%	100%	100%	100%	100%	
X-axis Send Stroke Movement Speed	100%	100%	100%	100%	100%	

^{*=}DRY Configuration IRA only has 1 Fork

X axis Position & Offset (Immersion)

Arm	Module	X Send Position	X Receive Position	Offset (X Receive - X Send)
0.0 ID 41	CPL / TRS / RSM	CCD Center - 27 pulse	CCD Center +341 pulse	368 pulse
9-0 IRAI	EIF	Stage Center (In Stage)	Stage Center (Out Stage)	Tool Specific

X axis Position & Offset (DRY)

Arm	Module	X Send Position	X Receive Position	Offset (X Receive - X Send)
8-0 IRAS	CPL / TRS / RSM / ISHU	CCD Center - 27 pulse	CCD Center + 341 pulse	368 pulse
8-0 IKAS	EIF	Stage Center (In Stage)	Stage Center (Out Stage)	Tool Specific

^{*} At the ASML's EIF, need to find out center position with their Re-alignment function at each pedestals (In & Out).

Y, Z and Theta axis Offset (Immersion)

1, Z anu	Theta axis Offset (Tilline	islon)		
Arm	Module	Offset (Y Receive - Y Send)	Offset (Z Send - Z Receive)	Offset (Th Receive - Th Send)
9-0 IRAI	CPL / TRS / RSM	0 pulse	1600 pulse	0 pulse
9-0 IKAI	EIF	Tool Specific	Tool Specific	Tool Specific

Y, Z and Theta axis Offset (DRY)

Arm	Module	Offset (Y Receive - Y Send)	Offset (Z Send - Z Receive)	Offset (Th Receive - Th Send)
	CPL / TRS / ISHU	0 pulse	1600 pulse	0 pulse
8-0 IRAS	RSM	0 pulse	1210 pulse	0 pulse
	EIF	Tool Specific	Tool Specific	Tool Specific

^{**= 1210} for DRY 1600 for Immersion

Then input offset value to out pedestal center position. $\ensuremath{^{**}}$ In non existing or reserved modules, values are allowed to be 0.

Block 3 PR Block, Developers [3-1] - [3-8] for 8x0 PTD Block 3 PR Block, Developers [3-1] - [3-4] for 4x4 PTD Block 3/5 PR Block, Developers [3-1/2/5/6 - 5-1/2] for 6x6 PTD

Reserved Flag	Invalid
Fork Simultaneous Swapping Level	1-2
Wafer Store Count	1
Start Slot	0

Dispense Parameter Shared Nozzle

DEV NOZZLE [1] = MGP Nozzle

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid
Nozzle Pattern No	Tool Specific

Dispense Mechanism Connection [1]

Valid, Invalid Valid

Dispense Monitoring Mechanism Connection

Valid, Invalid Valid

Fin flow type 1	Fin	flow	type	1
-----------------	-----	------	------	---

Dispense Monitoring Type Fin flow type 1

Supply System Valid, Invalid

Valid

DEV.SOLU.1 Supply System - [Tool Specific]

Refill Monitoring Time	180
Pre-Refill Decompress Time	20.0
Post-Refill Vent Time	1.0
Post-Refill Pressurize Time	15.0
Post-Refill Depressurize Time	60.0
Post-Refill Delay Time	1
N2 Dissolution Monitoring Time	0
Tank Switch during Dispensing	Valid

CSS Refill System

Valid, Invalid Valid

Failsafe Valve
Failsafe Valve Close Delay Time 0.0 sec

Dispense Monitoring Control Data Pulse Rate

Pulse Rate	0.05
Delay Time	0.6
Set Flow Rate	600
Flow Rate Sensor Check Timing	Dispense end
Calibration 1	1.00
Offset	0
Upper Limit Error Level	30.00%
Upper Limit Warning Level	20.00%
Lower Limit Error Level	30.00%
Lower Limit Warning Level	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0



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DEV NOZZLE 4

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid
Nozzle Pattern No	Tool Specific

Dispense Mechanism Connection [1]

Valid, Invalid Valid

Dispense Monitoring Mechanism Connection

Valid, Invalid Valid

Fin flow type 1
Dispense Monitoring Type Fin flow type 1

Supply System Valid, Invalid Valid

DEV.SOLU.1 Supply System

DEV.SOLU.I Supply System - [1001 Specif	iic
Refill Monitoring Time	180
Pre-Refill Decompress Time	20.0
Post-Refill Vent Time	1.0
Post-Refill Pressurize Time	15.0
Post-Refill Depressurize Time	60.0
Post-Refill Delay Time	1
N2 Dissolution Monitoring Time	0
Tank Switch during Dispensing	Valid

CSS Refill System

Valid, Invalid	Valid
----------------	-------

FailsafeValve
Failsafe Valve Close Delay Time 0.0 sec

Dispense Monitoring Control Data

Pulse Rate	0.05
Delay Time	0.60
Set Flow Rate	300
Flow Rate Sensor Check Timing	Dispense End
Calibration 1	1.00
Offset	0
Upper Limit Error Level	20.00%
Upper Limit Warning Level	15.00%
Lower Limit Error Level	20.00%
Lower Limit Warning Level	15.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0

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DEV NZL.4 Sub

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid
Nozzle Pattern No	Tool Specific

Dispense Mechanism Connection [1] Valid, Invalid Valid

Dispense Monitoring Mechanism Connection
| Valid, Invalid | Va Valid

Fin flow type 1

Dispense Monitoring Type Fin flow type 1

Supply System Valid, Invalid Valid

DEV.SOLU.1 Supply System - [Tool Specific]

DEV.SOLU.1 Supply System - [1001 Specific]	
Refill Monitoring Time	180
Pre-Refill Decompress Time	20.0
Post-Refill Vent Time	1.0
Post-Refill Pressurize Time	15.0
Post-Refill Depressurize Time	60.0
Post-Refill Delay Time	1
N2 Dissolution Monitoring Time	0
Tank Switch during Dispensing	Valid

CSS Refill System

Valid, Invalid Valid

FailsafeValve

Failsafe Valve Close Delay Time 0.0 sec

Dispense Monitoring Control Data

0.05
0.6
250
Dispense End
1.00
0
20.00%
15.00%
20.00%
15.00%
Valid
Execute
1.0



DEV NOZZLE2 \rightarrow Only present on TNE/TNG prior to HTP upgrade and TBL

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid
Nozzle Pattern No	Tool Specific

Dispense Mechanism Connection [1] Valid, Invalid

Dispense Monitoring Mechanism Connection
| Valid, Invalid Val Valid

Fin flow type 1
Dispense Monitoring Type Fin flow type 1 Supply System Valid, Invalid

DEV.SOLU.2 Supply System - [Tool Specific]

Refill Monitoring Time	180
Pre-Refill Decompress Time	20.0
Post-Refill Vent Time	1.0
Post-Refill Pressurize Time	15.0
Post-Refill Depressurize Time	60.0
Post-Refill Delay Time	1
N2 Dissolution Monitoring Time	0
Tank Switch during Dispensing	Valid

CSS Refill System

Valid, Invalid Valid

FailsafeValve
Failsafe Valve Close Delay Time 0.0 sec

Dispense Monitoring Control Data

Pulse Rate	0.05
Delay Time	0.60
Set Flow Rate	1800
Flow Rate Sensor Check Timing	Dispense end
Calibration 1	1.00
Offset	0
Upper Limit Error Level	30.00%
Upper Limit Warning Level	20.00%
Lower Limit Error Level	30.00%
Lower Limit Warning Level	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0

DEV NZL2(BYPASS) Only present on TNE/TNG prior to HTP upgrade and TBL

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid
Nozzle Pattern No	Tool Specific

Dispense Mechanism Connection [1] Valid, Invalid Valid

Dispense Monitoring Mechanism Connection

Valid, Invalid Valid

Fin flow type 1

Dispense Monitoring Type Fin flow type 1

Supply System Valid, Invalid Valid

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DEV.SOLU.2 Supply System - [Tool Specific]

Refill Monitoring Time	180
Pre-Refill Decompress Time	20.0
Post-Refill Vent Time	1.0
Post-Refill Pressurize Time	15.0
Post-Refill Depressurize Time	60.0
Post-Refill Delay Time	1
N2 Dissolution Monitoring Time	0
Tank Switch during Dispensing	Valid

CSS Refill System	
Valid, Invalid	Valid

Failsafe Valve Failsafe Valve Close Delay Time

Dispense Monitoring Control Data

Dispense Monitoring Control Data	
Pulse Rate	0.05
Delay Time	0.60
Set Flow Rate	250
Flow Rate Sensor Check Timing	Dispense end
Calibration 1	1.00
Offset	0
Upper Limit Error Level	30.00%
Upper Limit Warning Level	20.00%
Lower Limit Error Level	30.00%
Lower Limit Warning Level	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0

0.0 sec

DEV NZL2(AIRVNT) Only present on TNE/TNG prior to HTP upgrade and TBL

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid

Dispense Mechanism Connection [1]	
Valid, Invalid	Valid

DEV NZL2(RINSE) Only present on TNE/TNG prior to HTP upgrade and TBL

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid

Dispense Mechanism	Connection [1]	

Dispense Meenanism Connection [1]	
Valid, Invalid	Valid

Dispense Monitoring Mechanism Co.	nnection
Volid Involid	Valid

Fin flow type 1		

Dispense Monitoring Type **Dispense Monitoring Control Data**

Pulse Rate	0.05
Delay Time	0.60
Set Flow Rate	2500
Flow Rate Sensor Check Timing	Dispense end
Calibration 1	1.00
Offset	0
Upper Limit Error Level	30.00%
Upper Limit Warning Level	20.00%
Lower Limit Error Level	30.00%
Lower Limit Warning Level	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0

Fin flow type 1

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BATH EXH. CMN

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid

Dispense Mechanism Connection [1] Valid Valid, Invalid

BATH EXH. CMN2*

Divili Ezvii, Civii iz		
Process Recipe Attribute	Invalid	
Dummy Dispense Attribute	Valid	

*Only exist on 4×4 and 8×0 tracks

Dispense Mechanism Connection [1] Valid, Invalid Valid

DIW NZL.4 Sub

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid
Nozzle Pattern No	Tool Specific

Dispense Mechanism Connection [1] Valid, Invalid Valid

Dispense Monitoring Mechanism Connection

Valid, Invalid Valid

Fin flow type 1

Dispense Monitoring Type Fin flow type 1

Dispense Monitoring Control Data

Pulse Rate	0.05
Delay Time	0.6
Set Flow Rate	250
Flow Rate Sensor Check Timing	Dispense End
Calibration 1	1.00
Offset	0
Upper Limit Error Level	30.00%
Upper Limit Warning Level	20.00%
Lower Limit Error Level	30.00%
Lower Limit Warning Level	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0

EXH DRAIN PUMP

Process Recipe Attribute	Invalid
Dummy Dispense Attribute	Valid

Dispense Mechanism Connection [1]

Valid, Invalid Valid



Local Nozzle

ADR1 RINSE

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid
Nozzle Pattern No	Tool Specific

Dispense Mechanism Connection

Valid, Invalid	Valid

Dispense Monitoring Mechanism Connection
| Valid, Invalid | Va Valid

Fin flow type 1
Dispense Monitoring Type Fin flow type 1

Dispense Monitoring Control Data

Dispense Monitoring Control Data	
Pulse Rate	0.05
Delay time	0.60
Set Flow Rate 350	
Flow Rate Sensor Check Timing	Dispense end
Calibration 1	1.00
Offset	0
Upper Limit Error Level	30.00%
Upper Limit Warning Level	20.00%
Lower Limit Error Level	30.00%
Lower Limit Warning Level	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0

Flow Rate during Dispense Process*

Invalidated Flow Rate Monitoring Times during Dispense Process	2
Upper Limit Error Level for Flow Rate during Dispense Process	30.00%
Lower Limit Error Level for Flow Rate during Dispense Process	30.00%

^{*} Tools with XDR ONLY

ADR1 N2

Process	Recipe Attribute	Valid
Dummy	Dispense Attribute	Valid

Dispense Mechanism Connection [1]

Va	lid,	Inva	lid		Valid

Unexpected Pressure Watch

Unexpected Pressure Watch Valid	Valid
Delay Time Refore Unexpected Press Watch	3.0

CONFIDENTIAL INFORMATION

WATER SEAL

Process Recipe Attribute	Invalid
Dummy Dispense Attribute	Valid

Dispense Mechanism Connection [1] Valid, Invalid Valid

Valid

Fin flow type 1

Dispense Monitoring Type Fin flow type 1

Dispense Monitoring Control Data

Pulse Rate	0.005
Delay time	0.6
Set Flow Rate	100
Flow Rate Sensor Check Timing	Dispense end
Calibration 1	1.00
Offset	0
Upper Limit Error Level	0.00%
Upper Limit Warning Level	0.00%
Lower Limit Error Level	80.00%
Lower Limit Warning Level	40.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Not Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0

FIRM 1 - IF PRESENT

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid
Nozzle Pattern No	Tool Specific

Dispense Mechanism Connection [1]
Valid, Invalid Valid

Dispense Monitoring Mechanism Connection

Valid, Invalid Valid

Fin flow type 1

Dispense Monitoring Type Fin flow type 1

Supply System Valid, Invalid

FIRM 1 Supply System - [Tool Specific]

Refill Monitoring Time	180
Pre-Refill Decompress Time	20.0
Post-Refill Vent Time	1.0
Post-Refill Pressurize Time	15.0
Post-Refill Depressurize Time	30.0
Post-Refill Delay Time	1
N2 Dissolution Monitoring Time	33

CSS Refill System

Valid Valid, Invalid

FailsafeValve
Failsafe Valve Close Delay Time 0.0 sec

Container Refill System

Valid, Invalid Invalid

Automatic Air Vent

ratomatic ran vent	
Air Vent Monitoring Time	30 sec
Delay Time After LE Detection	3 sec
Prior Pressurization Time	5 sec

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Dispense Monitoring Control Data

0.05
0.6
240
Dispense End
1.00
0
30.00%
20.00%
30.00%
20.00%
Valid
Execute
1.0

RINSE 1

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid
Nozzle Pattern No	Tool Specific

Dispense Mechanism Connection [1]
Valid, Invalid Valid

Dispense Monitoring Mechanism Connection

Valid, Invalid	Valid
Fin flow type 1	.
Dispense Monitoring Type	Fin flow type 1

Dispense Monitoring Control Data

Dispense Monitoring Control Data	
Pulse Rate	0.05
Delay Time	0.6
Set Flow Rate	1000
Flow Rate Sensor Check Timing	Dispense end
Calibration 1	1.00
Offset	0
Upper Limit Error Level	30.00%
Upper Limit Warning Level	20.00%
Lower Limit Error Level	30.00%
Lower Limit Warning Level	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0

Flow Rate during Dispense Process*

1 10 W Rute during Dispense 1 rocess	
Invalidated Flow Rate Monitoring Times during Dispense Process	2
Upper Limit Error Level for Flow Rate during Dispense Process	30.00%
Lower Limit Error Level for Flow Rate during Dispense Process	30.00%

^{*} Tools with XDR ONLY

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BACK RINSE1

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Invalid

Dispense Mechanism Connection [1] Valid, Invalid Valid

Valid

Fin flow type 1
Dispense Monitoring Type Fin flow type 1

Dispense Monitoring Control Data

Dispense Monitoring Control Data	
Pulse Rate	0.005
Delay Time	0.6
Set Flow Rate	200
Flow Rate Sensor Check Timing	Dispense end
Calibration 1	1.00
Offset	0
Upper Limit Error Level	30.00%
Upper Limit Warning Level	20.00%
Lower Limit Error Level	30.00%
Lower Limit Warning Level	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Invalid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0

CUP EXH.

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Invalid

Dispense Mechanism Connection [1]
Valid, Invalid Valid

Spinner Exhaust Monitoring Control Data

High Pressure	0.00
High Pressure (Error Lower Limit)	0.00
Low Pressure	0.00
Low Pressure (Error Upper Limit)	0.00
Cup EXH. Monitoring Start Delay Time	2000
Offset	0.0
Cup EXH. Monitoring Valid(1)/Invalid(0)	0



XDR1 N2

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid

Dispense Mechanism Connection [1] Valid, Invalid Valid

Unexpected Pressure Watch

Unexpected Pressure Watch Valid	Valid
Delay Time Before Unexpected Press Watch	3.0

XDR1 RINSE

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid
Nozzle Pattern No	Tool Specific

Dispense Mechanism Connection

Valid, Invalid	Valid
vand, invand	vana

Dispense Monitoring Mechanism Connection
Valid, Invalid Va Valid

Fin flow type 1
Dispense Monitoring Type Fin flow type 1

Dispense Monitoring Control Data

Pulse Rate	0.05
Delay time	0.60
Set Flow Rate	430
Flow Rate Sensor Check Timing	In dispense + Dispense end
Calibration 1	1.00
Offset	0
Upper Limit Error Level	30.00%
Upper Limit Warning Level	20.00%
Lower Limit Error Level	30.00%
Lower Limit Warning Level	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0

Flow Rate during Dispense Process

Invalidated Flow Rate Monitoring Times during Dispense Process	2
Upper Limit Error Level for Flow Rate during Dispense Process	30.00%
Lower Limit Error Level for Flow Rate during Dispense Process	30.00%



Block 3 PR Block, Developers [3-5] -[3-8] W/ NTD for 4x4 NTD [TAQ/TNQ] [TAR/TNR/TNS/TAS/TAU/TNU/TNK] Block 3/5 PR Block, Developers [3-3,4,7,8] and [5-3,4] for 6x6 NTD

Reserved Flag	Invalid
Fork Simultaneous Swapping Level	1-2
Wafer Store Count	1
Start Slot	0

Dispense Parameter

Shared Nozzle

EXH DRAIN PUMP

Pr	ocess Recipe Attribute	Invalid
Dι	ımmy Dispense Attribute	Valid

Dispense Mechanism Connection [1] Valid, Invalid Valid

Local Nozzle

DEV3(Local Arm) / BEVEL RINSE V2 / RINSE1 / BACK RINSE1

Process Recipe Attribute	Valid	
Dummy Dispense Attribute	Valid *	* Invalid for BACK RINSE1 and BEVEL RINSE V2

Dispense Mechanism Connection [1]

Valid

Dispense Monitoring Mechanism Connection

Valid, Invalid Valid

Fin flow type 1

Dispense Monitoring Type Fin flow type 1

CRF Setting**

Valid, Invalid	Valid	** DEV3(LocalArm) and RINSE1 of CRF enabled tool

Interval for Circulation** Invalid Valid, Invalid Time for Circulation Recovery Time for Continuous Circulation 60

Valid

** DEV3(LocalArm) and RINSE1 of CRF enabled tool

Supply System Valid, Invalid

DEV.SOLU.2 Supply System / N.T.DEV SOLUTION1 Supply System / N.T.DEV SOLUTION2 Supply System / SOLVENT2 Supply System - [Tool Spec	em / N.T.DEV SOLUTION1 Supply System / N.T.DEV S	SOLUTION2 Supply System / SOLVENT2 Supply Sy	em - [Tool Specific

Item / Dispense	DEV3(Local Arm)	BEVEL RINSE V2	RINSE1	BACK RINSE 1
Refill Monitoring Time	180	180	180	180
Pre-Refill Decompress Time	20.0	20.0	20.0	20.0
Post-Refill Vent Time	1.0	1.0	1.0	1.0
Post-Refill Pressurize Time	15.0	15.0	15.0	15.0
Post-Refill Depressurize Time	60.0	60.0	60.0	60.0
Post-Refill Delay Time	1	1	1	1
N2 Dissolution Monitoring Time	0	0	0	0
Vent Time at IFF-S*	150	150	150	150
Tank Switch during Dispensing	Valid	Valid	Valid	Valid
Return Mode Setting	Valid	Valid	Valid	Valid

^{*=} Only Present IFF-S tools

CRF Setting

CKF Setting	
Wait Time for Circulation Recovery	240
Guarantee Time of Continuous Circulation	60
Circulation Buffer Pressure Release Time	1
Circulation Liquid Vent Monitoring Time	30
Pressurization Time for Circulation Switching	3
Vent Time for Circulation Switching	0
Small-Pressurization Time for Circulation Switching	1

CSS Refill System	
Valid Invalid	Valid

FailsafeValve	
Failcofe Valve Close Delay Time	Δ.

Dispense Monitoring Control Data

Item / Dispense	DEV3(Local Arm)	BEVEL RINSE V2	RINSE1	BACK RINSE 1
Pulse Rate	0.05	0.005	0.00333	0.005
Delay Time	0.60	0.60	0.60	0.60
Set Flow Rate	300	50	120	200
Flow Rate Sensor Check Timing	Dispense end	Dispense End	Dispense end	Dispense end
Calibration 1	1.00	1.00	1.00	1.00
Offset	0	0	0	0
Upper Limit Error Level	30.00	20.00	30.00	30.00
Upper Limit Warning Level	20.00	10.00	20.00	20.00
Lower Limit Error Level	30.00	20.00	30.00	30.00
Lower Limit Warning Level	20.00	10.00	20.00	20.00
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid	Invalid	Valid	Invalid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute	Execute	Execute	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time	1.0	1.0	1.0	1.0

CUP EXH.

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Invalid

Dispense Mechanism Connection [1] Valid, Invalid Valid

Spinner Exhaust Monitoring Control Data

High Pressure	0.00
High Pressure (Error Lower Limit)	0.00
Low Pressure	0.00
Low Pressure (Error Upper Limit)	0.00
Cup EXH. Monitoring Start Delay Time	2000
Offset	0.0
Cup EXH. Monitoring Valid(1)/Invalid(0)	0

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NTD FILTDRAIN1* /2* 3*

* - IFF-S Specific

Process Recipe Attribute	Invalid
Dummy Dispense Attribute	Invalid
IFF-S Supported Nozzle	Tool Specific

Dispense Monitoring Mechanism Connection
Valid, Invalid Valid

Dispense Monitoring Mechanism Connection		
Valid, Invalid	Valid	

Fin flow type 1 (3)
Dispense Monitoring Type Fin flow type 1

CRF Setting	
Valid, Invalid	Valid

Interval for Circulation

Valid, Invalid	Invalid
Time for Circulation Recovery	60
Time for Continuous Circulation	60

Supply System[1] Valid, Invalid Valid

SOLVENT-D Supply System

SOLVENI-D Supply System	
Supply System Type	Solvent super clean supply sys
Chemical Name	SOLVENT-D
Refill Monitoring Time	180
Pre-Refill Decompress Time	30.0
Post-Refill Vent Time	3.0
Post-Refill Pressurize Time	15.0
Post-Refill Depressurize Time	60.0
Post-Refill Delay Time	1
Vent Time at Chemical Drain	150
Filter Replacement Supply System No.	Tool Specific

NTD-RFILTDRAIN1*/2*/3*

- IFF-S Specific

Process Recipe Attribute	Invalid
Dummy Dispense Attribute	Invalid
IFF-S Supported Nozzle	Tool Specific

Dispense Mechanism Connection Valid, Invalid Valid

Dispense Monitoring Mechanism Connection
Valid, Invalid Valid

Fin flow type 1 (3)
Dispense Monitoring Type Fin flow type 1

erti setting	
Valid, Invalid	Valid

Interval for Circulation

Valid, Invalid	Invalid
Time for Circulation Recovery	60
Time for Continuous Circulation	60

Supply System[1] Valid, Invalid Valid

SOLVENT-A Supply System

Supply System Type	Solvent super clean supply sys
Chemical Name	SOLVENT-A
Refill Monitoring Time	180
Pre-Refill Decompress Time	30.0
Post-Refill Vent Time	1.0
Post-Refill Pressurize Time	15.0
Post-Refill Depressurize Time	60.0
Post-Refill Delay Time	1
Vent Time at Chemical Drain	150
Filter Replacement Supply System No.	Tool Specific



NTD FILTDRAIN1* 2* 3* / NTD-RFILTDRAIN1* 2* 3*

		Filter	Filter	Filter Replacement	Filter Replacement	Filter Replacement	Filter Replacement	Filter Renlacemen	Filter Replacement	Filter Replacement
		Replacement	Replacement	Sequence (3)[3]	Sequence (4)[4]	Sequence (5)[5]	Sequence (6)[6]	Sequence (7)[7]	Sequence (8)[8]	Sequence (9)[9]
		Sequence (1)[1]	Sequence (2)[2]	1 (-)[-1	1 (71)	1 (-)[-1	1 (-)2-3	1 (1)2.1	1 (-)1-1	1 (72)
OTTED //	Install Type	1	2	3	4	5	6	7	8	9
STEP#	Comment	IFF-1	IFF-2	IFF-3	IFF-4	IFF-5	IFF-6	IFF-7	IFF-8	IFF-9
	Process Time	10	10	10	0	0	0	0	0	0
STEP 1	Pressure Setting	LL	LL	LL	None	None	None	None	None	None
	Process Name	Hold	Hold	Hold	None	None	None	None	None	None
	Process Time	200	200	200	0	0	0	0	0	0
STEP 2	Pressure Setting	LL	LL	LL	None	None	None	None	None	None
	Process Name	Filter vent	Filter vent	Filter vent	None	None	None	None	None	None
	Process Time	640	100	640	0	0	0	0	0	0
STEP 3	Pressure Setting	L	L	L	None	None	None	None	None	None
	Process Name	Filter out	Filter out	Filter out	None	None	None	None	None	None
	Process Time	600	1200	600	0	0	0	0	0	0
STEP 4	Pressure Setting	None	L	None	None	None	None	None	None	None
	Process Name	Hold	Filter out	Hold	None	None	None	None	None	None
	Process Time	3200	0	3200	0	0	0	0	0	0
STEP 5	Pressure Setting	L	None	L	None	None	None	None	None	None
	Process Name	Filter out	None	Filter out	None	None	None	None	None	None
CTED	Process Time	0	0	10	0	0	0	0	0	0
STEP 6	Pressure Setting Process Name	None None	None	LL	None	None	None	None	None	None
	Process Name Process Time	0	None	Hold 200	None	None	None	None	None	None 0
STEP 7	Process Time Pressure Setting	None	0 None		0 None	0 None	0 None	0 None	0 None	
SIEP /	Process Name	None	None	Filter vent	None	None	None	None	None	None None
	Process Time	0	None 0	640	0	0	0	0	0	0
STEP 8	Pressure Setting	None	None	L	None	None	None	None	None	None
SILIO	Process Name	None	None	Filter out	None	None	None	None	None	None
	Process Time	0	0	600	0	0	0	0	0	0
STEP 9	Pressure Setting	None	None	None	None	None	None	None	None	None
JILI)	Process Name	None	None	Hold	None	None	None	None	None	None
	Process Time	0	0	3200	0	0	0	0	0	0
STEP 10	Pressure Setting	None	None	L	None	None	None	None	None	None
	Process Name	None	None	Filter out	None	None	None	None	None	None
	Process Time	0	0	10	0	0	0	0	0	0
STEP 11	Pressure Setting	None	None	LL	None	None	None	None	None	None
	Process Name	None	None	Hold	None	None	None	None	None	None
	Process Time	0	0	200	0	0	0	0	0	0
STEP 12	Pressure Setting	None	None	LL	None	None	None	None	None	None
	Process Name	None	None	Filter vent	None	None	None	None	None	None
	Process Time	0	0	640	0	0	0	0	0	0
STEP 13	Pressure Setting	None	None	L	None	None	None	None	None	None
	Process Name	None	None	Filter out	None	None	None	None	None	None
amn- :	Process Time	0	0	600	0	0	0	0	0	0
STEP 14	Pressure Setting	None	None	None	None	None	None	None	None	None
	Process Name	None	None	Hold	None	None	None	None	None	None
STEP 15	Process Time	0	0	3200	0	0	0	0	0	0
S1EP 13	Pressure Setting Process Name	None None	None	L Eilten aut	None	None	None	None	None	None
	Process Name Process Time	None 0	None 0	Filter out 10	None 0	None 0	None 0	None 0	None 0	None 0
STEP 16	Process Time Pressure Setting	None		LL				-		
31EP 10	Process Name	None None	None		None	None	None	None	None	None None
	Process Time	0	None 0	Hold 200	None 0	None 0	None 0	None 0	None 0	None
STEP 17	Pressure Setting	None	None	LL	None	None	None	None	None	None
J1L1 1/	Process Name	None	None	Filter vent	None	None	None	None	None	None
	Process Time	0	0	640	0	0	0	0	0	0
STEP 18	Pressure Setting	None	None	L	None	None	None	None	None	None
2121 10	Process Name	None	None	Filter out	None	None	None	None	None	None
	Process Time	0	0	600	0	0	0	0	0	0
STEP 19	Pressure Setting	None	None	None	None	None	None	None	None	None
/	Process Name	None	None	Hold	None	None	None	None	None	None
	Process Time	0	0	3200	0	0	0	0	0	0
STEP 20	Pressure Setting	None	None	L	None	None	None	None	None	None
	Process Name	None	None	Filter out	None	None	None	None	None	None

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NTD FILTDRAIN1* 2* 3* / NTD-RFILTDRAIN1* 2* 3*

Dispense Monitoring Control Data

Item / Dispense	NTD FILTDRAIN	NTD-RFILTDRAIN
Pulse Rate	0.05	0.00333
Delay Time	0.60	0.60
Set Flow Rate	75	75
Flow Rate Sensor Check Timing	None	None
Calibration 1	1.00	1.00
Offset	0	0
Upper Limit Error Level	30.00	30.00
Upper Limit Warning Level	20.00	20.00
Lower Limit Error Level	30.00	30.00
Lower Limit Warning Level	20.00	20.00
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Invalid	Invalid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Not Execute	Not Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time	1.0	1.0

NTD1 N2

Process Recipe Attribute	Valid	Dispense Mechanism Connection [1]	
Dummy Dispense Attribute	Valid	Valid, Invalid	Valid

MONITORING PARAMETER [For STD and NTD Configuration]

Developer 1&2 temp./ Motor flange temp./ Dilution temp.

Item	Dev 1 temp.	Dev 2 temp.*	Motor flange
Valid, Invalid	Valid	Valid	Valid
Measured Data ID	Dev 1 temp.	Dev 2 temp.	Motor flange temp.
Recipe Setting Method	System recipe	System recipe	System recipe
Temperature Control Method	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
Range Lower Limit	20.00	20.00	20.00
Range Upper Limit	25.00	25.00	25.00

= Not Present for 6x6 configuration

Controller TM150-CHILLER

Controller 1M150-CHILLER			
Item	Dev 1 temp.	Dev 2 temp.*	Motor flange
Controller ID	TM150-CHILLER	TM150-CHILLER	TM150-CHILLER
Channel No.	5	5	5
Monitoring Type	Use point read	Use point read	Use point read
Control Method	Standard	Standard	Standard
Usepoint reading method	AI reading	AI reading	AI reading
Use Point Offset	0.00	0	0.00
Band Monitoring Method at Process Start	Normal	Normal	Normal
Band Monitoring Invalid Time at Process Start	0.0	0	0.0
Band Monitoring Determine Method during Processing	No monitor	No monitor	No monitor
Band Monitoring Determine Time during Processing	0.0	0	0.0
Band Monitoring Value during Processing	0.00	0	0.00
Pump Frequency	30 ~ 60 Hz	30 ~ 60 Hz	30 ~ 60 Hz
Initial Data	23.00	23.00	23.00
Overtemperature	40.00	40.00	40.00
Setting Determination Time	5.0	5	5.0
Setting Time-out Time	3600.0	3600	3600.0
Offset Setting Method	Control setting	Control setting	Control setting
Offset	0.00	0	0.00

*= Not Present for 6x6 configuration

Cup temp./ Cup humidity

cup temps, cup numurey		
Item	Cup temp.	Cup humidity
Valid, Invalid	Valid	Valid
Measured Data ID	Cup temp.	Cup humidity
Recipe Setting Method	System recipe	System recipe
Temperature Control Method	Tmp ctl OFF	Tmp ctl OFF
Recipe Verification Range Lower Limit	20.00	28.00
Recipe Verification Range Upper Limit	27.00	55.00

Controller TM150-THC

Item	Cup temp.	Cup humidity
Controller ID	TM150-THC	TM150-THC
Channel No.	1	2
Monitoring Type	Use point read	Use point read
Control Method	Standard	Standard
Use Point Offset	0.00	0.00
Band Monitoring Method at Process Start	Normal	Normal
Band Monitoring Invalid Time at Process Start	0.0	0.0
Band Monitoring Determination Method	No monitor	No monitor
Band Monitoring Determination Time	0.0	0.0
Band Monitoring Value during Processing	0.00	0.00
Air Blower Frequency	30 ~ 60 Hz	30 ~ 60 Hz
Initial Data	22.20	40.70
Overtemperature	40.00	0.00
Settling Determination Time	5.0	5.0
Setting Time-out Time	3600.0	3600.0



Block Arm - Left/ Block Arm - Right/ Module Arm - Left

Spinner Arm Control Data		DEV MODULES				
Item	Block Arm - Left	Block Arm - Right (WET)	Block Arm - Right (DRY)	Module Arm - Left	Module Arm - Left	
Rail No. DEV3-1/2/3/4	Lower Rail	Lower Rail	Lower Rail	Lower Rail	Lower Rail	
Rail No. DEV 3-5/6/7/8	Upper Rail	Upper Rail	Upper Rail	Upper Rail	Upper Rail	
Rail No. DEV 5-1/2/3/4	Lower Rail			Lower Rail	Lower Rail	
Arm Presence	Exist	Exist	Exist	Exist	Exist	
Nozzle Type	GP Nozzle	GP Nozzle	NLD/LD Nozzle	Rinse Nozzle	Rinse Nozzle[NTD]	
Y-axis Drive Type	Motor Drive	Motor Drive	Motor Drive	Motor Drive	Motor Drive	
Z-axis Drive Type	Motor Drive	Motor Drive	Motor Drive	Cylinder Drive	Cylinder Drive	
Y-axis Pulse Rate	0.004883	0.004883	0.004883	0.012001	0.012001	
Z-axis Pulse Rate	0.006	0.006	0.006	N/A	N/A	
IN, OUT Speed	205000	205000	205000	29500	29500	
IN, OUT Acceleration	361000	361000	150000	147000	147000	
IN, OUT Deceleration	361000	361000	150000	147000	147000	
IN, OUT Speed(Outside the Cup)	205000	205000	205000	N/A	N/A	
IN, OUT Acceleration(Outside the Cup)	150000	150000	150000	N/A	N/A	
IN, OUT Deceleration(Outside the Cup)	150000	150000	150000	N/A	N/A	
UP, DOWN Speed	16600	16600	16600	N/A	N/A	
UP, DOWN Acceleration	166000	166000	166000	N/A	N/A	
UP, DOWN Deceleration	166000	166000	166000	N/A	N/A	
Maintenance Speed	50%	50%	50%	N/A	N/A	

Home Offset

	DEV Block Arm - L / R	DEV Module Arm - Left	NTD Module Arm - Left
Z-Axis Home Position Offse	Tool Specific	NA	NA

Home Position

	DEV Block Arm - L / R	DEV Module Arm - Left	NTD Module Arm - Left
Y - Position	Nozzle Specific	Nozzle Specific	Nozzle Specific
Z - Position	Nozzle Specific	Arm Down	Arm Down

Reference Point

	DEV Block Arm - L / R	DEV Module Arm - Left	NTD Module Arm - Left
Y - axis	Nozzle Specific	Nozzle Specific	Nozzle Specific
Z - axis	Nozzle Specific	Arm Down (Cylinder)	Arm Down (Cylinder)

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Recipe Position

	MGP Nozzle		LD Nozzle	
BLOCK ARM - Recipe Position Name	Block Arm - Left/Right (mm)*		Block Arm - Right (mm)*	
BLOCK ARW - Recipe i osition Name	Y Position	Z Position	Y Position	Z Position
Begin	140.00	12.60	-160.00	2.00
Center	0.00	12.60	0.00	2.00
End	0.00	12.60	160.00	2.00
Dispense 1	5.00	12.60	0.00	2.00
Dispense 2	100.00	12.60	0.00	2.00
Dispense 3	6.00	12.60	0.00	2.00
Dispense 4	-6.00	12.60	0.00	2.00
Dispense 5	0.00	12.60	0.00	2.00
Edge (B)	-145.00	12.60	0.00	2.00
Edge (E)	+140.00	12.60	0.00	2.00
MNT 1	0.00	5.00	0.00	5.00
MNT 2	0.00	5.00	0.00	5.00
MNT 3	0.00	5.00	0.00	5.00

^{*}Values displayed in mm on Parameter Editor may differ from values in the table below by up to 0.02 mm since the actual position is based on an integer number of pulses.

Recipe Position

_	ADR / XDR - Rinse Arm		NTD - Rinse Arm		
MODULE ARM	Module Arm - Left (mm)*		Module Arm	Module Arm - Left (mm)*	
- Recipe Position Name	Y Position	Z Position	Y Position	Z Position	
Begin	0.00	Arm Down	-140.00	Arm Down	
Center***	0.00	Arm Down	0.00	Arm Down	
End	-150.00**	Arm Down	0.00	Arm Down	
Dispense 1	0.00	Arm Down	-13.00	Arm Down	
Dispense 2	0.00	Arm Down	-100.00	Arm Down	
Dispense 3	-15.00	Arm Down	0.00	Arm Down	
Dispense 4	-40.00	Arm Down	0.00	Arm Down	
Dispense 5	-145.00	Arm Down	0.00	Arm Down	
Edge (B)	-100.00	Arm Down	0.00	Arm Down	
Edge (E)	-161.00**	Arm Down	0.00	Arm Down	
MNT 1	0.00	Arm Up	0.00	Arm Up	
MNT 2	0.00	Arm Up	0.00	Arm Up	
MNT 3	0.00	Arm Up	0.00	Arm Up	

^{*}Values displayed in mm on Parameter Editor may differ from values in the table below by up to 0.02 mm since the actual position is based on an integer number of pulses.

Spin Motor

Spin Motor Control Data

Spin Motor Control Data		
Rinse Arm Select	L Arm	
Maximum Speed	3000.00	
Maximum Acceleration	10000.00	
Speed at Rinse	1000.00	
Acceleration at Rinse	3000.00	
Rinse Time	15.00	
Spin Off Speed	1000.00	
Spin Off Acceleration	3000.00	
Spin Off Time	15.00	

^{**} For XDR enabled tool
*** For NTD ARM use the left nozzle as center reference point

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TOKYO ELECTRON AMERICA, INC.

Block 4,5,6 PR Block, Coater CRD PUMP ONLY

Reserved Flag	Invalid
Fork Simultaneous Swapping Level	1-2
Wafer Store Count	1
Start Slot	0

Dispense Parameter

Shared Nozzle

RESIST NOZZLE#

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid
Dry Free Suck Back	Valid

Dispense Mechanism Connection [1]

Valid, Invalid Valid*	Dispense Mechanism Connection [1]	
	Valid, Invalid	Valid*

*Invalid if Resist is not plumbed.

Supply System [Tool Specific	ic	l
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Valid, Invalid Valid*	
-----------------------	--

^{*}Invalid if Resist is not plumbed.

RESIST# Supply System [Tool Specific]

Air vent in process	Valid
The Number of Wafers to be Processed	100
Liquid Sensor Watch Time	2
Exhaust open delay at Reloading	2.4

Filter Vent Setting

Filter Vent Valid, Invalid	Invalid
Filter Vent Interval	100
Mini Tank Vent Interval	100
Filter Vent Time	0.5
Mini Tank Vent time	0.5
Prior Pressurization Time	5

Automatic Air Vent

Air Vent Monitoring Time	30
Delay Time after LE Sensor Detection	3
Prior Pressurization Time	5
Pressure Release Time	1

Laser DDS

Euser DDS	
Laser DDS Valid1(1)/Invalid(0)	Valid
Laser DDS Valid2(1)/Invalid(0)	Valid
Laser DDS Valid3(1)/Invalid(0)	Valid
Laser DDS Valid4(1)/Invalid(0)	Valid

Pump 17

rump 17	
Pump Capacity	3.00 ml
Pump Pressure Range	100
Pump Pressure Calibration	1.00
Pump Pressure Monitoring Range (Warning Upper Limit)	20.0
Pump Pressure Monitoring Range (Warning Lower Limit)	20.0
Pump Pressure Monitoring Range (Stop Upper Limit)	30.0
Pump Pressure Monitoring Range (Stop Lower Limit)	30.0
Pump Pressure Monitoring Valid(1)/Invalid(0)	1
Dispense Start Watch Time	30.00
Pump Supply Watch Time	8.1
Delay Time Before Pump Supply	1.00
Wafer In Control Time	11.1
AMC Close Timing Adjustment	Valid
AMC Close Timing Adjustment TYPE	TYPE2 = X10
Board ID	Layer Specific
Electric Valve Count	1
Detection Count of Consecutive Unexecuted Pump Supply	3
Target ID	Pump Specific

AMC Valve

AV Open Time	0
AV Close Time	0
SV Setup Time	0
SV Time	0
Calibration	1.00
Offset	0
Setup1 Time	300
Setup2 Time	300
Setup3 Time	300
Suckback1 Time	4000
Suckback2 Time	4000
Suckback3 Time	2000
Process Setup Position	13
Setup1 Position	0
Setup2 Position	0
Process Suckback Position	0
Suckback1 Position	30 [+/-1]
Suckback2 Position	25 [+/-1]
Suckback3 Position	5 [+/-1]
Hysteresis	0
Target ID	Same as Resist Nozzle Number

Pump Out Air Vent Setting

Pump Out Air Vent Valid, Invalid	Invalid
Pump Out Air Vent Interval	10000 shot
Pump Out Air Vent Time	0.3
Pump Out Air Vent additional reload time	3.5 sec

Block 4,5,6 PR Block, Coater ACRD Tool ONLY

Reserved Flag	Invalid
Fork Simultaneous Swapping Level	1-2
Wafer Store Count	1
Start Slot	0

Dispense Parameter

Shared Nozzle

Possible Number of Simultaneous Resist	10
Dispense Processes	10

RESIST NOZZLE#

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid
Out-Filter Vent Attribute	Valid
Dry Free Suck Back	Valid
Periodic Return Valid/Invalid	Valid

Pump 18	
ViscosityType	Standard
Switch of ACRD Pump Operation	0
PressureMonitoringWarningRange	20
PressureMonitoringStopRange	30
PumpPressureCalibration	1
Pressure for wait	20
ReloadPreparationPressure	35
ReloadInitialPressure	See Table 1
PumpTrapVentInitialPressure	2
PumpReturnVentInitialPressure	See Table 1
ReturnLineValid/InvalidForPumpVent	Valid*
PriorPressurizationTimeForPumpVent	2
TrapBDSensorMonitoringValid/Invalid	Valid
RetryCountForPumpVent	10
AMCCloseTimingAdjustValid	Valid
AMCCloseTimingAdjustType	1
FilterVentValid	Valid
FilterVentInterval	300
FilterVentTime	1
PriorPressurizationTimeForFilterVent	2
DelayTimeBeforeReload	3
PumpOutValveCloseDelayTime	0.1

^{*=} May be temp set to INVALID on **ONE LINE per DECK** while executing the line plumbing BKM

DES

DES	
ProcessSetupTime	0
SuckbackOffset	0
Setup1Time	300
Setup2Time	300
Setup3Time	300
Suckback1Time	4000
Suckback2Time	4000
Suckback3Time	2000
ProcessSetupPosition	13
Setup1Position	0
Setup2Position	0
ProcessSuckbackPosition	0
Suckback1Position	13 [+/-3]
Suckback2Position	15 [+/-3]
Suckback3Position	5 [+/-1]

Dispense Line Data

Dispense Eme Duta		
ResistFlowDataCollection Valid/Invalid	Valid	
PumpPressureDataCollection Valid/Invalid	Valid	

Resist Interval Return Setting

Excessive-Return Preventive Amount	33
Excessive-Return Preventive Purge Amount	3

IFF-R Setting

IFF-R Pressure	-45
IFF-R Time	10

Out-Filter Setting

Pump Out-Filter Vent Initial Pressure	2.0kPa
Out-Filter Vent Press Mode For Wait	Enclosed Press

Laser DDS

Laser DDS Valid1(1)/Invalid(0)	Valid*
Laser DDS Valid2(1)/Invalid(0)	Valid*
Laser DDS Valid3(1)/Invalid(0)	Valid*
Laser DDS Valid4(1)/Invalid(0)	Valid*

^{*}Invalid if RFM is Valid in Corresponding pump recipes

Dispense Mechanism Connection [1]	
Valid, Invalid	Valid*

^{*}Invalid if Resist is not plumbed.

Supply System [Tool Specific]

Valid, Invalid	Valid*

^{*}Invalid if Resist is not plumbed.

RESIST# Supply System [Tool Specific] · M-ACRD Package

RESIST# Supply System [1001 Specific] . Wi-ACRD Tackage	7
Air vent in process	Valid
The Number of Wafers to be Processed	0
Transfer Control / Chemical Amount to be Continued after Bottle Empty	50 mL
Liquid Sensor Watch Time	1
Bottle empty recovery mode	Refill movement
Refill Monitoring Time	30
PressAfterFreeTime	1

^{*} M-ACRD Patckage : HP-AMC + MACRD + 150ml or 100ml Reservoir tank

Refill System - [Tool Specific]

RefillSysNo	Nozzle Specific
RefillSystemValid	Valid

Multi tank refill system

with talk reim system		
	Supply Method	Vacuum
	Prior Pressurization Time	5sec

Bottle Empty Detection Setting

InstantDetectRefillStopSensor	Invalid
RefillStopSensorDetectFixTime	1.0
RefillStopSensorWatchInvalidTime	1.5

Rottlo

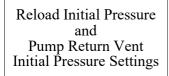
Dottie		
ContainerNo	1	

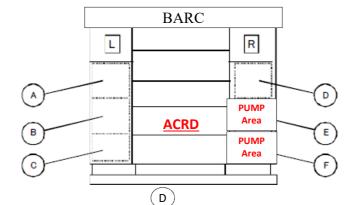
Dispense Monitoring Control Data *

Flow Rate Sensor Check Timing	Dispense End
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid
Auto Dummy Dispense Amount Measurement Valid/Invalid	Valid
Duration for Stabilizing Pressure to Validate Measurement Result	20.0

^{*} Only Present on lines with Dual Filter Upgrade

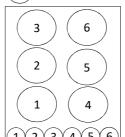
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No.	PARTS	POINT OF USE	Setting
1	BOTTLE1, L/E	5-1,2,3,4 RESIST4	9.0
2	BOTTLE1, L/E	5-1,2,3,4 RESIST5	9.0
3	BOTTLE1, L/E	5-1,2,3,4 RESIST6	9.0
4	BOTTLE1, L/E	6-1,2,3,4 RESIST4	4.5
5	BOTTLE1, L/E	6-1,2,3,4 RESIST5	4.5
6	BOTTLE1, L/E	6-1,2,3,4 RESIST6	4.5



No.	PARTS	POINT OF USE	Setting	1
1	BOTTLE1, L/E	5-1,2,3,4 RESIST7	9.0	1
2	BOTTLE1, L/E	5-1,2,3,4 RESIST8	9.0	1
3	BOTTLE1, L/E	6-1,2,3,4 RESIST10	4.5	,
4	BOTTLE1, L/E	6-1,2,3,4 RESIST7	4.5	1
5	BOTTLE1, L/E	6-1,2,3,4 RESIST8	4.5	1
6	BOTTLE1, L/E	6-1,2,3,4 RESIST9	4.5	1

*Use the below setting if not complete LE bottle

swap modification 3 BOTTLE1, L/E 5-1,2,3,4 RESIST9 **9.0** 1)(2)(3)(4)(5)(6)

MAINTENANCE SIDE

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(1)(2)(3)	(4)(5)(6)

No.	PARTS	POINT OF USE	Setting
1	BOTTLE1, L/E	5-1,2,3,4 RESIST1	4.5
2	BOTTLE1, L/E	5-1,2,3,4 RESIST2	4.5
3	BOTTLE1, L/E	5-1,2,3,4 RESIST3	4.5
4	BOTTLE1, L/E	6-1,2,3,4 RESIST1	0.0
5	BOTTLE1, L/E	6-1,2,3,4 RESIST2	0.0
6	BOTTLE1, L/E	6-1,2,3,4 RESIST3	0.0

MAINTENANCE SIDE

(E

Deck6 RESIST1 - RESIST10 Pump Area

MAINTENANCE SIDE

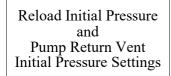
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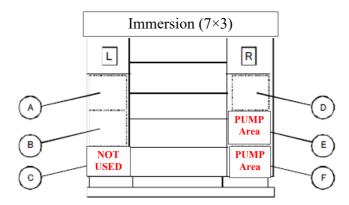


No.	PARTS	POINT OF USE	Setting
1	BOTTLE1, L/E	5-1,2,3,4 RESIST10	0.0
2	BOTTLE1, L/E	5-1,2,3,4 RESIST9	0.0

Deck5 RESIST1 - RESIST10 Pump Area

MAINTENANCE SIDE





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No.	PARTS	POINT OF USE	Setting
1	BOTTLE1, L/E	6-1,2 RESIST1	9.0
2	L/E	6-3,4 RESIST1	4.5
3	BOTTLE1, L/E	6-1,2 RESIST2	9.0
4	L/E	6-3,4 RESIST2	4.5
5	BOTTLE1, L/E	6-1,2 RESIST3	9.0
6	L/E	6-3,4 RESIST3	4.5

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3	6
2	5
	4
123	456

MAINTENANCE SIDE

No.	PARTS	POINT OF USE	Setting
1	BOTTLE1, L/E	4-1,2 RESIST1	9.0
2	BOTTLE1, L/E	4-3,4 RESIST1	4.5
3	BOTTLE1, L/E	4-1,2 RESIST2	9.0
4	BOTTLE1, L/E	4-3,4 RESIST2	4.5
5	BOTTLE1, L/E	4-1,2 RESIST3	9.0
6	BOTTLE1, L/E	4-3,4 RESIST3	4.5

MAINTENANCE SIDE

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12345	<u>(6)</u>

No.	PARTS	POINT OF USE	Setting
1	BOTTLE1, L/E	4-1,2 RESIST4	4.5
2	L/E	4-3,4 RESIST4	0.0
3	BOTTLE1, L/E	4-1,2 RESIST5	4.5
4	L/E	4-3,4 RESIST5	0.0
5	BOTTLE1, L/E	4-1,2 RESIST6	4.5
6	L/E	4-3,4 RESIST6	0.0
7	BOTTLE1, L/E	4-1,2 RESIST7	4.5
8	L/E	4-3,4 RESIST7	0.0

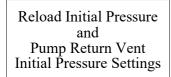
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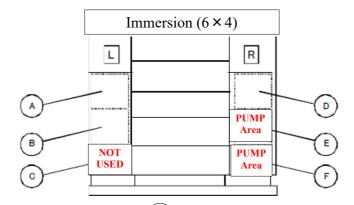
4-3,4 RESIST1 - RESIST7 / 6-3,4 RESIST1 - RESIST3 Pump Area

(F)

4-1,2 RESIST1 - RESIST7 / 6-1,2 RESIST1 - RESIST3 Pump Area

MAINTENANCE SIDE





(A)

3	5
123	456

No.	PARTS	POINT OF USE	Setting
1	BOTTLE1, L/E	6-1,2 RESIST1	9.0
2	L/E	6-3,4 RESIST1	4.5
3	BOTTLE1, L/E	6-1,2 RESIST2	9.0
4	L/E	6-3,4 RESIST2	4.5
5	BOTTLE1, L/E	6-1,2 RESIST3	9.0
6	L/E	6-3,4 RESIST3	4.5

MAINTENANCE SIDE

No.	PARTS	POINT OF USE	Setting
1	BOTTLE1, L/E	4-1,2 RESIST1	9.0
2	BOTTLE1, L/E	4-3,4 RESIST1	4.5
3	BOTTLE1, L/E	4-1,2 RESIST2	9.0
4	BOTTLE1, L/E	4-3,4 RESIST2	4.5
5	BOTTLE1, L/E	4-1,2 RESIST3	9.0
6	BOTTLE1, L/E	4-3,4 RESIST3	4.5

MAINTENANCE SIDE

WHITTEN HACE SIDE

(в)

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No.	PARTS	POINT OF USE	Setting
1	BOTTLE1, L/E	4-1,2 RESIST4	4.5
2	L/E	4-3,4 RESIST4	0.0
3	BOTTLE1, L/E	4-1,2 RESIST5	4.5
4	L/E	4-3,4 RESIST5	0.0
5	BOTTLE1, L/E	4-1,2 RESIST6	4.5
6	L/E	4-3,4 RESIST6	0.0
7	BOTTLE1, L/E	6-1,2 RESIST4	4.5
8	L/E	6-3,4 RESIST4	0.0

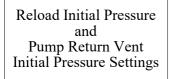
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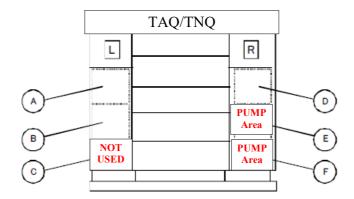
4-3,4 RESIST1 - RESIST6 / 6-3,4 RESIST1 - RESIST4 Pump Area

(F)

4-1,2 RESIST1 - RESIST6 / 6-1,2 RESIST1 - RESIST4 Pump Area

MAINTENANCE SIDE





(A)

3	6
2	5
1	4
123	456

No.	PARTS	POINT OF USE	Setting
1	BOTTLE, L/E	6-1,2,3,4 RESIST1	9.0
2	BOTTLE, L/E	6-1,2,3,4 RESIST2	9.0
3	BOTTLE, L/E	6-1,2,3,4 RESIST3	4.5
4	BOTTLE, L/E	6-1,2,3,4 RESIST4	4.5
5	BOTTLE, L/E	4-1,2,3,4 RESIST7	9.0
6	BOTTLE L/E	5-1.2.3.4 RESIST7	4.5

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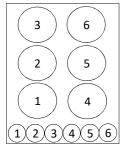
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3	6
2	5
	4
123	456

MAINTENANCE SIDE

No.	PARTS	POINT OF USE	Setting
1	BOTTLE1, L/E	4-1,2,3,4 RESIST1	9.0
2	BOTTLE1, L/E	4-1,2,3,4 RESIST2	9.0
3	BOTTLE1, L/E	4-1,2,3,4 RESIST3	9.0
4	BOTTLE1, L/E	4-1,2,3,4 RESIST4	9.0
5	BOTTLE1, L/E	4-1,2,3,4 RESIST5	9.0
6	BOTTLE1, L/E	4-1,2,3,4 RESIST6	9.0

MAINTENANCE SIDE

(B)



No.	PARTS	POINT OF USE	Setting
1	BOTTLE1, L/E	5-1,2,3,4 RESIST1	0.0
2	BOTTLE1, L/E	5-1,2,3,4 RESIST2	0.0
3	BOTTLE1, L/E	5-1,2,3,4 RESIST3	0.0
4	BOTTLE1, L/E	5-1,2,3,4 RESIST4	0.0
5	BOTTLE1, L/E	5-1,2,3,4 RESIST5	0.0
6	BOTTLE1, L/E	5-1,2,3,4 RESIST6	0.0

E

5-1,2,3,4 RESIST1 - RESIST7 / 6-1,2,3,4 RESIST3,4 Pump Area

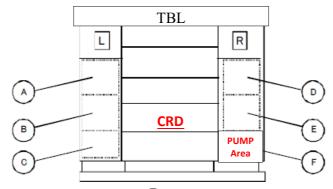
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4-1,2,3,4 RESIST1 - RESIST7 / 6-1,2,3,4 RESIST1,2 Pump Area

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TOKYO ELECTRON AMERICA, INC.

Reload Initial Pressure and Pump Return Vent Initial Pressure Settings



 (A)

3	6
2	5
	4
123	456

No.	PARTS	POINT OF USE	Setting
1	BOTTLE1, L/E	6-1,2,3,4 RESIST3	4.5
2	BOTTLE2, L/E	6-1,2,3,4 RESIST3	4.5
3	BOTTLE1, L/E	6-1,2,3,4 RESIST4	4.5
4	BOTTLE2, L/E	6-1,2,3,4 RESIST4	4.5
5	UNUSED		
6	UNUSED		

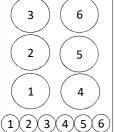
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	3	6	
	2	5	
	1	4	
1	2 (3	4 5	(6)

No.	PARTS	POINT OF USE	Setting
1	BOTTLE1, L/E	6-1,2,3,4 RESIST1	4.5
2	BOTTLE2, L/E	6-1,2,3,4 RESIST1	4.5
3	BOTTLE1, L/E	6-1,2,3,4 RESIST2	4.5
4	BOTTLE2, L/E	6-1,2,3,4 RESIST2	4.5
5	UNUSED		
6	UNUSED		

MAINTENANCE SIDE

(B)



PARTS	POINT OF USE	Setting
BOTTLE1, L/E	5-1,2,3,4 RESIST3	4.5
BOTTLE2, L/E	5-1,2,3,4 RESIST3	4.5
BOTTLE1, L/E	5-1,2,3,4 RESIST4	4.5
BOTTLE2, L/E	5-1,2,3,4 RESIST4	4.5
UNUSED		
UNUSED		
	BOTTLE1, L/E BOTTLE2, L/E BOTTLE1, L/E BOTTLE2, L/E UNUSED	BOTTLEI, L/E 5-1,2,3,4 RESIST3 BOTTLE2, L/E 5-1,2,3,4 RESIST3 BOTTLE1, L/E 5-1,2,3,4 RESIST4 BOTTLE2, L/E 5-1,2,3,4 RESIST4 UNUSED

MAINTENANCE SIDE

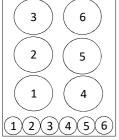
(E)

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2	5	
	4	
(1)(2)(3)	(4)(5)	(6

No.	PARTS	POINT OF USE	Setting
1	BOTTLE1, L/E	5-1,2,3,4 RESIST1	4.5
2	BOTTLE2, L/E	5-1,2,3,4 RESIST1	4.5
3	BOTTLE1, L/E	5-1,2,3,4 RESIST2	4.5
4	BOTTLE2, L/E	5-1,2,3,4 RESIST2	4.5
5	UNUSED		
6	UNUSED		

MAINTENANCE SIDE

(c)



No.	PARTS	POINT OF USE	Setting
1	UNUSED		
2	UNUSED		
3	UNUSED		
4	UNUSED		
5	UNUSED		
6	UNUSED		

(F

Deck5 and 6 RESIST1 - RESIST4 Pump Area

MAINTENANCE SIDE

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RRC NOZZLE1/ DRN CASE CLEAN/ NZL CLN/BATH CLN/NZL SC

Process Recipe Attribute	Valid*
Dummy Dispense Attribute	Valid*

Dispense Mechanism Connection [1]

ľ	Valid, Invalid	Valid

Dispense Monitoring Mechanism Connection

Valid, Invalid	Valid

Fin flow type 1

CRF Setting****

CKr Setting	
Valid, Invalid	Valid

Interval for Circulation for All except D6 IMM***

Valid, Invalid	Invalid
Time for Circulation Recovery	60
Time for Continuous Circulation	60

Interval for Circulation for D6 IMM***

Interval for encumeron for both the		
Valid, Invalid	Valid	
Time for Circulation Recovery	1200	
Time for Continuous Circulation	15	

RRC Nozzle Auto Dispense After DFT Valid, Invalid

Valid, Invalid	Valid

RRC Nozzle Auto Dispense Time After DFT

Time (sec)	1.0

Supply System [1]

1	Valid, Invalid	Valid

NOZZLE.SC when nozzle height is 4.5 mm (BARC)

Suckback Start Delay Time	2000
Suckback1 Position	5.00
Suckback2 Position	0.00
Suckback3 Position	5.00

NOZZLE.SC when nozzle height is 6.5 mm (IMM / DRY)

Suckback Start Delay Time	2000
Suckback1 Position	4.00
Suckback2 Position	-1.00
Suckback3 Position	4.00

Wash after Dispensing with Sub-operating Panel**

Set, Not Set	Not Set
--------------	---------

Wash Time after Dispensing**

Time (sec)	10

^{*} Invalid for NZL SC

SOLVENT 1 Supply System -[Tool Specific]

Item / Dispense	RRC NOZZLE1	DRN CASE CLEAN	NZL CLN/BATH CLN	NOZZLE. SC.
Refill Monitoring Time	180	180	180	180
Pre-Refill Decompress Time	20.0	20.0	20.0	20.0
Post-Refill Vent Time	1.0	1.0	1.0	1.0
Post-Refill Pressurize Time	15.0	15.0	15.0	15.0
Post-Refill Depressurize Time	60.0	60.0	60.0	60.0
Post-Refill Delay Time	1	1	1	1
N2 Dissolution Monitoring Time	0	0	0	0
Vent Time at IFF-S*	150sec	150sec	150sec	150sec
Tank Switch during Dispensing	Valid	Valid	Valid	Valid
Return Mode Setting	Valid	Valid	Valid	Valid

^{* -} IFF-S Specific

CRF Setting*

CRI Setting		_
Wait Time for Circulation Recovery	240	
Guarantee Time of Continuous Circulation	60*	* 0 for D6 IMM Tool Only
Circulation Buffer Pressure Release Time	1	
Circulation Liquid Vent Monitoring Time	30	
Pressurization Time for Circulation Switching	3	
Vent Time for Circulation Switching	0	
Small-Pressurization Time for Circulation Switching	1	1

^{*} For CRF enabled tool

CSS Refill System [1]	FailsafeValve

Valid, Invalid	Valid	Failsafe Valve Close Delay Time 0.0 se	ec

^{**} ONLY Present for NZL CLN/BATH CLN

^{***} RRC NOZZLE1 of CRF enabled tool

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Dispense Monitoring Control Data

Item / Dispense	RRC NOZZLE1	DRN CASE CLEAN	NZL CLN/BATH CLN	NOZZLE. SC.
Pulse Rate	0.00333	0.05	0.05	0.05
Delay Time	0.60	0.60	0.60	0.60
Set Flow Rate	70	250	10 NZL BATH 600 7 NZL BATH 440 4 NZL BATH 275	10 NZL BATH 900 7 NZL BATH 875 4 NZL BATH 525
Flow Rate Sensor Check Timing	Dispense end	Dispense end	Dispense end	Dispense end
Calibration 1	POS = 0.85 - 0.99 PGMEA = 1.00 - 1.15 EL = 0.98 - 1.12	1.00	1.00	1.00
Offset	0	0	0	0
Upper Limit Error Level	30.00%	30.00%	30.00%	20.00%
Upper Limit Warning Level	20.00%	20.00%	20.00%	10.00%
Lower Limit Error Level	30.00%	30.00%	30.00%	20.00%
Lower Limit Warning Level	20.00%	20.00%	20.00%	10.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid	Valid	Valid	Valid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute	Execute	Execute	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Disp.	1.0	1.0	1.0	1.0

CMN CUP EXH.*

Process Recipe Attribute	Invalid
Dummy Dispense Attribute	Invalid

^{*} This setting does not exist on TNU

Dispense Mechanism Connection
Valid, Invalid Valid

RESIST SUCKBACK

Process Recipe Attribute	Invalid
Dummy Dispense Attribute	Invalid

Dispense	Mechanism	Connection	

Valid, Invalid	Valid

RESIST SETUP

Process Recipe Attribute	Invalid
Dummy Dispense Attribute	Invalid

Dispense Mechanism Connection

Valid Invalid	Valid

RESIST SETUP END

Process Recipe Attribute	Invalid
Dummy Dispense Attribute	Invalid

Dispense Mechanism Connection

Valid, Invalid	Valid

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RST PRESS TRG.*

* - ACRD Specific

Process Recipe Attribute	Invalid
Dummy Dispense Attribute	Invalid

5.2. System Config Parameter, Spinners (COT/BCT)

Dispense Mechanism Connection

Valid, Invalid Valid

KEEP ARM POS[69]

Process Recipe Attribute	Valid	
Dummy Dispense Attribute	Invalid	

Dispense Mechanism Connection Valid, Invalid Valid

RRC FILTDRAIN1*/2*

* - IFF-S Specific

Process Recipe Attribute	Invalid
Dummy Dispense Attribute	Invalid
IFF-S Supported Nozzle	Tool Specific

Dispense Mechanism Connection

Valid, Invalid Valid

Dispense Monitoring Mechanism Connection

Valid, Invalid Valid

Fin flow type 1 (3)
Dispense Monitoring Type Fin flow type 1

Valid

Supply System[1] Valid, Invalid

SOLVENT-A/B/C Supply System

Supply System Type	Solvent super clean supply sys
Chemical Name	SOLVENT-A/B/C
Refill Monitoring Time	180
Pre-Refill Decompress Time	30
Post-Refill Vent Time	1
Post-Refill Pressurize Time	15
Post-Refill Depressurize Time	60
Post-Refill Delay Time	1
Vent Time at Chemical Drain	150
Filter Replacement Supply System No.	Tool Specific

* - IF	FF-S Specific	Filter Replacement Sequence (1)[1]	Filter Replacement Sequence (2)[2]	Filter Replacement Sequence (3)[3]	Filter Replacement Sequence (4)[4]	Filter Replacement Sequence (5)[5]	Filter Replacement Sequence (6)[6]	Filter Replacement Sequence (7)[7]	Filter Replacement Sequence (8)[8]	Filter Replacement Sequence (9)[9]
	Install Type	1	2	3	4	5	6	7	8	9
	Comment	IFF-1	IFF-2	IFF-3	IFF-4	IFF-5	IFF-6	IFF-7	IFF-8	IFF-9
	Process Time	10 sec	10	0	0	0	0	0	0	0
STEP 1	Pressure Setting	LL	LL	None	None	None	None	None	None	None
	Process Name	Hold	Hold	None	None	None	None	None	None	None
	Process Time	200	200	0	0	0	0	0	0	0
STEP 2	Pressure Setting	LL	LL	None	None	None	None	None	None	None
	Process Name	Filter vent	Filter vent	None	None	None	None	None	None	None
	Process Time	640	100	0	0	0	0	0	0	0
STEP 3	Pressure Setting	L	L	None	None	None	None	None	None	None
	Process Name	Filter out	Filter out	None	None	None	None	None	None	None
	Process Time	600	1200	0	0	0	0	0	0	0
STEP 4	Pressure Setting	None	L	None	None	None	None	None	None	None
	Process Name	Hold	Filter out	None	None	None	None	None	None	None
STEP 5	Process Time	3200	0	0	0	0	0	0	0	0
	Pressure Setting	L	None	None	None	None	None	None	None	None
	Process Name	Filter out	None	None	None	None	None	None	None	None
	Process Time	0	0	0	0	0	0	0	0	0
STEP 6	Pressure Setting	None	None	None	None	None	None	None	None	None
	Process Name	None	None	None	None	None	None	None	None	None
	Process Time	0	0	0	0	0	0	0	0	0
STEP 7	Pressure Setting	None	None	None	None	None	None	None	None	None
	Process Name	None	None	None	None	None	None	None	None	None
	Process Time	0	0	0	0	0	0	0	0	0
STEP 8	Pressure Setting	None	None	None	None	None	None	None	None	None
	Process Name	None	None	None	None	None	None	None	None	None
	Process Time	0	0	0	0	0	0	0	0	0
STEP 9	Pressure Setting	None	None	None	None	None	None	None	None	None
	Process Name	None	None	None	None	None	None	None	None	None
	Process Time	0	0	0	0	0	0	0	0	0
STEP 10	Pressure Setting	None	None	None	None	None	None	None	None	None
	Process Name	None	None	None	None	None	None	None	None	None

Valid, Invalid	VALID

Interva	l tor	Circulation	
Valid In	valid		

Valid, Invalid	Invalid
Time for Circulation Recovery	60
Time for Continuous Circulation	60

		Filter Replacement Sequence (1)[1]	Filter Replacement Sequence (2)[2]	Filter Replacement Sequence (3)[3]	Filter Replacement Sequence (4)[4]	Filter Replacement Sequence (5)[5]	Filter Replacement Sequence (6)[6]	Filter Replacement Sequence (7)[7]	Filter Replacement Sequence (8)[8]	Filter Replacement Sequence (9)[9]
	Install Type	1	2	3	4	5	6	7	8	9
	Comment	IFF-1	IFF-2	IFF-3	IFF-4	IFF-5	IFF-6	IFF-7	IFF-8	IFF-9
	Process Time	0	0	0	0	0	0	0	0	0
STEP 11	Pressure Setting	None	None	None	None	None	None	None	None	None
	Process Name	None	None	None	None	None	None	None	None	None
	Process Time	0	0	0	0	0	0	0	0	0
STEP 12	Pressure Setting	None	None	None	None	None	None	None	None	None
	Process Name	None	None	None	None	None	None	None	None	None
	Process Time	0	0	0	0	0	0	0	0	0
STEP 13	Pressure Setting	None	None	None	None	None	None	None	None	None
	Process Name	None	None	None	None	None	None	None	None	None
	Process Time	0	0	0	0	0	0	0	0	0
STEP 14	Pressure Setting	None	None	None	None	None	None	None	None	None
	Process Name	None	None	None	None	None	None	None	None	None
	Process Time	0	0	0	0	0	0	0	0	0
STEP 15	Pressure Setting	None	None	None	None	None	None	None	None	None
	Process Name	None	None	None	None	None	None	None	None	None
	Process Time	0	0	0	0	0	0	0	0	0
STEP 16	Pressure Setting	None	None	None	None	None	None	None	None	None
	Process Name	None	None	None	None	None	None	None	None	None
	Process Time	0	0	0	0	0	0	0	0	0
STEP 17	Pressure Setting	None	None	None	None	None	None	None	None	None
	Process Name	None	None	None	None	None	None	None	None	None
	Process Time	0	0	0	0	0	0	0	0	0
STEP 18	Pressure Setting	None	None	None	None	None	None	None	None	None
	Process Name	None	None	None	None	None	None	None	None	None
	Process Time	0	0	0	0	0	0	0	0	0
STEP 19	Pressure Setting	None	None	None	None	None	None	None	None	None
	Process Name	None	None	None	None	None	None	None	None	None
	Process Time	0	0	0	0	0	0	0	0	0
STEP 20	Pressure Setting	None	None	None	None	None	None	None	None	None
	Process Name	None	None	None	None	None	None	None	None	None

Dispense Monitoring Control Data

clist Monitoring Control Data	
Pulse Rate	0.00333
Delay Time	0.6
Set Flow Rate	75
Flow Rate Sensor Check Timing	None
Calibration 1	1
Offset	0
Upper Limit Error Level	30
Upper Limit Warning Level	20
Lower Limit Error Level	30
Lower Limit Warning Level	20
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Invalid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Not Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1

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Local Nozzle

E.B.R.1/ BACK RINSE1/ BEVEL RINSE V2/ EXH DUCT CLEAN

Process Recipe Attribute	Valid	7
Dummy Dispense Attribute	Valid *	* Invalid for BACKRINSE and BEVEL RINSE
		_
Dispense Mechanism Connection		_
Valid, Invalid	Valid	

Dispense Monitoring Mechanism Connection

Valid, Invalid Valid

Fin flow type 1

Dispense Monitoring Type Fin flow type 1

Supply System
Valid, Invalid Valid

SOLVENT 1 Supply System - [Tool Specific]

SOLVENT I Supply System - [1001 Special	iit j			
Item / Dispense	E.B.R.1	BACK RINSE1	BEVEL RINSE V2	EXH DUCT CLEAN
Refill Monitoring Time	180	180	180	180
Pre-Refill Decompress Time	20.0	20.0	20.0	20.0
Post-Refill Vent Time	1.0	1.0	1.0	1.0
Post-Refill Pressurize Time	15.0	15.0	15.0	15.0
Post-Refill Depressurize Time	60.0	60.0	60.0	60.0
Post-Refill Delay Time	1	1	1	1
N2 Dissolution Monitoring Time	0	0	0	0
Vent Time at IFF-S*	150sec	150sec	150sec	150sec
Tank Switch during Dispensing	Valid	Valid	Valid	Valid
Return Mode Setting	Valid	Valid	Valid	Valid

^{* -} IFF-S Specific

CRF Setting*

Wait Time for Circulation Recovery	240
Guarantee Time of Continuous Circulation	60
Circulation Buffer Pressure Release Time	1
Circulation Liquid Vent Monitoring Time	30
Pressurization Time for Circulation Switching	3
Vent Time for Circulation Switching	0
Small-Pressurization Time for Circulation Switching	1

^{*} For CRF enabled tool

CSS Refill System [1]	
Valid Invalid	Valid

Failsafe Valve Close Delay Time 0.0 sec

Dispense Monitoring Control Data

Item / Dispense	E.B.R.1	BACK RINSE1	BEVEL RINSE V2	EXH DUCT CLEAN
Pulse Rate	0.00333	0.005	0.00333	0.005
Delay Time	0.60	0.60	0.60	0.60
Set Flow Rate	20	100	50	200
Flow Rate Sensor Check Timing	Dispense end	Dispense end	Dispense end	Dispense end
Calibration 1	POS = 0.85 - 0.99 PGMEA = 1.00 - 1.15 EL = 0.98 - 1.12	1.00	1.00	1.00
Offset	0	0	0	0
Upper Limit Error Level	40.00%	30.00%	30.00%	30.00%
Upper Limit Warning Level	30.00%	20.00%	20.00%	20.00%
Lower Limit Error Level	30.00%	30.00%	30.00%	30.00%
Lower Limit Warning Level	20.00%	20.00%	20.00%	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid	Invalid	Invalid	Valid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute	Execute	Execute	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Disp.	1.0	1.0	1.0	1.0

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CUP EXH.

Process Recipe Attribute	Invalid*	* Valid for TNU
Dummy Dispense Attribute	Invalid	

Dispense Mechanism Connection
Valid, Invalid Valid

Spinner Exhaust Monitoring Control Data

Spinier Exhaust Monitoring Control Data	
Item / Dispense	CUP EXH.
High Pressure	0.00
High Pressure (Error Lower Limit)	0.00
Low Pressure	0.00
Low Pressure (Error Upper Limit)	0.00
Cup EXH. Monitoring Start Delay Time	2000
Offset	0.0
Cup EXH. Monitoring Valid(1)/Invalid(0)	0

EXH DRAIN PUMP

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Invalid

Dispense Mechanism Connection	
Valid, Invalid	Valid

Monitoring Parameter

Resist temp./ Cup temp./ Motor flange temp./ Cup humidity/ Cup exhaust flow

Item	Resist temp.	Cup temp.	Motor flange temp.	Cup humidity	Cup exhaust flow	
Valid,Invalid	Valid	Valid	Valid	Valid	Valid	
Measured Data ID	Resist temp.	Cup temp.	Motor flange temp.	Cup humidity	Cup exhaust flow	
Recipe Setting Method	System recipe	System recipe	System recipe	System recipe	System recipe	
Temperature Control Method	See Table	See Table	See Table	See Table	See Table	
Recipe Verify Range Lower Limit	20.00	20.00	20.00	28.00	0	
Recipe Verify Range Upper Limit	25.00	27.00	25.00	55.00	**500	

^{**=1000} for TNU L4 and L6

Table for Temperature Control Method

Module	Resist temp.	Cup temp.	Motor flange temp.	Cup humidity	Cup exhaust flow
4-1 COT	Tmp ctl ON	Tmp ctl ON	Tmp ctl OFF	Tmp ctl ON	Tmp ctl ON
4-2 COT	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
4-3 COT	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
4-4 COT	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
5-1 COT	Tmp ctl ON	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON
5-1 COT(TBL) 5-1 BCT (BARC)	Tmp ctl ON	Tmp ctl ON	Tmp ctl OFF	Tmp ctl ON	Tmp ctl ON
5-2 COT/BCT	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
5-3 COT/BCT	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
5-4 COT/BCT	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
6-1 COT/BCT	Tmp ctl ON	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON
6-2 COT/BCT	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
6-3 COT/BCT	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
6-4 COT/BCT	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF

See next page for TNU specific settings

Table for Temperature Control Method [TNU]

Module	Resist temp.	Cup temp.	Motor flange temp.	Cup humidity	Cup exhaust flow
4-1 COT	Tmp ctl ON	Tmp ctl ON	Tmp ctl OFF	Tmp ctl ON	Tmp ctl ON
4-2 COT	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
4-3 COT	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
4-4 COT	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
5-1 COT	N/A	N/A	N/A	N/A	N/A
5-2 COT	N/A	N/A	N/A	N/A	N/A
5-3 COT	N/A	N/A	N/A	N/A	N/A
5-4 COT	N/A	N/A	N/A	N/A	N/A
6-1 COT	Tmp ctl ON	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON
6-2 COT	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
6-3 COT	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
6-4 COT	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF

Controller TM150-CHILLER / THC

Controller TM150-CHILLER / THC				
Item	Resist temp.	Cup temp.	Motor flange temp.	Cup humidity
Controller ID	TM150-CHILLER	TM150-THC	TM150-CHILLER	TM150-THC
Channel No. *	See Table	1	See Table	2
Monitoring Type *	See Table	See Table	Use point read	See Table
Control Method	Standard	Standard	Standard	Standard
Usepoint reading method	AI reading	N/A	AI reading	N/A
Use Point Offset	Tool specific	Tool specific	Tool specific	Tool specific
Band Monitoring Method at Process Start	Normal	Normal	Normal	Normal
Band Monitoring Invalid Time at Process Start	0.0	0.0	0.0	0
Band Monitoring Determination Method during Processing	No monitor	No monitor	No monitor	No monitor
Band Monitoring Determine Time during Processing	0.0	0.0	0.0	0
Band Monitoring Value during Processing	0.00	0.00	0.00	0
Source Value Monitoring Valid	See Table	See Table	N/A	See Table
Source Value Monitoring Band *	10	10	N/A	10
Pump Frequency	Tool specific	N/A	Tool specific	N/A
Air Blower Frequency	N/A	$30 \sim 60 \text{ Hz}$	N/A	30 ~ 60 Hz
Initial Data	22.20	22.20	22.20	40.7
Overtemperature	40.00	40.00	40.00	0
Settling Determination Time	5.0	5.0	5.0	5
Settling Time-out Time	3600	3600	3600	3600
Offset Setting Method	Control setting	N/A	Control setting	N/A
Offset	0.00	N/A	0.00	N/A

^{*=}Only present with Temp control ON is active

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* Table for TM150-CHILLER / THC

		Resist temp.		Cup	temp.	Motor flange temp.	Cup humid	lity
Module	Channel No.	Monitoring Type	Source Value Monitoring Valid	Monitoring Type	Source Value Monitoring Valid	Channel No.	Monitoring Type	Source Value Monitoring
4-1 COT	0	Use point ctrl	Invalid	Use point ctrl	Invalid	0	Use point ctrl	Invalid
4-2 COT	0	Use point read	N/A	Use point read	N/A	0	Use point read	N/A
4-3 COT	0	Use point read	N/A	Use point read	N/A	0	Use point read	N/A
4-4 COT	0	Use point read	N/A	Use point read	N/A	0	Use point read	N/A
5-1 COT	1	Use point ctrl	Invalid	Use point read	N/A	1	Use point read	N/A
5-1 COT(TBL) 5-1 BCT (BARC)	1	Use point ctrl	Invalid	Use point ctrl	Invalid	1	Use point ctrl	Invalid
5-2 COT/BCT	1	Use point read	N/A	Use point read	N/A	1	Use point read	N/A
5-3 COT/BCT	1	Use point read	N/A	Use point read	N/A	1	Use point read	N/A
5-4 COT/BCT	1	Use point read	N/A	Use point read	N/A	1	Use point read	N/A
6-1 COT/BCT	2	Use point ctrl	Invalid	Use point read	N/A	2	Use point read	N/A
6-2 COT/BCT	2	Use point read	N/A	Use point read	N/A	2	Use point read	N/A
6-3 COT/BCT	2	Use point read	N/A	Use point read	N/A	2	Use point read	N/A
6-4 COT/BCT	2	Use point read	N/A	Use point read	N/A	2	Use point read	N/A

Controller EPCA

Item	Cup exhaust flow
Controller ID	EPCA
Channel No.	See Table for Channel No.
Monitoring Type	No sync
Control Method	Standard
Band Monitoring Method at Process Start	Normal
Band Monitoring Invalid Time at Process Start	0.0
Band Monitoring Determination Method during Processing	No monitor
Band Monitoring Determination Time during Processing	1.0
Band Monitoring Value during Processing	300
PID Setting Method	Control setting
P Constant	45.00
I Constant	0.3
Exhaust Pressure Rise Time	1.0
Exhaust Pressure Drop Time	2.0
Initial Data	400*
Settling Determination Time	3.0
Settling Time-out Time	1800.0
Pressure Sensor Type	1000Pa**

^{*=620}Pa for TNU L4/L6

Block Arm - Left /Right / Module Arm - Left

Spin Arm Parameter

Item	Block Arm - Left / Right	Module Arm - Left
Rail No.	Lower Rail	Lower Rail
Arm Presence	Exist	Exist
Middle Wait	Valid	N/A
Auto Bath Cleaning Interval Time	900 sec	N/A
Nozzle Type	Resist Nozzle	Rinse Nozzle
Y-axis Drive Type	Motor Drive	Motor Drive
Z-axis Drive Type	Motor Drive	Cylinder Drive
Y-axis Pulse Rate	0.004883	0.006
Z-axis Pulse Rate	0.006	N/A
IN, OUT Speed	205000	29000
IN, OUT Acceleration	150000	290000
IN, OUT Deceleration	150000	290000
IN, OUT Speed(Outside the Cup)	205000	N/A
IN, OUT Acceleration(Outside the Cup)	150000	N/A
IN, OUT Deceleration(Outside the Cup)	150000	N/A
UP, DOWN Speed	16600	N/A
UP, DOWN Acceleration	166000	N/A
UP, DOWN Deceleration	166000	N/A
Maintenance Speed	50%	N/A
Exh Exclusive Control Near Ready Time*	4.5	N/A

Table for Channel No.

All Other 1274	All Other 1274 Tools					
Module	Channel No.	Channel No.				
4-1 COT	2	2				
4-2 COT	2	2				
4-3 COT	2	2				
4-4 COT	2	2				
5-1 COT/BCT	3	N/A				
5-2 COT/BCT	3	N/A				
5-3 COT/BCT	3	N/A				
5-4 COT/BCT	3	N/A				
6-1 COT/BCT	4	4				
6-2 COT/BCT	4	4				
6-3 COT/BCT	4	4				
6-4 COT/BCT	4	4				

^{**= 1000}Pa Only present on TNU L4/L6

 $[\]boldsymbol{*}$ The parameter only exists on dual arm tracks except TNU.

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Home Offset

	Block Arm - L / R	Module Arm - Left
Z-Axis Home Position Offse	Tool Specific	NA

Home Position

	Block Arm - L / R	Module Arm - Left
Y - Position	Nozzle Specific	Nozzle Specific
Z - Position	Nozzle Specific	Arm Down

Nozzle Offset for all Layers

Nozzle Offset	Nozzle 2	Nozzle 3	Nozzle 4	Nozzle 5	Nozzle 6	Nozzle 7	Nozzle 8	Nozzle 9	Nozzle 10	RRC
Presence	Exist	Exist								
Y - Position	-9	-18	-27	-36	-54	-63	-72	-81	-90	-45
Z - Position	0	0	0	0	0	0	0	0	0	0

Reference Point

	Block Arm - L / R	Module Arm - Left
Y - axis	Nozzle Specific	Nozzle Specific
Z - axis	Nozzle Specific	Arm Down (Cylinder)

Recipe Position

D D	Block Arm - L	eft/Right (mm)	Module Arm - Left (mm)		
Recipe Position Name	Y Position	Z Position	Y Position	Z Position	
Module	COT/BCT	COT/BCT	COT/BCT	COT/BCT	
Begin	0.00	5.00	-106.06	Arm Down	
Center	0.00	5.00	0.00	Arm Down	
End	0.00	5.00	-106.06	Arm Down	
Dispense 1	0.00	30.00	-106.06	Arm Down	
Dispense 2	0.00	5.00	-106.06	Arm Down	
Dispense 3	0.00	5.00	-106.06	Arm Down	
Dispense 4	0.00	5.00	-106.06	Arm Down	
Dispense 5	SEE Table 1	85.00	-106.06	Arm Down	
Edge (B)	0.00	5.00	-107.47	Arm Down	
Edge (E)	0.00	5.00	-106.06	Arm Down	
Middle Standby	SEE Table 2	89.01	N/A	N/A	
MNT 1	0.00	85.00	0.00	Arm Up	
MNT 2	0.00	5.00	0.00	Arm Up	
MNT 3	0.00	5.00	0.00	Arm Up	

Table 1

Dispense 5	Single Arm	Dual Arm
Cup 1	-221+/-2mm	-221+/-2mm
Cup 2	-221+/-2mm	-221+/-2mm
Cup 3	-221+/-2mm	+252+/-2mm
Cup 4	-221+/-2mm	-221+/-2mm

Table 2

Middle Standby	Single Arm	Dual Arm
Cup 1	+192.39mm	+192.39mm
Cup 2	-282.24mm	-282.24mm
Cup 3	-282.24mm	+192.39mm
Cup 4	-282.24mm	-282.24mm

Spin Motor Parameter

Spin Motor Control Data

Rinse Arm No.	None
Maximum Speed	4000.00
Maximum Acceleration	30000.00
Speed at Rinse	1200.00
Acceleration at Rinse	10000.00
Rinse Time	15.00
Spin Off Speed	2000.00
Spin Off Acceleration	10000.00
Spin Off Time	10.0

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Block 8 IPB, I-Rinse / S-Rinse*

* For Immersion Configuration ONLY

Reserved Flag	Invalid*
Fork Simultaneous Swapping Level	1-2
Wafer Store Count	1
Start Slot	0

Dispense parameter

Local Nozzle

PDR1 N2

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid

Dispense Mechanism Connection	[1]
Valid, Invalid	Valid

RINSE1

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid

Dispense Mechanism	Connection	1	
Valid, Invalid			Valid

Dispense Monitoring Mechanism Connection Valid, Invalid Valid

Fin flow type 1	
Dispense Monitoring Type	Fin flow type 1

Dispense Monitoring Control Data

Pulse Rate	0.05
Delay Time	0.60
Set Flow Rate	150
Flow Rate Sensor Check Timing	Dispense end
Calibration 1	1.00
Offset	0
Upper Limit Error Level	30.00%
Upper Limit Warn Level	20.00%
Lower Limit Error Level	30.00%
Lower Limit Warning Level	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0

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BACK RINSE1

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Invalid

Dispense Mechanism Connection [1]

Valid, Invalid Valid

Dispense Monitoring Mechanism Connection

Valid, Invalid Valid

Fin flow type 1

Dispense Monitoring Type Fin flow type 1

Dispense Monitoring Control Data

Dispense Monitoring Control Data	
Pulse Rate	0.005
Delay Time	0.60
Set Flow Rate	200
Flow Rate Sensor Check Timing	Dispense end
Calibration 1	1.00
Offset	0
Upper Limit Error Level	30.00%
Upper Limit Warning Level	20.00%
Lower Limit Error Level	30.00%
Lower Limit Warning Level	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Invalid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0

CUP EXH.

Process Recipe Attribute	Invalid
Dummy Dispense Attribute	Invalid

Dispense Mechanism Connection [1]

Valid, Invalid	Valid
----------------	-------

Spinner Exhaust Monitoring Control Data

High Pressure	0.00
High Pressure (Error Lower Limit)	0.00
Low Pressure	0.00
Low Pressure (Error Lower Limit)	0.00
Cup EXH. Monitoring Start Delay Time	2000
Offset	0.0
Cup EXH. Monitoring Valid(1)/Invalid(0)	0

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IE NOZZLE *

Process Recipe Attribute	Valid	* For SRS Only
Dummy Dispense Attribute	Invalid	

Dispense Mechanism Connection [1]
Valid, Invalid Valid

Dispense Monitoring Mechanism Connection
Valid, Invalid Valid

Fin flow type 1
Dispense Monitoring Type Fin flow type 1

Dispense Monitoring Control Data

Pulse Rate	0.005
Delay Time	0.60
Set Flow Rate	200
Flow Rate Sensor Check Timing	Dispense end
Calibration 1	1.00
Offset	0
Upper Limit Error Level	30.00%
Upper Limit Warning Level	20.00%
Lower Limit Error Level	30.00%
Lower Limit Warning Level	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Invalid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0

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Monitoring Parameter

Cup temp./ Motor flange temp./ Cup humidity

Item	Cup temp.	Motor flange temp.	Cup humidity
Valid,Invalid	Valid	Valid	Valid
Measured Data ID	Cup temp.	Motor flange temp.	Cup humidity
Recipe Setting Method	System recipe	System recipe	System recipe
Temperature Control Method	Temp Ctl OFF**	Temp Ctl OFF	Temp Ctl OFF**
Recipe Verify Range Lower Limit	20.00	20.00	28.00
Recipe Verify Range Upper Limit	27.00	25.00	55.00

^{**=} PIR 8-1 for TNU is TMP CRTL ON

Controller TM150-CHILLER / THC

Item	Cup temp.	Motor flange temp.	Cup humidity
Controller ID	TM150-THC*	TM150-CHILLER	TM150-THC*
Channel No.	1	4	2
Monitoring Type	Use point read*	Use point read	Use point read*
Control Method	Standard	Standard	Standard
Usepoint reading method	N/A	AI reading	N/A
Use Point Offset	Tool specific	Tool specific	Tool specific
Band Monitoring Method at Process Start	Normal	Normal	Normal
Band Monitoring Invalid Time at Process Start	0.0	0.0	0.0
Band Monitoring Determination Method during Processing	No monitor	No monitor	No monitor
Band Monitoring Determine Time during Processing	0.0	0.0	0.0
Band Monitoring Value during Processing	0.00	0.00	0.00
Pump Frequency	N/A	Tool specific	N/A
Air Blower Frequency	Tool specific	N/A	Tool specific
Initial Data	22.20	22.20	40.70
Overtemperature	40.00	40.00	0.00
Settling Determination Time	5.0	5.0	5.0
Settling Time-out Time	3600.0	3600.0	3600.0
Offset Setting Method	N/A	Control setting	N/A
Offset	N/A	0.00	N/A

^{*=} TNU use Controller ID: (CF9010-F400) See Table 2 below for TNU tools

* Table 2 for CF9010-F400 -- TNU ONLY

1 abie 2 101 CF 9010-F 400 1 NU ONL 1				
	Cup temp.		Cup humidity	
Module	Manitanina Tyma	Source Value	Manitanina Trus	Source Value
	Monitoring Type	Monitoring Valid	Monitoring Type	Monitoring
8-1	Use point ctrl	Valid	Use point ctrl	Valid
8-2	Use point read	N/A	Use point read	N/A
8-3	Use point read	N/A	Use point read	N/A
8-4	Use point read	N/A	Use point read	N/A
8-6	Use point read	N/A	Use point ctrl	N/A
8-7	Use point read	N/A	Use point read	N/A
8-8	Use point read	N/A	Use point read	N/A
8-9	Use point read	N/A	Use point read	N/A
8-10	Use point read	N/A	Use point read	N/A

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Module Arm - Left

Spinner Arm Control Data

Item	Module Arm - Left	
Rail No.	Lower Rail	
Arm Presence	Exist	
Nozzle Type	Rinse Nozzle	
Y-axis Drive Type	Motor Drive	
Z-axis Drive Type	Cylinder Drive	
Y-axis Pulse Rate	0.012001	
IN, OUT Speed	29500	
IN, OUT Acceleration	147000	
IN, OUT Deceleration	147000	

Home Position

	Module Arm
Y - Position	Nozzle Specific
Z - Position	Arm Down

Reference Point

	Module Arm
Y - axis	Nozzle Specific
Z - axis	Arm Down (Cylinder)

Recipe Position

D i D i N	Module Arm - Left (mm)		
Recipe Position Name	Y Position	Z Position	
Begin	0.00	Arm Down	
Center	0.00	Arm Down	
End	0.00	Arm Down	
Dispense 1	-158.01	Arm Down	
Dispense 2	-24.00	Arm Down	
Dispense 3	-100.00	Arm Down	
Dispense 4	-130.00	Arm Down	
Dispense 5	0.00	Arm Down	
Edge (B)	0.00	Arm Down	
Edge (E)	0.00	Arm Down	
MTN 1	0.00	Arm Up	
MTN 2	0.00	Arm Up	
MTN 3	0.00	Arm Up	

Spin Motor Parameter

Spin Motor Control Data

Rinse Arm No.	L Arm
Maximum Speed	3000.00
Maximum Acceleration	10000.00
Speed at Rinse	1000.00
Acceleration at Rinse	3000.00
Rinse Time	15.00
Spin Off Speed	1000.00
Spin Off Acceleration	3000.00
Spin Off Time	15.0

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5.4 Spinner Parameter

Spinner Information Parameter

AutoBathCleaning Time	1	sec
Water Seal Time Initialize	30.00	sec
Water Seal Time	1.50	sec



Block 3/ Block 4/ Block 5/ Block6 PR Block, Chil PHP, PRP (CPHP/CPRP) Modules

Reserved Flag	Invalid
Fork Simultaneous Swapping Level	1-2
Wafer Store Count	1
Start Slot	0

Chamber Type

Chamber Type	SNS Chamber

Plate Type

ince Type	
Plate Type	*
* = Type C for CPRP/A2 for CPHP	

Cool Arm Parameter

 01 1 11 11 1 11 11 11 11 11 11 11 11 11	
Cool Arm Speed	STD Speed

Module Parameter

Monitoring parameter Plate temp.

Valid,Invalid	Valid
Measured Data ID	Plate temp.
Recipe Setting Method	Process recipe
Temperature Control Method	Tmp ctl ON
Recipe Verification Range Lower Limit	50.00
Recipe Verification Range Upper Limit	180.00

Controller E5ZR	
Controller ID	E5ZR
Start Channel No.	0
End Channel No.	6
Monitoring Type	No sync
Control Method	Epsilon ctrl
Chmber FB Ctrl. Valid	Valid
Band Monitoring Method at Process Start	Setting
Band Monitoring Invalid Time at Process Start	40.0
Band Monitoring Determination Method during Processing	No monitor
Band Monitoring Determination Time during Processing	1.0
Band Monitoring Value during Processing	3.00
PID Setting Method	Control setting
P Constant	1.50
I Constant	2.5
D Constant	0.5
Offset Setting Method	Table setting
Offset	0.00
Display Method Selection	Display all data
Stranded Wafer Detection Valid	Valid
Stranded Wafer Detection Method	Lowest Intergrated temp of all channels
Initial Data	50.00
Overtemperature	185.00
Settling band*	0.20
Settling Determination Time	3.0
Settling Time-out Time	1200.0
Loop Break Alarm Function Valid/Invalid	Invalid

^{*=} ONLY available with CD Optimizer SW

Control Table Data list (Except for BE DRY Tracks listed below)

	Valid, Invalid	Setting Lower	Setting Upper	Accum Threshold	Accum Time	Chm FB Fixed Temp.
Temp. Range	Valid	50.00	180.00	Not Input	Not Input	Not Input
Temp. Range	Valid	50.00	Not Input	Not Input	Not Input	35.00
Temp. Range	Valid	70.00	Not Input	20.00	15.00	Tool Specific
Temp. Range	Valid	75.00	Not Input	23.33	15.00	Not Input
Temp. Range	Valid	80.00	81.00	26.67	15.00	Not Input
Temp. Range	Valid	85.00	Not Input	30.00	15.00	Not Input
Temp. Range	Valid	90.00	Not Input	33.33	15.00	Not Input
Temp. Range	Valid	95.00	97.00	36.67	15.00	Not Input
Temp. Range	Valid	100.00	Not Input	40.00	15.00	Tool Specific
Temp. Range	Valid	105.00	Not Input	44.00	15.00	Not Input
Temp. Range	Valid	110.00	Not Input	48.00	15.00	Not Input
Temp. Range	Valid	115.00	Not Input	52.00	15.00	Not Input
Temp. Range	Valid	120.00	Not Input	56.00	15.00	Not Input
Temp. Range	Valid	125.00	Not Input	60.00	15.00	Tool Specific
Temp. Range	Valid	130.00	Not Input	64.00	15.00	Not Input
Temp. Range	Valid	135.00	Not Input	68.00	15.00	Not Input
Temp. Range	Valid	140.00	Not Input	72.00	15.00	Not Input
Temp. Range	Valid	145.00	Not Input	76.00	15.00	Not Input
Temp Range	Valid	150.00	Not Input	80.00	15.00	Tool Specific

^{*}Wafer Wedge setup by 1mm (wafer guide 5m)

Control Table Data list for TBL, TBM and (BE193 TNE, TNG only)

	Valid, Invalid	Setting Lower	Setting Upper	Accum Threshold	Accum Time	Chm FB Fixed Temp.
Temp. Range	Valid	50.00	180.00	Not Input	Not Input	Not Input
Temp. Range	Valid	50.00	Not Input	Not Input	Not Input	35.00
Temp. Range	Valid	70.00	Not Input	20.00	15.00	Tool Specific
Temp. Range	Valid	75.00	Not Input	23.33	15.00	Not Input
Temp. Range	Valid	80.00	81.00	26.67	15.00	Not Input
Temp. Range	Valid	85.00	Not Input	30.00	15.00	Not Input
Temp. Range	Valid	90.00	Not Input	20.00	15.00	Not Input
Temp. Range	Valid	90.10	Not Input	33.33	15.00	Not Input
Temp. Range	Valid	95.00	97.00	36.67	15.00	Not Input
Temp. Range	Valid	100.00	Not Input	20.00	15.00	Tool Specific
Temp. Range	Valid	100.10	Not Input	40.00	15.00	Not Input
Temp. Range	Valid	105.00	Not Input	22.00	15.00	Not Input
Temp. Range	Valid	105.10	Not Input	44.00	15.00	Not Input
Temp. Range	Valid	110.00	Not Input	22.00	15.00	Not Input
Temp. Range	Valid	110.10	Not Input	48.00	15.00	Not Input
Temp. Range	Valid	115.00	Not Input	26.00	15.00	Not Input
Temp. Range	Valid	115.10	Not Input	52.00	15.00	Not Input
Temp. Range	Valid	120.00	Not Input	28.00	15.00	Not Input
Temp. Range	Valid	120.10	Not Input	56.00	15.00	Not Input
Temp. Range	Valid	125.00	Not Input	60.00	15.00	Tool Specific
Temp. Range	Valid	130.00	Not Input	32.00	15.00	Not Input
Temp. Range	Valid	130.10	Not Input	64.00	15.00	Not Input
Temp. Range	Valid	135.00	Not Input	68.00	15.00	Not Input
Temp. Range	Valid	140.00	Not Input	72.00	15.00	Not Input
Temp. Range	Valid	145.00	Not Input	76.00	15.00	Not Input
Temp. Range	Valid	150.00	Not Input	80.00	15.00	Tool Specific
Temp. Range	Valid	180.00	Not Input	150.00	15.00	Tool Specific

^{*}Wafer Wedge setup by 1mm (wafer guide 5m)





Block 3/ Block 4/ Block 5/ Block6 PR Block, Chil PHP, PRP (CPHP, CPRP) Modules

Control Table Data (Temperature Range 50.00-180.00)

	Table Data 1	Table Data 2	Table Data 3	Table Data 4	Table Data 5	Table Data 6	Table Data 7]
Offset	Not Input	1						
P	Not Input							
I	Not Input							
D	Not Input							
Epsilon*	0.10	-0.50	-0.50	-0.20	-0.20	-0.20	-0.20	* CPRP
Epsilon**	-1.20	-0.50	-0.50	1.10	1.10	1.10	1.10	**CPHP

Control Table Data (Temperature Range 70, 100, 125, 150, 180)

	Table Data 1	Table Data 2	Table Data 3	Table Data 4	Table Data 5	Table Data 6	Table Data 7
Offset	Tool Specific						
P	Not Input						
I	Not Input						
D	Not Input						
Epsilon	Not Input						

Control Table Data (All Other)

	(
	Table Data 1	Table Data 2	Table Data 3	Table Data 4	Table Data 5	Table Data 6	Table Data 7
Offset	Not Input						
P	Not Input						
I	Not Input						
D	Not Input						
Epsilon	Not Input						

Cool Arm Chilly Water temp.

coorrant camp water temps	
Valid,Invalid	Valid
Measured Data ID	Cool Arm Chilly Water Temp
Recipe Setting Method	System recipe
Temperature Control Method	Tmp ctl OFF
Recipe Verification Range Lower Limit	20.00
Recipe Verification Range Upper Limit	25.00

Controller TM150-CHILLER

Controller ID	TM150-CHILLER
Channel No.	4
Monitoring Type	Use Point Read
Control Method	Standard
Usepoint reading method	AI reading
Use Point Offset	Tool specific
Band Monitoring Method at Process Start	Normal
Band Monitoring Invalid Time at Process Start	0.0
Band Monitoring Determination Method during Processing	No Monitor
Band Monitoring Determine Time during Processing	0.0
Band Monitoring Value during Processing	0.00
Pump Frequency	30 ~ 60
Initial Data	22.20
Overtemperature	40.0
Settling Determination Time	5.0
Settling Time-out Time	3600.0
Offset Setting Method*	Control setting
Offset*	0.00

^{*} Not exist v214 beyond



Block 3/ Block 4/ Block 5/ Block6 PR Block, Chil PHP, PRP (CPHP, CPRP) Modules

Chamber temp.

Valid,Invalid	Valid
Measured Data ID	Chamber temp.
Recipe Setting Method	Local
Temperature Control Method	Tmp ctl ON
Recipe Verification Range Lower Limit	50.00
Recipe Verification Range Upper Limit	250.00

Controller E5ZR

Controller ESZK	
Controller ID	E5ZR
Start Channel	7
End Channel	7
Monitoring Type	No sync
Control Method	Epsilon ctrl
Band Monitoring Method at Process Start	Normal
Band Monitoring Invalid Time at Process Star	0.0
Band Monitoring Determination Method during Processing	No monitor
Band Monitoring Determination Time during Processing	1.0
Band Monitoring Value during Processing	3.00
PID Setting Method	Control setting
P Constant	4.60
I Constant	16.4
D Constant	2.5
Offset Setting Method	Table setting
Offset	0.00
Display Method Selection	Display all data
Stranded Wafer Detection Method	Invalid
Initial Data	50.00
Overtemperature	190.00
Settling Determination Time	3.0
Settling Time-out Time	1200.0

Control Table Data list "Chamber Feedback"

	Valid / Invalid	Setting Lower	Setting Upper	Accum Thresh	Accum Time	Chm. FB Fixed Temp
Temp Range 1	Valid	Not Input	Not Input	Not Input	Not Input	Not Input
Temp Range 2	Valid	Not Input	Not Input	Not Input	Not Input	Not Input
Temp Range 3	Valid	Not Input	Not Input	Not Input	Not Input	Not Input
Temp Range 4	Valid	Not Input	Not Input	Not Input	Not Input	Not Input
Temp Range 5	Valid	Not Input	Not Input	Not Input	Not Input	Not Input
Temp Range 6	Valid	Not Input	Not Input	Not Input	Not Input	Not Input
Temp Range 7	Valid	Not Input	Not Input	Not Input	Not Input	Not Input
Temp Range 8	Valid	Not Input	Not Input	Not Input	Not Input	Not Input

Control Table Data "All Temp"

Control	i Table Data Ali Te	mp						
	Table Data 1	Table Data 2	Table Data 3	Table Data 4	Table Data 5	Table Data 6	Table Data 7	Table Data 8
Offset	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input
P	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input
I	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input
D	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input
Ensilon	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input



Block 5/ Block6 PR Block, [CGCH] Chil. General Heat Chamber HP Modules

Reserved Flag	Invalid
Fork Simultaneous Swapping Level	1-2
Wafer Store Count	1
Start Slot	0

FOR BARC Tools ONLY

Chamber Type

Chamber Type	STD Chamber
--------------	-------------

Plate Type

l	ite i vpe	
	Plate Type	B2.

Cool Arm Parameter

Cool Arm Speed	STD Speed

Monitoring parameter

Plate temp.	
Valid,Invalid	Valid
Measured Data ID	Plate temp.
Recipe Setting Method	Process recipe
Temperature Control Method	Tmp ctl ON
Recipe Verification Range Lower Limit	50.00
Recipe Verification Range Upper Limit	250.00

Controller REX-B879

Controller REX-B879	
Controller ID	REX-B879
Start Channel No.	0
End Channel No.	6
Monitoring Type	No sync
Control Method	PID Control
Band Monitoring Method at Process Start	Setting
Band Monitoring Invalid Time at Process Start	40.0
Band Monitoring Determination Method during Processing	No monitor
Band Monitoring Determination Time during Processing	1.0
Band Monitoring Value during Processing	3.00
PID Setting Method	Table setting
P Constant	1.00
I Constant	5.9
D Constant	1.5
Offset Setting Method	Table setting
Offset	0.00
Display Method Selection	Display all data
Stranded Wafer Detection Valid	Valid
Stranded Wafer Detection Method	Lowest Intergrated temp of all channels
Initial Data	50.00
Overtemperature	255.00
Settling Determination Time	3.0
Settling Time-out Time	2600.0
Loop Break Alarm Function Valid/Invalid	Invalid

Control Table Data list

	Valid, Invalid	Setting Lower	Setting Upper	Accum Threshold	Accum Time
Temp. Range1	Valid	50.00	250.00	Not Input	Not Input
Temp. Range2	Valid	170.00	Not Input	35.00	15.00
Temp. Range3	Valid	175.00 Not Input		38.00	15.00
Temp. Range4	Valid	190.00	Not Input	46.00	15.00
Temp. Range5	Valid	205.00	00 Not Input 5		15.00
Temp. Range6	Valid	225.00 Not Input		72.50	15.00
Temp. Range7	Valid	250.00	Not Input	110.00	15.00

^{*} Wafer wedge set up by 1mm ring. (Wafer guide 5mm)

Cool Arm Chilly Water temp.

Valid,Invalid	Valid
Measured Data ID	Cool Arm Chilly Water Temp
Recipe Setting Method	System recipe
Temperature Control Method	Tmp ctl OFF
Recipe Verification Range Lower Limit	20.00
Recipe Verification Range Upper Limit	25.00

Controller TM150-CHILLER

Controller ID	TM150-CHILLER
Channel No.	4
Monitoring Type	Use Point Read
Control Method	Standard
Usepoint reading method	AI reading
Use Point Offset	Tool specific
Band Monitoring Method at Process Start	Normal
Band Monitoring Invalid Time at Process Start	0.0
Band Monitoring Determination Method during Processing	No Monitor
Band Monitoring Determine Time during Processing	0.0
Band Monitoring Value during Processing	0.00
Pump Frequency	30 ~ 60
Initial Data	22.20
Overtemperature	40.0
Settling Determination Time	5.0
Settling Time-out Time	3600.0
Offset Setting Method	Control setting
Offset	0.00



Block 5/ Block6 PR Block, [CGCH] Chil. General Heat Chamber HP Modules Control Table Data (Temperature Range 50.00-250.00)

	Table Data 1	Table Data 2	Table Data 3	Table Data 4	Table Data 5	Table Data 6	Table Data 7
Offset	Not Input						
P	1.0	1.0	1.0	1.8	1.8	1.8	1.8
I	5.9	5.9	5.9	5.9	5.9	5.9	5.9
D	1.5	1.5	1.5	1.5	1.5	1.5	1.5

Control Table Data (Temperature Range 170, 205, 250)

		Table Data 1	Table Data 2	Table Data 3	Table Data 4	Table Data 5	Table Data 6	Table Data 7
Ī	Offset	Tool Specific						
Ī	P	Not Input						
ı	I	Not Input						
	D	Not Input						

Control Table Data (All Other)

Control Tuble Data (III Other)							
	Table Data 1	Table Data 2	Table Data 3	Table Data 4	Table Data 5	Table Data 6	Table Data 7
Offset	Not Input						
P	Not Input						
I	Not Input						
D	Not Input						

Monitoring parameter Cover temp.

Valid
Cover Temp
Local
Tmp ctl ON
50.00
180.00

Controller REX-B879	
Controller ID	REX-B879
Start Channel No.	7
End Channel No.	7
Monitoring Type	No sync
Control Method	PID Control
Band Monitoring Method at Process Start	Setting
Band Monitoring Invalid Time at Process Start	40.0
Band Monitoring Determination Method during Processing	No monitor
Band Monitoring Determination Time during Processing	1.0
Band Monitoring Value during Processing	3.00
PID Setting Method	Control Setting
P Constant	2.60
I Constant	24.0
D Constant	6.0
Offset Setting Method	Table setting
Offset	0.00
Display Method Selection	Display all data
Stranded Wafer Detection Valid	Invalid
Initial Data	50.00
Overtemperature	185.00
Settling Determination Time	3.0
Settling Time-out Time	2600.0

Control Table Data list

	Valid, Invalid	Setting Lower	Setting Upper	Accum Threshold	Accum Time	
Temp. Range1	Valid	180.00	Not Input	Not Input	Not Input	
Temp. Range2	Invalid	Not Input	Not Input	Not Input	Not Input	
Temp. Range3	Invalid	Not Input	Not Input	Not Input	Not Input	
Temp. Range4	Invalid	Not Input	Not Input	Not Input	Not Input	
Temp. Range5	Invalid	Not Input	Not Input	Not Input	Not Input	
Temp. Range6	Invalid	Not Input	Not Input	Not Input	Not Input	
Temp. Range7	Invalid	Not Input	Not Input	Not Input	Not Input	
Temp. Range8	Invalid	Not Input	Not Input	Not Input	Not Input	

Control Table Data (Temperature Range 180.00)

	Table Data 1	Table Data 2	Table Data 3	Table Data 4	Table Data 5	Table Data 6	Table Data 7
Offset	Tool Specific	Not Input					
P	2.6	Not Input					
I	24	Not Input					
D	6	Not Input					

Control Table Data (All Other)

Control Table Data (All Other)							
	Table Data 1	Table Data 2	Table Data 3	Table Data 4	Table Data 5	Table Data 6	Table Data 7
Offset	Not Input						
P	Not Input						
I	Not Input						
D	Not Input						



Block 2 MP Block/ Block 8 IPB, Chil Plt (CPL) Modules

Reserved Flag	Invalid
Fork Simultaneous Swapping Level	Invalid
Wafer Store Count	1
Start Slot	0

Monitoring parameter

Plate Chilly Water temp.

Valid,Invalid	Valid
Measured Data ID	Plate Chilly Water
Recipe Setting Method	System recipe
Temperature Control Method	See Table1
Recipe Verification Range Lower Limit	20.00
Recipe Verification Range Upper Limit	25.00

Controller TM150-CHILLER

Controller ID	TM150-CHILLER
Channel No.	See Table 1
Monitoring Type	See Table 1
Control Method	Standard
Usepoint reading method	AI reading
Use Point Offset	See Table 1
Band Monitoring Method at Process Start	Normal
Band Monitoring Invalid Time at Process Start	0.0
Band Monitoring Determination Method during Processing	No monitor
Band Monitoring Determination Time during Processing	0.0
Band Monitoring Value during Processing	0.00
Source Value Monitoring Valid	See Table 1
Source Value Monitoring Band	See Table 1
Pump Frequency	30 ~ 60
Initial Data	See Table 1
Overtemperature	40.00
Standed Wafer Detection Valid	Valid
Detect Time	3.00
Settling Determination Time	5.0
Settling Time-out Time	3600.0
Offset Setting Method	Control setting
Offset	0.00

Table 1

				I able I				
		Control	ler TM150-CHILLER	Plate Chilly Wafer temp.	Use Point Offset	Initial Data	Souce Value	Souce Value Monitoring
Configuration	Module	Channel No.	Monitoring Type	Temperature Control Method	Temperature Control Method	Temperature	Monitoring Valid	Band %
Non-CE TNE 4x4 Imm 8x0 TAQ	2-16 CPL	4	Use point control	Tmp ctl ON	Tool Specific	22.2	Valid	10
Non-CE TNE 4x4 Imm 8x0 TAQ	2-17 CPL	4	Use point read	Tmp ctl OFF	0.00	22.2	N/A	N/A
Imm	8-21 CPL	3	Use point control	Tmp ctl ON	Tool Specific	*	Valid	10
Imm	8-22 CPL	3	Use point read	Tmp ctl OFF	0.00	*	N/A	N/A
Dry	7-11 CPL	3	Use point control	Tmp ctl ON	Tool Specific	*	Valid	10
Dry	7-12 CPL	3	Use point read	Tmp ctl OFF	0.00	*	N/A	N/A
BARC	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A

^{*} NIKON = 22.2C AND ASML = 22.0C



Block 2 MP Block/ Block 3 PR Block/ Block 7 MP Block, S-CPL (SCPL) Modules

Reserved Flag	Invalid
Fork Simultaneous Swapping Level	1-2
Wafer Store Count	1
Start Slot	0

Plate Vacuum

Plate Vacuum	With
Plate Vac Control Info	
Plate Vac Check Start Timing	5000
DI-4- VOCCTii	2000

Monitoring parameter

Plate Chilly Water temp.

rate ching water temp	
Valid,Invalid	Valid
Measured Data ID	Plate Chilly Water
Recipe Setting Method	System recipe
Temperature Control Method	See Table
Recipe Verification Range Lower Limit	20.00
Recipe Verification Range Upper Limit	25.00

Controller TM150-CHILLER

Controller ID	TM150-CHILLER
Channel No.	See Table 2 next page
Monitoring Type	See Table 2 next page
Control Method	Standard
Usepoint reading method	AI reading
Use Point Offset	See Table 2 next page
Band Monitoring Method at Process Start	Normal
Band Monitoring Invalid Time at Process Start	0.0
Band Monitoring Determination Method during Processing	No Monitor
Band Monitoring Determine Time during Processing	0.0
Band Monitoring Value during Processing	0.00
Source Value Monitoring Valid	See Table 2 next page
Source Value Monitoring Band	See Table 2 next page
Pump Frequency	30 ~ 60
Initial Data	See Table 2 next page
Overtemperature	40.0
Standed Wafer Detection Valid	Valid
Detect Time	3.00
Settling Determination Time	5.0
Settling Time-out Time	3600.0
Offset Setting Method	Control setting
Offset	0.00

Table 2

				Table 2				
		Contro	ller TM150-CHILLER	Plate Chilly Wafer temp.	Use Point Offset	Initial Data	Souce Value	Souce Value Monitoring
Configuration	Module	Channel No.	Monitoring Type	Temperature Control Method	Temperature Control Method	Temperature	Monitoring Valid	Band %
TBL DRY w/ HTP TBM	2-15 SCPL	5	Use point control	Tmp ctl ON	Tool Specific	23	Valid	10
CE TNE TNG 6x6 Imm	2-23 SCPL	4	Use point control	Tmp ctl ON	Tool Specific	22.2	Valid	10
Non-CE TNE HVM TNE 4x4 Imm DRY w/ HTP TBM	2-23 SCPL	4	Use point read	Tmp ctl OFF	0	22.2	N/A	N/A
Dry / Imm	2-24 SCPL	4	Use point read	Tmp ctl OFF	0	22.2	N/A	N/A
Dry / Imm	2-25 SCPL	4	Use point read	Tmp ctl OFF	0	22.2	N/A	N/A
6x6 Imm	2-33 SCPL	5	Use point read	Tmp ctl OFF	0	23	N/A	N/A
6x6 Imm	2-34 SCPL	5	Use point read	Tmp ctl OFF	0	23	N/A	N/A
6x6 Imm	2-35 SCPL	5	Use point read	Tmp ctl OFF	0	23	N/A	N/A
Dry / Imm	3-41 SCPL	5	Use point control	Tmp ctl ON	Tool Specific	23	Valid	10
TBL / TBM CE TNE w/ HTP Non-CE TNE w/ HTP HVM-TNE w/ HTP TNG w/ HTP	3-41 SCPL	5	Use point read	Tmp ctl OFF	0	23	N/A	N/A
Dry / Imm	3-42 SCPL	5	Use point read	Tmp ctl OFF	0	23	N/A	N/A
Dry / Imm	3-43 SCPL	5	Use point read	Tmp ctl OFF	0	23	N/A	N/A
Non-CE TNE / HVM TNE / 4x4 Imm	7-33 SCPL	4	Use point read	Tmp ctl OFF	0	22.2	N/A	N/A
BARC / TBL Non-CE TNE w/ HTP HVM-TNE w/ HTP	7-33 SCPL	4	Use point control	Tmp ctl ON	Tool Specific	22.2	Valid	10
All ProV	7-34 SCPL	4	Use point read	Tmp ctl OFF	0	22.2	N/A	N/A
All ProV	7-35 SCPL	4	Use point read	Tmp ctl OFF	0	22.2	N/A	N/A
All ProV	7-43 SCPL	4	Use point read	Tmp ctl OFF	0	22.2	N/A	N/A
CE TNE w/ HTP TNG w/ HTP TBM	7-43 SCPL	4	Use point control	Tmp ctl ON	Tool Specific	22.2	Valid	10
All ProV	7-44 SCPL	4	Use point read	Tmp ctl OFF	0	22.2	N/A	N/A
All ProV	7-45 SCPL	4	Use point read	Tmp ctl OFF	0	22.2	N/A	N/A
DRY w/ HTP TBM	7-46 SCPL	4	Use point read	Tmp ctl OFF	0	22.2	N/A	N/A



Block 4 PR Block, C.ADH (ADH) Modules

Reserved Flag	Invalid
Fork Simultaneous Swapping Level	1-2
Wafer Store Count	1
Start Slot	0

Chamber Type

Chamber Type	STD Chamber
--------------	-------------

Cool Arm Parameter

Cool Arm Speed	STD Speed

Plate Type

 ite I j pe	
Plate Type	Type B

Module Parameter

Dispense Parameter - Local Nozzle - HMDS VAPOR

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid

Dispense Mechanism Connec	LUUII
Valid, Invalid	Valid

Dispense Monitoring Mechanism Connection
Valid, Invalid Val

Mass flow meter

	onitoring Type Mass flow meter
Dispense Monitoring Type	Mass flow meter

Supply System

Supply System	
Valid, Invalid	Valid

HMDS Supply System

Refill Monitoring Time	180 sec
Exhaust Value Close Delay Time	1.0 sec
HL Sensor Watch Time	4.0 sec

Automatic Air Vent

ratomatic rin vent	
Air Vent Monitoring Time	30 sec
Delay Time After LE Detection	1.0 sec
Prior Pressurization Time	5.0 sec

CHAMBER EXH.

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid

Dispense Mechanism Connection

Valid, Invalid	Valid

Dispense Monitoring Mechanism Connection

	Valid, Inva	lid	Valid
--	-------------	-----	-------

Mass flow meter	
D' M ' T	M C

	Upper	Limit	Warnin
--	-------	-------	--------

Pulse Rate	0.05
Delay Time	0.60
Set Flow Rate	2500
Flow Rate Sensor Check Timing	Dispense end
Calibration 1	Tool Specific
Offset	0
Upper Limit Error Level	30.00%
Upper Limit Warning Level	20.00%
Lower Limit Error Level	30.00%
Lower Limit Warning Level	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Invalid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0

Container Refill System

Valid, Invalid	Valid	
Prior Pressurization Time	20.0 sec	

Dispense Monitoring Control Data

Pulse Rate	0.05
Delay Time	0.60
Set Flow Rate	5000
Flow Rate Sensor Check Timing	Dispense end
Calibration 1	Tool Specific
Offset	0
Upper Limit Error Level	30.00%
Upper Limit Warning Level	20.00%
Lower Limit Error Level	30.00%
Lower Limit Warning Level	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid
Monitoring Flow Rate Upper Limit for Short Time Disp.	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0



Block 4 PR Block, C.ADH (ADH) Modules **BUFFER BUBBLING**

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid

Dispense Mechanism Connection

Valid, Invalid	Valid
----------------	-------

Monitoring parameter

Plate ten	ıp.
Valid Inva	lid

Valid,Invalid	Valid
Measured Data ID	Plate temp.
Recipe Setting Method	Process recipe
Temperature Control Method	Tmp ctl ON
Recipe Verification Range Lower Limit	50.00
Recipe Verification Range Upper Limit	180.00

Controller REX-B875

Controller REA-B8/5	
Controller ID	REX-B875
Channel No.	0
Monitoring Type	No sync
Control Method	Overshoot Rest ctrl
Band Monitoring Method at Process Start	Normal
Band Monitoring Invalid Time at Process Star	0.0
Band Monitoring Determination Method	No monitor
Band Monitoring Determination Time	1.0
Band Monitoring Value during Processing	3.00
PID Setting Method	Control setting
P Constant	0.45
I Constant	12.0
D Constant	3.0
Offset Setting Method	Table setting
Offset	0.00
Stranded Wafer Detection Valid	Valid
Initial Data	50.00
Overtemperature	185.00
Settling Determination Time	30.0
Settling Time-out Time	1800.0
Loop Break Alarm Function Valid/Invalid	Invalid

Control Table Data list (except for BE DRY Track listed below)

	Valid,Invalid	Setting Lower	Setting Upper	Accum Threshold	Accum Time
Temperature Range1	Valid	50.00	180.00	Not Input	Not Input
Temperature Range2	Valid	90.00	Not Input	37.00	10.000
Temperature Range3	Valid	110.00	Not Input	52.00	10.000
Temperature Range4	Valid	150.00	Not Input	80.00	10.000
Temperature Range5	Invalid	Not Input	Not Input	Not Input	Not Input
Temperature Range6	Invalid	Not Input	Not Input	Not Input	Not Input
Temperature Range7	Invalid	Not Input	Not Input	Not Input	Not Input

^{*} Wafer wedge set up by 3mm ring. (Wafer guide 3mm)

Control Table Data list for TBL, TBM and (BE193 TNE, TNG only)

	Valid,Invalid	Setting Lower	Setting Upper	Accum Threshold	Accum Time
Temperature Range1	Valid	50.00	180.00	Not Input	Not Input
Temperature Range2	Valid	90.00	Not Input	37.00	10.000
Temperature Range3	Valid	110.00	Not Input	52.00	10.000
Temperature Range4	Valid	150.00	Not Input	40.00	10.000
Temperature Range5	Valid	150.10	Not Input	80.00	10.000
Temperature Range6	Invalid	Not Input	Not Input	Not Input	Not Input
Temperature Range7	Invalid	Not Input	Not Input	Not Input	Not Input

^{*} Wafer wedge set up by 3mm ring. (Wafer guide 3mm)

Control Table Data All Other Temperature Ranges

	Table Data 1	
Offset	Not Input	
P	Not Input	
I	Not Input	
D	Not Input	

Control Table Data

(Temperature Range 150.00)

	Table Data 1
Offset	Module Specific
P	Not Input
I	Not Input
D	Not Input

Cool Arm Chilly Water temp.

Valid,Invalid	Valid
Measured Data ID	Water Temp
Recipe Setting Method	System recipe
Temperature Control Method	Tmp ctl OFF
Recipe Verification Range Lower Limit	20.00
Recipe Verification Range Upper Limit	25.00

Controller TM150-CHILLER

Controller ID	TM150-CHILLER
Channel No.	4
Monitoring Type	Use point read
Control Method	Standard
Use Point Reading Method	AI Reading
Use Point Offset	0.00
Band Monitoring Method at Process Start	Normal
Band Monitoring Invalid Time at Process Star	0.0
Band Monitoring Determination Method during Processing	No monitor
Band Monitoring Determination Time during Processing	0.0
Band Monitoring Value during Processing	0.00
Pump Frequency	30 ~ 60
Initial Data	22.20
Overtemperature	40.00
Settling Determination Time	5.0
Settling Time-out Time	3600.0
Offset Setting Method	Control setting
Offset	0.00



Block 2/ Block 7 MP Block, Buffer (SBU) Modules

Reserved Flag	Invalid	
Fork Simultaneous Swapping Level	Invalid	
Wafer Store Count	5 *	* 10 for 2-41 SBU only
Start Slot	1	

	MPRA	PRA
Pitch between Slots	1925	2666*

^{*=}Does not exist for 2-41 SBU

Block 2/ Block 4/Block 7 MP Block/ Block 8 IPB, Trans (TRS) Modules

Reserved Flag	Invalid
Fork Simultaneous Swapping Level	Invalid
Wafer Store Count	1
Start Slot	0

Block 4/ Block 5/ Block6 PR Block, Cup Wash (CWH) Modules

Reserved Flag	Invalid
Fork Simultaneous Swapping Level	Invalid
Wafer Store Count	1
Start Slot	0

Block 7 (DRY)/8 (Immersion), Shuttle (ISHU) Module

Reserved Flag	Invalid
Fork Simultaneous Swapping Level	Invalid
Wafer Store Count	2
Start Slot	0

Interface Shuttle Control Parameter

Speed Rate	100%
Maintenance Speed	50%
Receive Position	Tool Specific
Receive Wait Position	0
Send Position	Tool Specific
Send Wait Position	Tool Specific

Block 8 IPB, Resume (RSM) Modules

Reserved Flag	Invalid
Fork Simultaneous Swapping Level	Invalid
Wafer Store Count	1
Start Slot	0

Block 8 (DRY) / 9 (Immersion) IFB Sub, Exposure Interface (EIF) Modules

Reserved Flag	Invalid
Fork Simultaneous Swapping Level	Invalid
Wafer Store Count	Tool Specific
Start Slot	0

^{*} Scanner dependent: ASML=15 , Nikon=5

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7. AMHS Parameter

AMHS Monitor Timer

AMHS Maker	E84
AMHS TYPE	Type 4
Timer 1 Load(Unload) Request ON => TR Request ON	2
Timer 2 Ready ON => Busy ON	2
Timer 3 Busy ON => Carrier Detect(Remove)	60
Timer 4 Load(Unload) Request => Busy OFF	60
Timer 5 ready OFF => Valid OFF	2
Timer 6 Valid OFF => Valid ON(Continuous Handoff)	2
Curtain Sensor	Invalid

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GJG

SW Access before Carrier Load	Unnecessary
SW Access after Carrier Load	Unnecessary
SW Access before Carrier Unload	Unnecessary
SW Access after Carrier Unload	Unnecessary
Carrier Detect Timer	20000 msec
Carrier Confirm Timer	10000 msec
Carrier Load Complete Timer	20000 msec
Carrier Unload Complete Timer	20000 msec
Unclamp Control in Automatic Mode	After Undock
\"CJ Pausing\" Alarm Issue	Execute
\"PJ Pausing\" Alarm Issue	Execute
Verify Skip Setting in Local Mode	Not Execute
Option The Number of Remaining Wafers before Reporting Carrier Approaching Completion Event	0

Others

Automatic Registration Editor Level	Initialize Screen Level
LoadportTransfer Operation Level	User Service
Alarm Recovery Operation Level	User Service
Ingenio GL user account	Fixed Ingenio GL user account
WEE Centering Monitoring Range Setting	2000 um
NCSX	Valid
Time before Screen Saver Activation	10 (Default) min
Prevention of Dispensing Outside of Cup by Spinner Recipe Verification	Valid
Dispensing Invalidation during Wafer Processing	Invalid
Monitoring Time Setting for Resist Un-dispensing	300 sec
Protection Against Incorrect Setting of Exhaust Control in COT Recipes	Invalid
Protection Against Incorrect Setting of Exhaust Control in DEV Recipes	Invalid
Acceptable Delay Time before Reporting Macro Inspection Result	30 sec
MCI Heart Beat	Invalid
DDS mis-detection prevention function at time equipped with DDS	Invalid
Dispense 128 Online Support	Valid
Band Range Verification for Plate Temperature of ADH-Type Module (Thick Hot Plate)	Invalid
Band Range Verification for Plate Temperature of ADH-Type Module (Thin Hot Plate)	Invalid
DCI Heart Beat	Invalid
Delay time after pin-up of ISHU OUT side	0.00sec
Monitor at PIN UP Operation Upper Limit Time (Movable Chamber Oven)	1500ms
Monitor at PIN UP Operation Upper Limit Time (Fixed Chamber Oven)	1500ms
Monitor at PIN UP Operation Upper Limit Time (CPL-Type)	1500ms
Monitor at PIN UP Operation Lower Limit Time (Movable Chamber Oven)	400ms
Monitor at PIN UP Operation Lower Limit Time (Fixed Chamber Oven)	400ms
Monitor at PIN UP Operation Lower Limit Time (CPL-Type)	400ms
Automatic ESD collection	Invalid
Guard against Interference of Arm and Cup in Spinner Module	Valid
Recipe Verification Warning Display for Unset External Control Data	Display
Dispense Parameter Log Output at Parameter Transfer	Invalid
Self-diagnostic information logging	Valid
Brush Pressure Setting during BST wafer Processing	Invalid
Time Interval between Rechecking of Upstream Linked Recipes	200 ms
Recipe Security for TEL User	Valid
New Transfer Arm Control	Valid
Change of CRD Pump Pressure Settlement Timing	Valid
	0 ms without speed controllers
Option Delay Time before Pin Up after Chuck Vacuum OFF in Spinner Module	1200 ms with speed controllers
Option Upper Limit of Spin Speed When Dispensing with IE NOZZLE *	0 rpm
Option Lower Limit of Spin Speed When Dispensing with IE NOZZLE *	0 rpm
Option Wafer Spin Speed Upper Limit at Bevel Rinse V2 Dispensing	0 rpm
Option Automatic Dispensing with RRC Nozzle after DFT	Invalid

^{* =} Does not Exist on DRY or BARC tools

8. System Parameter

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Others(cont)

Option Upper limit of Wafer Acceleration When Dispensing with IE NOZZLE *	3000 rpm/sec
Option Optimized Offset Transfer at Manual Transfer of Wafer Flow Recipe *****	Valid
Option Setting for Excluding Specified Module from Wafer Flow in Online Remote	HOST
Option Detection of Shared Arm Z-Axis Belt Break****	Valid
Option Dispense Line Monitor *******	Valid
Option Pin Speed Selection for COT-Type Module	High Speed
Option Spinner System Module Detection of Belt Break Detection of Belt Break****	Valid
Option Margin Time at DEV Shared Arm Performance Improvement***	7.0 sec
Option Resist Dispensing Interval Verification for Dummy Dispense Process and Nozzle tip Wash	Valid
Option Standby time after dispense for PIR*	0.5sec
Option Standby time after dispense for SRS*	0.5sec
Option Estimated Disp. Press. Display (Pump/018)****	Display
Option Vent Exclusion Function for Shared Drain Line	Valid
Option Upper Limit of Wafer Spin Speed in XDR N2 Dispense Step ******	1100 rpm

^{* =} Does not Exist on DRY or BARC tools

Wafer Collection

Wait Time for Wafer Collection from Exposure	180000 msec
Rejected Wafer Collected in:	End Carrier
Real-time Save Recovery Info	Valid

Cup Wash

Executing Cup Wash Alarm Issue	Invalid
Alarm Output during Duct Wash	Valid
Washing Nozzle Tip Alarm Issue	Invalid
Parallel Module Wash Setting	VALID(All Spinners)
Cup Wash Execution When Wafer Exists in Another Cup in Same Layer	Not Execute Cup Wash
Interlock against Unset Nozzle Tip Wash	Warning and Stop
Option Automatic Cup Wash Skip	Valid(Alarm Off)
Option Post-Cup-Wash Cooling Time	0 sec

Monitoring

Recipe Verification against Unset Temperature Offset and Chamber FB Fixed Temp	Warning Setting
Wafer Transfer pausing against Unset Temperature Offset and Chamber FB Fixed Temp	Warning Setting
Option Interlock Setting at Stranded Wafer Detection	No Cycle Stop
Option Temperature Change MAP Customization	Valid*

^{*} ONLY on BARC tools

Maintenance

Notify Time to Replace Chemical, etc.	Invalid
Option Consecutive Executions of Replacing Chemical Bottle and Cleaning Dispense information	Valid
Option Operation-Less RIA Alarms	Valid (PURGE Class Only)

Basic Transfer Control

PJ End Specification for Multiple PJs Execution	PJ End
Wafer Send OUT Stop due to Inspect, Measure Tool Error	Execute
Wafer Send OUT Control at Resist Temperature Change	Valid
Wafer Send OUT Control at Hot Plate Temperature Change	Invalid

^{*** =} Doesn't Exist for BARC Tools

^{****=} Does not exist on CRD systems

^{*****} Requires CNP-0058i and SW Patch to show this parameter

^{***** =} It is only present on tools with CD Optimizer installed.

^{****** =} Only present on tools with XDR function

^{****** =} Enabled PPM software tools

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Basic Transfer Control (cont)

Cascade Process for High Speed Temperature Change	Valid
Upper Limit of Wafer Stay Time in Exposure	18000 msec
FIMS Door in Down Position Check	Valid
Control of Wafer Send Out to Exposure System	Valid
Monitoring Time Setting for Transfer Delay after Exposure System Trouble	0 sec
Wafer Transfer during Pump Reloading	Valid

Special Transfer Control

Wafer Transfer Excluding Specified Module	Invalid
TRANS Arm Init Wafer Count	0
TRANS Arm ALM Output Wafer Count	0
Cup Wash Cascade	Valid
WISD Bypass Control to Maintain Equipment Productivity	Invalid
Step Count Available for Sending PJ_CREATE to IM	5 step
Option Parallel Flow Control	Execute
Option Skip EIF From Trouble Wafer in Immersion System	Valid, without shortcut*
Option Prime Cascade Mode (Coating Flow)	Prioritize Throughput
Option Prime Cascade Mode (Development Flow)	Prioritize Throughput
Option Specifying Exclusion Alarm	Not Execute

^{*=} NOT USED FOR BARC CONFIGURATION

Bare-Si Thickness

Bare-Si Thickness Unit	nm
Option Base Barometric Pressure	* hPa

* Portland / Ireland: 1010.00hPa

* Phoenix: 970.00hPa * Albuquerque: 840.00hPa * Israel: 1000.00hPa

Equipment State Management

The "PAST log Output" function	Invalid
•	

Exposure Interface

Exposure Maker	Tool Specific*
Exposure Type	Tool Specific**
Exposure Carrier End Setting	Invalid
Exposure in Local Interlock Setting	Valid
Exposure APR Setting	***
EIF IN READY Wait Time	10000 msec
EIF Initialize Condition	Confirm ARM-signal
Exposure in Near Ready Setting	Invalid
Option Exposure Lot End Output	Execute
Option Linked Litho Application [Not Present for BARC]	Valid
Option Linked Litho Alarm Auto Recovery [Not Present for BARC]	Valid
Option Linked Litho Alarm Auto Timer [Not Present for BARC]	1000 msec
Option Linked Litho No Wafer Exposure Lot End [Not Present for BARC]	Execute

 $[\]star \overline{\ \ \ } Select\ "Nikon"\ \ for\ [TNE/TNG/TNS/TNR/TNQ/TNU/TNK]\ or\ "ASML"\ for\ [TAQ/TAR/TAS/TAU/TBL/TBM]\ or\ NONE\ for\ BARC,\ linked\ STP\ dependant.$

Dummy Dispense

Interlock with Dummy Dispense Recipe Unregistered	Valid
Prevention of Chemical Stream Crossing during Dummy Dispense Process	Valid
Option Change of Periodic Dummy Dispense Process Timing with DFT Disable	Invalid
Option Monitoring Time of Wafer Transfer Stop for Interval Dummy dispense Execution during PJ	10
Option Start Time of Periodic Resist Return Operation during Wafer Transfer Stop *	300 sec

^{*} IR function valid tool

^{**} ASML: TYPE 2, Nikon: TYPE 4, BARC: Type 1

^{***} Valid for ASML links, Invalid for others

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9. Equipment State Parameter

Wafer in Carrier Send OUT/IN Order Definition Group

Wafer in Carrier Send OUT/IN Order Information

Stage Type	Uni-Cassette
Send OUT Order/Send IN Order	Bottom

Wafer in Carrier Send OUT/IN Order Information

Stage Type	Pickup Stage
Send OUT Order/Send IN Order	Тор

10. Adjustment Tool Parameter

Transfer Arm No. 1-0 Calibration Data[1-0]

ArmBlockNo	1
ArmModuleNo	0

Tool Specific

DataId	Tool Specific
CalibModuleBlockNo	1
CalibModuleModuleNo	1
ToolSerialNo	Tool Specific

ForkPosition

ForkNo	1
PositionX	Not Input
PositionY	Not Input
PositionZ	Not Input
PositionTh	Not Input

Transfer Arm No. 2-0 Calibration Data[2-0]

1	ArmBlockNo	2
	ArmModuleNo	0

Tool Specific

DataId	Tool Specific
CalibModuleBlockNo	2
CalibModuleModuleNo	16
ToolSerialNo	Tool Specific

ForkPosition

ForkNo	1
PositionX	Not Input
PositionY	Not Input
PositionZ	Not Input
PositionTh	Not Input

Transfer Arm No. 3-0 Calibration Data[3-0]

ArmBlockNo	3
ArmModuleNo	0

Tool Specific

1 001 Specific	
DataId	Tool Specific
CalibModuleBlockNo	3
CalibModuleModuleNo	1
ToolSerialNo	Tool Specific

ForkPosition[0]

FOI KF OSITION[0]	
ForkNo	1
PositionX	Tool Specific
PositionY	Tool Specific
PositionZ	Tool Specific
PositionTh	0

ForkPosition[1]

ForkNo	2
PositionX	Tool Specific
PositionY	Tool Specific
PositionZ	Tool Specific
PositionTh	0

10. Adjustment Tool Parameter

Transfer Arm No. 4-0 Calibration Data[4-0]

ArmBlockNo	4
ArmModuleNo	0

Tool Specific	Resist Tracks	BARC Tracks	TBL Tracks
DataId	Tool Specific	Tool Specific	Tool Specific
CalibModuleBlockNo	4	4	2
CalibModuleModuleNo	1	42	24
ToolSerialNo	Tool Specific	Tool Specific	Tool Specific

ForkPosition[0] for Resist Tracks

ForkNo	1
PositionX	Tool Specific
PositionY	Tool Specific
PositionZ	Tool Specific
PositionTh	0

ForkPosition[1] for Resist Tracks

ForkNo	2
PositionX	Tool Specific
PositionY	Tool Specific
PositionZ	Tool Specific
PositionTh	0

ForkPosition[0] for TBL and BARC Tracks

ForkNo	1
PositionX	Tool Specific
PositionY	249865
PositionZ	Tool Specific
PositionTh	Tool Specific

ForkPosition[1] for TBL and BARC Tracks

ForkNo	2
PositionX	Tool Specific
PositionY	249865
PositionZ	Tool Specific
PositionTh	Tool Specific

Transfer Arm No. 5-0 Calibration Data[5-0]

ArmBlockNo	5
ArmModuleNo	0

Tool Specific

1001 8 peeme	
DataId	Tool Specific
CalibModuleBlockNo	5
CalibModuleModuleNo	1
ToolSerialNo	Tool Specific

ForkPosition[0]

ForkNo	1
PositionX	Tool Specific
PositionY	Tool Specific
PositionZ	Tool Specific
PositionTh	0

ForkPosition[1]

ForkNo	2
PositionX	Tool Specific
PositionY	Tool Specific
PositionZ	Tool Specific
PositionTh	0

Transfer Arm No. 6-0 Calibration Data[6-0]

ArmBlockNo	6
ArmModuleNo	0

Tool Specific

DataId	Tool Specific
CalibModuleBlockNo	6
CalibModuleModuleNo	1
ToolSerialNo	Tool Specific

ForkPosition[0]

ForkNo	1
PositionX	Tool Specific
PositionY	Tool Specific
PositionZ	Tool Specific
PositionTh	0

ForkPosition[1]

ForkNo	2
PositionX	Tool Specific
PositionY	Tool Specific
PositionZ	Tool Specific
PositionTh	0

10. Adjustment Tool Parameter

Transfer Arm No. 7-0 Calibration Data[7-0]

ArmBlockNo	7
ArmModuleNo	0

Tool Specific

DataId	Tool Specific
CalibModuleBlockNo	7
CalibModuleModuleNo	46
ToolSerialNo	Tool Specific

ForkPosition

I OI KI OSILIOII	
ForkNo	1
PositionX	Not Input
PositionY	Not Input
PositionZ	Not Input
PositionTh	Not Input

Transfer Arm No. 8-0 (DRY/Immersion) Calibration Data[8-0]

ArmBlockNo	8
ArmModuleNo	0

Tool Specific

DataId	Tool Specific
CalibModuleBlockNo	Tool Specific
CalibModuleModuleNo	Tool Specific
ToolSerialNo	Tool Specific

ForkPosition[0]

ForkNo	1
PositionX	Tool Specific
PositionY	Not Input
PositionZ	Tool Specific
PositionTh	Tool Specific

ForkPosition[1]

ForkNo	2
PositionX	Tool Specific
PositionY	Not Input
PositionZ	Tool Specific
PositionTh	Tool Specific

Transfer Arm No. 9-0 (Immersion) Calibration Data[9-0]

ArmBlockNo	9
ArmModuleNo	0

Tool Specific

1 our speeme	
DataId	Tool Specific
CalibModuleBlockNo	Tool Specific
CalibModuleModuleNo	Tool Specific
ToolSerialNo	Tool Specific

ForkPosition[0]

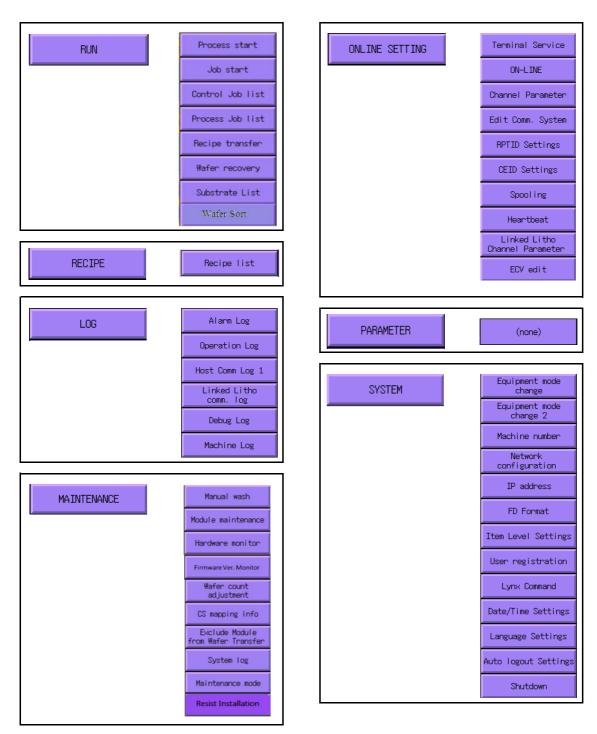
1 01111 05111011[0]	
ForkNo	1
PositionX	Tool Specific
PositionY	Tool Specific
PositionZ	Tool Specific
PositionTh	Tool Specific

ForkPosition[1]

ForkNo	2
PositionX	Tool Specific
PositionY	Tool Specific
PositionZ	Tool Specific
PositionTh	Tool Specific

11. EC Display Overview

Screen Tree



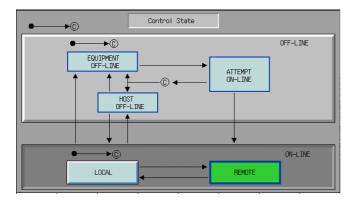
^{*} Settings are available on tracks linked to scanners.

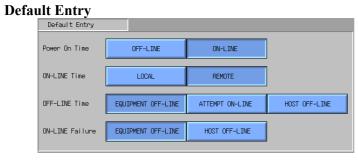


Terminal service

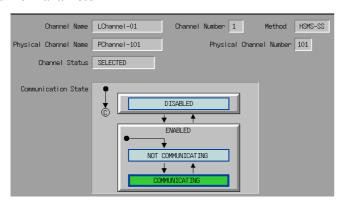


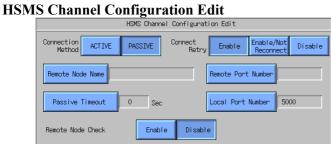
ON-LINE





Channel Parameter

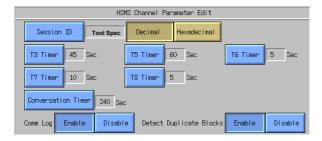




HSMS Channel Configuration Edit Detail



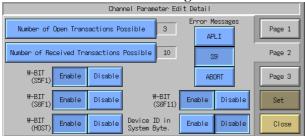
HSMS Channel Parameter Edit



Channel Parameter Edit Detail Page 1



Channel Parameter Edit Detail Page 2



Channel Parameter Edit Detail Page 3

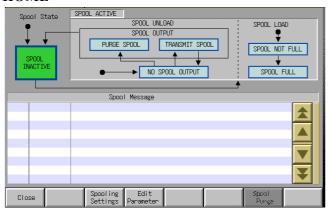


Communication Parameter

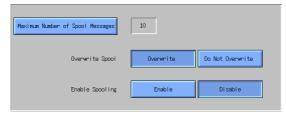


Spooling Setting

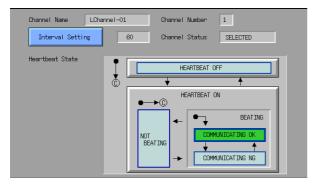
HOME



Edit Parameter



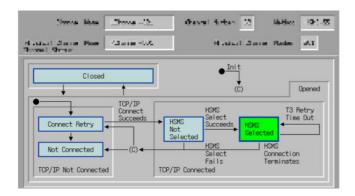
Heartbeat





Linked Litho Channel Parameter*

*settings are available only on tracks linked to scanners.



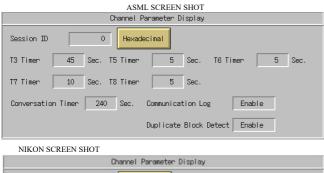
Config Display



Config Display Detail



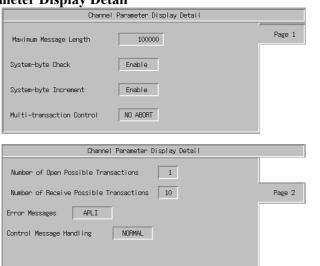
Parameter Display



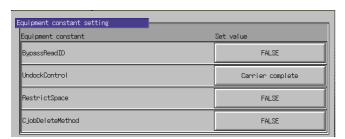


Linked Litho Channel Parameter * *settings are available only on tracks linked to scanners.

Parameter Display Detail



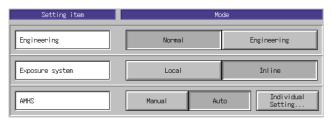
ECV edit





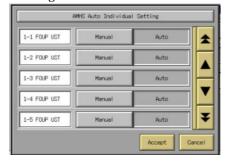
13. EC SYSTEM Setting

Equipment mode change

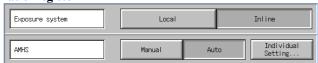


*LOCAL For BARC

Individual Setting

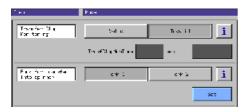


Automatic Register



*LOCAL For BARC

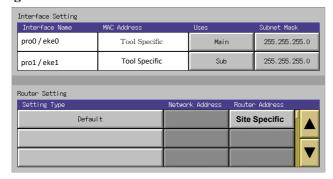
Equipment mode change 2





FOR BARC

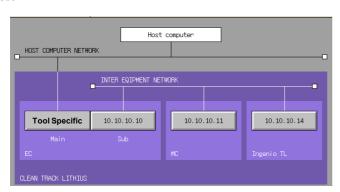
Network configuration



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13. EC SYSTEM Setting

IP address



13. EC SYSTEM Setting

Item Level Settings

Group Menu	Item Menu	Item Level
	Initialize	Maintainer *
	Process start	Operator
	Job start	Operator
	Control Job list	Operator
RUN	Process Job list	Operator
	Recipe transfer	Operator
	Wafer recovery	Maintainer
	Substrate List	Operator
	Aging Start	Maintainer **
	Wafer Sort	Service
RECIPE	Recipe list	Operator
	Alarm Log	Operator
	Operation Log	User service
100	Host Comm Log 1	User service
LOG	Linked Litho Log	User service ***
	Debug Log	User service
	Machine Log	User service
	Manual wash	Maintainer
	Module maintenance	Maintainer
	Hardware monitor	Operator
	Firmware Ver. Monitor	User Service
MAINTENANCE	Wafer count adjustment	Maintainer
MAINTENANCE	CS mapping info	Maintainer
	System log	User service
	Exclude Module	User Service
	Maintenance mode	Maintainer
	Resist Installation Assistance****	Maintainer
	Terminal Service	Operator
	ON-LINE	Operator
	Channel Parameter	Operator
	Edit Comm. System	User service
ONLINE SETTING	RPTID Settings	User service
ONLINE SETTING	CEID Settings	User service
	Spooling	User service
	Heartbeat	Service
	Linked Litho Channel Parameter ***	User service ***
	ECV edit	User service
	Equipment mode change	Maintainer
	Equipment mode change 2	Service
	Machine number	User service
	Network configuration	User service
	IP address	User service
	FD Format	Operator
SYSTEM	Item Level Settings	Service
	User registration	Service
	Lynx Command	User service
	Date/Time Settings	User service
	Language Settings	User service
	Auto logout Settings	User service
	Shutdown	User service

^{*} Must be audited prior to completion of the track initialization.

** Must be audited with track in Engineering mode.

*** For Linked Litho VALID system only.

**** For ACRD systems ONLY

Auto logout Settings

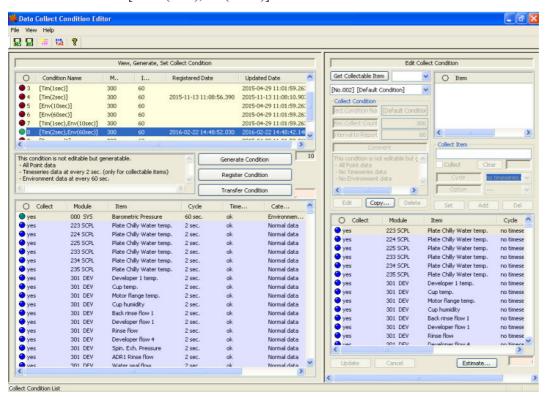


14. Data Collect Condition Editor

Data Collect Condition Editor can be found in the Ingenio within the Start\Lithius Clean Track directory

Verify that Data Collect Condition Editor has been set up with the following condition name generated, registered, and transferred

Condition Name: [Time (2sec),Env(60sec)]



CIM Control Number: 09TEA-CT-00192-1.00

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15. Parameter Editor

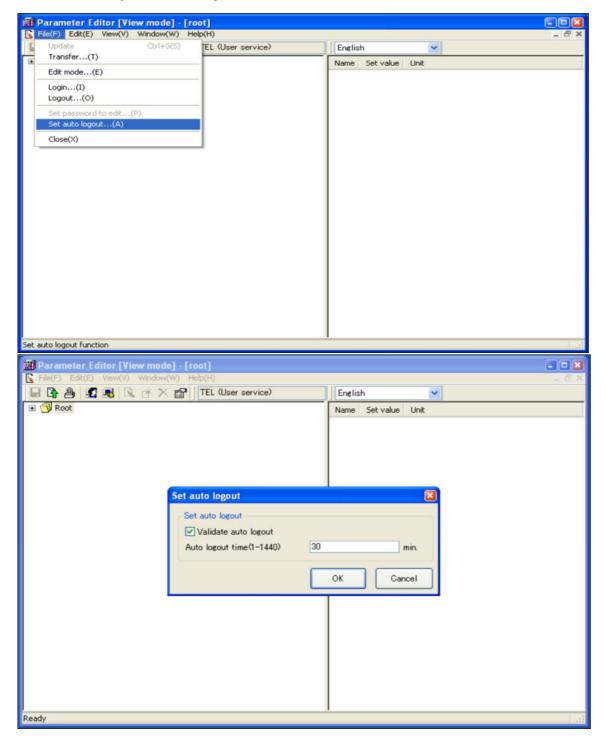


(Parameter Editor can be found in the Ingenio within the Start\LITHIUS ProV Clean Track directory)

Auto logout setting

Validate Auto Logout	Validate
Auto Logout Time	30 min.

*Location of setting is shown in the picture as below.



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Hardware FPD Revision History (1/5)

Date	Rev.	Appro		Location	Old	New											
2/25/2014	1.00	INTEL V. Dreeter	TEL Sam. S	Original Release	NI/A	100.0.53.6 MCr287											
3/25/2014	1.00	K. Proctor	Jaill. 3	Section 2.SYSTEM(FAB) - Updated DEV and NTD Exhaust Supply Description	N/A N/A	Update to config Type description											
				Section 3.SYSTEM(SUB-FAB) - Update to LNR VAC setting	-45kPa	-65kPa											
				Section 3.SYSTEM(SUB-FAB) - Update to LNR VAC U/L Limit settings	-29.0	-49.0											
				Section 3.SYSTEM(SUB-FAB) - Update DEV Sol 2 source location	-99.9 DEV Cabinet	-99.9 COT Cabinet											
				Section 3.SYSTEM(SUB-FAB) - Update DEV Cabinet to include new DIW supply pressure if C.V.P is installed	N/A	Added											
				Section 3.SYSTEM(SUB-FAB) - Update DEV Cabinet to include C.V.P pressure settings	N/A	Added											
				Section 4.DEV - Addition on new INTEL Cup Height range spec. Section 4.DEV - Addition on new INTEL Cup Height range spec.	N/A N/A	0.2mm from the 3 adj pts 0.5mm from all 6 measurement pts											
				Section 4.DEV - Update tolerance for NTD INTEL cup height adjustments	2.3 ~ 3.3	2.6 ~ 3.0											
0.5.00.00.4.4		** **		Section 5.COT TCT BCT - Addition on new INTEL Cup Height range spec.	N/A	0.2mm from the 3 adj pts											
05/28/2014	1.01	K. Proctor	Sam. S	Section 5.COT TCT BCT - Addition on new INTEL Cup Height range spec. Section 5.COT TCT BCT - Update tolerance for BCT INTEL cup height adjustments	N/A 2.3 ~ 3.3	0.5mm from all 6 measurement pts $2.6 \sim 3.0$											
				Section 5.COT TCT BCT - Update tolerance for COT INTEL cup height adjustments	2.3 ~ 3.3	2.6 ~ 3.0											
				Section 5.COT TCT BCT - Update tolerance for TCT INTEL cup height adjustments	2.0 ~ 3.0	2.3 to 2.7											
				Section: 6.PIR SRS BST - Update tolerance for NTD INTEL cup height adjustments Section: 6.PIR SRS BST - Addition on new INTEL Cup Height range spec.	2.3 ~ 3.3 N/A	$2.6 \sim 3.0$ 0.2mm from the 3 adj pts											
				Section: 6.PIR SRS BST - Addition on new INTEL Cup Height range spec.	N/A	0.5mm from all 6 measurement pts											
				Section: 6.PIR SRS BST - Addition of the BST Local Exhaust setting	N/A	> -13											
				Section 2.SYSTEM(FAB) - Updated the Chem L Exhaust Range	50 to 250 Sub-Op can see both times for L/R.	50 to 300											
				Section: 7 OVEN - Update to remarks for all ovens with moving chambers - Chamber-R/L OPEN / CLOSED	Accurate UP/DOWN, review times and set speed accordingly	L/R Must Match											
				Section 2. SYSTEM(FAB) - CSB - Load Port Air Supply Setting - Remarks	ONLY if Split LP CT-PCP-13-0007 is	ONLY if Split LP CT-PCP-13-0007 Rev											
				Section 2. SYSTEM(FAB) - PRB - Spinner Wind Pressure-L - Tool Setting	complete 175	is complete 200											
				Section 2. SYSTEM(FAB) - PRB - Spinner Wind Pressure-R - Tool Setting	175	200											
				Section 2. SYSTEM(FAB) - PRB - Spinner Wind Pressure-L *	N/A	Added *=TAX and TNU ONLY											
				Section 2. SYSTEM(FAB) - PRB - Spinner Wind Pressure-R * Section 2. SYSTEM(FAB) - PRB - Spinner Wind Pressure-L * - Remarks	N/A Dual Resist Arm COT Tools	Added *=TAX and TNU ONLY Removed comments											
				Section 2. SYSTEM(FAB) - PRB - Spinner Wind Pressure-R * - Remarks	Dual Resist Arm COT Tools	Removed comments											
				Section 2. SYSTEM(FAB) - IPRB** - Positive Pressure (PIR/SRS) - TEL Std	PIR/SRS =PRAi</td <td>PIR/SRS>/=PRAi</td>	PIR/SRS>/=PRAi											
				Section 3. SYSTEM(SUB-FAB) - Constant Pressure Valves - DEV Rinse Nozzle - Tolerance Section 3. SYSTEM(SUB-FAB) - Constant Pressure Valves - Title for Description of setting	0.15 ~ 0.17 N/A	0.25 ~ 0.27 Matched title between FPD and Tool											
							Section 5. COT/TCT/BCT - COT- Middle Cup Height - Tool Setting	2.8	3.2								
				Section 5. COT/TCT/BCT - COT- Middle Cup Height - Tolerance	2.6 ~ 3.0	2.8 ~ 3.6											
					COT Spinner was BV Cup	COT Spinner year BV Cun											
						COT Spinner uses PV Cup [Torque 75cn*m] Check current Torque Do	COT Spinner uses PV Cup [Torque 75cn*m] Check current Torque I										
08/07/2014	1.02	K. Proctor	P. Ito	Section 5. COT/TCT/BCT - COT- Middle Cup Height - Remarks	Direct reading will be 2.0mm from the TOF												
					of the wafer to the top of the middle cup	of the wafer to the top of the middle cu											
				Section 5. COT/TCT/BCT - COT/BCT - Resist / RRC Center Nozzle Height - Remarks	Measure from the top of the resist bath to the bottom of the resist nozzle base.	Measured from top of wafer surface on chuck											
				Section 5. COT/TCT/BCT - COT/BCT - Resist Nozzle Height Home Position - Remarks	Set by using measuring scale	Set by using measuring scale Measure from the top of the resist bath to the bottom of resist nozzle base.											
				Section 6. PIR/SRS/BST - BST+	N/A	Added											
				Section 7. OVEN - TRS/SBU/RSM	N/A	Merge TRS and SBU section, and add RS											
				Section 9. Sensor Setting - CRD - RESIST Pump Purge - SPED Section 9. Sensor Setting - CRD - RESIST Pump Purge - Comment	2.5* * TKL setting is 5.0	2.5 Removed comments											
				Section 9. Sensor Setting - CRD - AMC N2 Purge - SPED	2.5*	2.5											
															Section 9. Sensor Setting - CRD - AMC N2 Purge - Comment	* TKL setting is 5.0	Removed comments
				Section 9. Sensor Setting - BST+ - BST Back Side Air Nozzle Section 9. Sensor Setting - BST+ - BST Wafer Edge Air Nozzle	N/A N/A	Added Added											
				Section 4. DEV - DEV/NTD - Knife Edge Height - Tool Setting	1.0	-1.0											
				Section 4. DEV - DEV/NTD - Knife Edge Height - Tolerance	0.8 to 1.2	-0.8 to -1.2 3 points of measurement, gauge doesn'											
				Continue A DEVI. DEVIAVED. Maio, Ed., Haida B.	3 points of measurement, gauge doesn't	move during Cup UP/DOWN[Torque											
				Section 4. DEV - DEV/NTD - Knife Edge Height - Remarks	move during Cup UP/DOWN	75cn*m] Check current Torque DocUs											
						Digital cup height JIG											
					COT Spinner uses PV Cup[Torque 75cn*m	COT Spinner uses PV Cup[Torque 75cn* Check current Torque DocDirect readin											
				Section 5. COT/TCT/BCT - COT - Middle Cup Height - Remarks	Check current Torque DocDirect reading	will be 2 4mm from the TOP of the wafer											
					will be 2.4mm from the TOP of the wafer to the top of the middle cup.	the top of the middle cup.											
					and top of the initialic cup.	Use Digital cup height JIG											
					COT Spinner uses PV Cup[Torque 75cn*m	COT Spinner uses PV Cup[Torque 75cn* Check current Torque DocDirect readin											
				Section 5. COT/TCT/BCT - BCT TAX ONLY - Middle Cup Height - Remarks	Check current Torque DocDirect reading	will be 2.0mm from the TOP of the wafer											
08/13/2014	1.03	C. Allen	P. Ito		will be 2.0mm from the TOP of the wafer to the top of the middle cup.	the top of the middle cup.											
				Section 5. COT/TCT/BCT - BCT BARC ONLY - Middle Cup Height - Tool Setting	2.5	Use Digital cup height JIG											
				Section 5. COT/TCT/BCT - BCT BARC ONLY - Middle Cup Height - Tolerance	2.3 to 2.7	-2.5 -2.3 to -2.7											
					BCT Spinner uses TCT Cup[Torque	BCT Spinner uses TCT Cup[Torque											
				Section 5. COT/TCT/BCT - BCT BARC ONLY - Middle Cup Height - Remarks	75cn*m] Check current Torque DocMeasured from the bottom of the wafer	75cn*m] Check current Torque											
				- Transition Del Del Delle Grad - Indiane Cap Holgin - Remarks	to the top of the INNER cup. Use Digital	DocMeasured from the bottom of the wa											
				a - C DID ODGOT DID ODG W 'S DI W'IL TI IS -	cup height JIG	to the top of the INNER cup.											
				Section 6. PIR/SRS/BST - PIR/SRS - Knife Edge Height - Tool Setting Section 6. PIR/SRS/BST - PIR/SRS - Knife Edge Height - Tolerance	2.5 2.3 ~ 2.7	-2.5 -2.3 ~ -2.7											
				osenon v. 1 nvorcas Do 1 = 1 nvorca = reinic Euge freignt = 1 orefance	2.3 ~ 2.1	-2.3 ~ -2.7 Measured @ 3 points Set by using PRO-											
					Measured @ 3 points Set by using PRO-V	tool[Torque 75cn*m] Check current Torc											
				Section 6. PIR/SRS/BST - PIR/SRS - Knife Edge Height - Remarks	Measured @ 3 points Set by using PRO-V tool	DocMeasured from the bottom of the wa											
						to the top of the INNER cup Use Digital of											
				1	1	height JIG											





Date	Rev.	Appro INTEL	oval TEL	Location	Old	New
				Section 4. DEV - NTD - Middle Cup Height - Remarks	NTD with IC cup	Use Digital cup height JIGNTD with Io cup[Torque 75cn*m] Check current Tor Doc
				Section 5. COT/TCT/BCT - BCT TAX ONLY - Middle Cup Height - Remarks	-	BCT Spinner for TAX tools uses PV C
				Section 5. COT/TCT/BCT - BCT BARC ONLY - Middle Cup Height - Remarks	-	BCT Spinner for BARC tools uses TCT
				Section 5. COT/TCT/BCT - COT/BCT - Resist Nozzle Height Home Position - Tool Setting Section 5. COT/TCT/BCT - COT/BCT - Resist Nozzle Height Home Position - Tolerance	4.5 4.0 ~ 5.0	4.5 * / 6.5 4.0 ~ 5.0 * /6.0 ~ 7.0
				Section 5. COT/TCT/BCT - COT/BCT - Resist Nozzle Height Home Position - Remarks	Set by using measuring scale Measure from the topo the resist bath to the bottom of the resist nozzle base	Set by using measuring scale Measure fr
				Section 7. OVEN - CPRP/CPHP/CHCH/CGCH/CSWP - Module	N/A	Added "CPHP"
				Section 7. OVEN - CPRP/CPHP/CHCH/CGCH/CSWP - CGCH/CHCH - Module Exhaust Setting (E9) - Tool Setting Section 7. OVEN - CPRP/CPHP/CHCH/CGCH/CSWP - CGCH/CHCH - Module Exhaust Setting (E9) - Tolerance	265 245 to 275	550 520 - 580
12/11/2014	1.04	K. Proctor	P. Ito	Section 7. OVEN - CPRP/CPHP/CHCH/CGCH/CSWP - CGCH/CHCH - Module EXH U/L Setting (Nagano Keiki) (E9) - Tool Setting	305	580
				Section 7. OVEN - CPRP/CPHP/CHCH/CGCH/CSWP - CGCH/CHCH - Module EXH L/L Setting (Nagano Keiki) (E9) - Tool Setting	225	520
				Section 7. OVEN - CPRP/CPHP/CHCH/CGCH/CSWP - CGCH/CHCH - Module Exhaust Setting (E16) - Tool Setting	210	500
				Section 7. OVEN - CPRP/CPHP/CHCH/CGCH/CSWP - CGCH/CHCH - Module Exhaust Setting (E16) - Tolerance Section 7. OVEN - CPRP/CPHP/CHCH/CGCH/CSWP - CGCH/CHCH - Module EXH U/L Setting (Nagano Keiki) (E16) - Tool	190 to 230	470 - 530
				Setting	250	530
				Section 7. OVEN - CPRP/CPHP/CHCH/CGCH/CSWP - CGCH/CHCH - Module EXH L/L Setting (Nagano Keiki) (E16) - Tool Setting	170	470
				Section 7. OVEN - CPRP/CPHP/CHCH/CGCH/CSWP - CGCH/CHCH - Individual Chamber Exhaust Setting - Tool Setting	9.4 7.4 - 11.3	19.0 16.0 - 22.0
				Section 7. OVEN - CPRP/CPHP/CHCH/CGCH/CSWP - CGCH/CHCH - Individual Chamber Exhaust Setting - Tolerance Section 7. OVEN - CPRP/CPHP/CHCH/CGCH/CSWP - CGCH/CHCH - Individual Chamber Exhaust U/L Setting - Tool Setting	11.3	22.0
				Section 7. OVEN - CPRP/CPHP/CHCH/CGCH/CSWP - CGCH/CHCH - Individual Chamber Exhaust L/L Setting - Tool Setting	7.4	16.0
				Section 3. SYSTEM (SUB-FAB) - Constant Pressure Valves - External - DEV Cabinet - MGP1 SUB DIW - Tolerance Section 3. SYSTEM (SUB-FAB) - Constant Pressure Valves - External - DEV Cabinet - SRS Rinse / Back Rinse - Tolerance	0.15 ~ 0.17 0.15 ~ 0.17	0.20 ~ 0.22 0.20 ~ 0.22
				Section 3. SYSTEM (SUB-FAB) - Constant Pressure Valves - External - DEV Cabinet - PIR Rinse / Back Rinse - Tolerance	0.15 ~ 0.17	$0.20 \sim 0.22$
				Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configurations - TBE Section 4. DEV - PRB - DEV/NTD - 3-PIN Up - Tool Setting	N/A 1.5	Added N/A*
				Section 4. DEV - PRB - DEV/NTD - 3-PIN Up - Remarks	Motor Driven	*Controlled by motor. Nominal timing
				Section 4. DEV - PRB - DEV/NTD - 3-PIN Down - Tool Setting	1.5	1.5s. N/A*
				Section 4. DEV - PRB - DEV/NTD - 3-PIN Down - Remarks	Motor Driven	*Controlled by motor. Nominal timing
3/20/2015	1.05	K. Proctor	P. Ito	Section 5. COT/TCT/BCT - PRB - COT/BCT - 3-PIN Up - Tool Setting	1.5	1.5s. N/A*
3/20/2013	1.03	K. I IOCIOI	1.110	Section 5. COT/TCT/BCT - PRB - COT/BCT - 3-PIN Up - Teoristaning	Motor Driven	*Controlled by motor. Nominal timing
				Section 5. COT/TCT/BCT - PRB - COT/BCT - 3-PIN Op - Remarks Section 5. COT/TCT/BCT - PRB - COT/BCT - 3-PIN Down - Tool Setting	1.5	1.0s. N/A*
				-	Motor Driven	*Controlled by motor. Nominal timing
				Section 5. COT/TCT/BCT - PRB - COT/BCT - 3-PIN Down - Remarks Section 5. COT/TCT/BCT - Module	BCT BARC ONLY	1.0s. BCT BARC TCT Shrink
				Section 5. COT/TCT/BCT - Noture Section 5. COT/TCT/BCT - COT/BCT - Resist Nozzle Height Home Position - Tool Setting Section 5. COT/TCT/BCT - COT/BCT - Resist Nozzle Height Home Position - Tolerance	4.5 * / 6.5 4.0 ~ 5.0 * /6.0 ~ 7.0	6.5 6.0 ~ 7.0
				Section 6. PIR**/SRS**/BST*** - PRB - PIR/SRS - 3-PIN Up - Tool Setting Section 6. PIR**/SRS**/BST*** - PRB - PIR/SRS - 3-PIN Up - Remarks	N/A N/A	Added Added
				Section 1. Overview (Configuration)	N/A	Added [TSH] / [TSL] / [TAQSI] / [TAQS / [TAQ Sl/Sh Hybrid] Configuration
				Section 2. SYSTEM(FAB) - PRB - TCT - Solvent Bath (Dispense Rate	N/A	Added
				Section 2. SYSTEM(FAB) - PRB - DEV - XDR (Dispense Rate) Section 2. SYSTEM(FAB) - PRB - DEV - XDR N2 Source Pressure	N/A N/A	Added Added
				Section 2. SYSTEM(FAB) - PRB - DEV - XDR N2 Flow Setting	N/A	Added
				Section 2. SYSTEM(FAB) - PRB - DEV - XDR N2 Pressure Setting Section 2. SYSTEM(FAB) - PRB - DEV - XDR N2 Pressure Sensor U/L XDR N2 Pressure Sensor L/I	N/A N/A	Added Added
				Section 3. SYSTEM (SUB-FAB) - COT Cabinet - External - COT Cabinet - IFFS Control box P_1 setting	N/A	Added
				Section 3. SYSTEM (SUB-FAB) - COT Cabinet - External - COT Cabinet - IFFS Control box P 2 setting Section 3. SYSTEM (SUB-FAB) - COT Cabinet - External - COT Cabinet - IFFS Control box P 3 setting	N/A N/A	Added Added
				Section 3. SYSTEM (SUB-FAB) - COT Cabinet - External - COT Cabinet - CRF Return Line	N/A	Added
				Section 3. SYSTEM (SUB-FAB) - COT Cabinet - External - COT Cabinet - CRF Drain Line Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configurations - Tool Config	N/A TAS/TNU/TNK	Added TAS/TNU/TNK/TSH/TSL
				Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART	TNE - CE	TNE - CE / TNG
				Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART Section 4. DEV - PRB - DEV - XDR N2 Nozzle Height	TAS/TNU/TNK	TAS/TNU/TNK/TSH/TSL
5/6/2015	2.00	K.Proctor	P. Ito	Section 4. DEV - PRB - DEV - XDR-Rinse Nozzle Height	N/A N/A	Added Added
5.0.2015	2.00	12.1.100101	1.100	Section 5. COT/TCT/BCT - PRB - Module Section 5. COT/TCT/BCT - PRB - COT - Middle Cup Height - Tolerance	COT/BCT 2.8 ~ 3.6	COT/BCT/TCT 2.7 ~ 3.7
				Section 5, CO1/1C1/DC1 - FKD - CO1 - Middle Cup Height - Tolerance	2.8 ~ 3.6 Use Digital cup height JIGCOT Spinner	Average of 6 measurements with digital of
					uses PV Cup[Torque 75cn*m] Check	height jig COT Spinner uses PV Cup[Torque 75cn*m] Check current Torc
				Section 5. COT/TCT/BCT - PRB - COT - Middle Cup Height - Remarks	current Torque DocDirect reading will be 2.4mm from the TOP of the wafer to the top	DocActual reading will be 2.4mm from t
					of the middle cup	TOP of the wafer to the top of the midd
				Section 5. COT/TCT/BCT - PRB - COT - Knife Edge Height	N/A	cup Added
				Section 5. COT/TCT/BCT - PRB - COT/TCT/BCT - Resist Nozzle Height Home Position 6.5 mm - Remarks	Set by using measuring scale Measure from the topo the resist bath to the bottom of the resist nozzle base.	For Dry tools and not complete CN-CT CMP-14-0015 toolsSet by using measuri scale Measure from the topo the resist ba to the bottom of the resist nozzle base.
				Section 5. COT/TCT/BCT - PRB - COT/TCT/BCT - Resist Nozzle Height Home Position 4.5 mm	N/A	Added
					N/A	
				Section 3. CO1/1C1/BC1-1 RB-CO1/1C1/BC1- Resist NOZZE Height Hollie Toshton 4.5 min	Z-Height -	Added

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Hardware FPD Revision History (3/5)

Data	Day	Appro	oval	Logotion	Old	Now							
Date	Rev.	INTEL	TEL	Location	Old	New							
				Section 2. SYSTEM(FAB) - PRB - DEV - XDR N2 Pressure Setting - Tool Setting	TBD	265							
				Section 2. SYSTEM(FAB) - PRB - DEV - XDR N2 Pressure Setting - Tolerance Section 2. SYSTEM (SUB FAB) - COT Cobingt - External - COT Cobingt - IEES Control box B. Leatting	TBD 0.09 ~ 0.11	150 ~ 300 0.08 ~ 0.12							
				Section 3. SYSTEM (SUB-FAB) - COT Cabinet - External - COT Cabinet - IFFS Control box P_1 setting Section 3. SYSTEM (SUB-FAB) - COT Cabinet - External - COT Cabinet - IFFS Control box P_2 setting	0.09 ~ 0.11 0.13~ 0.15	0.08 ~ 0.12 0.12 ~ 0.16							
				Section 3. SYSTEM (SUB-FAB) - COT Cabinet - External - COT Cabinet - IFFS Control box P 3 setting	0.18 ~ 0.20	0.17 ~ 0.21							
				Section 3. SYSTEM (SUB-FAB) - NTD Cabinet - External - COT Cabinet - IFFS Control box P_1 setting	N/A	Added							
		K. Proctor		Section 3. SYSTEM (SUB-FAB) - NTD Cabinet - External - COT Cabinet - IFFS Control box P 2 setting Section 3. SYSTEM (SUB-FAB) - NTD Cabinet - External - COT Cabinet - IFFS Control box P 3 setting	N/A N/A	Added Added							
8/6/2015	2.01	H. Sarthak K. Kevin	P. Ito	Section 3. SYSTEM (SUB-FAB) - NTD Cabinet - External - COT Cabinet - CRF Return Line	N/A	Added							
		K. Kevili		Section 3. SYSTEM (SUB-FAB) - NTD Cabinet - External - COT Cabinet - CRF Drain Line	N/A	Added							
				Section 4. DEV - PRB - DEV - XDR N2 Nozzle Height - Tool Setting Section 4. DEV - PRB - DEV - XDR N2 Nozzle Height - Tolerance	12 11.5 ~ 12.5	3 2.8 ~ 3.2							
				Section 4. DEV - PRB - DEV - XDR N2 Nozzle Height - TEL Std.	12 +/- 0.5	3 +/- 0.2							
				Section 4. DEV - PRB - DEV - XDR-Rinse Nozzle Height - Tool Setting	3	12							
				Section 4. DEV - PRB - DEV - XDR-Rinse Nozzle Height - Tolerance Section 4. DEV - PRB - DEV - XDR-Rinse Nozzle Height - TEL Std.	2.8 ~ 3.2 3 +/- 0.2	11.5 ~ 12.5 12 +/- 0.5							
11/12/2015	2.02	K. Proctor	K. Proctor	K. Proctor	2.02 K. Proctor	P. Ito	No HW change in this revisior	NA	NA				
				Section 1. Overview (Configuration) -1.1 [TAX] Immersion Configuration (Resist Tracks) - 5-1/5-2 COT - Add Commt	NA	BCT module on TAX430/TAX431							
				Section 1. Overview (Configuration) -1.1 [TAX] Immersion Configuration (Resist Tracks) - 6-1/6-2 COT - Add Commi Section 2. SYSTEM(FAB) - PRB - DEV - MGP (Dispense Rate)	NA 300	TCT module on TAX430/TAX431 300 / 400*							
				Section 2. SYSTEM(FAB) - PRB - DEV - MGP (Dispense Rate) - Remarks	Dynamic Setting	Dynamic Setting, *400 for Post SEI							
				Section 2. SYSTEM(FAB) - PRB - DEV - GP (Dispense Rate)	600	600 / 500*							
				Section 2. SYSTEM(FAB) - PRB - DEV - GP (Dispense Rate) - Remarks Section 2. SYSTEM(FAB) - PRB - DEV - XDR N2 Source Pressure -Tolerance	Dynamic Setting 0.32 to 0.38	Dynamic Setting, *500 for Post SEE 0.32 to 0.35							
				Section 2. SYSTEM(FAB) - PRB - DEV - ADR N2 Source Pressure - Forerance Section 2. SYSTEM(FAB) - PRB - DEV - XDR N2 Source Pressure - TEL Std.	0.32 to 0.38	0.32 to 0.33							
				Section 2. SYSTEM(FAB) - PRB - DEV - XDR N2 Source Pressure -Remarks	Dynamic Setting	Static Setting							
				Section 2. SYSTEM(FAB) - PRB - DEV/NTD -Supply Exhaust NTD (E1,E2,E23) (6x6 Config) - Description of Setting Section 2. SYSTEM(FAB) - PRB - DEV/NTD -Supply Exhaust NTD (E1) (6x6 Config) - Description of Setting	E1,E2,E23	E2/E23							
				Section 2. SYSTEM(FAB) - PRB - DEV/N1D - Supply Exhaust N1D (E1) (6x6 Config) - Description of Setting Section 3. SYSTEM (SUB-FAB) - COT Cabinet - External - COT Cabinet - 4/6-1,2,3,4 RRC / Solvent Bath DIW supply pressure	NA NA	Added (300 to 600) Added							
				Section 3. SYSTEM (SUB-FAB) - COT Cabinet - External - COT Cabinet - 4/6-1,2,3,4 Backrinse / Exhaust Duct /EBR DIW	NA	Added							
				supplypressure Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configurations - TN									
				Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configurations - TN/ Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configurations - TAS/TNU/TNK/TSH/TSL - EA1	NA 52.0	Added							
				TARGET CFM	53.0	21.2							
											Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configurations - TAS/TNU/TNK/TSH/TSL - EC1 TARGET CFM	35.3	21.2
					Cathannia DDO Vartor tal	The setting is information only The height							
				Section 4. DEV - PRB - DEV - ADR N2 Nozzle Height - Remarks	Set by using PRO-V set up tool	set up by ADR Rinse nozzle heigh							
						The setting is informal only on XDR equipped tools ADR Rinse enabled tool							
				Section 4. DEV - PRB - DEV - ADR-Rinse Nozzle Height - Remarks	Set by using PRO-V set up tool	ADR rinse nozzle by using PRO-V setu							
2/24/2015	2.03	K. Proctor	P. Ito			tool							
				Section 4. DEV - PRB - DEV - XDR N2 Nozzle Height - Remarks	Set by using PRO-V set up tool	XDR enabled tool set XDR N2 nozzle height by using PRO-V setup too							
				Continue A DEV. DDD. DEV. VDD Disco Novels Holds Domodo	Cathannia DDO Vartor tal	The setting is information only The height							
				Section 4. DEV - PRB - DEV - XDR-Rinse Nozzle Height - Remarks	Set by using PRO-V set up tool	set up by XDR N2 nozzle height							
				Section 5. COT/TCT/BCT - PRB - COT - Knife Edge Height - Remarks - added comment	NA	The setting is information only Cup is se by Middle Cup Heigh							
							Section 5. COT/TCT/BCT - PRB - Module	BCTTAX ONLY	BCT TAX430/431 ONLY				
					Section 7. OVEN - CPRP/CPHP/CHCH/CGCH/CSWP - PRB - Module - E12	CPHP/CPRP/CSWP	CPHP/CPRP/CSWP/CGCH						
					Section 7. OVEN - CPRP/CPHP/CHCH/CGCH/CSWP - PRB - CGCH/CHCH - Module EXH U/L Setting (Nagano Keiki) (E9) - Tool Setting	580	610						
							Section 7. OVEN - CPRP/CPHP/CHCH/CGCH/CSWP - PRB - CGCH/CHCH - Module EXH L/L Setting (Nagano Keiki) (E9)	520	490				
									Tool Setting	320	490		
				Section 7. OVEN - CPRP/CPHP/CHCH/CGCH/CSWP - PRB - CGCH/CHCH - Module EXH U/L Setting (Nagano Keiki) (E16) Tool Setting	530	550							
							Section 7. OVEN - CPRP/CPHP/CHCH/CGCH/CSWP - PRB - CGCH/CHCH - Module EXH L/L Setting (Nagano Keiki) (E16)	470	450				
				Tool Setting	4/0								
										Section 7. OVEN - CPRP/CPHP/CHCH/CGCH/CSWP - PRB - CPHP/CPRP/CSWP - ODOR Exhaust Setting (E21/E22) - Remarks	SET BY Target Pressure	SET by CFMFor TAQ/TNQ [E22 Only] TNE/TNG/TAX [E21/E22]	
				Section 7. OVEN - CPRP/CPHP/CHCH/CGCH/CSWP - PRB - CPHP/CPRP - ODOR Exhaust Setting (E21/E22 - Layer 3)-	SET BY Target Pressure	SET by CFM[E21/E22]For 6x6 Tools							
				Remarks Section 0. Sensor Setting. CC20 Sensor, DDD, OVEN. Individual Chember Eul. Ed.	F-3	F-5							
				Section 9. Sensor Setting - GC30 Sensor - PRB - OVEN - Individual Chamber Exh FiL Section 9. Sensor Setting - GC30 Sensor - PRB - OVEN - CSWP Exhaust - Uni	F-3 kPa	Pa							
				Section 9. Sensor Setting - GC30 Sensor - PRB - OVEN - CSWP Exhaust - FiL	F-2	F-3							
				Section 9. Sensor Setting - GC30 Sensor - External - COT CAB - Exh (Supply Cabinet) - CnP Section 9. Sensor Setting - GC30 Sensor - External - DEV CAP - Exh (Supply Cabinet) - CnP	Win	Hys							
				Section 9. Sensor Setting - GC30 Sensor - External - DEV CAB - Exh (Supply Cabinet) - CnP Section 1. Overview (Configuration) -1.1 [TAX] Immersion Configuration (Resist Tracks	Win Exist	Hys Deleted (Moved to 1276 FPD)							
				Section 3. SYSTEM (SUB-FAB) - DEV Cabinet - XDR N2 Pressure Source	N/A	Added							
				Section 3. SYSTEM (SUB-FAB) - DEV Cabinet - DEV Rinse Nozzle - TEL Std.	0.20 (+0.02/-0)	0.15 (+0.02/-0) -60.0 ~ - 70.0							
				Section 3. SYSTEM (SUB-FAB) - NTD Cabinet - COT Cabinet - Solvent 2 PCS (1,2) VAC Setting - Tolerance Section 3. SYSTEM (SUB-FAB) - COT Cabinet1 TAX Only - table	-40.0 to -50.0 Exist	-60.0 ~ - 70.0 Deleted (Moved to 1276 FPD)							
				Section 3. SYSTEM (SUB-FAB) - COT Cabinet2 TAX Only - table	Exist	Deleted (Moved to 1276 FPD)							
				Section 3. SYSTEM (SUB-FAB) - DEV Cabinet TAX Only - table Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configurations - TAX table	Exist Exist	Deleted (Moved to 1276 FPD) Deleted (Moved to 1276 FPD)							
				Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for an Configurations - TAX table Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - TAX	Exist	Deleted (Moved to 1276 FPD) Deleted (Moved to 1276 FPD)							
				Section 4. DEV - PRB - DEV - MGP sub DEV - title	DEV SUB	MGP sub DEV							
5/2/2015	3.00	K. Proctor	P. Ito	Section 4. DEV - PRB - DEV - MGP sub DEV - Setting Section 4. DEV - PRB - DEV - MGP sub DEV - Remarks	12.6 N/A	20.0 The setting is information only							
				Section 4. DEV - PRB - DEV - MGP sub DEV - Remarks Section 4. DEV - PRB - DEV - MGP sub DIW - title	N/A DIW SUB	The setting is information only MGP sub DIW							
				Section 4. DEV - PRB - DEV - MGP sub DIW - Setting	12.6	20.0							
				Section 4. DEV - PRB - DEV - MGP sub DIW - Remarks	N/A	The setting is information only							
l				Section 6. PIR/SRS	Exist BST setting	Deleted all BST settings (Moved to 12' FPD)							
				a i a aveni anno anno anno anno anno anno anno an	E ' COMP'	Deleted all CSWP settings (Moved to 12							
				Section 7. OVEN - CPRP/CPHP/CHCH/CGCH	Exist CSWP setting								
					Exist CSWP setting	FPD)							
				Section 7. OVEN - CPRP/CPHP/CHCH/CJGCH Section 9. Sensor Setting - DP100 Sensor - PRB - CRD/ACRD - RESIST Pump Purge - SPED Section 9. Sensor Setting - DP100 Sensor - PRB - CRD/ACRD - AMC N2 Purge - SPED	2.5 2.5	FPD) 5000 5000 Added							

Hardware FPD Revision History (4/5)



1970 1970	ъ.	-	Appro	oval		011	N				
1920 1930	Date	Rev.			Location	Old	New				
Page					Section 2. System (FAB) -IPRB** - Positive Pressure - IPRB-SRS/PIR - Add Remarks	NA	INTEL Setting : SRS/PIR at 0.3 < PRA				
	7/22/2016	3.01	K. Proctor	H.Nagai							
March											
Section Sect											
1972 1972					Section 1. Overview (Configuration) -1.6 [TSL] Slim Configuration	Exist	Deleted				
1972 1972											
Part											
18					Section 1. Overview (Configuration) -1.6 [THYlc] Slim/Shrink Hybrid Configuration	NA	Added				
No. No. No. No. No. No. No.											
1					Section 3. SYSTEM(SUB-FAB) - Constant Pressure Value Table - Title						
							Constant Pressure Valves TAO/TNO [NTD and Post SED]				
1972 1972					Section 3. SYSTEM(SUB-FAB) - Chemical Cabinet Exhaust Setting - TAS/TNU/TNK/THY - Title		TAS/TNU/TNK/THY				
No. No.											
1912-2016 18.0											
10122056 A-01							Added				
10172000 14.					Section 5. COT/TCT/BCT - PRB - COT - Middle Cup Height - Tool Setting	3.2					
1912/2016 A. P. Pack P. P. P. Pack P.					Carlos & COTTOTROT DDD COT Mills Con Haids Talabarra	27 27					
1972/2016 A. B. P. Danie A. B. Danie					Section 5. CO1/TC1/BC1 - PRB - CO1 - Middle Cup Height - Tolciance	2.7 ~ 3.7	PostSED = 2.3 ~ 3.3				
1912/2016 R. P.							height jigCOT Spinner uses PV Cun				
1912/2011 AU R. Proces							[Torque 75cn*m] Check current Torqu				
1912-2016 1912 19					Section 5. COT/TCT/BCT - PRB - COT - Middle Cup Height - Remarks		DocActual reading will be 2.3mm/2.0n				
Section 5 COTTCTBCT - PRB - COT - Scale Edge Hight - Tool Section 5 COTTCTBCT - PRB - COT - Scale Edge Hight - Tool Section 5 COTTCTBCT - PRB - COT - Scale Edge Hight - Tool Section 5 COTTCTBCT - PRB - COT - Scale Edge Hight - Tool Section 5 COTTCTBCT - PRB - COT - Scale Edge Hight - Tool Section 5 COTTCTBCT - PRB - COT - Scale Edge Hight - Remarks	10/12/2016	4.00	K Proctor	K. Proctor	K. Proctor			reading will be 2.4mm from the TOP of the			
Nection COUTCTERCT - PRIS - COT - Knife Edge Height - Tool Setting				ri.inagai		wafer tothe top of the middle cup	The setting is information only, cup is se				
Section S.COTTCTBCT - PRB - COT - Actif Edge Height - Releases 1.5 - 2.0							by knife edge gar				
Scale S. College S. College Scale S. College Scale S. College Scale S. College Scale S. College S. College Scale S. College S					Section 5. COT/TCT/BCT - PRB - COT - Knife Edge Height - Tool Setting	-1.5					
Section 5. COTTCTBCT - PRB - NCT Oxy. Madie Cup Height					Section 5, COT/TCT/BCT - PRB - COT - Knife Edge Height - Tolelance	-1.0~-2.0	Resist = $-1.0 \sim -2.0$				
Section 5. CUTTCT-BCT. FRBCOT Knafe Belge Height - Remarks Section 5. CUTTCT-BCT. FRBCOT Knafe Belge Height - Remarks Section 5. CUTTCT-BCT. FRBCOT Knafe Belge Height - Remarks Section 5. CUTTCT-BCT. FRBDCT Only Middle Cips Height Section 5. CUTTCT-BCT. FRBDCT Only Middle Cips Height Section 5. CUTTCT-BCT. FRBDCT Only Middle Cips Height Section 5. CUTTCT-BCT. FRBDCT BARK TCT Streak - Knafe Belge Height - Remarks Date Deal only being HERITE TYPE Section 5. CUTTCT-BCT. FRBDCT BARK TCT Streak - Knafe Belge Height - Remarks Date Deal only being HERITE TYPE Section 5. CUTTCT-BCT. FRBDCT BARK TCT Streak - Knafe Belge Height - Remarks Date Deal only being HERITE TYPE Section 5. CUTTCT-BCT. FRBDCT BARK TCT Streak - Knafe Belge Height - Remarks Date Deal only being HERITE TYPE Section 5. CUTTCT-BCT-PTBDCT BARK TCT Streak - Knafe Belge Height - Remarks Date Deal only being HERITE TYPE Section 5. CUTTCT-BCT-PTBDCT BARK TCT Streak - Knafe Belge Height - Remarks Date Deal only being HERITE TYPE Section 5. CUTTCT-BCT-PTBDCT BARK TCT Streak - Knafe Belge Height - Remarks Date Deal only being HERITE TYPE Section 5. CUTTCT-BCT-PTBDCT BARK TCT Streak - Knafe Belge Height - Remarks Date Deal only being HERITE TYPE Section 5. CUTTCT-BCT-PTBDCT BARK TCT Streak - Knafe Belge Height - Remarks Date Deal only being HERITE TYPE Date Deal only being HERITE T							PostSED = -1.2 ~ -2.2				
Section COUNT-CERCE - PRB - BCT Chairy - Madall Cog Height Section SCOTTCTRICT - PRB - BCT Chairy - Madall Cog Height - Remarks But Cog Height - R										height jigCOT Spinner uses PV Cup[Torque	Average of 6 measurements with digital cu
Section 5. COTTCTBCT-PEB-BCT Only, Middle Cup Regigls										Section 5. COT/TCT/BCT - PRB - COT - Knife Edge Height - Remarks	
Section 5 COLITCT PCT - PRB - BCT BARC TCT Sterols - Kmfle Edge Height - Remarks					A COMPANY OF THE COMP	Height					
Section 5. COTTCTBCT - PRB - BCT BARC TCT Shrink. Kanfe Edge Height - Remarks					Section 5. COT/TCT/BCT - PRB - BCT Only - Middle Cup Height	Exist					
Scale Scal							BARC tools uses TCT Cup with smoo				
Part					C .' A CONTROLL DED DOLLD'S TOTAL 'I W'S EL H'I D						
Deck Section OVEN CPHP-CPCP-CG-HGIGH CPHP-CPR P - Chamber (LR) Purge flowmate UI. Setting, Chamber (LR) Purge Setty Sub-Op darplay centered flower to the few one follower of the holler of					Section 5. CO1/TC1/BC1 - PRB - BC1 BARC TC1 Shrink - Knife Edge Height - Remarks						
Section OVEN CPIPIC PEP CCHIPIC CRIT CPIPIC PEP C Chamber (LR) Page Rounder (LR) Page Rounde							DocMeasured from the bottom of the wa				
Part					Castion 7 OVEN CDUD/CDDD/CCCH/CHCH CDUD/CDDD Chambar (L/D) Days of average L/L Satting Chambar (L/D) Days		to the top of the INNER cur				
Section 7.0VEN - CADIL - HP Copp pin - Televance						Set by Sub-Op display	removed comment				
Section 7, OVEN - CADIF - Local Fabusor (E11)					Section 7. OVEN - CADH - HP Gap pin - Tolerance						
12/2017 4/02 K Proctor 1 Nogal Section 2. SYSTEM (FAB) - PRB - COT - Bock Rose Objectors Rept - Stapes for ITC models 100 mlmins Deleted											
26/2017 4.03 K. Protor H.Naga Section 9, Semor Setting .PP100 semor .PRB -CRD - RESIST Pump Purge 2.5 5.000	1/22/2017	4.02	V Drootor	U Nagai							
Section J. Overview Configuration CET NPIX - Added					Section 9. Sensor Setting - DP100 sensor - PRB - CRD - RESIST Pump Purge	2.5	5000				
Section Overview (Configuration) - Non-CE TNE - Added NA HVM TNE	2/0/2017	4.03	K. Hoctor	11.1vagai							
Section O-Perview (Configuration) - TNG - Added NA TNG Section Section SYSTEM/SIAP PRB - COTRACT - Need Rims Speed Convoller - Added NA Stunes Section SYSTEM/SIAP PRB - COTRACT - Section SYSTEM/SIAP PRB - COTRACT - Section SYSTEM/SIAP SECTION Section SYSTEM/SIAP Section SySTE											
Section 2.5YSTEMS(B)-FAB)- COT Eabred External - COT Cabinet - FLITER PURGE - Tolerane NA 54 to 66											
Section 3, SYSTEMS(BR-PAB) = COT Cabinet - External - COT Cabinet - FLETR PENT - Tolerane											
Section 3. SYSTEMSUB-FAB). COT Cabinet - CRF Return Line - Tolerane					Section 3. SYSTEM(SUB-FAB) - COT Cabinet - External - COT Cabinet - FILTER VENT - Toleranc	NA	54 to 66				
Section 3. SYSTEM/SUB-FAB). P.OT Cabinet - External - COT Cabinet - Toleranc											
Section 3. SYSTEMSUB-FAB). NTD Cabinet - External - COT Cabinet - FILTER PURGE - Tolerane											
6.9/2017					Section 3. SYSTEM(SUB-FAB) - NTD Cabinet - External - COT Cabinet - FILTER VENT - Toleranc	NA	54 to 66				
Section 3. SYSTEM(SUB-FAB) - NTD Cabinet - External - COT Cabinet - CRE Point Line - Tolerane NA	6/9/2017	4 04	K. Proctor	H.Nagai							
Section 3. SYSTEMSUB-FAB STHIC CHILLER FLOW RATE SETTING CHART - CETNE - Setting tabl	0.7.2017		11.110001	zz rugui	Section 3. SYSTEM(SUB-FAB) - NTD Cabinet - External - COT Cabinet - CRF Drain Line - Toleranc	NA	54 to 66				
Section 3. SYSTEM(SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - HVM TNE - Secting tabl NA Added Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - TNG - Setting tabl NA Added Section 3. SYSTEM (SUB-FAB) - TND EDV Cabine NA Added Section 3. SYSTEM (SUB-FAB) - TND EDV Cabine NA Added Section 3. SYSTEM (SUB-FAB) - TND EDV Cabine Section 3. SYSTEM (SUB-FAB) - TO EDV Cabine NA Added Section 3. SYSTEM (SUB-FAB) - TO EDV Cabine NA Added Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configurations - TNE [HVM] NA Added Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configurations - TNE [HVM] NA Added Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configurations - TNE [HVM] NA Added Section 7. OVEN - CPHPCRPP.CGCH-CHCH- PRB - CPHPCPRP - ODOR Exhaust Setting (E21/E22) - Remarks NA Added Section 7. OVEN - PRB - NTD - NTD Rinse Nozzle Height - Remarks Na Measure from Tip of nozzle to wafer surface-only since the arm is calibrated with the Nozzle Na Section 7. OVEN - PRB - NTD - NTD Rinse Nozzle Height - Tool Setting Section 7. OVEN - PRB - CPHP/CPRP/CGCH - Cool Arm to 3-Pin Up Height - Tool Setting 2. 2. 1.5 Section 7. OVEN - PRB - CPHP/CPRP/CGCH - Cool Arm to 3-Pin Up Height - Tool Setting 2. 2. 1.5 Section 7. OVEN - PRB - CPHP/CPRP/CGCH - Cool Arm to 3-Pin Up Height - Tool Setting 2. 2. 1.5 Section 7. OVEN - PRB - CPHP/CPRP/CGCH - Cool Arm to 3-Pin Up Height - Tool Setting 3. Section 8. ARM - PRB - PRA - Fork Diameter (3.0, 4.0, 5.0, 6.0) Fork 2 - Tolerance NA 4 +/- 0.020 Section 8. ARM - PRB - PRA - Fork Diameter (3.0, 4.0, 5.0, 6.0) Fork 2 - Tolerance NA 4 +/- 0.020 Section 8. ARM - PRB - PRA - Fork Diameter (3.0, 4.0, 5.0, 6.0) Fork 2 - Tolerance NA 4 +/- 0.020 Section 8. ARM - PRB - PRA - Fork Diameter (3.0, 4.0, 5.0, 6.0) Fork 2 - Tolerance NA 4 +/- 0.020 Section 8. ARM - PRB - PRA - Fork Diameter (3.0, 4.0, 5.0, 6.0) Fork 2 - Tolerance NA 4 +/- 0.020 Section 8. SYSTEM (FAB) - COT Cabinet - Exhemal - COT Cabinet - 4/6-1,2											
Section 3. SYSTEM(SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - TNG - Setting tabl											
Section 3. SYSTEM (SUB-FAB) - TARTAR DEV Cabine NA Added					Section 3. SYSTEM(SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - TNG - Setting tabl	NA	Added				
Section 3. SYSTEM (SUB-FAB) - Inmersion and Post SED DEV Cabine NA Added											
Section 3. SYSTEM (SUB-FAB) - Immersion and Post SED DEV Cabine NA Added					Section 3. SYSTEM (SUB-FAB) - TAR/TNR DEV Cabine						
Section 7. OVEN - CPHP/CPRP/CGCH/CHCH - PRB - CPHP/CPRP - ODOR Exhaust Setting (E21/E22) - Remarks					Section 3. SYSTEM (SUB-FAB) - Immersion and Post SED DEV Cabine	NA	Added				
NTD Rinse Nozzle height as "information Nozzle Nozz											
Section 7. OVEN - PRB - CPHP/CPRP/CGCH - Cool Arm to 3-Pin Up Height - Tool Setting 2 >1.5					-		NTD Rinse Nozzle height as "informational				
10/2/2017 4.07 4.07 4.07 4.07 4.07 4.07 4.07 4.07 4.07 4.08 4.07 4.08 4.07 4.08 4.08 4.09 4.08 4.09 4.09 4.08 4.09 4.	7/7/2017	4.05	K. Proctor	H.Nagai	Section 4. DEV – PRB – NTD – NTD Rinse Nozzle Height – Remarks	Measure from Tip of nozzle to wafer surfac					
Section 7. OVEN - PRB - CADH - Cool Arm to 3-Pin Up Height - Tool Setting 2 51.5						2	>1.5				
10/2/2017 4.07 K. Proctor H.Nagai Section 7. OVEN - PRB - CADH - Cool Arm to 3-Pin Up Height - Tolerance 2-1.5 2-4											
Section 7. OVEN - PRB - CGCH - Cool Arm Gap Pin Section 8. ARM - PRB - PRA - Fork Diameter (3-0, 4-0, 5-0, 6-0) Fork 1 - Tolerance NA	10/2/2017	4.07	K. Proctor	H.Nagai							
Section 8. ARM - PRB - PRA - Fork Diameter (3-0, 4-0, 5-0, 6-0) Fork 2 - Tolerance Section 1. Overview (Configuration)					Section 7. OVEN - PRB - CGCH - Cool Arm Gap Pin	NA	0.35				
Section 1. Overview (Configuration) Section 1. Overview (Configuration) Section 1. Overview (Configuration) Section 1. Overview (Configuration) Section 2. SYSTEM (FAB) - PRB - DEV - MGP (Dispense Rate) - PostSED specific setting Section 2. SYSTEM (FAB) - PRB - DEV - GP (Dispense Rate) - PostSED specific setting Section 2. SYSTEM (FAB) - STB - SYSTEM - Resist Bottle Pressure - Remark Section 3. SYSTEM (SUB-FAB) - COT Cabinet - External - COT Cabinet - 4/6-1,2,3,4 RRC / Solvent Bath DIW supply pressur Section 3. SYSTEM (SUB-FAB) - COT Cabinet - External - COT Cabinet - 4/6-1,2,3,4 Backrinse / Exhaust Duct / EBR DIW supply pressure Section 3. SYSTEM (SUB-FAB) - COT Cabinet External - COT Gabinet - 4/6-1,2,3,4 Backrinse / Exhaust Duct / EBR DIW supply pressure Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet External - COT Gabinet - 4/6-1,2,3,4 Backrinse / Exhaust Duct / EBR DIW supply pressure Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet External - COT Gabinet - 4/6-1,2,3,4 Backrinse / Exhaust Duct / EBR DIW supply pressure Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING GHART TAQ/TNQ (NTD and PostSED) TAQ/TNQ											
Section 1. Overview (Configuration) Section 2. SYSTEM (RAB) - PRB - DEV - GP (Dispense Rate) - PostSED specific setting 400 Removed											
Section 2. SYSTEM (FAB) - PRB - DEV - OP (Dispense Rate) - PostSED specific setting 500 Removed					Section 1. Overview (Configuration)	TAQhb	Removed				
Section 2, SYSTEM(FAB) - STB - SYSTEM - Resist Bottle Pressure - Remark Static Pressure Setting Dynamic Pressure Setting											
Section 3. SYSTEEM (SUB-FAB) - COT Cabinet - External - COT Cabinet - 4/6-1,2,3,4 Backrinse / Exhaust Duct / EBR DIW supply pressure Section 3. SYSTEEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configuration THY / PostSED Removed from Tool configuration Section 3. SYSTEEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART TAQ/TNQ (NTD and PostSED) TAQ/TNQ					Section 2. SYSTEM(FAB) - STB - SYSTEM - Resist Bottle Pressure - Remark	Static Pressure Setting	Dynamic Pressure Setting				
supply pressure Section 3. SYSTEEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configuration Section 3. SYSTEEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART TAQ/TNQ (NTD and PostSED) TAQ/TNQ	12/14/2017	4.08	K. Proctor	H.Nagai		0.15	Removed				
Section 3. SYSTEEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configuration THY / PostSED Removed from Tool config Section 3. SYSTEEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART TAQ/TNQ (NTD and PostSED) TAQ/TNQ						0.15	Removed				
					Section 3. SYSTEEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configuration						
Section 5. COT / TCT / BCT - ALL All categories Removed all TCT and PostSED its											

Hardware FPD Revision History (5/5)

Date	Rev.	Appr		Location	Old	New
		INTEL	TEL	Section 3. SYSTEM(SUB-FAB) - COT Cabinet - Added COT CAB Installation Height (V5)		90mm
7/9/2018	4.10	K. Proctor	Sam S./ J.	Section 3. SYSTEM(SUB-FAB) - DEV Cabinet - Added DEV CAB Installation Height (V5) Section 8. ARM - Add comment to PRA Z-Height - Cup Wash		90mm Check height of 5.5mm at center of Co
			Robinson	Section 9. Sensor Setting - Remove part numbers next to each sensor type	Part Numbers	Wash module Removed
9/7/2018	5.00	K. Proctor	H.Nagai	Section 9. Sensor setting – DP100 sensor - CSB Cover Revision	NA 5.00	Added 5.01
11/28/2018	5.01	K. Proctor	H.Nagai	Section 2. SYSTEM (FAB) - IPRB - SRS - IE Nozzle (Dispense Rate)2 Section 7. OVEN - CPHP/CPRP/CGCH/CHCH/CSWP - PRB - CPRP - HP Gap Pin - Outer Circle (Tool Setting / Tolerance)	not for BST NA	Deleted the row Added
				Section 7. OVEN - CPHP/CPRP/CGCH/CHCH/CSWP - PRB - CPRP - HP Gap Pin - Middle Circle (Tool Setting / Tolerance) Section 7. OVEN - CPHP/CPRP/CGCH/CHCH/CSWP - PRB - CPRP - HP Gap Pin - Inner Circle (Tool Setting / Tolerance)	NA NA	Added Added
				Section 2, SYSTEM (FAB) - CSB - SYSTEM - Load Port Door OPEN/CLOSED Speed (Old setting) Section 2, SYSTEM (FAB) - CSB - SYSTEM - Load Port Air Supply Setting - Tolerance	NA NA	2.8 (±0.3) 0.42 ~ 0.48
				Section 2, SYSTEM (FAB) - CSB - SYSTEM - Load Port Door OPEN/CLOSED Speed - Tolerance Section 2, SYSTEM (FAB) - CSB - SYSTEM - Door Protrusion Check - Tolerance	NA NA	2.3±0.3 1.7+/-0.2
				Section 3. SYSTEM (SUB-FAB) - DEV Cabinet - External - DEV Cabinet - XDR N2 Pressure Source Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configurations - TNG - COT Cabinet - Exhaust	DEV Cabinet	COT Cabinet
				HMDS (EA5) - Tolerance	15 to 325	5 to 100
				Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configurations - TAS/TAU/YNU/TNK - COT Cabinet - Exhaust HMDS (EA5) - Setting	25	15
				Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configurations - TNG - COT Cabinet - Exhaust HMDS (EA5) - Setting	25	15
				Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configurations - TNG - COT Cabinet - Exhaust HMDS U/L Setting (EA5) - Tool Setting	350	100
				Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configurations - TNG - COT Cabinet - Exhaus	10	5
				HMDS L/L Setting (EA5) - Tool Setting Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configurations - TAS/TAU/YNU/TNK - CO	15 to 325	5 to 100
				Cabinet - Exhaust HMDS (EA5) - Tolerance Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configurations - TAS/TAU/YNU/TNK - CO	350	100
2/20/2019	5.02	K. Proctor	H.Nagai	Cabinet - Exhaust HMDS U/L Setting (EA5) - Tool Setting Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configurations - TAS/TAU/YNU/TNK - CO	10	5
				Cabinet - Exhaust HMDS L/L Setting (EA5) - Tool Setting Section 3. SYSTEM (SUB-FAB) - STHC1 - External - THC - Utility Supply (PCW) - Remark	NA NA	Not present on all tracks
				Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - TAQ/TNQ - External - CHILLER - Utility Supply (PCW) - Remark:	NA	Not present on all tracks
				Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - NON-CE TNE - External - CHILLER - Utility Supply (PCW) - Remark:	NA	Not present on all tracks
				Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - CE TNE - External - CHILLER - Utility Supply (PCW) - Remarks	NA	Not present on all tracks
				Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - HVM TNE - External - CHILLER	NA	Not present on all tracks
				Utility Supply (PCW) - Remark: Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - TNG - External - CHILLER - Utility	NA	Not present on all tracks
				Supply (PCW) - Remarks Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - TBC/TBE - External - CHILLER	NA	Not present on all tracks
İ				Utility Supply (PCW) - Remark: Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - TAS/TAU/TNU/TNK - External	NA	Not present on all tracks
				CHILLER - Utility Supply (PCW) - Remark: Section 7. OVEN - CPHP/CPRP/CGCH/CHCH/CSWP - PRB - CPRP - HP Gap Pin - Outer Circle -Tool Setting	NA	Added
İ				Section 7. OVEN - CPHP/CPRP/CGCH/CHCH/CSWP - PRB - CPRP - HP Gap Pin - Outer Circle -Tolerance Section 7. OVEN - CPHP/CPRP/CGCH/CHCH/CSWP - PRB - CPRP - HP Gap Pin - Middle Circle -Tolerance	NA NA	Added Added
				Section 9. Sensor Settings - GC30 Sensor - LoP Cover Revision	0 5.02	Tool specific 5.03
l				INDEX - High Altitude Setting Fab/Sub-Fab Section 1. Overview (Configuration) - 1.8 TBL Configuration	NA NA	Added Added
		K. Proctor	r H.Nagai	Section 2. SYSTEM (FAB) - PRB - CPRP - CPRP Chamber N2 Purge Source Pressure Section 3. SYSTEM (SUB-FAB) - DEV Cabinet - TNG DEV Cabine	NA TNG DEV Cabinet	Added (Deck 4 specific) TNG/TBL DEV Cabinet
4/05/2019	5.03			Section 3. SYSTEM (SUB-FAB) - Chemical Cabinet Exhaust Setting for all Configurations - Tool Config - TNG Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - TBL Tabl	TNG NA	TNG / TBL Added
İ				Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - External - CHILLER - Utility Supply (PCW) - Remarks	Not present on all trracks (for all specification)	Deleted the row
İ				(FCW) - Refinance Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - TBL Table Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - TBL Table	NA NA	Added
				Section 10. High Altitude Setting Fab/Sub-Fab	NA	Added Added
İ				Cover Revision Section 2. SYSTEM(FAB) - PRB - SYSTEM - Positive Pressure - Remarks	5.03 NA	6.00 PRB ≥ CSB
				Section 2. SYSTEM(FAB) - PRB - DEV/NTD - Positive Pressure - Tool Setting Section 2. SYSTEM(FAB) - PRB - DEV/NTD - Positive Pressure - Tolerance	0.7 0.5 to 0.9	0.6 0.5 to 0.6
İ				Section 2. SYSTEM(FAB) - PRB - DEV/NTD - DEV/NTD Positive Pressure Bias Section 3. SYSTEM(SUB-FAB) - TNG/TBL DEV Cabinet - External - DEV Cabinet - C.P.V for D.I. Wafer	NA TBD	Added 0.19 ~ 0.21
İ				Section 3. SYSTEM(SUB-FAB) - Immersion DEV Cabinet - External - DEV Cabinet - C.P.V for D.I. Wafer Section 3. SYSTEM(SUB-FAB) - Immersion DEV Cabinet - External - DEV Cabinet - C.P.V for MGP Sub D.I. Water	TBD TBD	0.19 ~ 0.21 0.14 ~ 0.16
				Section 3. SYSTEM(SUB-FAB) - Immersion DEV Cabinet - External - DEV Cabinet - C.P.V for SRS Section 3. SYSTEM(SUB-FAB) - Immersion DEV Cabinet - External - DEV Cabinet - C.P.V for SRS Section 3. SYSTEM(SUB-FAB) - Immersion DEV Cabinet - External - DEV Cabinet - C.P.V for PIR	TBD TBD	0.14 ~ 0.16 0.14 ~ 0.16
				Section 3. SYSTEM(SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - TBL - External - CHILLER	3.0	0.14 ~ 0.16 2.0
6/11/2019	6.00	K. Proctor	H.Nagai	Temperature Control Water Flow Rate(CH4-1) Bypass - Tool Settin, Section 3. SYSTEM(SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - TBL - External - CHILLER	CPL - D	CPL-M 2-15
				Temperature Control Water Flow Rate(CH5-2-1] Section 3. SYSTEM(SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - TBL - External - CHILLER	9.0	3.0
				Temperature Control Water Flow Rate(CH5-2-1) - Tool Settin _! Section 3. SYSTEM(SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - TBL - External - CHILLER	CPL-M 2-15	
				Temperature Control Water Flow Rate(CH5-2-2) Section 3. SYSTEM(SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - TBL - External - CHILLER		CPL - D
				Temperature Control Water Flow Rate(CH5-2-2) - Tool Settin; Section 5. COT/BCT - PRB - Module - CUP EXH	3.0 COT TNE/TNG	9.0 COT TBL/TNE/TNG
				Secion 7. OVEN - CADH - PRB - Local Exhaust (E11) - for 7CADH systems (w/ Upper/Lower Limits) Secion 7. OVEN - CADH - PRB - Local Exhaust (E11) - Tool Setting	NA NA	Added 450
				Secion 7, OVEN - CADH - PRB - Local Exhaust (E11) - Tolerance Secion 7, OVEN - CADH - PRB - EXH Upper Limit (E11)	NA NA	400 to 500 500
				Secion 7. OVEN - CADH - PRB - EXH Lower Limit (E11)	NA	400
0/15/00:		W 70	***	Cover - Teaching Version Cover - Main Software version	1.27 100.0.58.225	1.28 100.0.58.226
8/15/2019	6.01	K. Proctor	H. Nagai	Cover - Revision Section 1. Overview (Configuration) - 1.4 TBEna Configuration	6.00 NA	6.01 Added
				Section 3. SYSTEM(Sub FAB) - STHC CHILLER FLOW RATE SETTING CHART - TBEna setting table Cover - Revision	NA 6.01	Added 6.02
				Section 1. Overview (Configuration) - TBM Section 1. Overview (Configuration) - TNE/TNG High Throughput upgrade	NA NA	Added Added
				Section 3. SYSTEM (SUB-FAB) - TBM Related items Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - NON-CE TNE with High Troughput Up	NA NA	Added Added
10/28/2019	6.02	K Decator	H Naco	Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - ROW-CE THE with High Troughput Upgrade Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - CE TNE with High Troughput Upgrade Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - HVM TNE with High Troughput Upgra	NA NA NA	Added Added Added
10/20/2019	0.02	K. Proctor	11. INagai	Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - TNG with High Troughput Upgrade	NA	Added
				Section 3. SYSTEM (SUB-FAB) - Ultrasonic flowmeter setting for "Liquid Kind" - Solvent Section 5. COT/BCT - PRB - COT/BCT/TCT - Resist Nozzle Height Home Position - Remarks	Solvent -	Solvent (POS, PGMEA, EL) 6.5mm: For DRY / IMM tools
				Section 5. COT/BCT - PRB - COT/BCT/TCT - TBM Related items	NA	4.5mm: For BARC tools Added
1	1			Section 7. OVEN - CPHP/CPRP/CGCH/CHCH/CSWP - ODOR Exhaust Setting (E21/22) - TBL/TBM settings	NA	Added

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Hardware FPD Revision History (6/6)

Date	Rev.	Appr		Location	Old	New
Date	Rev.	INTEL	TEL	Location	Olu	New
				Section 1. Overview (Configuration) - 1.9 HVM TNE Configuration_D5 Blanke	NA	Added
				Section 1. Overview (Configuration) - 1.9 HVM TNE Configuration_D5/D6 Blanke	NA	Added
				Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - D5 Blanked HVM TN	NA	Added
				Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - D5 Blanked HVM TNE with Higl	NA	Added
				Troughput Upgrade		Added
2/20/2020	6.03	K. Proctor	H.Nagai	Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - D5/D6 Blanked HVM TNI	NA	Added
2/20/2020	0.05	K. Hoctor	11.1vagai	Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - D5/D6 Blanked HVM TNE with Higl	NA	Added
				Troughput Upgrade	NA.	Added
				Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - TNG with High Throughput Upgrad	1.9 to 2.1	12.5 to 13.5
				and TBM - CH4-2 - Tolerance	1.9 to 2.1	12.3 to 13.3
				Section 3. SYSTEM (SUB-FAB) - STHC CHILLER FLOW RATE SETTING CHART - TNG with High Throughput Upgrade	2+/-0.1	13+/-0.5
				and TBM - CH4-2 - TEL Std	277-0.1	13+7-0.3
				Cover - Revision	3.06	4.00
	7.00			Cover - Software Version - All Tools except Dry	100.0.58.218	100.0.58.226
				Cover - Software Version - TBL only	NA	100.0.58.228
				Section 5. COT /TCT / BCT - PRB - COT - Knife Edge Height - Remarks	NA	when checking fork for tightness, use the
4/15/2020		K. Proctor	H.Nagai	Section 3. COT/TCT/BCT-FRB-COT-Kinne Euge Height - Remarks	INA	300.3mm disc.
				Section 7. OVEN - CADH - PRB - CADH - Local Exhaust (E11) - 7 CADH units - Tolerance	400 to 500	430 to 470
				Section 7. OVEN - CADH - PRB - CADH - Local Exhaust (E11) - 9 CADH units - Tolerance	0.450 to 0.550	0.480 to 0.520
					Section 8. ARM - MPRA/PRA/PRAI - Fork Diameter - Remarks	NA
				Section 6. ARIVI - IVI RAT RAT RAT RAT - FOR Diameter - Remarks		by Middle Cup height
3/12/2021	7.01	K. Proctor	Dan	Cover - Revision	4.00	4.01
3/12/2021	7.01	K. Flocioi	Dali	Cover - Software Version for Dry Too	100.0.58.213	100.0.58.218
4/2/2021	7.02	K. Proctor	Dan	9.Sensor Setting	N/A	Setting listed
4/2/2021	7.02	K. Proctor	Dan	REV liquid sensor setting		
				5.2. System Config Parameter, Spinners (COT/BCT)	Valid, Invalid=Invalid	Valid, Invalid=Valid
	7.03	K. Proctor	Dan	Adding Circulation setting for D6 IMM*** specific.	Time for circulation recovery=60	Time for circulation recovery=1200
				Adding Circulation setting for Do Ivini · · · specific.	Time for continuous circulation=60	Time for continuous circulation=1.
6/4/2021				5.2. System Config Parameter, Spinners (COT/BCT)	CRF Setting	CRF Setting
0/4/2021	7.03	K. Proctor	Dan	CRF Setting for D6 IMM*** specific.	Guarantee Time of Continuous	Guarantee Time of Continuous
				CRF Setting for Do IMM*** specific.	Circulation=60	Circulation=0
	7.02	I/ D	ъ	9. Sensor Setting		Adding
	7.03	K. Proctor	Dan	Adding setting info for E3X-MD36T-T Senso		Adding setting

Software FPD Revision History (1/9)

		Ann	oval			
Date	Rev.	Appi INTEL	TEL	Location	Old	New
3/25/2014	1.00	K. Proctor	Sam. S	Original Release	N/A	100.0.53.6 MCr287
				Section: 5.1.Sys Config(DEV) - Block Arm - Right(WET) updated	LD nozzle	GP nozzle
				Section: 5.1.Sys Config(DEV) - Block Arm - Right(WET) - Acceleration parameter update	150000	361000
				Section: 5.2.Sys Config(COT) - Addition to DFT spec setting for ACRD Pumps Section: 5.2.Sys Config(COT) - Update to RRC Calibration setting POS	N/A 0.85 - 0.95	[+/-1] 0.85 - 0.99
				Section: 5.2.Sys Config(COT) - Change RST PRES TRG	IFFS specific	ACRD specific
				Section: 5.2.Sys Config(COT) - Corrected EBR calibration setting	100	1.00
05/28/2014	1.01	K. Proctor	Sam. S	Section: 5.2.Sys Config(COT) - Addition to ReturnLineValid/InvalidForPumpVent setting	*	Valid*
				Section: 5.2.Sys Config(COT) - Update Refill System - [Tool Specific] - Refill No Setting Section: 5.3.Sys Config(PIR,SRS,BST) - Update comment for Controller TM150-CHILLER / THC - Cup Temp/Cup Humidity	Resist Specific N/A	Nozzle Specific Added TH (Lithius Spec)
				Section: 5.3.Sys Config(FIR,SRS,BST) - Update comment for Controller TM150-CHILLER Table 2	N/A	Added TH (Lithius Spec)
				Section: 6.Sys Config(Oven) - CGCH - Control Table Data list - Updated to Threshold setting	106	110
				Section: 6.Sys Config(Oven) - CGCH - Update to temp for Control Table Data (Temperature Range 170, 205, 240)	240	250
				Section: 13. EC SYSTEM Setting - Updated Equipment Mode Change 2 for BARC tools 5.3.Sys Config(PIR,SRS,BST) - Updated comment for TNU Temp/Humidity control O	Invalid ** See table 1	Valid / 300 sec ** PIR8-1 in TNU is TEMP CTRL ON
				Cover / ACRD tools / Software version	N/A	100.0.58.200
				Cover / ACRD tools / Sub Operation Panel version	N/A	5.01.35
				Cover / CRD tools / Software version	N/A	100.0.53.6
				Cover / CRD tools / MCr Patch Cover / CRD tools / Sub Operation Panel version	N/A N/A	287 5.01.32
				Section: 5.1.Sys Config(DEV) - ADR1 Rinse - Calibration1	Tool Specific	1.00
				Section: 5.1.Sys Config(DEV) - NTD - Dispense Prm - Local Nozzle - Dummy Dispense Attribute	Valid	Valid*
				Section: 5.1.Sys Config(DEV) - NTD - Dispense Prm - Local Nozzle - Dummy Dispense Attribute - comment	N/A	*Invalid for BACK RINSE1 and BEVEL
						RINSE V2 Merge DEV3, DEV9, BEVEL RINSE V2
				Section: 5.1.Sys Config(DEV) - NTD - Dispense Prm - Local Nozzle - Supply system	N/A	RINSE1 and BACK RINSE1 into 1 table
				Section: 5.1.Sys Config(DEV) - NTD - Dispense Prm - Local Nozzle - Supply system	N/A	Vent Time at IFF-S
				Section: 5.1.Sys Config(DEV) - NTD - Dispense Prm - Local Nozzle - Dispense Monitoring Control Data	N/A	Merge DEV3, DEV9, BEVEL RINSE V2
				Section: 5.2.Sys Config(COT/BCT/TCT) - Block 4,5,6 PR Block, Coater CRD PUMP ONLY - Dispense Parameter - Share		RINSE1 and BACK RINSE1 into 1 table
				Nozzle - RESIST NOZZLE# - RESIST# Supply System [Tool Specific] - Exhaust open delay at Reloadin	N/A	2.4
08/07/2014	1.02	K. Proctor	P.Ito	Section: 5.2.Sys Config(COT/BCT/TCT) - Block 4,5,6 PR Block, Coater CRD PUMP ONLY - Dispense Parameter - Share	NIA	1
				Nozzle - RESIST NOZZLE# - RESIST# Supply System [Tool Specific] - Pressure Release Tirr	N/A	1
				Section: 5.2.Sys Config(COT/BCT/TCT) - Reload Initial Pressure and Pump Return Vent Initial Pressure Settin	N/A	Corrected all table and add Setting value
				Section: 5.2.Sys Config(COT/BCT/TCT) - Block Arm - Left/Right / Module - Left, title	Block Arm - Left / Module Arm - Left	Block Arm - Left /Right / Module Arm - Left
				Section: 5.2.Sys Config(COT/BCT/TCT) - Block Arm - Left/Right / Module - Left - Spin Arm Parameter - Block Arm - Lef	Block Arm - Left	
				Right, title	Block Arm - Left	Block Arm - Left /Right
				Section: 5.2.Sys Config(COT/BCT/TCT) - Block Arm - Left/Right / Module - Left - Spin Arm Parameter - Exh Exclusive Contr Near Ready Time	N/A	Added
				Section: 5.2.Sys Config(COT/BCT/TCT) - Block Arm - Left/Right / Module - Left - Home Position - Block Arm -Left / Right, title	e Block Arm - Left	Block Arm - Left / Right
				Section: 5.3.Sys Config(BST) - AIR NOZZLE1 [5] - Process Recipe Attribut	N/A	Added
				Section: 5.3.Sys Config(BST) - AIR NOZZLE1 [5] - Dummy Dispense Attribut	N/A	Added
				Section: 5.3.Sys Config(BST) - AIR NOZZLE1 [5] - Dispense Mechanism Connection [1] - Valid, Inval	N/A Valid	Added Invalid
				Section: 8. System Parameter - Cup Wash - Washing Nozzle Tip Alarm Issu Section: 10. BST Control Parameter	N/A	Added (All portion)
				Section: 14. EC SYSTEM Setting - Item Level Settings - MAINTENANCE - Exclude Modul	Service	User Service
08/13/2014	1.03	C. Allen	P. Ito	No SW change in this revisior	N/A	N/A
				Section: 5.1.Sys Config(DEV) - LND/ LNR FILTDRAIN1 / RFILTDRAIN1 - Filter Replacement Sequence (1)[1] - STEP1 - Prol Section: 5.1.Sys Config(DEV) - LND/ LNR FILTDRAIN1 / RFILTDRAIN1 - Filter Replacement Sequence (1)[1] - STEP4 - Prol Section: 5.1.Sys Config(DEV) - LND/ LNR FILTDRAIN1 / RFILTDRAIN1 - Filter Replacement Sequence (1)[1] - STEP4 - Prol Section: 5.1.Sys Config(DEV) - LND/ LND / LND	None None	Hold Hold
				Section: 5.1.Sys Config(DEV) - LND/ LNR FILTDRAIN1 / RFILTDRAIN1 - Filter Replacement Sequence (2)[2] - STEP1 - Pro	None	Hold
				Section: 5.2.Sys Config(COT/BCT/TCT) - Block 4,5,6 PR Block, Coater CRD PUMP ONLY - Dispense Parameter - Share	Valid**	See Pro-V BKM spec for details
				Nozzle - Filter Vent Setting - Filter Vent Valid, Invalid	vanu	See F10-V BKW spec for details
				Section: 5.2.Sys Config(COT/BCT/TCT) - Block 4,5,6 PR Block, Coater CRD PUMP ONLY - Dispense Parameter - Share Nozzle - Laser DDS	N/A	Added
				Section: 5.2.Sys Config(COT/BCT/TCT) - Block 4,5,6 PR Block, Coater CRD PUMP ONLY - Dispense Parameter - Share	Valid	Invalid
				Nozzle - Pump Out Air Vent Settins Section: 5.2.Sys Config(COT/BCT/TCT) - Block 5,6 PR Block, Coater ACRD Tool ONLY - Dispense Parameter - Shared Nozzle		
				RESIST# Supply System [Tool Specific] - Refill Watch Tim	30	NOZZLE. SC. when nozzle height is 4.5m
1				Section: 5.2.Sys Config(COT/BCT/TCT) - NOZZLE.SC when nozzle height is 4.5mm *** - title	NOZZLE. SC. ***	***
1				Section: 5.2.Sys Config(COT/BCT/TCT) - NOZZLE.SC when nozzle height is 6.5mm **	N/A	Added
					[POS]	[POS]
				Section: 5.2.Sys Config(COT/BCT/TCT) - Local Nozzle - Dispense Monitoring Control Data - Calibration 1 - E.B.R. 1	0.80 - 0.95 [PGMEA]	0.80 - 0.99 [PGMEA]
					1.00 - 1.15	1.00 - 1.15
12/11/2014	1.04	K. Proctor	P.Ito	Section: 6. System Config Parameter, Ovens - Block 3 PR Block, Chil SWP (CSWP) Modules - Control Table Data list - Temp	N/A	60.00
				Range3 - Accum Threshold	10/1	00.00
				Section: 6. System Config Parameter, Ovens - Block 3 PR Block, Chil SWP (CSWP) Modules - Control Table Data list - Temp Range9 - Accum Thresholc	100.00	120.00
				Section: 6. System Config Parameter, Ovens - Block 3 PR Block, Chil SWP (CSWP) Modules - Control Table Data list - Temp	450.00	155.00
				Range14 - Accum Threshold	150.00	175.00
				Section: 6. System Config Parameter, Ovens - Block 3 PR Block, Chil SWP (CSWP) Modules - Control Table Data list - Temp	15.00	5.00
				Range3-8,10-13,15-18 - Accum Time Section: 6. System Config Parameter, Ovens - Block 3 PR Block, Chil SWP (CSWP) Modules - Control Table Data list - Temp		
				Range3 - Accum Threshold VAC ON	N/A	60.00
				Section: 6. System Config Parameter, Ovens - Block 3 PR Block, Chil SWP (CSWP) Modules - Control Table Data list - Temp Range9 - Accum Threshold VAC ON	100.00	120.00
				Section: 6. System Config Parameter, Ovens - Block 3 PR Block, Chil SWP (CSWP) Modules - Control Table Data list - Temp Range 14 - Accum Threshold VAC ON	150.00	175.00
				Range 1-4 Necturi Trucision V Corres - Block 3 PR Block, Chil SWP (CSWP) Modules - Control Table Data list - Temp Range 3-8,10-13,15-18 - Accum Time	15.00	5.00
				Range 5-8,10-13,15-18 - Accum Time Section: 8. System Parameter - Cup Wash - Option Automatic Cup Wash Ski	Invalid	Valid (Alarm Off)
1				Section: 11. Adjustment Tool Parameter - Transfer Arm No. 4-0 Calibration Data [4-0] - 4-1 [Resist Tracks] or 4-11[BARC		
				Tracks] - Datald - BARC Tracks	0x02	0x08
				Cover / ACRD tools / Software version	100.0.58.200	100.0.58.203
				Cover / CRD tools / Software version Cover / CRD tools / MCr Patch	100.0.53.6 MCr287	100.0.58.202 Deleted
			D Is.	Cover / CRD tools / Nict Fatch Cover / CRD tools / Sub Operation Panel version	5.01.32	5.01.35
3/20/2015	1.05	K. Proctor	roctor P.Ito			
3/20/2015	1.05	K. Proctor	P.Ito	Section: 5.1.Sys Config(DEV) - Dispense Parameter - Shared Nozzle - Dispense Monitoring Control Data - Set Flow Rate	600	600*
3/20/2015	1.05	K. Proctor	P.110			

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Date	Rev.	Appi INTEL		Location	Old	New				
		INTEL	TEL	Section: 5.1.Sys Config(DEV) - DEV NZL4(Sub) - Dispense Monitoring Control Data - Comment	N/A	* 400 for Post SED *** NC and SC are not available for Water				
				Section: 5.2.Sys Config(COT/BCT/TCT) - NOZZLE. SC when nozzle height is 4.5mm/6.5mm *** - Comment	base solvent baths	base solvent baths (TCT)				
				Section: 5.2.Sys Config(COT/BCT/TCT) - Block Arm - Left / Right / Module Arm - Left / Exh Exclusive Control Near Reac Time - Item	Exh Exclusive Control Near Ready Time	Exh Exclusive Control Near Ready Time				
				Section: 5.2.Sys Config(COT/BCT/TCT) - Block Arm - Left / Right / Module Arm - Left / Exh Exclusive Control Near Reac Time - Commen	N/A	* The parameter only exists on TAX/TNU tools				
				Section: 5.3.Sys Config (PIR/SRS/BST) - Block 8 IPB, I-RINSE / S-Rinse* - Reserved Fla Section: 5.3.Sys Config (PIR/SRS/BST) - Block 8 IPB, I-RINSE / S-Rinse* - Reserved Flag - Comme	Invalid N/A	Invalid** ** Valid for Post SED Tracks				
				Section: 6. System Config Parameter, Ovens - Block 3/ Block 4/ Block 5/ Block 6 PR Block, Chil PHP,PRP (CPHP/CPRI	N/A	Added Temp. Range 20/21/22/23/24				
				Modules - Control Table Data list - Table Section: 6. System Config Parameter, Ovens - Block 3/ Block 4/ Block 5/ Block6 PR Block, Chil PHP,PRP (CPHP/CPRI	N/A	** For Post SED tracks				
				Modules - Control Table Data list - Commen Section: 6. System Config Parameter, Ovens - Block 3/ Block 4/ Block 5/ Block6 PR Block, Chil PHP,PRP (CPHP,CPRI	Control Table Data (Temperature Range 70					
				Modules - Control Table Data - Title Section: 6. System Config Parameter, Ovens - Block 4 PR Block, C.ADH (ADH) Modules - Control Table Data list - Temperatur	100, 125, 150)	70, 100, 125, 150, 175)				
				Range 4 - Title Section: 6. System Config Parameter, Ovens - Block 4 PR Block, C.ADH (ADH) Modules - Control Table Data list - Temperatur	Temperature Range4	Temperature Range4**				
3/20/2015	1.05	K. Proctor	P.Ito	Range 4 - Setting Lower	N/A	125.00				
				Section: 6. System Config Parameter, Ovens - Block 4 PR Block, C.ADH (ADH) Modules - Control Table Data list - Temperatur Range 4 - Accum Thresholc	N/A	62.29				
				Section: 6. System Config Parameter, Ovens - Block 4 PR Block, C.ADH (ADH) Modules - Control Table Data list - Temperatur Range 4 - Commen	N/A	** For Post SED tracks				
				Section: 8. System Parameter - GJG - Option The Number of Remaining Wafers before Reporting Carrier Approaching Complete Event	N/A	0				
				Section: 8. System Parameter - Others - Self-diagnostic information logging ⁴ Section: 8. System Parameter - Others - Self-diagnostic information logging ** - Comme	N/A N/A	Valid ** = Available v54 and beyond				
1				Section: 8. System Parameter - Others - Brush Pressure Setting during BST wafer Processin	N/A	Invalid				
				Section: 8. System Parameter - Others - Option Optimized Offset Transfer at Manual Transfer of Wafer Flow Recipe **** Section: 8. System Parameter - Others - Option Optimized Offset Transfer at Manual Transfer of Wafer Flow Recipe ******	N/A N/A	Valid ***** = It is only present on tools with C				
				Comment	*Settings are available only on immersion	Optimizer installed. * Settings are available on tracks linked to				
				Section: 12. EC Display Overview - Linked Litho common log* - Comment Section: 13. EC ON-LINE Setting - Linked Litho Channel Parameter* - Commer	systems with Linked Litho valid	scanners. *settings are available only on tracks linke				
				-	N/A	to scanners.				
				Section: 14. EC SYSTEM Setting Equipment mode change - Exposure system - Comme Section: 14. EC SYSTEM Setting Equipment mode change - Automatic Register - Exposure system - Commo	*LOCAL For BARC Tools *LOCAL For BARC Tools	*LOCAL For BARC and pose SED tracks *LOCAL For BARC and pose SED tracks				
				Section: 14. EC SYSTEM Setting Equipment mode change2 - Commes Section: 4. System Configuration Parameter, Arm - Block 3, 4, 5, 6 PR Block - Z-axis Multistep Movement - CPL / TF	FOR BARC Invalid	FOR BARC and post SED tracks Invalid / Valid *				
				Section: 4. System Configuration Parameter, Arm - Block 3, 4, 5, 6 PR Block - Z-axis Multistep Movement - CPHP / CAD//CPRP / CGCH / CSWP	Invalid	Invalid / Valid *				
				Section: 4. System Configuration Parameter, Arm - Block 3, 4, 5, 6 PR Block - Z-axis Multistep Movement - SCI	Invalid	Invalid / Valid *				
				Section: 4. System Configuration Parameter, Arm - Block 3, 4, 5, 6 PR Block - Z-axis Multistep Movement - SB Section: 4. System Configuration Parameter, Arm - Block 3, 4, 5, 6 PR Block - Z-axis Multistep Movement - Comment	Invalid N/A	Invalid / Valid * * Softlanding function installed tool				
				Section: 4. System Configuration Parameter, Arm - Block 3, 4, 5, 6 PR Block - Z-axis Multistep Movement (Receiv	N/A	Added				
				Section: 4. System Configuration Parameter, Arm - Block 3, 4, 5, 6 PR Block - Z-axis Multistep Movement (Sen Section: 4. System Configuration Parameter, Arm - Block 8 IPB-Immersion Configuration ONLY - Z-axis Multistep Movemen	N/A	Added				
				TRS	Invalid	Invalid / Valid *				
				Section: 4. System Configuration Parameter, Arm - Block 8 IPB-Immersion Configuration ONLY - Z-axis Multistep Movemen ISHU	Invalid	Invalid / Valid *				
				Section: 4. System Configuration Parameter, Arm - Block 8 IPB-Immersion Configuration ONLY - Z-axis Multistep Movement CPL	Invalid	Invalid / Valid *				
				Section: 4. System Configuration Parameter, Arm - Block 8 IPB-Immersion Configuration ONLY - Z-axis Multistep Movement - Comment	N/A	** Softlanding function installed tool				
								Section: 4. System Configuration Parameter, Arm - Block 8 IPB-Immersion Configuration ONLY - Z-axis Multistep Moveme	N/A	Added
								(Receive) Section: 4. System Configuration Parameter, Arm - Block 8 IPB-Immersion Configuration ONLY - Z-axis Multistep Moveme	N/A	Added
					(Send) Section: 5.1.Sys Config(DEV) - XDR1 N2	N/A	Added			
				Section: 5.1.Sys Config(DEV) - XDR1 RINSE Section: 5.1.Sys Config(DEV) - Block 3 PR Block, Developers [3-5] -[3-8] W/ NTD [TAQ/TNQ/TAX] Block 3/5 PR Block,	N/A	Added				
				Developers [3-3,4,7,8] and [5-3,4] for 6x6 NTD [TAR/TNR/TNS/TAS/TNU/TNK] - CRF Setting**	N/A	Added				
				Section: 5.1.Sys Config(DEV) - Block 3 PR Block, Developers [3-5] -[3-8] W/NTD [TAQ/TNQ/TAX] Block 3/5 PR Block,	NI/A	4.11.1				
				Developers [3-3,4,7,8] and [5-3,4] for 6x6 NTD [TAR/TNR/TNS/TAS/TNU/TNK] - DEV.SOLU.2 Supply System / N.T.DEV SOLUTION1 Supply System / N.T.DEV SOLUTION2 Supply System / SOLVENT2 Supply System - Return Mode Setting **	N/A	Added				
5/6/2015	2.00	K.Proctor	P. Ito	Section: 5.1.Sys Config(DEV) - Block 3 PR Block, Developers [3-5] -[3-8] W/ NTD [TAQ/TNQ/TAX] Block 3/5 PR Block Developers [3-3,4,7,8] and [5-3,4] for 6x6 NTD [TAR/TNR/TNS/TAS/TNU/TNK] - Dispense Parameter - Local Nozzle - CRF	NI/A	Added				
				Setting*	N/A	Added				
				Section: 5.1.Sys Config(DEV) - Block Arm - Left/ Block Arm - Right/ Module Arm - Left - Recipe Position - ADR / XDR - Rins Arm - Title	ADR - Rinse Arm	ADR / XDR - Rinse Arm				
				Section: 5.1.Sys Config(DEV) - Block Arm - Left/ Block Arm - Right/ Module Arm - Left - Recipe Position - ADR / XDR - Rin: Arm - Recipe Position Name -Enc	0.00	-150.00**				
				Section: 5.1.Sys Config(DEV) - Block Arm - Left/ Block Arm - Right/ Module Arm - Left - Recipe Position - ADR / XDR - Rin: Arm - Recipe Position Name - Edge (E	0.00	-161.00**				
				Section: 5.2.Sys Config(COT/BCT/TCT) - Block 5,6 PR Block, Coater ACRD Tool ONLY - Dispense Parameter - Shared Nozzle RESIST NOZZLE# - Periodic Return Valid/Invalia	N/A	Added				
				Section: 5.2.Sys Config(COT/BCT/TCT) - Block 5,6 PR Block, Coater ACRD Tool ONLY - Dispense Parameter - Shared Nozzlo	N/A	Added				
				Dispense Line Data Section: 5.2.Sys Config(COT/BCT/TCT) - Block 5,6 PR Block, Coater ACRD Tool ONLY - Dispense Parameter - Shared Nozzle	N/A	Added				
				Resist Interval Return Setting Section: 5.2.Sys Config(COT/BCT/TCT) - Block 5,6 PR Block, Coater ACRD Tool ONLY - Dispense Parameter - Shared Nozzle						
				IFF-R Setting Section: 5.2.Sys Config(COT/BCT/TCT) - Reload Initial Pressure and Pump Return Vent Initial Pressure Settings - Toc	N/A TNU/TAS/TNK	Added TNU/TAS/TNK/TSH/TSL				
				Section: 5.2.Sys Config(COT/BCT/TCT) - CRF Setting***	N/A	Added				
ı				Section: 5.2.Sys Config(COT/BCT/TCT) - Monitoring Parameter - Table for Temperature Control Method - Module	4-X COT, 5-X COT/BCT, 6-X COT/BCT	4-X COT/TCT, 5-X COT/BCT/TCT, 6-X COT/BCT/TCT				
				Section: 5.2.Sys Config(COT/BCT/TCT) - * Table for TM150-CHILLER / THC	4-X COT, 5-X COT/BCT, 6-X COT/BCT	4-X COT/TCT, 5-X COT/BCT/TCT, 6-X COT/BCT/TCT				
				Section: 5.2.Sys Config(COT/BCT/TCT) - Table for Channel No. Section: 6. Sys Config, Ovens - Block 3/ Block 4/ Block 5/ Block6 PR Block, Chil PHP,PRP (CPHP/CPRP) Modules - Controller	4-X COT, 5-X COT/BCT, 6-X COT/BCT	4-X COT/TCT, 5-X COT/BCT/TCT, 6-X COT/BCT/TCT				

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Date	Rev.	Appi INTEL	roval TEL	Location	Old	New
				Section: 6. Sys Config, Ovens - Block 3/ Block 4/ Block 5/ Block 6 PR Block, Chil PHP,PRP (CPHP/CPRP) Modules - Control	N/A	Added Temp. Ramge3 / 4 / 5 / 6
5/6/2015	2.00	K.Proctor	P. Ito	Table Data listValid/Invalid Section: 6. Sys Config, Ovens - Block 3/ Block 4/ Block 5/ Block6 PR Block, Chil PHP,PRP (CPHP/CPRP) Modules - Control	(Temperature Range 60, 70, 100, 125, 150,	(Temperature Range 55, 60, 70, 100, 125,
				Table Data (Temperature Range)	175)	150, 175)
				Section: 5.1.Sys Config Prm Spinners (DEV) - Local Nozzle - ADR1 RINSE - "Flow Rate during Dispense Process" tab Section: 5.1.Sys Config Prm Spinners (DEV) - Local Nozzle - RINSE1 - "Flow Rate during Dispense Process" tab	N/A N/A	Added Added
				Section: 5.1.Sys Config(DEV) - Block 3 PR Block, Developers [3-5] -[3-8] W/ NTD [TAQ/TNQ/TAX] Block 3/5 PR Block Developers [3-3,4,7,8] and [5-3,4] for 6x6 NTD [TAR/TNR/TNS/TAS/TNU/TNK] - Dispense Parameter - Shared Nozzle - EXH	N/A	Added
0.15.00.4.5		K. Proctor		DRAIN PUMP Section: 5.2.Sys Config(COT/BCT/TCT) - Block Arm - Left / Right / Module Arm - Left - Recipe Position - "TCT" section Section: 6. Sys Config, Ovens - Block 3/ Block 4/ Block 5/ Block6 PR Block, Chil PHP.PRP (CPHP/CPRP) Modules - Monitorin	N/A	Added
8/6/2015	2.01	S. Havelia K. Krantz	P. Ito	parameter - Control Table Data List - Temp Range 3 - Accum Threshol	20	18
				Section: 6. Sys Config, Ovens - Block 3/ Block 4/ Block 5/ Block6 PR Block, Chil PHP,PRP (CPHP/CPRP) Modules - Monitorin parameter - Control Table Data List - Temp Range 4 - Accum Threshol	20	18
				Section: 6. Sys Config, Ovens - Block 3/ Block 4/ Block 5/ Block6 PR Block, Chil PHP,PRP (CPHP/CPRP) Modules - Monitorin parameter - Control Table Data List - Temp Range 5 - Accum Threshol	20	18
				Section: 6. Sys Config, Ovens - Block 3/ Block 4/ Block 5/ Block6 PR Block, Chil PHP,PRP (CPHP/CPRP) Modules - Monitorin parameter - Control Table Data List - Temp Range 6 - Accum Threshol	g 20	18
				Cover / ACRD tools / Software version	100.0.58.203	100.0.58.204
				Cover / CRD tools / Software version	100.0.58.202	*= Not present on BARC & Invalid for
				Section: 2. Start Up Setting - LINKED LITHO Interface - Comments	*= Not present on TBC & Invalid for TAX	PostSED tracks
				Section: 5.2. Sys Config(COT/BCT/TCT) - Reload Initial Pressure and Pump Return Vent Initial Pressure Settings - To	TBC	BARC
				Section: 5.2.Sys Config(COT/BCT/TCT) - Reload Initial Pressure and Pump Return Vent Initial Pressure Settings - TA Section: 5.2.Sys Config(COT/BCT/TCT) - Interval for Circulation ***	N/A N/A	Added Added
				Section: 5.2.Sys Config(COT/BCT/TCT) - SOLVENT1 Supply System [Tool Specific] - Item / Dispen	Return Mode Setting	Return Mode Setting *1
				Section: 6. System Config Parameter, Ovens - Block 2 MP Block/ Block 8 IPB, Chil Plt (CPL) Modules - Table1 - Configuration	4x4 IMM TNE NON-CE	Dry Non-CE 4x4Imm 4x4PostSED
				Section: 6. System Config Parameter, Ovens - Block 2 MP Block/ Block 8 IPB, Chil Plt (CPL) Modules - Table1 - Configuration	4x4 IMM / 6x6 IMM TAX	EUV Imm PostSED
				Section: 6. System Config Parameter, Ovens - Block 2 MP Block/ Block 8 IPB, Chil Plt (CPL) Modules - Table1 - Configuration	TNE CE / NON-CE	Dry
				Section: 6. System Config Parameter, Ovens - Block 2 MP Block/ Block 8 IPB, Chil Plt (CPL) Modules - Table1 - Configuration	TBC *	BARC *
				Section: 6. System Config Parameter, Ovens - Block 2 MP Block/ Block 8 IPB, Chil Plt (CPL) Modules - Table1 - *	Post SED TAQ and NIKON = 22.2C AND ASML = 22.0C	PostSED and NIKON = 22.2C AND ASM = 22.0C
				Section: 6. System Config Parameter, Ovens - Block 2 MP Block/ Block 3 PR Block/ Block 7 MP Block, S-CPL (SCPL) Module Table 2 - Configuration	TNE CE/NTD 6x6 IM	Dry CE / EUV6x6 Imm / 6x6 PostSED
				Section: 6. System Config Parameter, Ovens - Block 2 MP Block/ Block 3 PR Block/ Block 7 MP Block, S-CPL (SCPL) Module Table 2 - Configuration	NTD 4x4 IM TNE NON-CE	Dry NON-CE 4x4 Imm / 4x4 PostSED
11/12/2015	2.02	K. Proctor	P. Ito	Section: 6. System Config Parameter, Ovens - Block 2 MP Block/ Block 3 PR Block/ Block 7 MP Block, S-CPL (SCPL) Module Table 2 - Configuration	NTD 4x4 IMTNE NON-CENTD 6x6 IMTNE CE	Dry / EUV / Imm / PostSED
				Section: 6. System Config Parameter, Ovens - Block 2 MP Block/ Block 3 PR Block/ Block 7 MP Block, S-CPL (SCPL) Module Table 2 - Configuration	N I D 6x6 IM	6x6 Imm6x6 PostSED
				Section: 6. System Config Parameter, Ovens - Block 2 MP Block/ Block 3 PR Block/ Block 7 MP Block, S-CPL (SCPL) Module Table 2 - Configuration	TBC/TBE	BARC
				Section: 6. System Config Parameter, Ovens - Block 2 MP Block/ Block 3 PR Block/ Block 7 MP Block, S-CPL (SCPL) Module		BARC Dry Non-CE EUV
				Table 2 - Configuration	NTD 6x6 IM TBC NTD 4x4 IM TNE NON-CE	4x4 Imm 4x4 PostSED
				Section: 6. System Config Parameter, Ovens - Block 2 MP Block/ Block 3 PR Block/ Block 7 MP Block, S-CPL (SCPL) Module Table2 - Configuration	TNE CE NTD 6x6 IM TBC/TBE	All ProV
				Section: 8. System Parameter - Exposure Interface	Option Linked Litho Application [Not	Option Linked Litho Application [Not Present for BARC and 6x6 PostSED, Inval
					Present for TBC] Option Linked Litho Alarm Auto Recovery	for 4x4 PostSED] Option Linked Litho Alarm Auto Recover
				Section: 8. System Parameter - Exposure Interface	[Not Present for TBC]	[Not Present for BARC and 6x6 PostSED
				Section: 8. System Parameter - Exposure Interface	Option Linked Litho Alarm Auto Times [Not Present for TBC]	Option Linked Litho Alarm Auto Timer [N Present for BARC and 6x6 PostSED]
				Section: 8. System Parameter - Exposure Interface	Option Linked Litho No Wafer Exposure Lot End [Not Present for TBC]	Option Linked Litho No Wafer Exposure Lot End [Not Present for BARC and 6x6
				Section: 14. EC SYSTEM Setting - Item Level Settings - LOG - Linked Litho Log - Item Lev	User Service	PostSED] User service ***
				Section: 14. EC SYSTEM Setting - Auto logout Settings - Auto logout time settir	30 min	60 min
				Cover / ACRD tools / Software version Cover / CRD tools / Software version	100.0.58.204 100.0.58.204	100.0.58.207 100.0.58.207
				Cover / CRD tools / Software version Cover / ACRD tools / Sub Operation Panel version	5.01.35	5.01.37
				Cover / CRD tools / Sub Operation Panel version	5.01.35	5.01.37
				Cover / Teaching Version Cover / Temperature Version	1.18 1.24	1.22 1.28
				Section: 4. System Configuration Parameter, Arm - Block 1 CS Block - Transfer Arm Control Parameter - Specifying Wafer Cour		Added
				Section: 4. System Configuration Parameter, Arm - Block 1 CS Block - Transfer Arm Control Parameter - Wafer Count for Maint	NA	Added
				Section: 4. System Configuration Parameter, Arm - Block 2, 7 MP Block - Transfer Arm Control Parameter - Specifying Was	NA	Added
				Section: 4. System Configuration Parameter, Arm - Block 2, 7 MP Block - Transfer Arm Control Parameter - Wafer Count for Mi	NA	Added
				Section: 4. System Configuration Parameter, Arm - Block 3, 4, 5, 6 PR Block - Transfer Arm Control Parameter - Specifyir Wafer Count for Maintenance Notification '	NA	Added
2/24/2016	2.03	K. Proctor	P. Ito	Section: 4. System Configuration Parameter, Arm - Block 3, 4, 5, 6 PR Block- Transfer Arm Control Parameter - Wafer Count for Section: 4. System Configuration Parameter, Arm - Block 8 IPB-Immersion Configuration ONLY - Transfer Arm Contr Parameter - Specifying Wafer Count for Maintenance Notification	NA NA	Added Added
				Section: 4. System Configuration Parameter, Arm - Block 8 IPB-Immersion Configuration ONLY- Transfer Arm Control Parame		Added
				Section: 5.1.Sys Config Prm Spinners (DEV) - TAX DEV NOZZLE 5 - Dispense Monitoring Control Data tab Section: 5.1.Sys Config Prm Spinners (DEV) - FIRM 1 - IF PRESENT - Automatic Air Vent tabl	NA NA	Added Added
				Section: 5.1.Sys Config Prm Spinners (DEV) - Dispense Parameter - Local Nozzle - DEV3(Local Arm) / DEV9(Local Arm)*		** DEV3(Local Arm) and RINSE1 of CRI
				BEVEL RINSE V2 / RINSE1 / BACK RINSE1 *TAX Only - CRF Setting** - Commer	**For CRF enabled tool	enabled tool
				Section: 5.1.Sys Config Prm Spinners (DEV) - Dispense Parameter - Local Nozzle - DEV3(Local Arm) / DEV9(Local Arm)* BEVEL RINSE V2 / RINSE1 / BACK RINSE1 *TAX Only - Interval for Circulation** tabl	NA	Added
				Section: 5.1.Sys Config Prm Spinners (DEV) - Dispense Parameter - Local Nozzle - DEV3(Local Arm) / DEV9(Local Arm)*	*For CRF enabled tool	* DEV3(Local Arm) and RINSE1 of CRE
				BEVEL RINSE V2 / RINSE1 / BACK RINSE1 *TAX Only - CRF Setting* - Commet Section: 5.2.Sys Config(COT/BCT/TCT) - Reload Initial Pressure and Pump Return Vent Initial Pressure Settings - Tox	TAX	enabled tool TAX430/431
				Section: 5.2.Sys Config(COT/BCT/TCT) - Reload Initial Pressure and Pump Return Vent Initial Pressure Settings - TAX432/433	NA NA	Added
				Section: 5.2.Sys Config(COT/BCT/TCT) - Interval for Circulation**** comme	**** For CRF enabled too	**** RRC NOZZLE1 of CRF enabled too
					. or Cita enabled too	TATE TO ELECT OF CITY CHARGES IN

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Date	Rev.	App INTEL	roval TEL	Location	Old	New
I				Section: 5.2.Sys Config(COT/BCT/TCT) -CUP EXH Process Recipe Attribut	Invalid	Invalid*
				Section: 5.2.Sys Config(COT/BCT/TCT) -CUP EXH Process Recipe Attribute - Commer	NA	* Valid for TNU
				Section: 5.4.Sys Config(BST) - RINSE 1 [49] - Dispense Monitoring Control Data - Set Flow Rat	150	200
				Section: 5.4.Sys Config(BST) - Cup temp./ Motor flange temp./ Cup humidity - Controller TM150-CHILLER / THC - Controll ID - Cup temp.	CF9010-F400	TM150-THC *
				Section: 5.4.Sys Config(BST) - Cup temp./ Motor flange temp./ Cup humidity - Controller TM150-CHILLER / THC - Controll ID - Cup Humidity	CF9010-F400	TM150-THC *
				Section: 5.4.Sys Config(BST) - Cup temp./ Motor flange temp./ Cup humidity - Controller TM150-CHILLER / THC - Monitorii Type - Cup temp.	Use point Control	Use point Control **
				Section: 5.4.Sys Config(BST) - Cup temp./ Motor flange temp./ Cup humidity - Controller TM150-CHILLER / THC - Monitorii Type - Cup Humidity	Use point Read	Use point Control **
				Section: 5.4.Sys Config(BST) - Cup temp./ Motor flange temp./ Cup humidity - Controller TM150-CHILLER / THC - Source	NA	Added
				Section: 5.4.Sys Config(BST) - Cup temp./ Motor flange temp./ Cup humidity - Controller TM150-CHILLER / THC - Soura	NA	Added
				Section: 5.4.Sys Config(BST) - Cup temp./ Motor flange temp./ Cup humidity - Controller TM150-CHILLER / THC - * Comment	NA	* TAX430/431 : CF9010-F400
				Section: 5.4.Sys Config(BST) - Cup temp./ Motor flange temp./ Cup humidity - Controller TM150-CHILLER / THC - ** Comment	NA	** TAX430/431 : Use point read
				Section: 5.4.Sys Config(BST) - Cup temp./ Motor flange temp./ Cup humidity - Controller TM150-CHILLER / THC - ** Comment	NA	*** TAX430/431 8-1 Only
				Section: 5.4.Sys Config(BST) - Spinner Arm Control Data - Theta-axis Reference Point [Pulse] - Rinse Ar	30567	Tool Specific
2/24/2016	2.03	K. Proctor	P. Ito	Section: 5.4.Sys Config(BST) - Spinner Arm Control Data - Theta-axis Reference Point [Pulse] - Brush Ar	31788	Tool Specific
				Section: 5.4.Sys Config(BST) - Spinner Arm Control Data - Theta-axis Reference Point [Deg] - Rinse Ar	45.85	Tool Specific
				Section: 5.4.Sys Config(BST) - Spinner Arm Control Data - Theta-axis Reference Point [Deg] - Brush Ar	127.15	Tool Specific
				Section: 5.4.Sys Config(BST) - Spinner Arm Control Data - Z-axis Reference Point (Cylinder) - Brush Ar	12196	NA
				Section: 5.4.Sys Config(BST) - Spinner Arm Control Data - Z-axis Reference Point (Motor)[puls	NA	Added
				Section: 5.4.Sys Config(BST) - Spinner Arm Control Data - Z-axis Reference Point (Motor)[puls	NA	Added
				Section: 5.4.Sys Config(BST) - Recipe Position - Home Position - Rinse Arm - Theta Positio	-767	Tool Specific
				Section: 5.4.Sys Config(BST) - Recipe Position - Center - Brush Arm - Z Position-MOTO	680	Tool Specific
				Section: 5.4.Sys Config(BST) - Recipe Position - Bath - Brush Arm - Theta Positio	-33875	Tool Specific
				Section: 5.4.Sys Config(BST) - Recipe Position - Bath - Brush Arm - Z Position-MOTO	1040	Tool Specific
				Section: 5.4.Sys Config(BST) - Recipe Position - Bath - Brush Change - Z Position-MOTO	1040	Tool Specific
				Section: 5.4.Sys Config(BST) - Recipe Position - PAD Arr	Theta Position	X Position (Offset)
				Section: 5.4.Sys Config(BST) - Recipe Position - Center - PAD Arm - X Position (Offse	114980	11980
				Section: 8. System Parameter - Others(cont) - Option Upper Limit of Wafer Spin Speed in XDR N2 Dispense Step *****	NA	Added
				Section: 8. System Parameter - Dummy Dispense - Option Start Time of Periodic Resist Return Operation during Wafer Transf Stop *	NA	Added
				Section: 10.BST Control Parameter - BST Module Parameter - Spin Motor Info. Tabl	NA	Added
				Section: 14. EC SYSTEM Setting - Network configuration - Interface setting - Interface Nam	pro0	pro0/eke0
				Section: 14. EC SYSTEM Setting - Network configuration - Interface setting - Interface Nam	pro1	pro1/eke1
				Section: 15. Data Collect Condition Editor - Condition Name	[Time (2sec)]	[Time (2sec),Env(60s)]
				Cover / Teaching Version	1.22	1.23
				Section: 4. System Configuration Parameter, Arm - Each arm - Transfer Arm Control Parameter - Specifying Wafer Count for Maintenance Notification	Exist	Deleted (Moved to 1276 FPD)
			r P. Ito	Section: 4. System Configuration Parameter, Arm - Each arm - Transfer Arm Control Parameter - Wafer Count for Maintenance	Exist	Deleted (Moved to 1276 FPD)
				Notification Section: 5.1.Sys Config Prm Spinners (DEV) - TAX DEV NOZZLE 2 - Tabl	Exist	Deleted (Moved to 1276 FPD)
				Section: 5.1.Sys Config Prin Spinners (DEV) - TAX DEV NOZZLE 2 - Tabl Section: 5.1.Sys Config Prin Spinners (DEV) - TAX DEV NOZZLE 5 - Tabl	Exist	Deleted (Moved to 1276 FPD)
				Section: 5.1.Sys Config Prin Spinners (DEV) - TAX DEV NOZZZEE 5 - 1 abi	Exist	Deleted (Moved to 1276 FPD)
				Section: 5.1.Sys Config Prm Spinners (DEV) - TAX DIW NZL[5] Sub - Tabl	Exist	Deleted (Moved to 1276 FPD)
5/2/2016	3.00	K. Proctor		Section: 5.1.Sys Config Prm Spinners (DEV) - Block Arm - Left/ Block Arm - Right/ Module Arm - Left - Recipe position - FIRM	Exist	Deleted (Moved to 1276 FPD)
				Table Section: 5.1. System Config Parameter, Spinners (DEV) - NTD FILTDRAIN1*/2*/3* - Sovent-D supply System - Post-Refill Ve	1.0	3.0
				Time Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Reload Initial Pressure and Pump Return Vent Initial Pressu		
				Settings - TAX Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Table for Temperature Control Method [TA].	Exist Exist	Deleted (Moved to 1276 FPD) Deleted (Moved to 1276 FPD)
				Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Table for Channel No TA	Exist	Deleted (Moved to 1276 FPD)
				Section: 5.2. System Config Parameter, Spinners (COT/BCT) - Table for Chainlet No TA Section: 5.3. System Config Parameter, Spinners (PIR/SRS) - Module Arm - Left - Recipe position - Dispense 4 - Y position	0.00	-130.00
				Section: 5.4. System Config Parameter, Spinners (BST	Exist	Deleted (Moved to 1276 FPD)
				Section: 13. EC SYSTEM Setting - Item Level Settings - MAINTENANCE - Firmware Ver. Monits	Service	User Service
				Cover / ACRD tools / Software version	ACRD tools	Dual Resist Arm Systems
1				Cover / Except for BARC and Dry tools / Software version	100.0.58.207	100.0.58.208
				Cover / CRD tools / Software version	CRD tools	Single Resist Arm systems
				Section: 3. System Configuration Parameter, System - Israel : Barometric pressur	NA NA	1000.00hPa
				Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - RESIST# Supply System [Tool Specific] - RefillWatchTime	RefillWatchTime	Refill Monitoring Time
				Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - RESIST# Supply System [Tool Specific]	NA	RESIST# Supply System
7/22/2016	3.01	K. Proctor	H.Nagai	Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - RESIST# Supply System [Tool Specific]	NA	[Tool Specific] : POR RESIST# Supply System [Tool Specific] :
,,22,2010	5.01	2. 1700101		Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - RESIST# Supply System [Tool Specific]: M-ACRD Packag		ACRD Package
				The Number of Wafers to be Processeα	NA	50
				Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - RESIST# Supply System [Tool Specific] : M-ACRD Packag Refill Monitoring Time	NA	30.0
				Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Reload Initial Pressure and Pump Return Vent Initial Pressu Setting	TNU/TAS/TNK/TSH/TSL	Immersion (7×3) and TSL/TSH
				Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Reload Initial Pressure and Pump Return Vent Initial Pressure	NA	Immersion (6×4)
	1			<u>-</u>		1

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Date	Rev.	App: INTEL	roval TEL	Location	Old	New							
				Section: 5.1. System Config Parameter, Spinners (DEV) - Block 3 PR Block, Developers [3-1] - [3-8] for 8x0 PTD - title	Block 3 PR Block, Developers [3-1] - [3-8] for PTD DRY-CE	Block 3 PR Block, Developers [3-1] - [3-8 for 8x0 PTD							
				Section: 5.1. System Config Parameter, Spinners (DEV) - DEV NOZZLE2> TNE/TNG Config ONLY LD Nozzle - title	DEV NOZZLE2> TNE Config ONLY LD Nozzle	DEV NOZZLE2> TNE/TNG Config ONLY LD Nozzle							
				Section: 5.1. System Config Parameter, Spinners (DEV) - Block 3 PR Block, Developers [3-5] -[3-8] W/ NTD for 4x4 NTD [TAG	Block 3 PR Block, Developers [3-5] -[3-8] W/ NTD [TAQ/TNQ]	Block 3 PR Block, Developers [3-5] -[3-8 W/ NTD for 4x4 NTD [TAQ/TNQ]							
				Section: 5.1. System Config Parameter, Spinners (DEV) - NTD FILTDRAIN 1*/2*/3* - CRF Setting Section: 5.1. System Config Parameter, Spinners (DEV) - NTD FILTDRAIN 1*/2*/3* - Interval for Circulation	NA NA	Added Added							
				Section: 5.1. System Config Parameter, Spinners (DEV) - NTD RFILTDRAIN 1*/2* - CRF Settir	NA NA	Added							
				Section: 5.1. System Config Parameter, Spinners (DEV) - NTD RFILTDRAIN 1*/2* - Interval for Circulatic	NA	Added							
				Section: 5.1. System Config Parameter, Spinners (DEV) - NTD FILTDRAIN 1*/2*/3* / NTD-RFILTDRAIN 1*2* - Dispens Monitoring Control Data - Matrix	NA	Added							
				Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Block 4,5,6 PR Block, Coater CRD PUMP ONLY - Dispens Paramter - Shared Nozzle - RESIST NOZZLE# - Filter Vent Setting - Filter Vent Valid, Invali	See Pro-V BKMspec for details	Invalid							
				Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Block 4,5,6 PR Block, Coater ACRD tool ONLY - Dispens Parameter - Shared Nozzle - RESISTN OZZLE# - RESIST# Supply System [Tool Specific]: M-ACRD Package - The Number of Wafers to be Processed - Settins	50	See table below							
				Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Block 4,5.6 PR Block, Coater ACRD tool ONLY - Dispens Parameter - Shared Nozzle - RESIST NOZZLE# - RESIST# Supply System [Tool Specific]: M-ACRD Package - The Number of Wafers to be Processed - Table	NA	Added							
			P. Ito	Waters to be Processed - 1 able Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Reload Initial Pressure and Pump Return Vent Initial Pressu Settings - Immersion (7x3) - title	Immersion (7×3) and TSL/TSH	Added Immersion (7×3) TAQ Added Added [POS]0.85 - 0.99 [PGMEA]1.00 - 1.15 [H2O]TBD [POS]0.80 - 0.99 [PGMEA]1.00 - 1.15 [H2O]TBD (Temperature Range 55*, 60*, 70, 100, 125 150, 175*) * Post SED Only Added Dry Non-CE 4x4 Imm 8x0 TAQ Dry CE 6x6 Imm / 8x0 THY							
2016/09/XX	4.00	K. Proctor	/H.Nagai	Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Reload Initial Pressure and Pump Return Vent Initial Pressu	TAQ/TNQ	TAQ							
				Settings - TAQ/TNQ - title Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Reload Initial Pressure and Pump Return Vent Initial Pressu	NA	Added							
				Settings - THYlc Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Reload Initial Pressure and Pump Return Vent Initial Pressu									
				Settings - THYli and TAQht	NA								
				Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Shared Nozzle - Dispense Monitoring Control Data - RRC Nozzlel - Calibration 1	[POS]0.85 - 0.99 [PGMEA]1.00 - 1.15	[PGMEA]1.00 - 1.15 [H2O]TBD							
				Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Local Nozzle - Dispense Monitoring Control Data - EBR 1-Calibration 1	[POS]0.80 - 0.99 [PGMEA]1.00 - 1.15	[PGMEA]1.00 - 1.15							
				Section: 6. System Config Parameter, Ovens - Block 3/ Block 4/ Block 5/ Block6 PR Block, Chil PHP,PRP (CPHP,CPRI Modules - Control Table Data (Temperature Range 55*, 60*, 70, 100, 125, 150, 175*	Temperature Range 55, 60, 70, 100, 125, 150, 175)	(Temperature Range 55*, 60*, 70, 100, 12:							
				Section: 6. System Config Parameter, Ovens - Block 3/ Block 4/ Block 5/ Block6 PR Block, Chil PHP,PRP (CPHP,CPRI Modules - Control Table Data (Temperature Range 55*, 60*, 70, 100, 125, 150, 175*) - Commer	NA	* Post SED Only							
				Section: 6. System Config Parameter, Ovens - Block 5/ Block6 PR Block, [CGCH] Chil. General Heat Chamber HP Modules Controller REX-B879 - Loop Break Alarm Function Valid/Invali	NA	Added Dry Non-CE 4x4 Imm							
				Section: 6. System Config Parameter, Ovens - Block 2 MP Block/ Block 8 IPB, Chil Plt (CPL) Modules - Table1 - 2-16 CPL -	Dry Non-CE 4x4 Imm	Dry Non-CE 4x4 Imm 8x0 TAQ							
				Configuration	4x4 PostSED								
				Section: 6. System Config Parameter, Ovens - Block 2 MP Block/ Block 3 PR Block/ Block 7 MP Block, S-CPL (SCPL) Module Table 2 - 2-23 SCPL - Configuration	Dry CE 6x6 Imm / 6x6 PostSED								
				Section: 6. System Config Parameter, Ovens - Block 2 MP Block/ Block 3 PR Block/ Block 7 MP Block, S-CPL (SCPL) Module:	Dry NON-CE	Dry CE							
				Table2 - 2-23 SCPL - Configuration	4x4 Imm / 4x4 PostSED	6x6 Imm / 8x0 TAQ							
				Section: 6. System Config Parameter, Ovens - Block 2 MP Block/ Block 3 PR Block/ Block 7 MP Block, S-CPL (SCPL) Module Table 2 - 2-33/34/35 SCPL - Configuration	6x6 Imm 6x6 PostSED								
				Section: 6. System Config Parameter, Ovens - Block 2 MP Block/ Block 3 PR Block/ Block 7 MP Block, S-CPL (SCPL) Module	Dry NON-CE A/ 4x4 Imm/	Dry NON-CE A/ 4x4 Imm /							
				Table 2 - 7-33 SCPL - Configuration	4x4 PostSED BARC	8XU TAQ BARC							
			P. Ito	Section: 6. System Config Parameter, Ovens - Block 2 MP Block/ Block 3 PR Block/ Block 7 MP Block, S-CPL (SCPL) Module Table 2 - 7-34/35 SCPL - Configuration	Dry Non-CE 4x4 Imm / 4x4 PostSED	Dry Non-CE							
10/12/2016	4.00	K. Proctor	/H.Nagai	Section: 6. System Config Parameter, Ovens - Block 4 PR Block, C.ADH (ADH) Modules - Controller REX-B875 - Loop Brea Alarm Function Valid/Invalic	NA	Added							
				Ataini Function Vandriivan	* Portland: 1010.00hPa	* Portland/Ireland : 1010.00hPε							
											Section: 8. System Parameter - Bare-Si Thickness - Option Base Barometric Pressue	* Phoenix: 970.00hPa	
											* Albuquerque: 840.00hPa * Ireland: 1010.00hPa		
								Section: 8. System Parameter - Others(cont) - Option Dispense Line Monito	NA	Added			
				Section: 8. System Parameter - Others(cont) - Option Dispense Line Monitor - Commen Section: 11. EC Display Overview - Screen Tree - MAINTENANCE - Firmware Ver. Monito	NA NA	Immersion (7×3) TAQ							
				Section: 5.1. System Config Parameter, Spinners (DEV) - NTD FILTDRAIN1* 2* 3* / NTD-RFILTDRAIN1* 2* - Set Flow Rate Section: 5.2. 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Local Nozzle - E.B.R.1/BACK RINSE1/BEVEI	0	/5							
11/11/2016	4.01	K. Proctor	H.Nagai	RINSE V2/ EXH DUCT CLEAN -SOLVENT 1 Supply System - [Tool Specific] - Return Mode Setting *	NA								
				Section: 5.2, 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Local Nozzle - E.B.R.1/ BACK RINSE1/ BEVEI RINSE V2/ EXH DUCT CLEAN - SOLVENT I Supply System - CRF Settini	NA	Added							
				Section: 5.1. System Config Parameter, Spinners (DEV) - NTD RFILTDRAIN1* 2¹ Section: 5.1. System Config Parameter, Spinners (DEV) - NTD FILTDRAIN1* 2* 3* / NTD-RFILTDRAIN1* 2* 3* - Filtx	NTD RFILTDRAIN1* 2*	NTD RFILTDRAIN1* 2* 3*							
				Replacement Sequence (3)	NA								
				Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - The Number of Wafers to be Processed - PostSE Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Out-Filter Setting - Out-Filter Vent Valid In PJ Dumr	50 NA								
1/23/2017	4.02	K. Proctor	H.Nagai	Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Out-Filter Setting - Out-Filter Vent Interv	NA NA	Added Immersion (7×3) TAQ Added Added [POS]0.85 - 0.99 [PGMEA]1.00 - 1.15 [H2O]TBD [POS]0.80 - 0.99 [PGMEA]1.00 - 1.15 [H2O]TBD [TOS]0.80 - 0.99 [PGMEA]1.00 - 1.15 [H2O]TBD (Temperature Range 55*, 60*, 70, 100, 1 150, 175*) * Post SED Only Added Dry Non-CE 4x4 Imm 8x0 TAQ Dry CE 6x6 Imm / 8x0 THY Dry CE 6x6 Imm / 8x0 THY Dry NON-CE A/4x4 Imm / 8x0 TAQ 6x6 Imm / 8x0 TAQ 6x7 Imm / 8x0 TAQ 6x7 Imm / 8x0 TAQ 6x7 Imm / 8x0 TAQ 6x7 Imm / 8x0 TAQ 6x8 Imm /							
				Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - THYle - Reload Initial Pressure and Pump Return Vent Initi Pressure Settings - A	See Rev.4.01	Aligned with other specification							
				Section: 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - THYli and TAQhb - Reload Initial Pressure and Pump Return Vent Initial Pressure Settings - A	See Rev.4.01	[PGMEA]1.00 - 1.15							
				Vent Initial Pressure Settings - A Section: 8. System Parameter - Exposure Interface - Exposure ARP Settin	Invalid								
				Cover / All tools except Dry tool - Software version	NA								
	4.03	K. Proctor	H.Nagai	Cover / All tools except Dry tool - Sub Operation Panel versior Section: 6. System Config Parameter, Ovens - Block 4 PR Block, C.ADH (ADH) Modules - Control Table Data list - Temperature	NA .	5.01.39							
2/6/2017	11.00				Valid								

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			Cover / All tools except Dry tool - Software version Section 5.1 System Config Parameter, Spinners (DEV) - Local Nozzle - ADR N2 - Unexpected Pressure Watch - Unexpecte Pressure Watch Vaild - Addec Section 5.1 System Config Parameter, Spinners (DEV) - Local Nozzle - ADR N2 - Unexpected Pressure Watch - Delay Tim Before Unexpected Press Watch - Added	100.0.58.211 NA NA	100.0.58.213 Valid
			Pressure Watch Vaild - Added Section 5.1 System Config Parameter, Spinners (DEV) - Local Nozzle - ADR N2 - Unexpected Pressure Watch - Delay Tim Before Unexpected Press Watch -		Valid
			Before Unexpected Press Watch -	NΔ	
				1471	3.0
			Section 5.1 System Config Parameter, Spinners (DEV) - XDR N2 - Unexpected Pressure Watch -Unexpected Pressure Watch Vaild - Added	NA	Valid
			Section 5.1 System Config Parameter, Spinners (DEV) - XDR N2 - Unexpected Pressure Watch - Delay Time Before Unexpecte Press Watch - Added	NA	3.0
			Section 5.1 System Config Parameter, Spinners (DEV) - Block Arm - Left/ Block Arm - Right/ Module Arm - Left - Hon	NA	Added Home position table
			Position Section 5.1.System Config Parameter, Spinners (DEV) - Block Arm - Left/Block Arm - Right/ Module Arm - Left - Referen	NA	Added Reference Point table
			Point Section 5.2. System Config Parameter, Spinners (COT/BCT/TCT) – Reference Poi	NA	Added Reference Point table
			Section 5.3. System Config Parameter, Spinners (PIR/SRS) – Module Arm – Left - Home Position Section 5.3. System Config Parameter, Spinners (PIR/SRS) – Module Arm – Left - Reference Poi	NA NA	Added Home position table Added Reference Point table
			Section 5.2 System Config Parameter, Spinners (COT/BCT/TCT) - Block 4,5,6 PR Block, Coater ACRD Tool ONLY - Out-Filter		Valid
			Setting - Out-Filter Vent Valid In PJ Dummy Section 5.2 System Config Parameter, Spinners (COT/BCT/TCT) - Block 4,5,6 PR Block, Coater ACRD Tool ONLY - Out-Filte	300	See recipe spec
			Setting - Out-Filter Vent Interva Section 5.2 System Config Parameter, Spinners (COT/BCT/TCT) - Block 4,5,6 PR Block, Coater ACRD Tool ONLY - Out-Filte	NA	2.0 kPa
			Setting - Pump Out-Filter Initial Pressure - Addes Section 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Block Arm - Left /Right / Module Arm - Left - Spin Arm		
			Parameter - Exh Exclusive Control Near Ready Time - * Section 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Spin Motor Parameter - Spin Motor Control Data - Rinse Ari	The parameter only exist on TNU tools	The parameter only exist on dual arm track
			No. Section 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Spin Motor Parameter - Spin Motor Control Data - Speed:	L Arm	None
6/9/2017 4.04	K. Procto	H.Nagai	Rinse	100.00	1200.00
			Section 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Spin Motor Parameter - Spin Motor Control Data Acceleration at Rinse	1000.00	10000.00
			Section 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Spin Motor Parameter - Spin Motor Control Data - Rinse Time	te 5.00	15.00
			Section 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Spin Motor Parameter - Spin Motor Control Data - Spin O Acceleration	1000.00	10000.00
			Section 6. System Config Parameter, Ovens – Table 1 – 2-23 SCPl Section 6. System Config Parameter, Ovens – Table 1 – 2-23 SCPl	NA NA	Added TNG Table Added HMV TNE Table
			Section 6. System Config Parameter, Ovens - Block 5/ Block6 PR Block, [CGCH] Chil. General Heat Chamber HP Modules	220.00	Deleted
			Control Table Data list - Temp. Range 6 Section 6. System Config Parameter, Ovens - Block 5/ Block6 PR Block, [CGCH] Chil. General Heat Chamber HP Modules	240.00	Deleted
			Control Table Data list - Temp. Range \(\) Section 6. System Config Parameter, Ovens – Block 4 PR Block, C.ADH (ADH) Modules BUFFER BUBBLING - Controller	3.0s	30.0s
			REX-B875 – Setting Determination Time Section 10. Adjustment Tool Parameter - 4-1 [Resist Tracks]or 4-11 [BARC Tracks	4-11 [BARC Tracks]	4-42 [BARC Tracks]
			Section 10. Adjustment Tool Parameter - 4-1 [Resist Tracks]or 4-42 [BARC Tracks] - ForkPosition[0]	-	Separated Resist Tracks and BARC Track
			Section 10. Adjustment Tool Parameter - 4-1 [Resist Tracks]or 4-42 [BARC Tracks] - ForkPosition[1]	-	Separated Resist Tracks and BARC Tracks
			Section 10. Adjustment Tool Parameter - 4-1 [Resist Tracks]or 4-42 [BARC Tracks] - ForkPosition[0] for BARC Tracks	Tool Specific	249865
			Position Y Section 10. Adjustment Tool Parameter - 4-1 [Resist Tracks]or 4-42 [BARC Tracks] - ForkPosition[1] for BARC Tracks	·	249865
			Position Y Section 10. Adjustment Tool Parameter - 4-1 [Resist Tracks]or 4-42 [BARC Tracks] - ForkPosition[0] for BARC Tracks	Tool Specific	
			Position Th Section 10. Adjustment Tool Parameter - 4-1 [Resist Tracks]or 4-42 [BARC Tracks] - ForkPosition[1] for BARC Tracks	0	Tool Specific
			Position Th Section 14. Data Collect Condition Editor - Condition Name: [Time (2sec),Env(60sec)] - Transfer Condition	0 847	Tool Specific 887
			Section 4. System Configuration Parameter, Arm – X axis Position & Offset (DRY) – 8-0 IR.	ISHU	CPL/TRS/RSM/ISHU
			Section 4. System Configuration Parameter, Arm – X axis Position & Offset (DRY) – 8-0 IRA - CPL/TRS/RSM/ISHU - X Sen Position	CCD Center	CCD Center – 27 pulse
			Section 4. System Configuration Parameter, Arm – X axis Position & Offset (DRY) – 8-0 IRA - CPL/TRS/RSM/ISHU - 2 Receive Position	CCD Center	CCD Center + 341 pulse
			Section 4. System Configuration Parameter, Arm – X axis Position & Offset (DRY) – 8-0 IRA - CPL/TRS/RSM/ISHU - OFFSet (DRY) – 8-0 IRA - CPL/TRS/RSM/ISHU - OFFSet (DRY) – 8-0 IRA - CPL/TRS/RSM/ISHU - OFFSet (DRY) – 8-0 IRA - CPL/TRS/RSM/ISHU -	0 pulse	368 pulse
7/7/2017 4.05	K. Procto	H Nagai	Section 4. System Configuration Parameter, Arm - Y, Z and Theta axis Offset (DRY) – ISHI Section 4. System Configuration Parameter, Arm - Y, Z and Theta axis Offset (DRY) – RSM - Adde	ISHU NA	CPL/TRS/ISHU RSM
7772017	12. 1 10010	TIII tugui	Section 5.1. System Config Parameter, Spinners (DEV) – Local Nozzle – ADR1 N2 – Unexpected Pressure Watch - Added	NA NA	*ADR N2 Unexpected Pressure Watch table
			comment with*	NA .	as present only on tools with XDR upgrade
			Section 5.1. System Config Parameter, Spinners (DEV) - DEV.SOLU.2 Supply System / N.T.DEV SOLUTION1 Supply System N.T.DEV SOLUTION2 Supply System / SOLVENT2 Supply System - [Tool Specific]- DEV9 (Local Arr:	DEV9 (Local Arm)	Deleted
			Section 5.1. System Config Parameter, Spinners (DEV) - Dispense Monitoring Control Data - DEV9 (Local Arn Section 6. System Config Parameter, Ovens - Block 2 MP Block/Block 3 PR Block/ Block 7 MP Block, S-CPL (SCPL) Modules	DEV9 (Local Arm) - Non-CE TNE / 4x4 Imm / 8x0 TAQ	Deleted Non-CE TNE / HVM TNE /
			Table 2 – Non-CE TNE / 4x4 Imm / 8x0 TAQ – 7-33 SCPL - Added HVM TNI Cover / All tools except Dry tool - Software version - Marge	100.0.58.207	4x4 Imm / 8x0 TAQ 100.0.58.213
8/4/2017 4.06	K. Procto	H.Nagai	Section 5.1. System Config Parameter, Spinners (DEV) - Local Nozzle - ADR N2 - Unexpected Pressure Watch - *Comment	*ADR N2 Unexpected Pressure Watch table	*Only Available on tool with Version
			Section 5.2. System Config Parameter, Spinners (COT) -RRC FILTDRAIN1* - SOLVENT-B/C Supply Syste	as present only on tools with XDR upgrade. SOLVENT-B/C Supply System	. 100.0.58.211 or Later SOLVENT-A/B/C Supply System
		****	Section 5.2. System Config Parameter, Spinners (COT) -RRC FILTDRAINT* - SOLVENT-B/C Supply System - Chemical Name	SOLVENT-B/C Supply System SOLVENT-B/C Supply System	SOLVENT-A/B/C Supply System
10/2/2017 4.07	K. Procto	H.Nagai	Section 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Dispense Monitoring Control Data - Add	NA	Added
			Section 8. System Parameter - Wafer Collection - Real-time Save Recovery Inf Cover page. Temperature Version	Invalid 1.28	Valid 1.29
			Section 2. Start Up Setting - Comment	*= Not present on BARC & Invalid for PostSED tracks	*= Not present on BARC
			Section 4. System Configuration Parameter, Arm - Fork1 and 2 Section 4. System Configuration Parameter, Arm - Z-axis Multistep Movemer	DEV/TCT/COT/BCT/NTD DEV/TCT/COT/BCT/NTD	DEV/COT/BCT/NTD DEV/COT/BCT/NTD
			Section 4. System Configuration Parameter, Arm - Z-axis Multistep Movement (Receive) Softlanding function installed tool only	DEV/TCT/COT/BCT/NTD	DEV/COT/BCT/NTD
			Section 4. System Configuration Parameter, Arm - Z-axis Multistep Movement (Send) Softlanding function installed tool or	DEV/TCT/COT/BCT/NTD	DEV/COT/BCT/NTD
		****	Section 5.1. System Config Parameter, Spinner (DEV) - Dispense Parameter - Shared Nozzle - Dispense Monitoring Control Data Set Flow Rate	*500 for PostSED	Removed
12/14/2017 4.08	K. Procto	H.Nagai	Section 5.1. System Config Parameter, Spinner (DEV) - Dispense Parameter - DEV NZL.4 Sub - Dispense Monitoring Contro Data - Set Flow Rate	*400 for PostSED	Removed
			Section 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - AL Section 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Bottle Empty Detection Setting	All categories	Removed all TCT and PostSED item:
			RefillStopSensorDetectFixTimt Section 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Solvent Bath [Water Base TCT Modul	0.1 Solvent Bath Settings	1.0 Removed
			Section 5.3. System Config Parameter, Spinners (PIR/SRS) - AL	All categories	Removed all TCT and PostSED item:
			Section 6. System Config Parameter, Ovens - ALl Section 8. System Parameter - Exposure Interface - PostSED setting	All categories PostSED	Removed all TCT and PostSED item: Removed
			Section 13. EC SYSTEM Setting - Equipment mode change - *comme: Section 13. EC SYSTEM Setting - Equipment mode change2 - comme:	LOCAL For BARC and PostSED tracks FOR BARC and PostSED tracks	LOCAL For BARC FOR BARC



Software FPD Revision History (7/9)

Date	Rev.	App		Location	Old	New
		INIEL	IEL	5.1 System Config. Parameter, Spinner (DEV) - Remove Dummy Dispense Attribute line from BATH EXH. CM	Exist	Removed
				5.1 System Config. Parameter, Spinner (DEV) - Format change for CRF setting and Interval for Circulation table	Indented in Column (Moved to Column E
				5.1 System Config. Parameter, Spinner (DEV) - Update to BackRinse discription in supply system tab	Back Rinse *= Only Present IFF-S tools	Back Rinse 1
				5.1 System Config. Parameter, Spinner (DEV) - Removed the astrisk comments under the supply system table	**= Only Present CRF tools	Removed
				5.1 System Config. Parameter, Spinner (DEV) - Removed the astrisk from Return mode settii 5.1 System Config. Parameter, Spinner (DEV) - DEV3(Local Arm) / BEVEL RINSE V2 / RINSE1 / BACK RINSE1 - Remov	Return Mode Setting * CRF Setting * and	* Removed
				Comment and astrisks from CRF Setting Table - ** DEV3(LocalArm) and RINSE1 of CRF enabled tool and the astrisk from CRF	** DEV3(LocalArm) and RINSE1	* Removed and Comment Removed und the CRF Table
				Setting Table 5.1 System Config. Parameter, Spinner (DEV) - Update to BackRinse discription in Dispense Monitoring Control D€	of CRF enabled tool Back Rinse	Back Rinse 1
				5.1 System Config. Parameter, Spinner (DEV) - Format change for IFF-S Specific tit	Indented in Column A	Moved to Column F
				5.1 System Config. Parameter, Spinner (DEV) - IFF-S Supported Nozzle Chang	24 CRF Setting * and	Tool Specific
				5.1 System Config. Parameter, Spinner (DEV) - NTD FILTDRAIN1*/2*/3* - Remove Comment and astrisks from ** DEV3(LocalArm) and RINSE1 of CRF enabled tool and the astrisk from CRF Setting Table	** DEV3(LocalArm) and RINSE1 of CRF enabled tool	* Removed and Comment Removed und the CRF Table
				5.1 System Config. Parameter, Spinner (DEV) - NTD-RFILTDRAIN1* /2* / 3* - Remove Comment and astrisks from ** DEV3(LocalArm) and RINSE1 of CRF enabled tool and the astrisk from CRF Setting Table	CRF Setting * and ** DEV3(LocalArm) and RINSE1 of CRF enabled tool	* Removed and Comment Removed und the CRF Table
				5.1 System Config. Parameter, Spinner (DEV) - NTD FILTDRAIN1*/2*/3* - Remove Comment and astrisks from ** DEV3(LocalArm) and RINSE1 of CRF enabled tool and the astrisk from Interval for Circulation**	Interval for Circulation and ** DEV3(LocalArm) and RINSE1 of CRF enabled tool	* Removed and Comment Removed und the Interval for Circulation
				5.1 System Config. Parameter, Spinner (DEV) - NTD-RFILTDRAIN1* /2* / 3* - Remove Com'ment and astrisks from ** DEV3(LocalArm) and RINSE I of CRF enabled tool and the astrisk fromInterval for Circulation**	Interval for Circulation and ** DEV3(LocalArm) and RINSE1 of CRF enabled tool	* Removed and Comment Removed und the Interval for Circulation
				5.1 System Config. Parameter, Spinner (DEV) - Format to separate the Monitoring Parameter Section	No Break	Separated
3/27/2018	4.09	K. Proctor	Sam S.	5.1 System Config. Parameter, Spinner (DEV) - Change table title from Standard Configuration to DEV Modul 5.1 System Config. Parameter, Spinner (DEV) - Block Arm - Left/ Block Arm - Right/ Module Arm - Left - Add HOME OFFSE	Standard Configuration	DEV Modules
				13.1 System Connig. Parameter, Spinner (DEV) - Block Arm - Lett Block Arm - Right Module Arm - Lett - Add HOME OFFSE TABLE	Not Exist	Added
				5.1 System Config. Parameter, Spinner (DEV) - Block Arm - Left/ Block Arm - Right/ Module Arm - Left - HOME POSITIO	Block Arm - Left / Righ	DEV Block Arm - L / R
				TABLE Renamed to match HOME OFFSET TABLI 5.1 System Config. Parameter, Spinner (DEV) - Block Arm - Left/ Block Arm - Right/ Module Arm - Left - REFERANCE POIN	Module Arm - Left Block Arm - Left / Righ	NTD Module Arm - Left DEV Block Arm - L / R
				TABLE Renamed to match HOME OFFSET TABLI	Module Arm - Lefi	NTD Module Arm - Left
				5.2 System Config. Parameter, Spinner (COT/BCT) - Moved Keep Arm Position [69] under RST PressTRG 5.2 System Config. Parameter, Spinner (COT/BCT) - Added CRF, Interval Circulation and Dispense Monitoring Mechanism	page 65	page 64
				Connection Table to RRCFILTDRAIN	Not Exist	Added
				5.2 System Config. Parameter, Spinner (COT/BCT) - Removed RRC FILTDRAIN1 title from filtration recipe tab	RRC FILTDRAIN1	Removed
				5.2 System Config. Parameter, Spinner (COT/BCT) - Removed CSS Refill System and FailSafe table after the filtration recipe table	e Existed	Removed
				5.2 System Config. Parameter, Spinner (COT/BCT) - Update the Pressure Sensor Type setting for Controller EPCA Tab	500**	1000**
				5.2 System Config. Parameter, Spinner (COT/BCT) - Update the ** comment for Pressure Sensor Type setting for Controller EPC Table	**= 100PA ONLY for TNU Layers L4/L6	**= 100PA ONLY exist for TNU L4/L6
				5.2 System Config. Parameter, Spinner (COT/BCT) - Reorder of the spinner arm tables on page69 and added the HOME OFFSE Table	Mis-Arranged	Corrected
				6. System Config Parameter, Ovens - C.ADH Module - Monitoring Parameter - Control Table Data List - Temp # ord	Temp #'s not in sequential orde:	Temp #'s in sequential order
				6. System Config Parameter, Ovens - Block 5/ Block6 PR Block, [CGCH] Chil. General Heat Chamber HP Modules - Monitorin Parameter - Control Table Data List - Temp # orde	Temp #'s not in sequential order	Temp #'s in sequential order
				6. System Config Parameter, Ovens - Block 3/ Block 4/ Block 5/ Block6 PR Block, Chil PHP,PRP (CPHP/CPRP) Modules Monitoring Parameter - Control Table Data List - Temp # orde	Temp #'s not in sequential order	Temp #'s in sequential order
				12. EC ON-LINE Setting - Added SPOOLING Home screer	Not Exist	Added
				12. EC ON-LINE Setting - Blur the Link Litho Channel Parameter as they can not be change	Visable	Un-readable
				13.EC SYSTEM Setting - Change Auto log out picture from 30 to 60 mii 14. Data Collec Editor - Format the above comment to be read easie	no Bold emphasis	60 Bold emphasized
				Cover Page. Teaching Software	1.23V	1.27V
				Cover Page. Temp Cal Software	1.29V Specify wafer count for maintenance	1.30V
				Section 4. System Configuration Parameter, ARM - Block 1 CS Block - Remove BST specific rows from CSB Arm table	notification	Removed
				Section 4. System Configuration Parameter, ARM - Block 1 CS Block - Remove BST specific rows from CSB Arm tal Section 5.1 System Config Parameter, Spinner (DEV) - SOLVENT-D Supply System - Filter Replacement Supply System N	Wafer count for maintenance notification 27	Removed Tool Specific
						Tools with XDR ONLY
				Section 5.1 System Config Parameter, Spinner (DEV) - ADR1 RINSE - Flow Rate during Dispense Process - Comment Added		
				Section 5.1 System Config Parameter, Spinner (DEV) - RINSE1 - Flow Rate during Dispense Process - Comment Add		Tools with XDR ONLY
			Sam S./	Section 5.2. System Config Parameter, Spinners (COT/BCT) - Possible Number of Simultaneous Resist Dispense Processes Update	е т	10
7/9/2018	4.10	K. Proctor	J.	Section 5.2. System Config Parameter, Spinners (COT/BCT) - Possible Number of Simultaneous Resist Dispense Processes - Removal of commen	Set to number of plumbed resist lines	Deleted
				Section 5.2. System Config Parameter, Spinners (COT/BCT) - Dispense Monitoring Control Data - Remove comment under table	80 mL/min for TAQ/TNQ Top Coat Modules "ONLY"	Deleted
				Section 6. Sys Config(Oven) - Correct Initial Data Value for CPL 7-11 & CPL 7-1: Section 10. Adjustment Tool Parameter - Transfer Arm No. 1-0/2-0/3-0/4-0/5-0/6-0/7-0 Calibration Data [1-0/2-0/3-0/4-0/5-0/6-0/7-0] - Header Update	22.0C Various	22.2C Tool Specific
				0/7-0] - DataID Update Orall - DataID Update Orall - DataID Update Orall - DataID Update	Various	Tool Specific
				Section 10. Adjustment Tool Parameter - Transfer Arm No. 1-0/2-0/3-0/4-0/5-0/6-0/7-0 Calibration Data [1-0/2-0/3-0/4-0/5-0/6-0/7-0] - CalibModuleModuleNo Updata	Various	Tool Specific
				Section 12. EC ON-LINE Setting - HSMS Channel Parameter Edit - Session ID Update	16008	Tool Specific
				Cover - Main Version - All tools except Dry tool - Software versior	100.0.58.213	100.0.58.218
				Section 5.1. System Config Parameter, Spinners (DEV) – BATH EXH. CMN2* - *Comment Adds	NA NA	Only exist on 4×4 and 8×0 tracks
				Section 5.2. System Config Parameter, Spinners (COT/BCT) - Out-Filter Setting Section 5.2. System Config Parameter, Spinners (COT/BCT) - Solvent1 Supply system [Tool Specific] - Comment	NA **_CRF Specific, V202 beyonc	Added Removed
9/7/2018	5.00	K. Proctor	H.Nagai	Section 5.2. System Config Parameter, Spinners (COT/BCT) – Dispense Monitoring Control Data – RRC Nozzle1 - H20	H2O : TBD	Removed
2010	2.50	2. 2. 2. 200.01	ugui	Section 5.2. System Config Parameter, Spinners (COT/BCT) – CMN CUP EXH - Comment* Adda Section 5.2. System Config Parameter, Spinners (COT/BCT) – SOLVENT 1 Supply System [Tool Specific] - Comment	NA **_CRF Specific, V202 beyond	This Setting does not exist on TNU Removed
				Section 5.2. System Config Parameter, Spinners (COT/BCT) – SOL VENT 1 Supply System [100] Specific - Comment Revised Section 5.2. System Config Parameter, Spinners (COT/BCT) – Block Arm – Left / Right / Module Arm – Left - *Comment Revised Section 5.2. System Config Parameter, Spinners (COT/BCT) – Block Arm – Left / Right / Module Arm – Left - *Comment Revised Section 5.2. System Config Parameter, Spinners (COT/BCT) – Block Arm – Left / Right / Module Arm – Left - *Comment Revised Section 5.2. System Config Parameter, Spinners (COT/BCT) – Block Arm – Left - Right / Module Arm – Left - *Comment Revised Section 5.2. System Config Parameter, Spinners (COT/BCT) – Block Arm – Left - Right / Module Arm – Left - *Comment Revised Section 5.2. System Config Parameter, Spinners (COT/BCT) – Block Arm – Left - Right / Module Arm – Left - *Comment Revised Section 5.2. System Config Parameter, Spinners (COT/BCT) – Block Arm – Left - Right / Module Arm – Left - *Comment Revised Section 5.2. System Config Parameter, Spinners (COT/BCT) – Block Arm – Left - Right / Module Arm – Left - *Comment Revised Section 5.2. System Config Parameter, Spinners (COT/BCT) – Block Arm – Left - Right / Module Arm – Left - *Comment Revised Section 5.2. System Config Parameter, Spinners (COT/BCT) – Block Arm – Left - Right / Module Arm – Left - *Comment Revised Section 5.2. System Config Parameter, Spinners (COT/BCT) – Block Arm – Left - Right / Module Arm – Left - Right / Module Arm – Left - Right / Module Arm – Left - Right / Module Arm – Left - Right / Module Arm – Left - Right / Module Arm – Left - Right / Module Arm – Left - Right / Module Arm – Left - Right / Module Arm – Left - Right / Module Arm – Right / Module Arm – Right / Module Arm – Right / Module Arm – Right / Module Arm – Right / Module Arm – Right / Module Arm – Right / Module Arm – Right / Module Arm – Right / Module Arm – Right / Module Arm – Right / Module Arm – Right / Module Arm – Right / Module Arm – Right / Module Arm – Right / Module Arm – Right / Module Arm – Right / Modu		The Parameter only exist on dual arm track
				Section 5.2. System Config Parameter, Spinners (PIR/SRS) – Monitoring Parameter – Table 2 – 8-6 Monitoring ty ₁	Use point ctrl	except TNU Use point read
					ose point our	

CONFIDENTIAL INFORMATION his material contains confidential information. ou shall not copy, or disclose to any third party, without fior written consent of TEA.

Date	Rev.	App INTEL	roval TEL	Location	Old	New
				Section 4. System Configulation Parameter, Arm - Transfer Arm Control Parameter -	* Does not exist for TNE tools	Does not exist for DRY tools
				Section 4. System Configulation Parameter, Arm - Fork1 and 2* - Section 4. System Configuration Parameter, Arm - Block 3,4,5,6 PR Block - Z-axis Multistep Movement -	*TNE Configuration IRA only has 1 Forl *Softlanding function installed too	*DRY Configuration IRA only has 1 F
				Section 4. System Configuration Parameter, Arm - Block 3,4,5,6 PR Block - Z-axis Multistep Movement - Section 4. System Configuration Parameter, Arm - Block 3,4,5,6 PR Block - Z-axis Multistep Movement - OVEN/SCPL/SB	Invalid / Valid *	Deleted Valid
				Section 4. System Configuration Parameter, Arm - Block 8 IPB-Immersion Configuration ONLY - Z-axis Multistep Movement -	* **Softlanding function installed tool	Deleted
				Section 4. System Configuration Parameter, Arm - Block 8 IPB-Immersion Configuration ONLY - Z-axis Multistep Movemen		
				TRS/ISHU/CPL	Invalid / Valid **	Valid
				Section 5.1. System Config Parameter, Spinners (DEV) - ADR1 N2 - Unexpected Pressure Watch Section 5.1. System Configuration Parameter, Spinners (DEV) - NTD FILTDRAIN1*/2*/3* - Dispense Monitoring Mechanis	*Only Available on~	Deleted
				Connection	NA	Added
				Section 5.1. System Configuration Parameter, Spinners (DEV) - NTD RFILTDRAIN1*/2*/3* - Dispense Monitoring Mechanisi Connection	NA	Added
11/28/2018	5.01	K. Proctor	H.Nagai	Section 5.2. System Config Parameter, Spinners (COT/BCT) - RESIST# Supply System [Tool Specific] : M-ACRD Package - Tl	See table below	0
				Number of Wafers to be Processec Section 5.2. System Config Parameter, Spinners (COT/BCT) - The Number of Wafers to be Processe	Setting Table	Deleted
				Section 5.2. System Config Parameter, Spinners (COT/BCT) - The Number of Waters to be Process Section 5.2. System Config Parameter, Spinners (COT/BCT) - RESIST# Supply System [Tool Specific]: M-ACRD Package	-	
				Transfer Control / Chemical Amount to be Continued after Bottle Emp Section 5.2. System Config Parameter, Spinners (COT/BCT) - Pump17 - AMC Close Timing adjustment TYPE - *	NA ***TYPE, X5 - X6	50 mL
				Section 5.2. System Config Parameter, Spinners (COT/BCT) - Pump 1/ - AMC Close Timing adjustment 1 YPE - * Section 5.2. System Config Parameter, Spinners (COT/BCT) - Pump Out Air Vent Setting -	*Based on Pump Out Air Vent Tim	Deleted Deleted
				Section 5.2. System Config Parameter, Spinners (COT/BCT) – Out-Filter Setting* - Setting table for Ver.211/213/21	Setting table for Ver.211/213/214	Deleted
				Section 5.2. System Config Parameter, Spinners (COT/BCT) – Out-Filter Setting* - Setting table for Ver.216 and beyon Section 5.2. System Config Parameter, Spinners (COT/BCT) – RESIST# Supply System [Tool Specific] : PC	*DF parameter for ~ POR Setting table	Deleted Deleted
				Section 5.2. System Config Parameter, Spinners (COT/BCT) – RESIST NOZZLE# -	*DF parameter for ~	Deleted
				Section 8. System Parameter - Others(cont) - ' Section 8. System Parameter - Others - '	*Does not Exist on TNE or BARC tool: *Does not Exist on TNE or BARC tool:	*Does not Exist on DRY or BARC to *Does not Exist on DRY or BARC to
				Section 13. Equipment mode change -	*Local For BARC and Post SED tracks	*Local For BARC tracks
				Section 5.2. System Config Parameter, Spinners (COT/BCT) - RRC FILTDRAIN*	RRC FILTDRAIN*1	RRC FILTDRAIN*1 / 2*
				Section 10. Adjustment Tool Parameter - Transfer Arm No. 1-0 Calibration Data [1-0] - Tool Specific - CalibModuleModuleNo	Tool Specific	1
				Section 10. Adjustment Tool Parameter - Transfer Arm No. 2-0 Calibration Data [2-0] - Tool Specific - CalibModuleModuleNo	Tool Specific	16
				Section 10. Adjustment Tool Parameter - Transfer Arm No. 3-0 Calibration Data [3-0] - Tool Specific - CalibModuleModuleNo	Tool Specific	1
2/20/2019	5.02	K. Proctor	H Nagai	Section 10. Adjustment Tool Parameter - Transfer Arm No. 4-0 Calibration Data [4-0] - Tool Specific - CalibModuleModuleNo - Resist Tracks	Tool Specific	1
2/20/2019	5.02	11. 1100101	11vagar	Section 10. Adjustment Tool Parameter - Transfer Arm No. 4-0 Calibration Data [4-0] - Tool Specific - CalibModuleModuleNo	Tool Specific	42
				BARC Tracks		
				Section 10. Adjustment Tool Parameter - Transfer Arm No. 5-0 Calibration Data [5-0] - Tool Specific - CalibModuleModuleNo	Tool Specific	1
				Section 10. Adjustment Tool Parameter - Transfer Arm No. 6-0 Calibration Data [6-0] - Tool Specific - CalibModuleModuleNo	Tool Specific	1
					T 10 :5	44
				Section 10. Adjustment Tool Parameter - Transfer Arm No. 7-0 Calibration Data [7-0] - Tool Specific - CalibModuleModuleNo	Tool Specific	46
				Section 1. Overview - Parameter Layout - Page Infi Section 5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Bottle/Pump Location - TBL	NA	Revised Added
				Secttion 6. System Config Parameter, Ovens - Block 3/ Block 4/ Block 5/ Block 6 PR Block, Chil PHP,PRP (CPHP,CPRI	Offset Setting Method	Deleted
				Modules - Controller TM150-CHILLER Secttion 6. System Config Parameter, Ovens - Block 3/ Block 4/ Block 5/ Block 6 PR Block, Chil PHP,PRP (CPHP,CPRI		
4/05/2019	5.03	K. Proctor	H Nagai	Modules - Controller TM150-CHILLER	Offset	Deleted
				Secttion 6. System Config Parameter, Ovens - Block 2 MP Block/ Blocdk 8 IPB, Chil Plt (CPL) Modules - Table 1 - Configuratio - Dry - 7-11 CPL- Initial Data Temperature	22.2	*
				Secttion 6. System Config Parameter, Ovens - Block 2 MP Block/ Blocdk 8 IPB, Chil Plt (CPL) Modules - Table 1 - Configuration	22.2	*
				- Dry - 7-12 CPL- Initial Data Temperature Section 6. System Config Parameter, Ovens - Block 2 MP Block/ Block 3 PR Block/ Block 7 MP Block, S-CPL (SCPL) Modules		
				TBL Settings	NA	Added
				Section 5.1. System Config Parameter, Spinners (DEV) - DEV Nozzle2 - Target tool Section 5.1. System Config Parameter, Spinners (DEV) - DEV Nozzle2(BYPASS) - Target tool	TNE/TNG Config ONLY LD Nozzle TNE/TNG Config ONLY	TBL/TNE/TNG Config ONLY LD No: TBL/TNE/TNG Config ONLY
				Section 5.1. System Config Parameter, Spinners (DEV) - DEV NOZZEZ(B17AS5) - Target tool	TNE/TNG Config ONLY	TBL/TNE/TNG Config ONLY
6/11/2019	6.00	K. Proctor	H.Nagai	Section 5.1. System Config Parameter, Spinners (DEV) - DEV NZL2(RINSE) - Target tool	TNE/TNG Config ONLY	TBL/TNE/TNG Config ONLY
			_	Section 5.2. System Config Parameter, Spinners (COT/BCT) - Table for Temperature Control Method - Modu Section 5.2. System Config Parameter, Spinners (COT/BCT) - * Table for TM150-CHILLER / THC - Modu	5-1 BCT 5-1 BCT	5-1 COT(TBL) / 5-1 BCT (BARC) 5-1 COT(TBL) / 5-1 BCT (BARC)
				Section 5.2. System Config Parameter, Spinners (COT/BCT) - * Table for TM150-CHILLER / THC - 5-1 BCT	N/A	Invalid
				- Source Value Monitoring Valic - Section 5.2. System Config Parameter, Spinners (COT/BCT) - Block Arm - Left /Right / Module Arm - Left - Spin Arm Parameter		
				IN, OUT Speed(Outside the Cup	112700	205000
				Section 5.2. System Config Parameter, Spinners (COT/BCT) - Block Arm - Left /Right / Module Arm - Left - Spin Arm Paramete IN, OUT Acceleration(Outside the Cup	61440	150000
8/15/2019	6.01	K. Proctor	H.Nagai	Section 5.2. System Config Parameter, Spinners (COT/BCT) - Block Arm - Left /Right / Module Arm - Left - Spin Arm Parameter	61440	150000
				IN, OUT Deceleration(Outside the Cup Section 6. System Config Parameter, Ovens - Block 3/ Block 4/ Block 5/ Block6 PR Block, Chil PHP,PRP (CPHP,CPRP) Module	01440	130000
				Control Table Data list - Temp. Range20*4	NA	Added (180C)
				Section 5.2. System Configuration Parameter, Spinners - Nozzle. SC when nozzle height is 6.5mm - Scuback 1 Position	3.00	4.00
				Section 5.2. System Configuration Parameter, Spinners - Nozzle. SC when nozzle height is 6.5mm - Scuback 2 Positi Section 5.2. System Configuration Parameter, Spinners - Nozzle. SC when nozzle height is 6.5mm - Scuback 3 Positi	-2.00 3.00	-1.00 4.00
				Section 5.2. System Configuration Parameter, Spinners – Nozzie Section 5.2. System Configuration Parameter, Spinners – Dispense Monitoring Control Data – RRC Nozzle Calibration 1 – E	5.00 NA	Added
				setting	IVA	Added
0/28/2019	6.02	K. Proctor	H.Nagai	Section 5.2. System Configuration Parameter, Spinners – Dispense Monitoring Control Data – E.B.R.1 Calibration 1 – EL setting	NA	Added
				Section 6. System Config Parameter, Ovens – Block 2 MP Block – Use point control Configuration - HPT and TBM Specification	NA	Added
				Section 8. System Parameter – Others - remove the asterisks from "Recipe Verification" and "Dispense Parameter	Asterisk	Removed
				Section 10. Adjustment Tool Parameter - Transfer Arm No. 4-0 Calibration Data[4-0] - ForkPosition[0] and [1] for BARC Tracks	for BARC Tracks	for TBL and BARC Tracks
				Section 6. System Config Parameter, Ovens –Block 2 MP Block/ Block 3 PR Block/ Block 7 MP Block, S-CPL (SCPL) Modules		
				Table 2 - Configuration - DRY w/HTP TBM - 7-46 SCPI	NA	Added
				Section 6. System Config Parameter, Ovens - Block 3/ Block 4/ Block 5/ Block6 PR Block, Chil PHP,PRP (CPHP/CPRP) Modul - Control Table Data list - Temp,Range12 - Setting Lowe	NA	110.10
				Section 6. System Config Parameter, Ovens - Block 3/ Block 4/ Block 5/ Block PR Block, Chil PHP, PRP (CPHP/CPRP) Modul	NA	24.00
2/20/2020	6.03	K. Proctor	H.Nagai	- Control Table Data list - Temp.Range12 - Accum Threshol Section 6. System Config Parameter, Ovens - Block 3/ Block 4/ Block 5/ Block6 PR Block, Chil PHP,PRP (CPHP/CPRP) Modul-		
				- Control Table Data list - Temp.Range17 - Setting Lowe	NA	130.10
				Section 6. System Config Parameter, Ovens - Block 3/ Block 4/ Block 5/ Block PR Block, Chil PHP, PRP (CPHP/CPRP) Modul	NA	32
				- Control Table Data list - Temp.Range17 - Accum Threshol Section 8. System Parameter - Exposure State Management - asterisk - **	Valid for ASMLImmersion links,	Valid for ASML links,
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Software FPD Revision History (9/9)



Date	Rev.	Appı	roval	Location	Old	Now
Date	Rev.	INTEL	TEL		Olu	20 Enclosed Press TBL only TBL deck4 CPRP Only 200 ms Valid 0 ms without speed controller: 1200 ms with speed controller:
				5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Block 4,5,6 PR Block, Coater ACRD Tool ONLY - Pump 18 - Pressure for wait	NA	20
				5.2. System Config Parameter, Spinners (COT/BCT/TCT) - Block 4,5,6 PR Block, Coater ACRD Tool ONLY - Out-Filter Setting Out-Filter Vent Press Mode For Wait	NA	Enclosed Press
				Section 6. System Config Parameter, Ovens - Block 3/ Block 4/ Block 5/ Block6 PR Block, Chil PHP,PRP (CPHP/CPRP) Modul - Control Table Data list - Temp range 12***/17**	NA	TBL only
	7.00	K.Proctor	H.Nagai	Section 6. System Config Parameter, Ovens - Block 3/ Block 4/ Block 5/ Block6 PR Block, Chil PHP,PRP (CPHP/CPRP) Modul - Control Table Data list - Temp range 20***	NA	TBL deck4 CPRP Only
4/15/2020	7.00	K.Proctor	n.Nagai	Section 8. System Parameter - Others - Time Interval between Rechecking of Upstream Linked Recipe	NA	200 ms
				Section 8. System Parameter - Others - Recipe Security for TEL Use	NA	
				Section 8. System Parameter - Others - Option Delay Time before Pin Up after Chuck Vacuum OFF in Spinner Module	NA	
				Section 8. System Parameter - Others(cont) - Option Vent Exclusion Function for Shared Drain Lii	NA	Valid
				Section 8. System Parameter - Maintenance - Option Consecutive Executions of Replacing Chemical Bottle and Cleaning Dispen information	NA	Valid
				Section 8. System Parameter - Maintenance - Option Operation-Less RIA Alarm	NA	Valid (PURGE Class Only)

Date	Rev.	App	roval	Location	Old	New	
	Date	Rev.	INTEL	TEL	Location	Olu	New
					5.2. System Config Parameter, Spinners (COT/BCT)	NA	*Invalid if RFM is Valid in Corresponding
					Laser DDS. Adding the comment of "*Invalid if RFM is Valid in Corresponding pump recipe	NA.	pump recipes*
	3/12/2021	7.01	K.Proctor	Dan	6. System Config Parameter, Ovens/Control Table Data lis		
	3/12/2021	7.01	K.FIOCIOI	Dali	Add temperature ranges for dry TBL tools.(90.1,100.1,105,1,115,120,1).	NA	Add temperature ranges for dry TBL
						NA.	tools.(90.1,100.1,105,1,115,120,1).

Date	Rev.	App	roval TEL	Location	Old	New
				5.2. System Config Parameter, Spinners (COT/BCT Add D6 Immersion Setting	NA	Valid,Invalid setting=Valid Time for circulation recovery=1200 Time for continuous circulation=15
4/2/2021	7.02	K.Proctor		6.Sys Config(Oven) Add the condition cirtification	NA	*** TBL and copper TBM/TNE/TNG only **** TBL only
				6.Sys Config(Oven)		

Date	Rev.	Approva		Location	Old	New
Date	Rev.	INTEL	TEL		Olu	116W
				5.2. System Config Parameter, Spinners (COT/BCT Block 4,5,6 PR Block, Coater ACRD Tool ONLY - Suckback! Position from 13±1 to 13±3 - Suckback2Position from 15±1 to 15±3	- Suckback1Position 13±1 - Suckback2Position 15±1	- Suckback1Position 13±3 - Suckback2Position 15±3
7/30/2021	7.03	K.Proctor	Dan	5.2. System Config Parameter, Spinners (COT/BCT Dispense Monitoring Control Data NZL CLN/BATH CLN - Set Flow Rate 10 NZL BATH 600 7 NZL BATH 440 4 NZL BATH 275 NOZZLE. SC Set Flow Rate 10 NZL BATH 900 7 NZL BATH 975 4 NZL BATH 525	NZL CLN/BATH CLN · Set Flow Rate =600 NOZZLE. SC. · Set Flow Rate =900	NZL CLN/BATH CLN · Set Flow Rate 10 NZL BATH 600 7 NZL BATH 440 4 NZL BATH 275 NOZZLE. SC. · Set Flow Rate 10 NZL BATH 900 7 NZL BATH 875 4 NZL BATH 525
				6.Sys Config(Oven) Adding new Control Table Data List for CPRP -Control Table Data List (except for BE DRY tracks listed below) -Control Table Data list (except for BE DRY tracks listed below) 6.Sys Config(Oven) Adding new Control Table Data List for ADH -Control Table Data list (except for BE DRY tracks listed below) -Control Table Data list for TBL, TBM, and (BE193 TNE, TNG only)		